PIC16LF1904/6/7

28/40/44-Pin 8-Bit Flash Microcontrollers with XLP Technology

High-Performance RISC CPU:

- C Compiler Optimized Architecture
- Only 49 Instructions
- Up to 14 Kbytes Self-Write/Read Flash Program Memory Addressing
- Up to 256 Bytes Data Memory Addressing
- Operating Speed:
  - DC – 20 MHz clock input @ 3.6V
  - DC – 16 MHz clock input @ 1.8V
  - DC – 200 ns instruction cycle
- Interrupt Capability with Automatic Context Saving
- 16-Level Deep Hardware Stack with Optional Overflow/Underflow Reset
- Direct, Indirect and Relative Addressing modes:
  - Two full 16-bit File Select Registers (FSRs)
  - FSRs can read program and data memory

Memory

- Up to 14 Kbytes Self-Write/Read Flash Program Memory Addressing
- Up to 256 Bytes Data Memory Addressing
- High-Endurance Flash Data Memory (HEF)
  - 128B of nonvolatile data storage
  - 100K erase/write cycles

Flexible Oscillator Structure:

- 16 MHz Internal Oscillator Block:
  - Accuracy to ± 3%, typical
  - Software selectable frequency range from 16 MHz to 31.25 kHz
- 31 kHz Low-Power Internal Oscillator
- Three External Clock modes up to 20 MHz
- Two-Speed Oscillator Start-up
- Low-Power RTC Implementation via LPT1OSC

Special Microcontroller Features:

- Operating Voltage Range:
  - 1.8V-3.6V
- Self-Programmable under Software Control
- Power-on Reset (POR)
- Power-up Timer (PWRT)
- Low-Power Brown-Out Reset (LPBOR)
- Extended Watchdog Timer (WDT)
- In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Enhanced Low-Voltage Programming (LVP)
- Programmable Code Protection
- Power-Saving Sleep mode

eXtreme Low-Power (XLP) Features (PIC16LF1904/6/7):

- Sleep Current:
  - 30 nA @ 1.8V, typical
- Watchdog Timer Current:
  - 300 nA @ 1.8V, typical
- Secondary Oscillator:
  - 500 nA @ 32 kHz, 1.8V, typical

Analog Features:

- Analog-to-Digital Converter (ADC):
  - 10-bit resolution, up to 14 channels
  - Conversion available during Sleep
  - Dedicated ADC RC oscillator
  - Fixed Voltage Reference (FVR) as channel
- Integrated Temperature Indicator
- Voltage Reference module:
  - Fixed Voltage Reference (FVR) with 1.024V and 2.048V output levels

Peripheral Highlights:

- Up to 36 I/O Pins and 1 Input-only Pin:
  - High current 25 mA sink/source
  - Individually programmable weak pull-ups
  - Individually programmable interrupt-on-change (IOC) pins
- Integrated LCD Controller:
  - At least 19 segment pins and as many as 116 total segments
  - Variable clock input
  - Contrast control
  - Internal voltage reference selections
- Timer0: 8-Bit Timer/Counter with 8-Bit Programmable Prescaler

- Enhanced Timer1:
  - 16-bit timer/counter with prescaler
  - External Gate Input mode
  - Dedicated low-power 32 kHz oscillator driver
- Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART):
  - RS-232, RS-485 and LIN compatible
  - Auto-Baud Detect
  - Auto-wake-up on start

PIC16LF190X Family Types

Device	Data Sheet Index	Program Memory Flash (words)	Data SRAM (bytes)	High-Endurance Flash (bytes)	I/O's(2)	10-bit ADC (ch)	Timers (8/16-bit)	EUSART	LCD			Debug(1)	XLP
									Common Pins	Segment Pins	Total Segments		
PIC16LF1902	(1)	2048	128	128	25	11	1/1	—	4	19	72(3)	H	Y
PIC16LF1903	(1)	4096	256	128	25	11	1/1	—	4	19	72(3)	H	Y
PIC16LF1904	(2)	4096	256	128	36	14	1/1	1	4	29	116	I/H	Y
PIC16LF1906	(2)	8192	512	128	25	11	1/1	1	4	19	72(3)	I/H	Y
PIC16LF1907	(2)	8192	512	128	36	14	1/1	1	4	29	116	I/H	Y

Note 1: Debugging Methods: (I) – Integrated on Chip; (H) – using Debug Header; (E) – using Emulation Header.

2: One pin is input-only.

3: COM3 and SEG15 share a pin, so the total segments are limited to 72 for 28-pin devices.

Data Sheet Index: (Unshaded devices are described in this document.)

1: DS40001455 PIC16LF1902/3 Data Sheet, 28-Pin Flash, 8-bit Microcontrollers.

2: DS40001569 PIC16LF1904/6/7 Data Sheet, 28/40/44-Pin Flash, 8-bit Microcontrollers.

Note: For other small form-factor package availability and marking information, please visit **http://www.microchip.com/packaging** or contact your local sales office.

FIGURE 1: 28-PIN PDIP, SOIC, SSOP PACKAGE DIAGRAM FOR PIC16LF1906

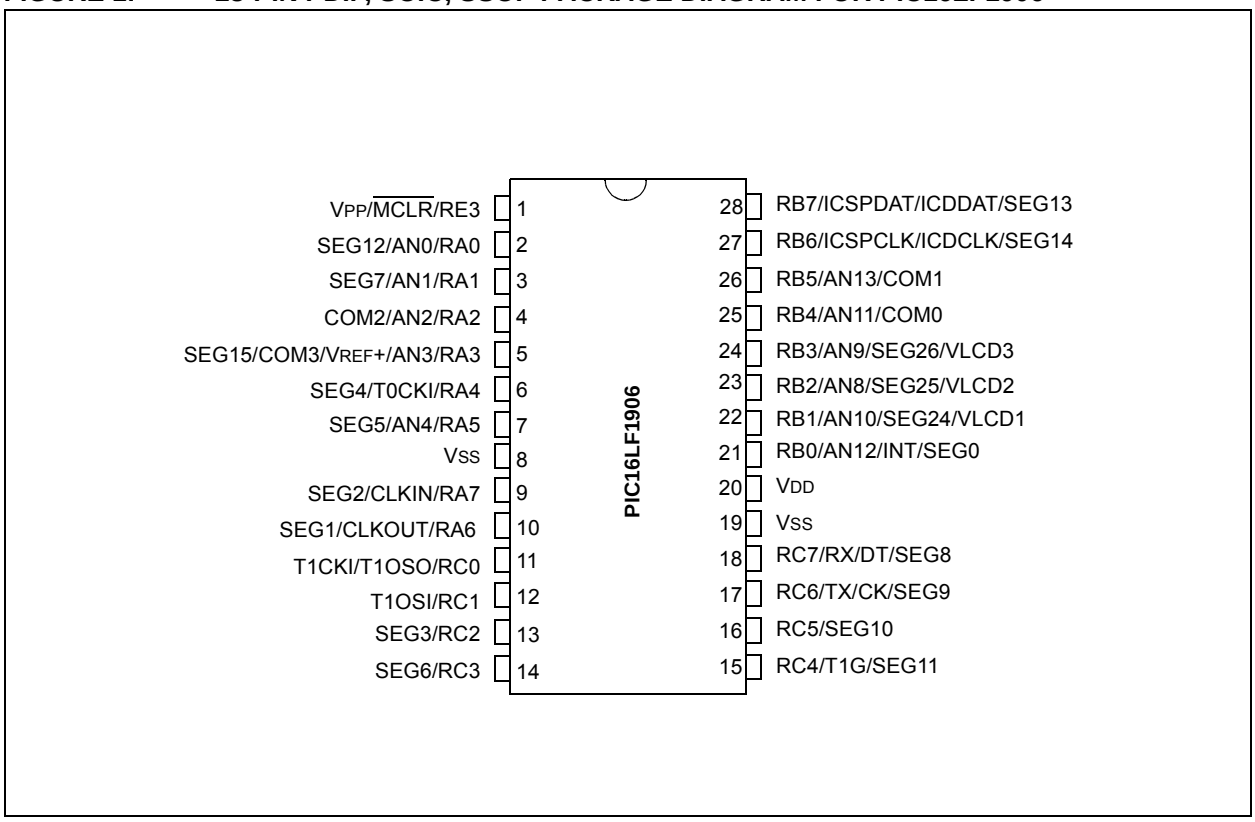

FIGURE 2: 28-PIN UQFN PACKAGE DIAGRAM FOR PIC16LF1906

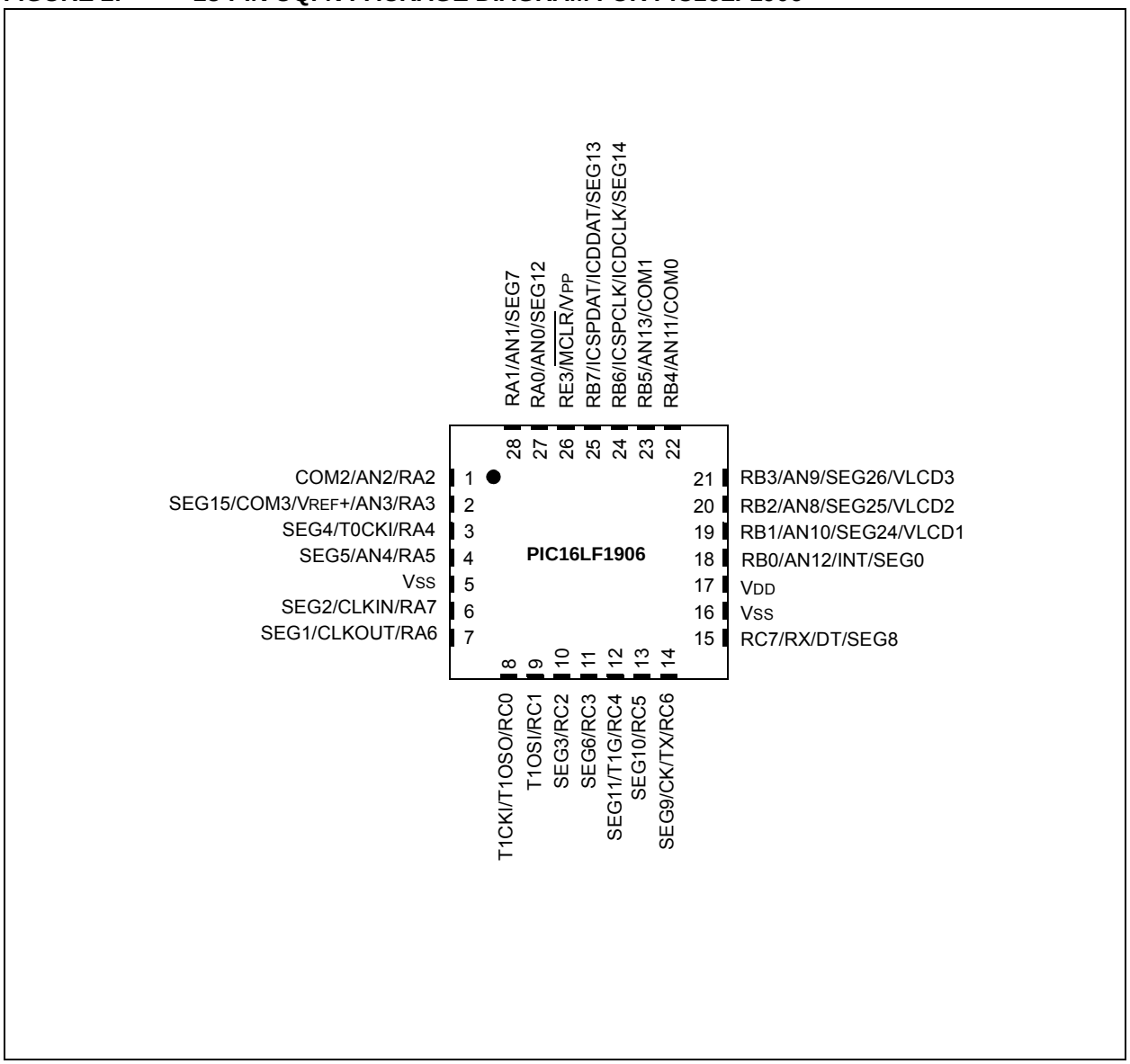

FIGURE 3: 40-PIN PDIP PACKAGE DIAGRAM FOR PIC16LF1904/7

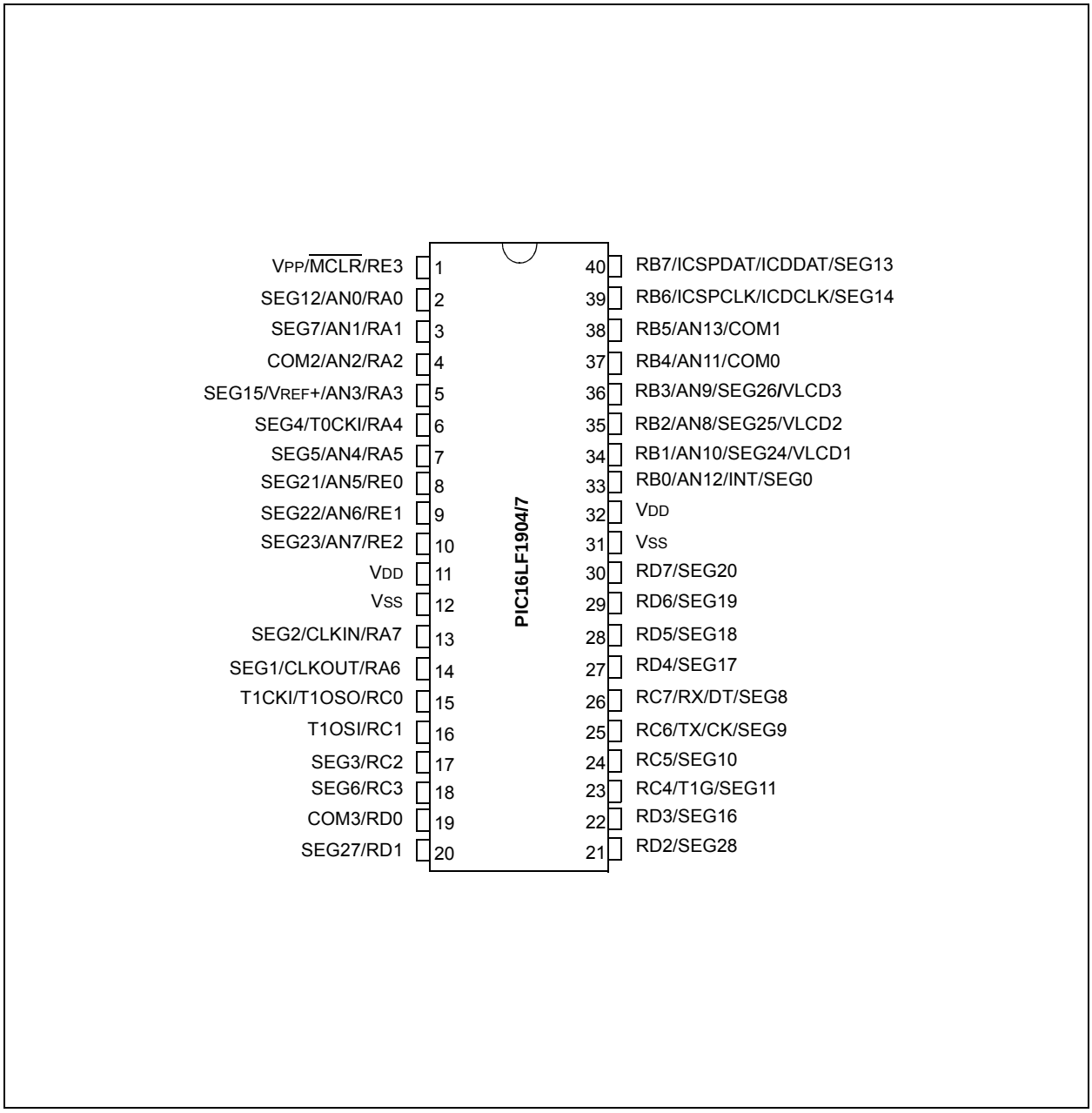

FIGURE 4: 44-PIN TQFP (10X10) PACKAGE DIAGRAM FOR PIC16LF1904/7

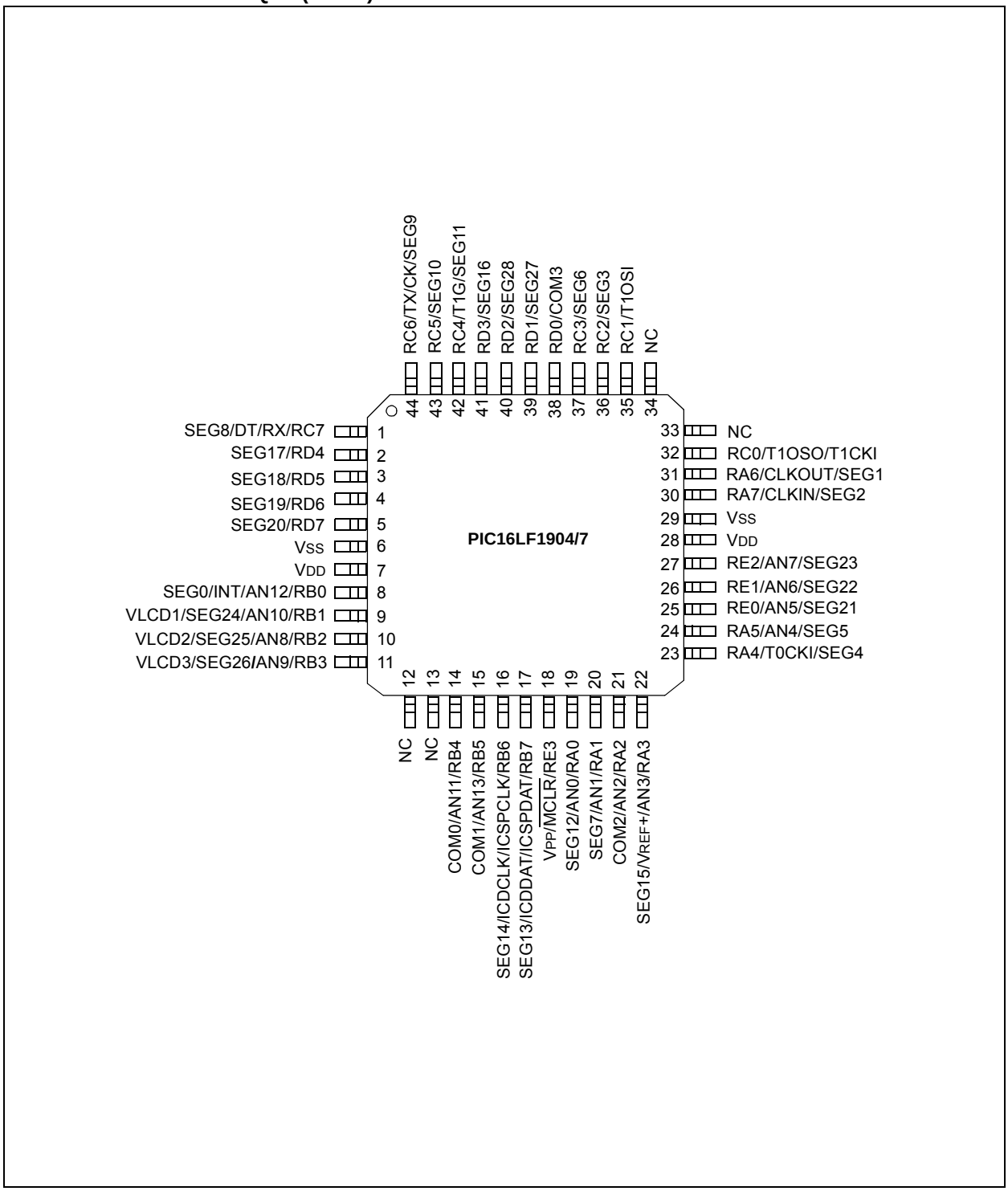

FIGURE 5: 40-PIN UQFN (5X5) PACKAGE DIAGRAM FOR PIC16LF1904/7

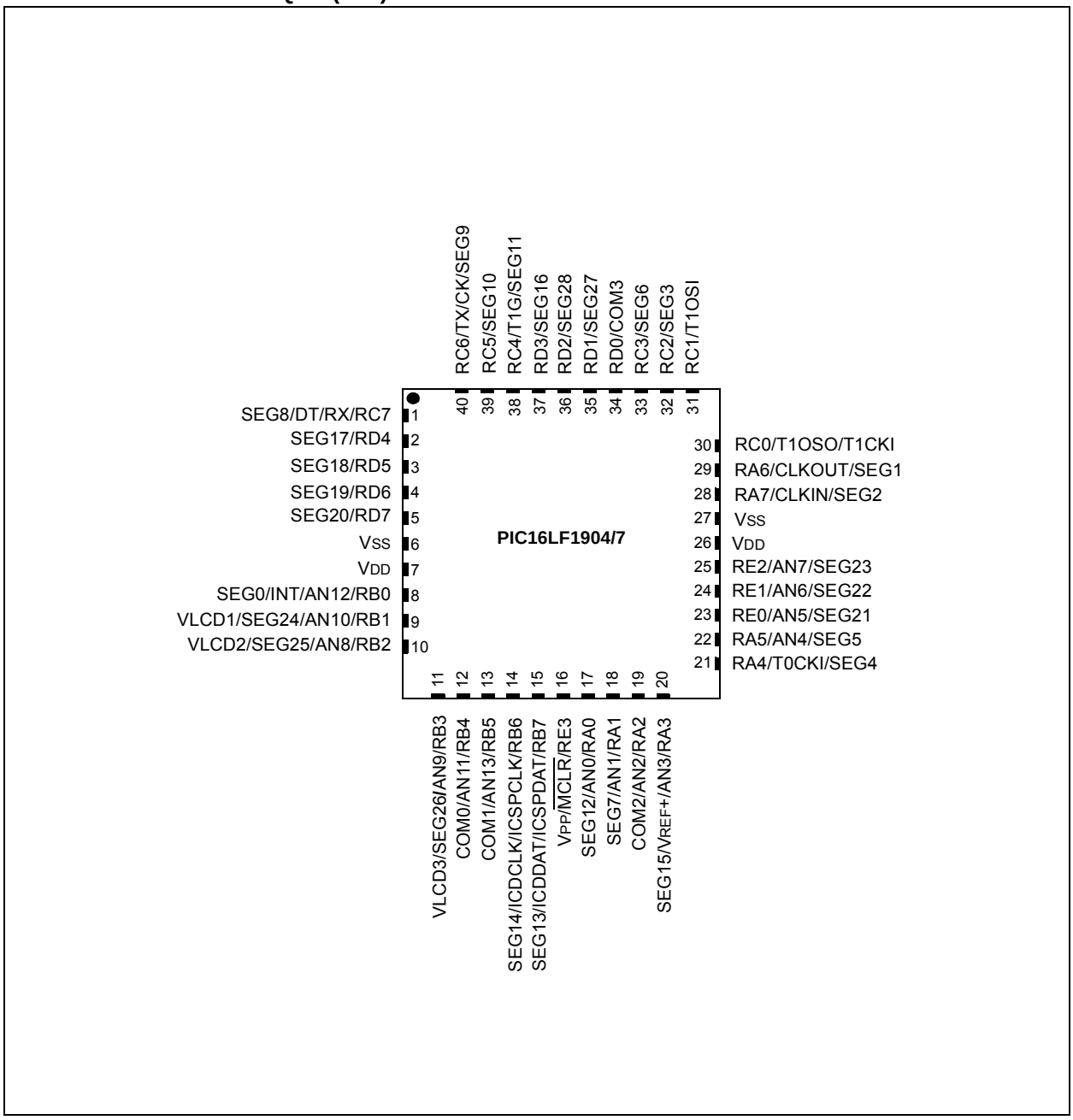

TABLE 1: 28/40/44-PIN ALLOCATION TABLE (PIC16LF1904/6/7)

I/O	28-Pin PDIP/ SOIC/SSOP	28-Pin UQFN	40-Pin PDIP	44-Pin TQFP	40-Pin UQFN	A/D	Timers	EUSART	LCD	Interrupt	Pull-up	Basic
RA0	2	27	2	19	17	AN0	—	—	SEG12	—	—	—
RA1	3	28	3	20	18	AN1	—	—	SEG7	—	—	—
RA2	4	1	4	21	19	AN2	—	—	COM2	—	—	—
RA3	5	2	5	22	20	AN3/ VREF+	—	—	SEG15/ COM3(2)	—	—	—
RA4	6	3	6	23	21	—	T0CKI	—	SEG4	—	—	—
RA5	7	4	7	24	22	AN4	—	—	SEG5	—	—	—
RA6	10	7	14	31	29	—	—	—	SEG1	—	—	CLKOUT
RA7	9	6	13	30	28	—	—	—	SEG2	—	—	CLKIN
RB0	21	18	33	8	8	AN12	—	—	SEG0	INT/ IOC	Y	—
RB1	22	19	34	9	9	AN10	—	—	VLCD1/ SEG24	IOC	Y	—
RB2	23	20	35	10	10	AN8	—	—	VLCD2/ SEG25	IOC	Y	—
RB3	24	21	36	11	11	AN9	—	—	VLCD3/ SEG26	IOC	Y	—
RB4	25	22	37	14	12	AN11	—	—	COM0	IOC	Y	—
RB5	26	23	38	15	13	AN13	—	—	COM1	IOC	Y	—
RB6	27	24	39	16	14	—	—	—	SEG14	IOC	Y	ICSPCLK/ ICDCLK
RB7	28	25	40	17	15	—	—	—	SEG13	IOC	Y	ICSPDAT/ ICDDAT
RC0	11	8	15	32	30	—	T1OSO/ T1CKI	—	—	—	—	—
RC1	12	9	16	35	31	—	T1OSI	—	—	—	—	—
RC2	13	10	17	36	32	—	—	—	SEG3	—	—	—
RC3	14	11	18	37	33	—	—	—	SEG6	—	—	—
RC4	15	12	23	42	38	—	T1G	—	SEG11	—	—	—
RC5	16	13	24	43	39	—	—	—	SEG10	—	—	—
RC6	17	14	25	44	40	—	—	TX/CK	SEG9	—	—	—
RC7	18	15	26	1	1	—	—	RX/DT	SEG8	—	—	—
RD0	—	—	19	38	34	—	—	—	COM3(3)	—	—	—
RD1	—	—	20	39	35	—	—	—	SEG27	—	—	—
RD2	—	—	21	40	36	—	—	—	SEG28	—	—	—
RD3	—	—	22	41	37	—	—	—	SEG16	—	—	—
RD4	—	—	27	2	2	—	—	—	SEG17	—	—	—
RD5	—	—	28	3	3	—	—	—	SEG18	—	—	—
RD6	—	—	29	4	4	—	—	—	SEG19	—	—	—
RD7	—	—	30	5	5	—	—	—	SEG20	—	—	—
RE0	—	—	8	25	23	AN5(4)	—	—	SEG21	—	—	—
RE1	—	—	9	26	24	AN6(4)	—	—	SEG22	—	—	—
RE2	—	—	10	27	25	AN7(4)	—	—	SEG23	—	—	—
RE3	1	26	1	18	16	—	—	—	—	—	Y(1)	$\overline{MCLR}$/VPP
VDD	20	17	11,32	7,28	7, 26	—	—	—	—	—	—	VDD
Vss	8,19	5,16	12,31	6,29	6, 27	—	—	—	—	—	—	VSS
NC	—	—	—	12,13, 33,34	—	—	—	—	—	—	—	VDD

Note 1: Weak pull-up always enabled when $\overline{MCLR}$ is enabled, otherwise the pull-up is under user control.
2: 28-pin only pin location (PIC16LF1906). Location different on 40/44-pin device.
3: 40/44-pin only pin location (PIC16LF1904/7). Location different on 28-pin device.
4: ADC channel is reserved on the PIC16LF1906 28-pin devices.

Table of Contents

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1.0 DEVICE OVERVIEW

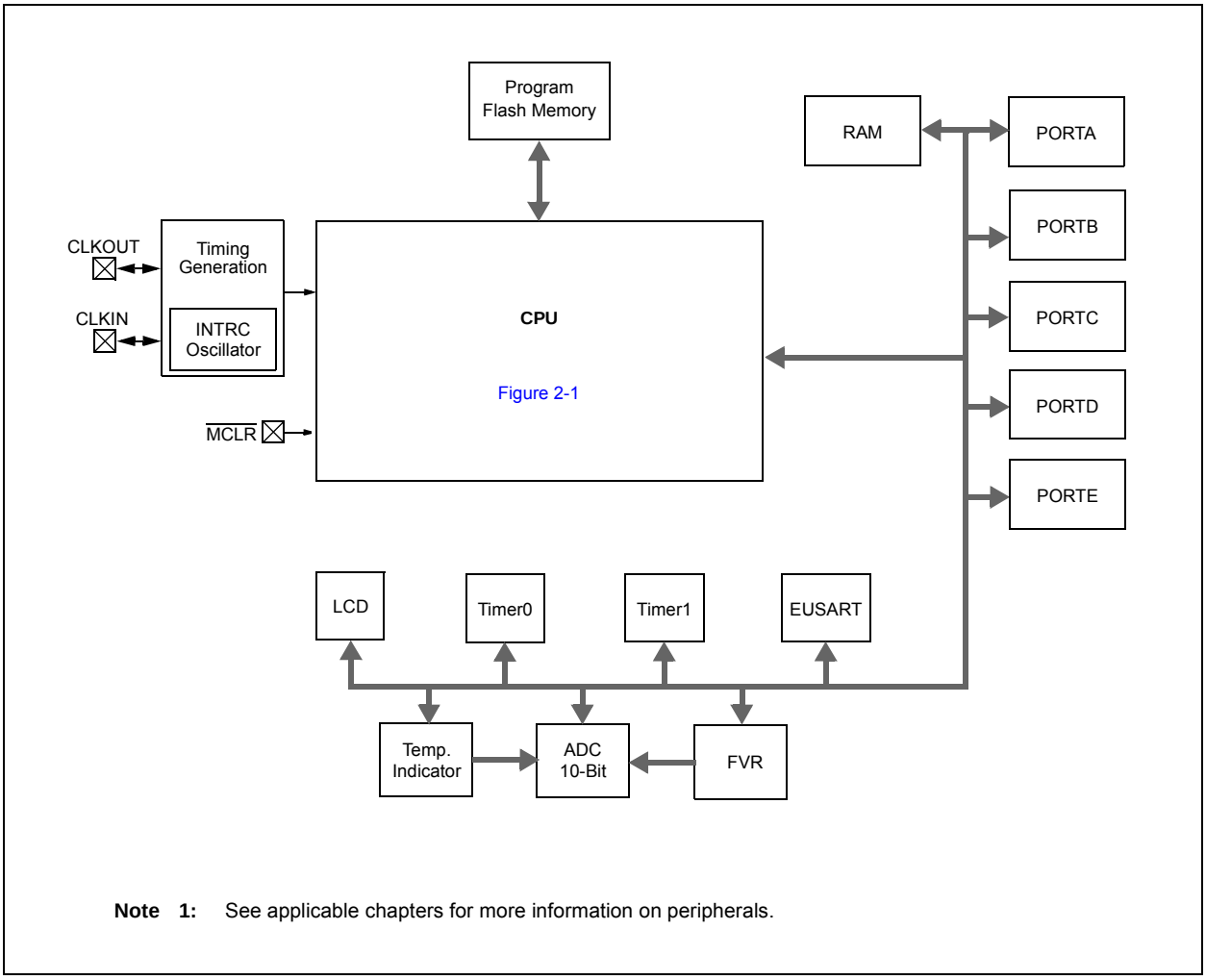
The PIC16LF1904/6/7 are described within this data sheet. They are available in 28, 40 and 44-pin packages. Figure 1-1 shows a block diagram of the PIC16LF1904/6/7 devices. Table 1-2 shows the pinout descriptions.

Reference Table 1-1 for peripherals available per device.

TABLE 1-1: DEVICE PERIPHERAL SUMMARY

Peripheral		PIC16LF1906	PIC16LF1904/7
ADC		●	●
EUSART		●	●
Fixed Voltage Reference (FVR)		●	●
LCD		●	●
Temperature Indicator		●	●
Timers			
	Timer0	●	●
	Timer1	●	●

FIGURE 1-1: PIC16LF1904/6/7 BLOCK DIAGRAM



Note 1: See applicable chapters for more information on peripherals.

TABLE 1-2: PIC16LF1904/6/7 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/SEG12	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel 0 input.
	SEG12	—	AN	LCD Analog output.
RA1/AN1/SEG7	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel 1 input.
	SEG7	—	AN	LCD Analog output.
RA2/AN2/COM2	RA2	TTL	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel 2 input.
	COM2	—	AN	LCD Analog output.
RA3/AN3/VREF+/COM3(2)/ SEG15	RA3	TTL	CMOS	General purpose I/O.
	AN3	AN	—	A/D Channel 3 input.
	VREF+	AN	—	A/D Voltage Reference input.
	COM3	—	AN	LCD Analog output.
	SEG15	—	AN	LCD Analog output.
RA4/T0CKI/SEG4	RA4	TTL	CMOS	General purpose I/O.
	T0CKI	ST	—	Timer0 clock input.
	SEG4	—	AN	LCD Analog output.
RA5/AN4/SEG5	RA5	TTL	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	SEG5	—	AN	LCD Analog output.
RA6/CLKOUT/SEG1	RA6	TTL	CMOS	General purpose I/O.
	CLKOUT	—	CMOS	FOSC/4 output.
	SEG1	—	AN	LCD Analog output.
RA7/CLKIN/SEG2	RA7	TTL	CMOS	General purpose I/O.
	CLKIN	CMOS	—	External clock input (EC mode).
	SEG2	—	AN	LCD Analog output.
RB0/AN12/INT/SEG0	RB0	TTL	CMOS	General purpose I/O.
	AN12	AN	—	A/D Channel 12 input.
	INT	ST	—	External interrupt.
	SEG0	—	AN	LCD Analog output.
RB1(1)/AN10/SEG24/VLCD1	RB1	TTL	CMOS	General purpose I/O.
	AN10	AN	—	A/D Channel 10 input.
	SEG24	—	AN	LCD Analog output.
	VLCD1	AN	—	LCD analog input.
RB2(1)/AN8/SEG25/VLCD2	RB2	TTL	CMOS	General purpose I/O.
	AN8	AN	—	A/D Channel 8 input.
	SEG25	—	AN	LCD Analog output.
	VLCD2	AN	—	LCD analog input.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C levels
HV = High Voltage; XTAL = Crystal

Note 1: These pins have interrupt-on-change functionality.
2: PIC16LF1906/7 only.

TABLE 1-2: PIC16LF1904/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB3(1)/AN9/SEG26/VLCD3	RB3	TTL	CMOS	General purpose I/O.
	AN9	AN	—	A/D Channel 9 input.
	SEG26	—	AN	LCD Analog output.
	VLCD3	AN	—	LCD analog input.
RB4(1)/AN11/COM0	RB4	TTL	CMOS	General purpose I/O.
	AN11	AN	—	A/D Channel 11 input.
	COM0	—	AN	LCD Analog output.
RB5(1)/AN13/COM1	RB5	TTL	CMOS	General purpose I/O.
	AN13	AN	—	A/D Channel 13 input.
	COM1	—	AN	LCD Analog output.
RB6(1)/ICSPCLK/ICDCLK/ SEG14	RB6	TTL	CMOS	General purpose I/O.
	ICSPCLK	ST	—	Serial Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
	SEG14	—	AN	LCD Analog output.
RB7(1)/ICSPDAT/ICDDAT/ SEG13	RB7	TTL	CMOS	General purpose I/O.
	ICSPDAT	ST	—	Serial Programming Clock.
	ICDDAT	ST	CMOS	In-Circuit Data I/O.
	SEG13	—	AN	LCD Analog output.
RC0/T1OSO/T1CKI	RC0	TTL	CMOS	General purpose I/O.
	T1OSO	XTAL	XTAL	Timer1 oscillator connection.
	T1CKI	ST	—	Timer1 clock input.
RC1/T1OSI	RC1	TTL	CMOS	General purpose I/O.
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
RC2/SEG3	RC2	TTL	CMOS	General purpose I/O.
	SEG3	—	AN	LCD Analog output.
RC3/SEG6	RC3	TTL	CMOS	General purpose I/O.
	SEG6	—	AN	LCD Analog output.
RC4/T1G/SEG11	RC4	TTL	CMOS	General purpose I/O.
	T1G	XTAL	XTAL	Timer1 oscillator connection.
	SEG11	—	AN	LCD Analog output.
RC5/SEG10	RC5	TTL	CMOS	General purpose I/O.
	SEG10	—	AN	LCD Analog output.
RC6/TX/CK/SEG9	RC6	TTL	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	SEG9	—	AN	LCD Analog output.
RC7/RX/DT/SEG8	RC7	TTL	CMOS	General purpose I/O.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	SEG8	—	AN	LCD Analog output.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: These pins have interrupt-on-change functionality.
2: PIC16LF1906/7 only.

TABLE 1-2: PIC16LF1904/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RD0(2)/COM3	RD0	TTL	CMOS	General purpose I/O.
	COM3	—	AN	LCD Analog output.
RD1(2)/SEG27	RD1	TTL	CMOS	General purpose I/O.
	SEG27	—	AN	LCD Analog output.
RD2(2)/SEG28	RD2	TTL	CMOS	General purpose I/O.
	SEG28	—	AN	LCD Analog output.
RD3(2)/SEG16	RD3	TTL	CMOS	General purpose I/O.
	SEG16	—	AN	LCD Analog output.
RD4(2)/SEG17	RD4	TTL	CMOS	General purpose I/O.
	SEG17	—	AN	LCD Analog output.
RD5(2)/SEG18	RD5	TTL	CMOS	General purpose I/O.
	SEG18	—	AN	LCD Analog output.
RD6(2)/SEG19	RD6	TTL	CMOS	General purpose I/O.
	SEG19	—	AN	LCD Analog output.
RD7(2)/SEG20	RD7	TTL	CMOS	General purpose I/O.
	SEG20	—	AN	LCD Analog output.
RE0(2)/AN5/SEG21	RE0	TTL	CMOS	General purpose I/O.
	AN5	AN	—	A/D Channel 5 input.
	SEG21	—	AN	LCD Analog output.
RE1(2)/AN6/SEG22	RE1	TTL	CMOS	General purpose I/O.
	AN6	AN	—	A/D Channel 6 input.
	SEG22	—	AN	LCD Analog output.
RE2(2)/AN7/SEG23	RE2	TTL	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
	SEG23	—	AN	LCD Analog output.
RE3/$\overline{MCLR}$/VPP	RE3	TTL	CMOS	General purpose I/O.
	$\overline{MCLR}$	ST	—	Master Clear with internal pull-up.
	VPP	HV	—	Programming voltage.
VDD	VDD	Power	—	Positive supply.
VSS	VSS	Power	—	Ground reference.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C levels
HV = High Voltage; XTAL = Crystal

Note 1: These pins have interrupt-on-change functionality.
2: PIC16LF1906/7 only.

2.0 ENHANCED MID-RANGE CPU

This family of devices contain an enhanced mid-range 8-bit CPU core. The CPU has 49 instructions. Interrupt capability includes automatic context saving. The hardware stack is 16 levels deep and has Overflow and Underflow Reset capability. Direct, Indirect, and Relative addressing modes are available. Two File Select Registers (FSRs) provide the ability to read program and data memory.

- Automatic Interrupt Context Saving
- 16-level Stack with Overflow and Underflow
- File Select Registers
- Instruction Set

2.1 Automatic Interrupt Context Saving

During interrupts, certain registers are automatically saved in shadow registers and restored when returning from the interrupt. This saves stack space and user code. See **Section 7.5 "Automatic Context Saving"**, for more information.

2.2 16-Level Stack with Overflow and Underflow

These devices have an external stack memory 15 bits wide and 16 words deep. A Stack Overflow or Underflow will set the appropriate bit (STKOVF or STKUNF) in the PCON register, and if enabled, will cause a software Reset. See **Section 3.4 "Stack"** for more details.

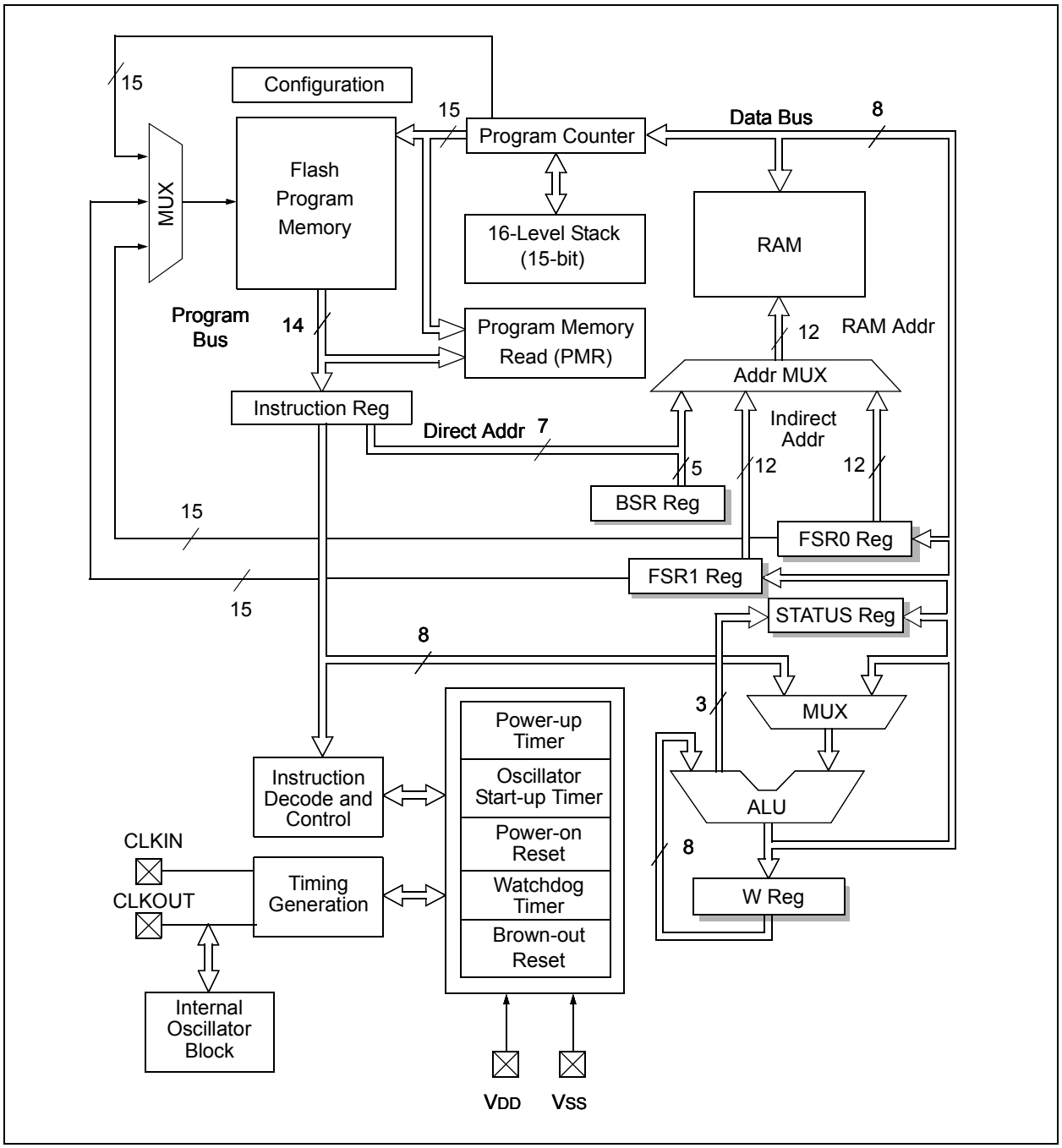
2.3 File Select Registers

There are two 16-bit File Select Registers (FSR). FSRs can access all file registers and program memory, which allows one Data Pointer for all memory. When an FSR points to program memory, there is one additional instruction cycle in instructions using INDF to allow the data to be fetched. General purpose memory can now also be addressed linearly, providing the ability to access contiguous data larger than 80 bytes. There are also new instructions to support the FSRs. See **Section 3.5 "Indirect Addressing"** for more details.

2.4 Instruction Set

There are 49 instructions for the enhanced mid-range CPU to support the features of the CPU. See **Section 21.0 "Instruction Set Summary"** for more details.

FIGURE 2-1: CORE BLOCK DIAGRAM



3.0 MEMORY ORGANIZATION

These devices contain the following types of memory:

- Program Memory
  - Configuration Words
  - Device ID
  - User ID
  - Flash Program Memory
- Data Memory
  - Core Registers
  - Special Function Registers
  - General Purpose RAM
  - Common RAM

The following features are associated with access and control of program memory and data memory:

- PCL and PCLATH
- Stack
- Indirect Addressing

3.1 Program Memory Organization

The enhanced mid-range core has a 15-bit program counter capable of addressing 32K x 14 program memory space. Table 3-1 shows the memory sizes implemented for the PIC16LF1904/6/7 family. Accessing a location above these boundaries will cause a wrap-around within the implemented memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figures 3-1, and 3-2).

TABLE 3-1: DEVICE SIZES AND ADDRESSES

Device	Program Memory Space (Words)	Last Program Memory Address	High-Endurance Flash Memory Address Range (1)
PIC16LF1904	4,096	0FFFh	0F80h-0FFFh
PIC16LF1906/7	8,192	1FFFh	1F80h-1FFFh

Note 1: High-endurance Flash applies to low byte of each address in the range.

FIGURE 3-1: PROGRAM MEMORY MAP AND STACK FOR PIC16LF1904

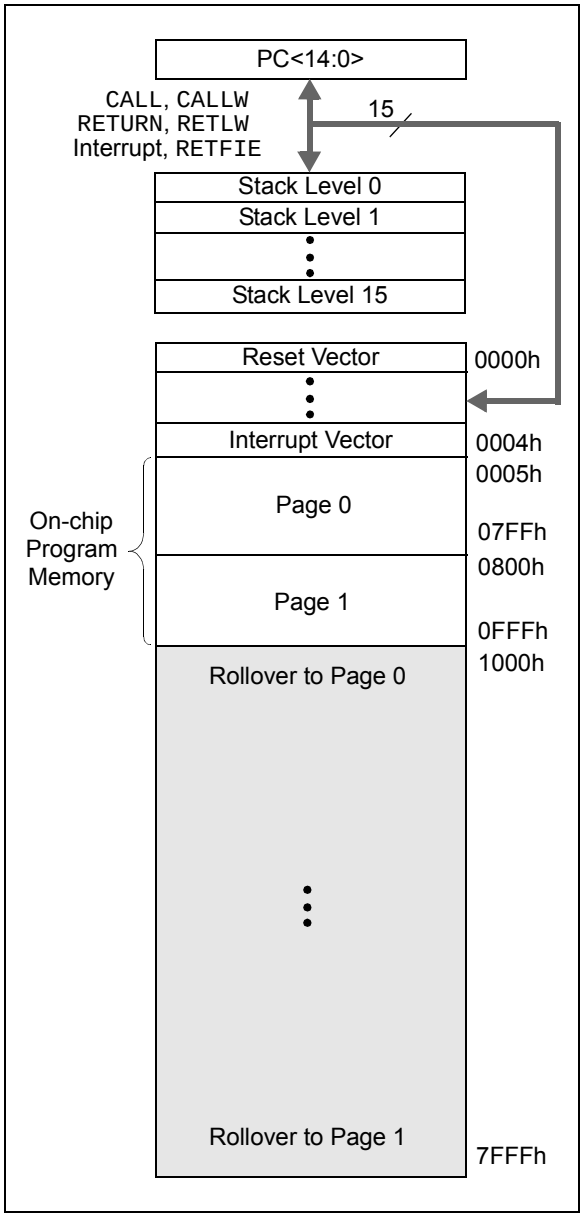
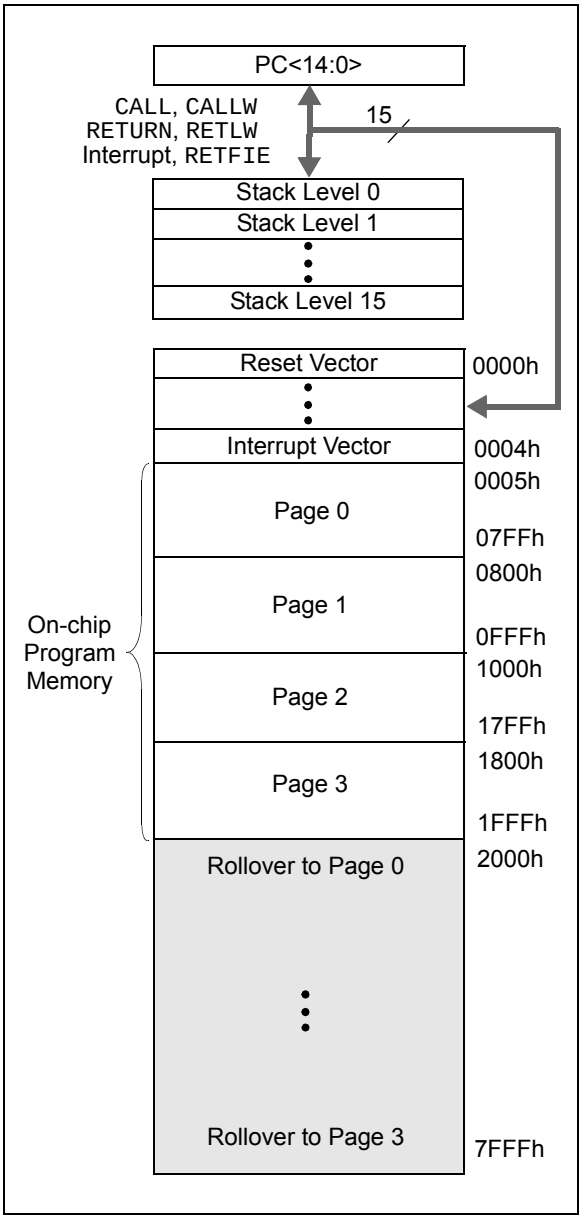


FIGURE 3-2: PROGRAM MEMORY MAP AND STACK FOR PIC16LF1906/7



3.1.1 READING PROGRAM MEMORY AS DATA

There are two methods of accessing constants in program memory. The first method is to use tables of RETLW instructions. The second method is to set an FSR to point to the program memory.

3.1.1.1 RETLW Instruction

The RETLW instruction can be used to provide access to tables of constants. The recommended way to create such a table is shown in Example 3-1.

EXAMPLE 3-1: RETLW INSTRUCTION

```
constants
    BRW                 ;Add Index in W to
                        ;program counter to
                        ;select data
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3


my_function
    ;… LOTS OF CODE…
    MOVLW       DATA_INDEX
    call constants
    ;… THE CONSTANT IS IN W
```

The BRW instruction makes this type of table very simple to implement. If your code must remain portable with previous generations of microcontrollers, then the BRW instruction is not available so the older table read method must be used.

3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower eight bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The HIGH directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW   LOW constants
    MOVWF   FSR1L
    MOVLW   HIGH constants
    MOVWF   FSR1H
    MOVIW 0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

3.2 Data Memory Organization

The data memory is partitioned in 32 memory banks with 128 bytes in a bank. Each bank consists of (Figure 3-3):

- 12 core registers
- 20 Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '0'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See **Section 3.5 "Indirect Addressing"** for more information.

Data memory uses a 12-bit address. The upper seven bits of the address define the Bank Address and the lower five bits select the registers/RAM in that bank.

3.2.1 CORE REGISTERS

The core registers contain the registers that directly affect the basic operation. The core registers occupy the first 12 addresses of every data memory bank (addresses x00h/x08h through x0Bh/x8Bh). These registers are listed below in Table 3-2. For detailed information, see Table 3-4.

TABLE 3-2: CORE REGISTERS

Addresses	BANKx
x00h or x80h	INDF0
x01h or x81h	INDF1
x02h or x82h	PCL
x03h or x83h	STATUS
x04h or x84h	FSR0L
x05h or x85h	FSR0H
x06h or x86h	FSR1L
x07h or x87h	FSR1H
x08h or x88h	BSR
x09h or x89h	WREG
x0Ah or x8Ah	PCLATH
x0Bh or x8Bh	INTCON

3.2.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as '`000u u1uu`' (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 21.0 "Instruction Set Summary"**).

Note:	The C and DC bits operate as $\overline{Borrow}$ and $\overline{Digit\ Borrow}$ out bits, respectively, in subtraction.

REGISTER 3-1: STATUS: STATUS REGISTER

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC(1)	C(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{TO}$:** Time-out bit
`1` = After power-up, `CLRWDT` instruction or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-Down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Digit\ Borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
`1` = A carry-out from the 4th low-order bit of the result occurred
`0` = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{Borrow}$ bit(1) (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{Borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

3.2.2 SPECIAL FUNCTION REGISTER

The Special Function Registers are registers used by the application to control the desired operation of peripheral functions in the device. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh). The registers associated with the operation of the peripherals are described in the appropriate peripheral chapter of this data sheet.

3.2.3 GENERAL PURPOSE RAM

There are up to 80 bytes of GPR in each data memory bank. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh).

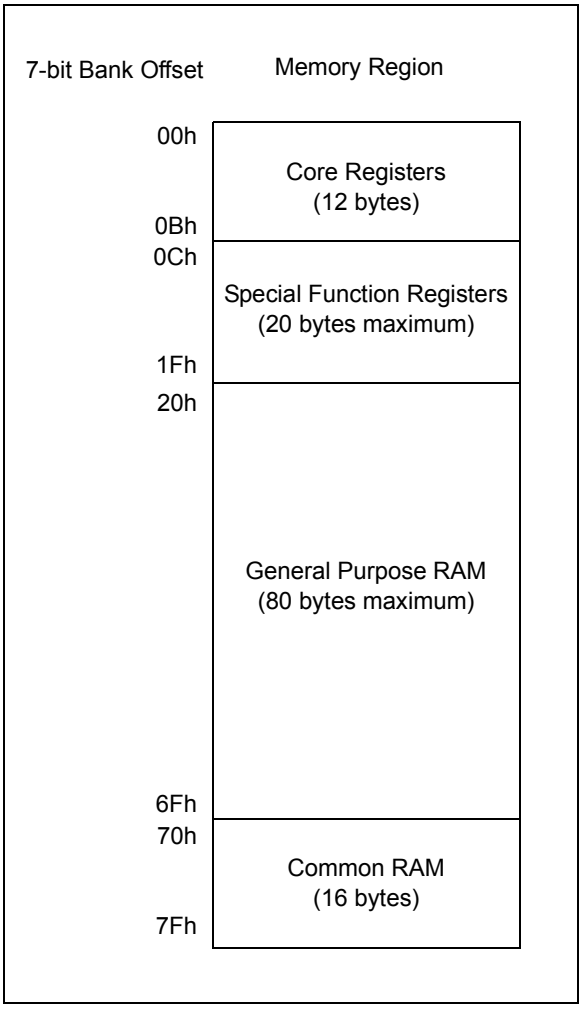
3.2.3.1 Linear Access to GPR

The general purpose RAM can be accessed in a non-banked method via the FSRs. This can simplify access to large memory structures. See **Section 3.5.2 "Linear Data Memory"** for more information.

3.2.4 COMMON RAM

There are 16 bytes of common RAM accessible from all banks.

FIGURE 3-3: BANKED MEMORY PARTITIONING



3.2.5 DEVICE MEMORY MAPS

The memory maps for PIC16LF1904/6/7 are as shown in Table 3-3.

TABLE 3-3: PIC16LF1904/6/7 MEMORY MAP

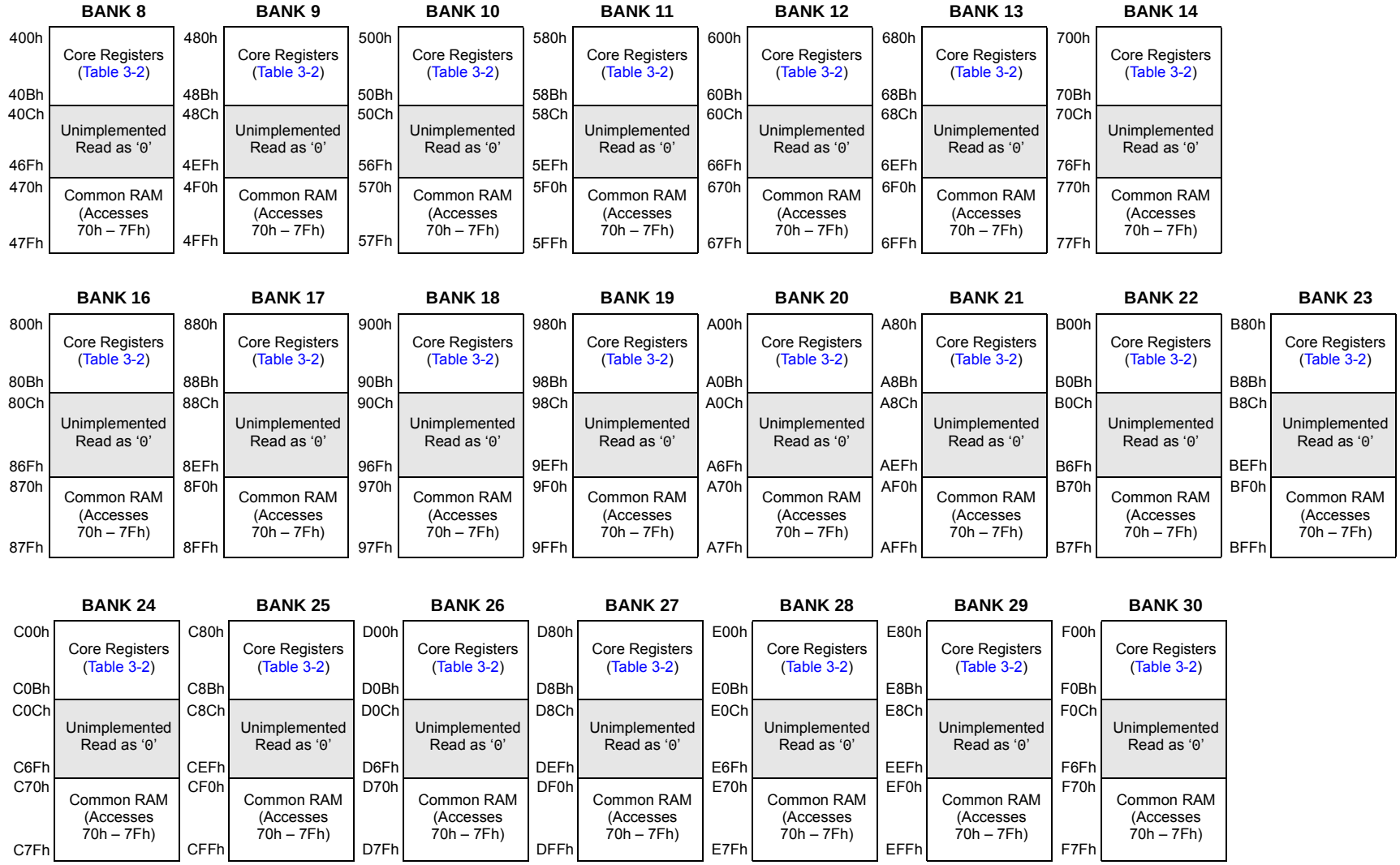
	BANK 0	BANK 1	BANK 2	BANK 3	BANK 4	BANK 5	BANK 6	BANK 7
000h	Core Registers (Table 3-2)	080h Core Registers (Table 3-2)	100h Core Registers (Table 3-2)	180h Core Registers (Table 3-2)	200h Core Registers (Table 3-2)	280h Core Registers (Table 3-2)	300h Core Registers (Table 3-2)	380h Core Registers (Table 3-2)
00Bh		08Bh	10Bh	18Bh	20Bh	28Bh	30Bh	38Bh
00Ch	PORTA	08Ch TRISA	10Ch LATA	18Ch ANSELA	20Ch —	28Ch —	30Ch —	38Ch —
00Dh	PORTB	08Dh TRISB	10Dh LATB	18Dh ANSELB	20Dh WPUB	28Dh —	30Dh —	38Dh —
00Eh	PORTC	08Eh TRISC	10Eh LATC	18Eh —	20Eh —	28Eh —	30Eh —	38Eh —
00Fh	PORTD(1)	08Fh TRISD(1)	10Fh LATD(1)	18Fh —	20Fh —	28Fh —	30Fh —	38Fh —
010h	PORTE	090h TRISE(1)	110h LATE(1)	190h ANSELE(1)	210h WPUE	290h —	310h —	390h —
011h	PIR1	091h PIE1	111h —	191h PMADRL	211h —	291h —	311h —	391h —
012h	PIR2	092h PIE2	112h —	192h PMADRH	212h —	292h —	312h —	392h —
013h	—	093h —	113h —	193h PMDATL	213h —	293h —	313h —	393h —
014h	—	094h —	114h —	194h PMDATH	214h —	294h —	314h —	394h IOCBP
015h	TMR0	095h OPTION_REG	115h —	195h PMCON1	215h —	295h —	315h —	395h IOCBN
016h	TMR1L	096h PCON	116h BORCON	196h PMCON2	216h —	296h —	316h —	396h IOCBF
017h	TMR1H	097h WDTCON	117h FVRCON	197h —	217h —	297h —	317h —	397h —
018h	T1CON	098h —	118h —	198h —	218h —	298h —	318h —	398h —
019h	T1GCON	099h OSCCON	119h —	199h RCREG	219h —	299h —	319h —	399h —
01Ah	—	09Ah OSCSTAT	11Ah —	19Ah TXREG	21Ah —	29Ah —	31Ah —	39Ah —
01Bh	—	09Bh ADRESL	11Bh —	19Bh SPBRG	21Bh —	29Bh —	31Bh —	39Bh —
01Ch	—	09Ch ADRESH	11Ch —	19Ch SPBRGH	21Ch —	29Ch —	31Ch —	39Ch —
01Dh	—	09Dh ADCON0	11Dh —	19Dh RCSTA	21Dh —	29Dh —	31Dh —	39Dh —
01Eh	—	09Eh ADCON1	11Eh —	19Eh TXSTA	21Eh —	29Eh —	31Eh —	39Eh —
01Fh	—	09Fh —	11Fh —	19Fh BAUDCON	21Fh —	29Fh —	31Fh —	39Fh —
020h	General Purpose Register 96 Bytes	0A0h General Purpose Register 80 Bytes	120h General Purpose Register 80 Bytes	1A0h General Purpose Register 80 Bytes(2)	220h General Purpose Register 80 Bytes(2)	2A0h General Purpose Register 80 Bytes(2)	320h General Purpose Register 32 Bytes(2)	3A0h Unimplemented Read as '0'
06Fh		0EFh	16Fh	1EFh	26Fh	2EFh	36Fh Unimplemented Read as '0'	3EFh
070h		0F0h Accesses 70h – 7Fh	170h Accesses 70h – 7Fh	1F0h Accesses 70h – 7Fh	270h Accesses 70h – 7Fh	2F0h Accesses 70h – 7Fh	370h Accesses 70h – 7Fh	3F0h Accesses 70h – 7Fh
07Fh		0FFh	17Fh	1FFh	27Fh	2FFh	37Fh	3FFh

Legend: = Unimplemented data memory locations, read as '0'.

Note 1: PIC16LF1904/7 only.

2: PIC16LF1906/7 only.

TABLE 3-3: PIC16LF1904/6/7 MEMORY MAP (CONTINUED)



Legend: = Unimplemented data memory locations, read as '0'

TABLE 3-3: PIC16LF1904/6/7 MEMORY MAP (CONTINUED)

	BANK 15		BANK 31
780h	Core Registers (Table 3-2)	F80h	Core Registers (Table 3-2)
78Bh		F8Bh	
78Ch	Unimplemented Read as '0'	F8Ch	Unimplemented Read as '0'
790h		FE3h	
791h	LCDCON	FE4h	STATUS_SHAD
792h	LCDPS	FE5h	WREG_SHAD
793h	LCDREF	FE6h	BSR_SHAD
794h	LCDCST	FE7h	PCLATH_SHAD
795h	LCDRL	FE8h	FSR0L_SHAD
796h	—	FE9h	FSR0H_SHAD
797h	—	FEAh	FSR1L_SHAD
798h	LCDSE0	FEBh	FSR1H_SHAD
799h	LCDSE1	FECh	—
79Ah	LCDSE2(1)	FEDh	STKPTR
79Bh	LCDSE3	FEEh	TOSL
79Ch	Unimplemented Read as '0'	FEFh	TOSH
79Fh		FF0h	Common RAM (Accesses 70h – 7Fh)
7A0h	LCDDATA0	FFFh	
7A1h	LCDDATA1		
7A2h	LCDDATA2(1)		
7A3h	LCDDATA3		
7A4h	LCDDATA4		
7A5h	LCDDATA5(1)		
7A6h	LCDDATA6		
7A7h	LCDDATA7		
7A8h	LCDDATA8(1)		
7A9h	LCDDATA9		
7AAh	LCDDATA10		
7ABh	LCDDATA11(1)		
7ACh	LCDDATA12		
7ADh	—		
7AEh	—		
7AFh	LCDDATA15		
7B0h	—		
7B1h	—		
7B2h	LCDDATA18		
7B3h	—		
7B4h	—		
7B5h	LCDDATA21		
7B6h	—		
7B7h	—		
7B8h	Unimplemented Read as '0'		
7EFh			

Legend: = Unimplemented data memory locations, read as '0'.

Note 1: PIC16LF1904/7 only.

3.2.6 CORE FUNCTION REGISTERS SUMMARY

The Core Function registers listed in Table 3-4 can be addressed from any Bank.

TABLE 3-4: CORE FUNCTION REGISTERS SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 0-31											
x00h or x80h	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
x01h or x81h	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
x02h or x82h	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
x03h or x83h	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
x04h or x84h	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
x05h or x85h	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
x06h or x86h	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
x07h or x87h	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
x08h or x88h	BSR	—	—	—	BSR4	BSR3	BSR2	BSR1	BSR0	---0 0000	---0 0000
x09h or x89h	WREG	Working Register								0000 0000	uuuu uuuu
x0Ah or x8Ah	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
x0Bh or x8Bh	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 0											
00Ch	PORTA	PORTA Data Latch when written: PORTA pins when read								xxxx xxxx	uuuu uuuu
00Dh	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
00Eh	PORTC	PORTC Data Latch when written: PORTC pins when read								xxxx xxxx	uuuu uuuu
00Fh	PORTD(3)	PORTD Data Latch when written: PORTD pins when read								xxxx xxxx	uuuu uuuu
010h	PORTE	—	—	—	—	RE3	RE2(2)	RE1(2)	RE0(2)	---- xxxx	---- uuuu
011h	PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	0000 ---0	0000 ---0
012h	PIR2	—	—	—	—	—	LCDIF	—	—	---0 -0--	---0 -0--
013h	—	Unimplemented								—	—
014h	—	Unimplemented								—	—
015h	TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
016h	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
017h	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
018h	T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	0000 00-0	uuuu uu-u
019h	T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	0000 0x00	uuuu uxuu
01Ah to 01Fh	—	Unimplemented								—	—
Bank 1											
08Ch	TRISA	PORTA Data Direction Register								1111 1111	1111 1111
08Dh	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
08Eh	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
08Fh	TRISD(3)	PORTD Data Direction Register								1111 1111	1111 1111
090h	TRISE	—	—	—	—	—(2)	TRISE2(3)	TRISE1(3)	TRISE0(3)	---- 1111	---- 1111
091h	PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	0000 ---0	0000 ---0
092h	PIE2	—	—	—	—	—	LCDIE	—	—	---- -0--	---- -0--
093h	—	Unimplemented								—	—
094h	—	Unimplemented								—	—
095h	OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
096h	PCON	STKOVF	STKUNF	—	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	00-1 11qq	qq-q qquu
097h	WDTCON	—	—	WDTPS4	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN	--01 0110	--01 0110
098h	—	Unimplemented								—	—
099h	OSCCON	—	IRCF3	IRCF2	IRCF1	IRCF0	—	SCS1	SCS0	-011 1-00	-011 1-00
09Ah	OSCSTAT	T1OSCR	—	OSTS	HFIOFR	—	—	LFIOFR	HFIOFS	0-q0 --00	q-qq --0q
09Bh	ADRESL	A/D Result Register Low								xxxx xxxx	uuuu uuuu
09Ch	ADRESH	A/D Result Register High								xxxx xxxx	uuuu uuuu
09Dh	ADCON0	—	CHS4	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	-000 0000	-000 0000
09Eh	ADCON1	ADFM	ADCS2	ADCS1	ADCS0	—	—	ADPREF1	ADPREF0	0000 ----	0000 ----
09Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

3: PIC16LF1904/7 only.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 2											
10Ch	LATA	PORTA Data Latch								xxxx xxxx	uuuu uuuu
10Dh	LATB	PORTB Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATC	PORTC Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATD(3)	PORTD Data Latch								xxxx xxxx	uuuu uuuu
10Eh	LATE(3)	—	—	—	—	—	LATE2	LATE1	LATE0	---- -xxx	---- -uuu
111h to 115h	—	Unimplemented								—	—
116h	BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	10-- ---q	uu-- ---u
117h	FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR1	ADFVR0	0q00 --00	0q00 --00
118h to 11Fh	—	Unimplemented								—	—
Bank 3											
18Ch	ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	--1- 1111	--11 1111
18Dh	ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
18Eh	—	Unimplemented								—	—
18Fh	—	Unimplemented								—	—
190h	ANSELE(3)	—	—	—	—	—	ANSE2	ANSE1	ANSE0	---- -111	---- -111
191h	PMADRL	Program Memory Address Register Low Byte								0000 0000	0000 0000
192h	PMADRH	—(2)	Program Memory Address Register High Byte							1000 0000	1000 0000
193h	PMDATL	Program Memory Read Data Register Low Byte								xxxx xxxx	uuuu uuuu
194h	PMDATH	—	—	Program Memory Read Data Register High Byte						--xx xxxx	--uu uuuu
195h	PMCON1	—(2)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	1000 x000	1000 q000
196h	PMCON2	Program Memory Control Register 2								0000 0000	0000 0000
197h	—	Unimplemented								—	—
198h	—	Unimplemented								—	—
199h	RCREG	USART Receive Data Register								0000 0000	0000 0000
19Ah	TXREG	USART Transmit Data Register								0000 0000	0000 0000
19Bh	SPBRG	BRG<7:0>								0000 0000	0000 0000
19Ch	SPBRGH	BRG<15:8>								0000 0000	0000 0000
19Dh	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19Eh	TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	0000 0010
19Fh	BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	01-0 0-00	01-0 0-00
Bank 4											
20Ch	—	Unimplemented								—	—
20Dh	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	1111 1111	1111 1111
20Eh	—	Unimplemented								—	—
20Fh	—	Unimplemented								—	—
210h	WPUE	—	—	—	—	WPUE3	—	—	—	---- 1---	---- 1---
211h to 21Fh	—	Unimplemented								—	—
Bank 5											
28Ch — 29Fh	—	Unimplemented								—	—
Bank 6											
30Ch — 31Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16LF1904/7 only.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 7											
38Ch — 393h	—	Unimplemented								—	—
394h	IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	0000 0000	0000 0000
395h	IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	0000 0000	0000 0000
396h	IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	0000 0000	0000 0000
397h — 39Fh	—	Unimplemented								—	—
Bank 8-14											
x0Ch or x8Ch to x1Fh or x9Fh	—	Unimplemented								—	—
Bank 15											
78Ch — 790h	—	Unimplemented								—	—
791h	LCDCON	LCDEN	SLPEN	WERR	—	CS1	CS0	LMUX1	LMUX0	000- 0011	000- 0011
792h	LCDPS	WFT	BIASMD	LCDA	WA	LP3	LP2	LP1	LP0	0000 0000	0000 0000
793h	LCDREF	LCDIRE	—	LCDIRI	—	VLCD3PE	VLCD2PE	VLCD1PE	—	0-0- 000-	0-0- 000-
794h	LCDCST	—	—	—	—	—	LCDCST2	LCDCST1	LCDCST0	---- -000	---- -000
795h	LCDRL	LRLAP1	LRLAP0	LRLBP1	LRLBP0	—	LRLAT2	LRLAT1	LRLAT0	0000 -000	0000 -000
796h	—	Unimplemented								—	—
797h	—	Unimplemented								—	—
798h	LCDSE0	SE7	SE6	SE5	SE4	SE3	SE2	SE1	SE0	0000 0000	uuuu uuuu
799h	LCDSE1	SE15	SE14	SE13	SE12	SE11	SE10	SE9	SE8	0000 0000	uuuu uuuu
79Ah	LCDSE2	SE23	SE22	SE21	SE20	SE19	SE18	SE17	SE16	0000 0000	uuuu uuuu
79Bh	LCDSE3	—	—	—	SE28	SE27	SE26	SE25	SE24	---0 0000	---u uuuu
79Dh — 79Fh	—	Unimplemented								—	—
7A0h	LCDDATA0	SEG7 COM0	SEG6 COM0	SEG5 COM0	SEG4 COM0	SEG3 COM0	SEG2 COM0	SEG1 COM0	SEG0 COM0	xxxx xxxx	uuuu uuuu
7A1h	LCDDATA1	SEG15 COM0	SEG14 COM0	SEG13 COM0	SEG12 COM0	SEG11 COM0	SEG10 COM0	SEG9 COM0	SEG8 COM0	xxxx xxxx	uuuu uuuu
7A2h	LCDDATA2(3)	SEG23 COM0	SEG22 COM0	SEG21 COM0	SEG20 COM0	SEG19 COM0	SEG18 COM0	SEG17 COM0	SEG16 COM0	xxxx xxxx	uuuu uuuu
7A3h	LCDDATA3	SEG7 COM1	SEG6 COM1	SEG5 COM1	SEG4 COM1	SEG3 COM1	SEG2 COM1	SEG1 COM1	SEG0 COM1	xxxx xxxx	uuuu uuuu
7A4h	LCDDATA4	SEG15 COM1	SEG14 COM1	SEG13 COM1	SEG12 COM1	SEG11 COM1	SEG10 COM1	SEG9 COM1	SEG8 COM1	xxxx xxxx	uuuu uuuu
7A5h	LCDDATA5(3)	SEG23 COM1	SEG22 COM1	SEG21 COM1	SEG20 COM1	SEG19 COM1	SEG18 COM1	SEG17 COM1	SEG16 COM1	xxxx xxxx	uuuu uuuu
7A6h	LCDDATA6	SEG7 COM2	SEG6 COM2	SEG5 COM2	SEG4 COM2	SEG3 COM2	SEG2 COM2	SEG1 COM2	SEG0 COM2	xxxx xxxx	uuuu uuuu
7A7h	LCDDATA7	SEG15 COM2	SEG14 COM2	SEG13 COM2	SEG12 COM2	SEG11 COM2	SEG10 COM2	SEG9 COM2	SEG8 COM2	xxxx xxxx	uuuu uuuu
7A8h	LCDDATA8(3)	SEG23 COM2	SEG22 COM2	SEG21 COM2	SEG20 COM2	SEG19 COM2	SEG18 COM2	SEG17 COM2	SEG16 COM2	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16LF1904/7 only.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 15 (Continued)											
7A9h	LCDDATA9	SEG7 COM3	SEG6 COM3	SEG5 COM3	SEG4 COM3	SEG3 COM3	SEG2 COM3	SEG1 COM3	SEG0 COM3	xxxx xxxx	uuuu uuuu
7AAh	LCDDATA10	SEG15 COM3	SEG14 COM3	SEG13 COM3	SEG12 COM3	SEG11 COM3	SEG10 COM3	SEG9 COM3	SEG8 COM3	xxxx xxxx	uuuu uuuu
7ABh	LCDDATA11(3)	SEG23 COM3	SEG22 COM3	SEG20 COM3	SEG19 COM3	SEG18 COM3	SEG17 COM3	SEG16 COM3	SEG15 COM3	xxxx xxxx	uuuu uuuu
7ACh	LCDDATA12	—	—	—	SEG28 COM0	SEG27 COM0	SEG26 COM0	SEG25 COM0	SEG24 COM0	---x xxxx	---u uuuu
7ADh	—	Unimplemented								—	—
7AEh	—	Unimplemented								—	—
7AFh	LCDDATA15	—	—	—	SEG28 COM1	SEG27 COM1	SEG26 COM1	SEG25 COM1	SEG24 COM1	---x xxxx	---u uuuu
7B0h	—	Unimplemented								—	—
7B1h	—	Unimplemented								—	—
7B2h	LCDDATA18	—	—	—	SEG28 COM2	SEG27 COM2	SEG26 COM2	SEG25 COM2	SEG24 COM2	---x xxxx	---u uuuu
7B3h	—	Unimplemented								—	—
7B4h	—	Unimplemented								—	—
7B5h	LCDDATA21	—	—	—	SEG28 COM3	SEG27 COM3	SEG26 COM3	SEG25 COM3	SEG24 COM3	---x xxxx	---u uuuu
7B6h — 7EFh	—	Unimplemented								—	—
Bank 16-30											
x0Ch or x8Ch to x1Fh or x9Fh	—	Unimplemented								—	—
Bank 31											
F8Ch — FE3h	—	Unimplemented								—	—
FE4h	STATUS_SHAD	—	—	—	—	—	Z_SHAD	DC_SHAD	C_SHAD	---- -xxx	---- -uuu
FE5h	WREG_SHAD	Working Register Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_SHAD	—	—	—	Bank Select Register Normal (Non-ICD) Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_SHAD	—	Program Counter Latch High Register Normal (Non-ICD) Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_SHAD	Indirect Data Memory Address 0 Low Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_SHAD	Indirect Data Memory Address 0 High Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_SHAD	Indirect Data Memory Address 1 Low Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_SHAD	Indirect Data Memory Address 1 High Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top of Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top of Stack High byte							-xxx xxxx	-uuu uuuu

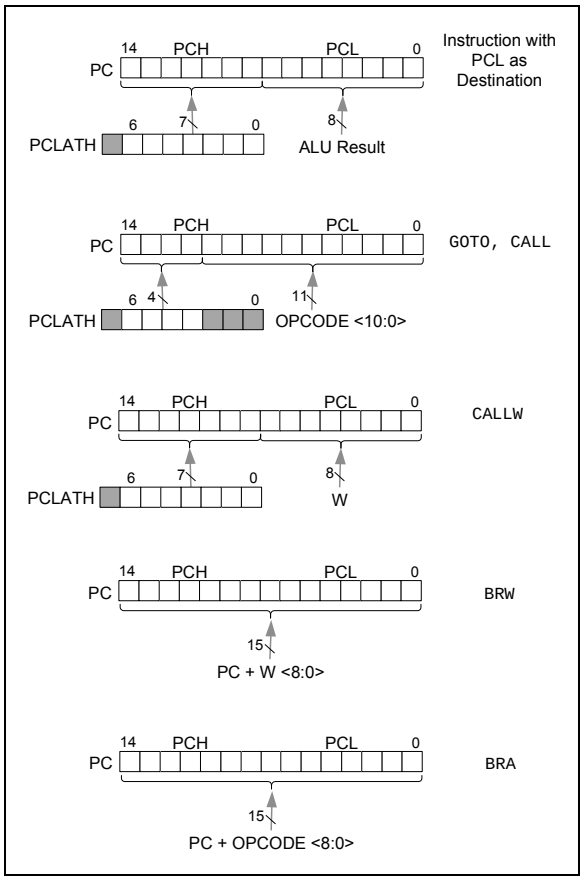
Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: Unimplemented, read as '1'.
3: PIC16LF1904/7 only.

3.3 PCL and PCLATH

The Program Counter (PC) is 15 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<14:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 3-4 shows the five situations for the loading of the PC.

FIGURE 3-4: LOADING OF PC IN DIFFERENT SITUATIONS



3.3.1 MODIFYING PCL

Executing any instruction with the PCL register as the destination simultaneously causes the Program Counter PC<14:8> bits (PCH) to be replaced by the contents of the PCLATH register. This allows the entire contents of the program counter to be changed by writing the desired upper seven bits to the PCLATH register. When the lower eight bits are written to the PCL register, all 15 bits of the program counter will change to the values contained in the PCLATH register and those being written to the PCL register.

3.3.2 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to Application Note AN556, *"Implementing a Table Read"* (DS00556).

3.3.3 COMPUTED FUNCTION CALLS

A computed function CALL allows programs to maintain tables of functions and provide another way to execute state machines or look-up tables. When performing a table read using a computed function CALL, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block).

If using the CALL instruction, the PCH<2:0> and PCL registers are loaded with the operand of the CALL instruction. PCH<6:3> is loaded with PCLATH<6:3>.

The CALLW instruction enables computed calls by combining PCLATH and W to form the destination address. A computed CALLW is accomplished by loading the W register with the desired address and executing CALLW. The PCL register is loaded with the value of W and PCH is loaded with PCLATH.

3.3.4 BRANCHING

The branching instructions add an offset to the PC. This allows relocatable code and code that crosses page boundaries. There are two forms of branching, BRW and BRA. The PC will have incremented to fetch the next instruction in both cases. When using either branching instruction, a PCL memory boundary may be crossed.

If using BRW, load the W register with the desired unsigned address and execute BRW. The entire PC will be loaded with the address PC + 1 + W.

If using BRA, the entire PC will be loaded with PC + 1 +, the signed value of the operand of the BRA instruction.

3.4 Stack

All devices have a 16-level x 15-bit wide hardware stack (refer to Figure 3-5). The stack space is not part of either program or data space. The PC is PUSHed onto the stack when CALL or CALLW instructions are executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer if the STVREN bit is programmed to '0' (Configuration Word 2). This means that after the stack has been PUSHed sixteen times, the seventeenth PUSH overwrites the value that was stored from the first PUSH. The eighteenth PUSH overwrites the second PUSH (and so on). The STKOVF and STKUNF flag bits will be set on an Overflow/Underflow, regardless of whether the Reset is enabled.

Note:	There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, CALLW, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

3.4.1 ACCESSING THE STACK

The stack is available through the TOSH, TOSL and STKPTR registers. STKPTR is the current value of the Stack Pointer. TOSH:TOSL register pair points to the TOP of the stack. Both registers are read/writable. TOS is split into TOSH and TOSL due to the 15-bit size of the PC. To access the stack, adjust the value of STKPTR, which will position TOSH:TOSL, then read/write to TOSH:TOSL. STKPTR is five bits to allow detection of overflow and underflow.

Note:	Care should be taken when modifying the STKPTR while interrupts are enabled.

During normal program operation, CALL, CALLW and Interrupts will increment STKPTR while RETLW, RETURN, and RETFIE will decrement STKPTR. At any time STKPTR can be inspected to see how much stack is left. The STKPTR always points at the currently used place on the stack. Therefore, a CALL or CALLW will increment the STKPTR and then write the PC, and a return will unload the PC and then decrement the STKPTR.

Reference Figure 3-5 through Figure 3-8 for examples of accessing the stack.

FIGURE 3-5: ACCESSING THE STACK EXAMPLE 1

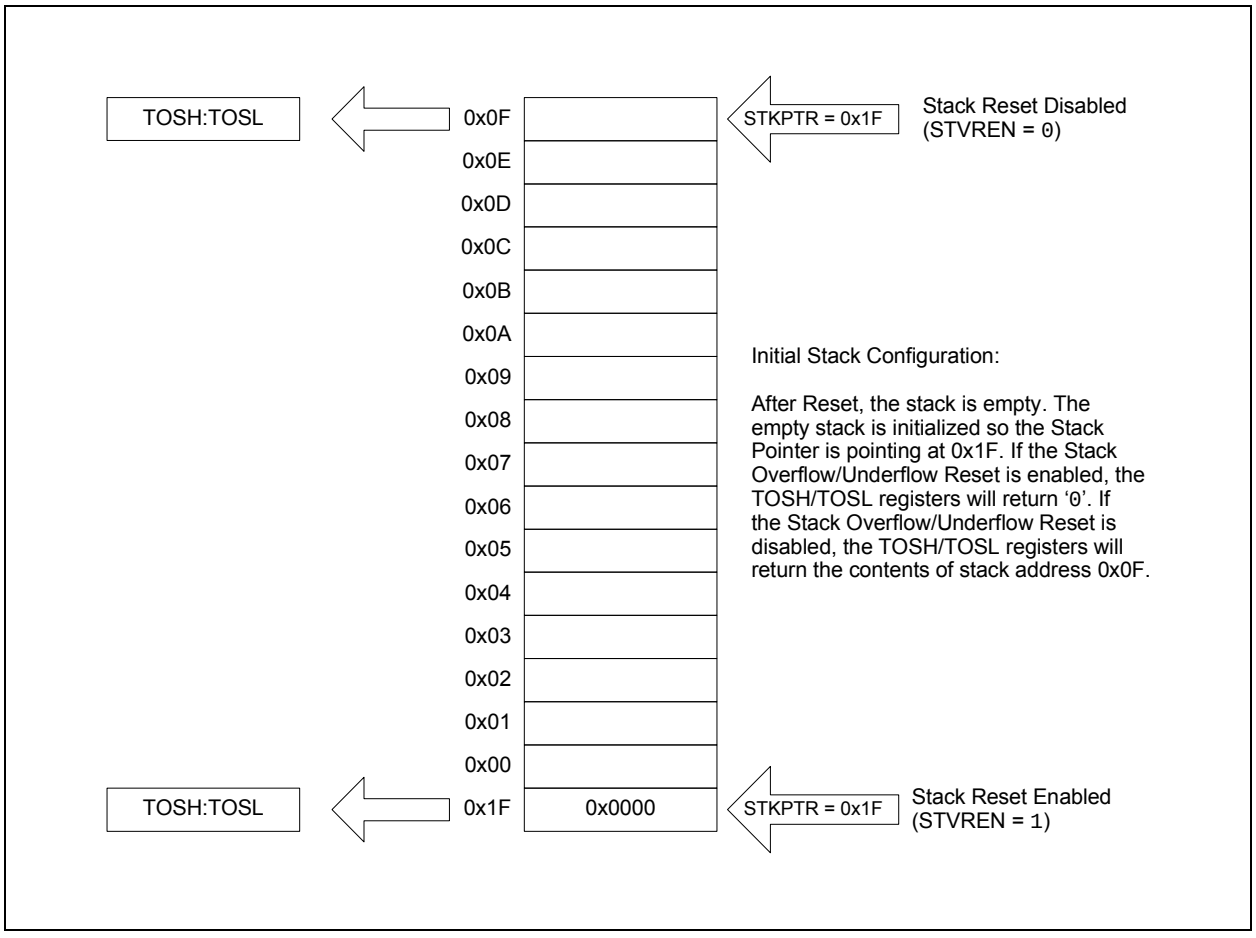


FIGURE 3-6: ACCESSING THE STACK EXAMPLE 2

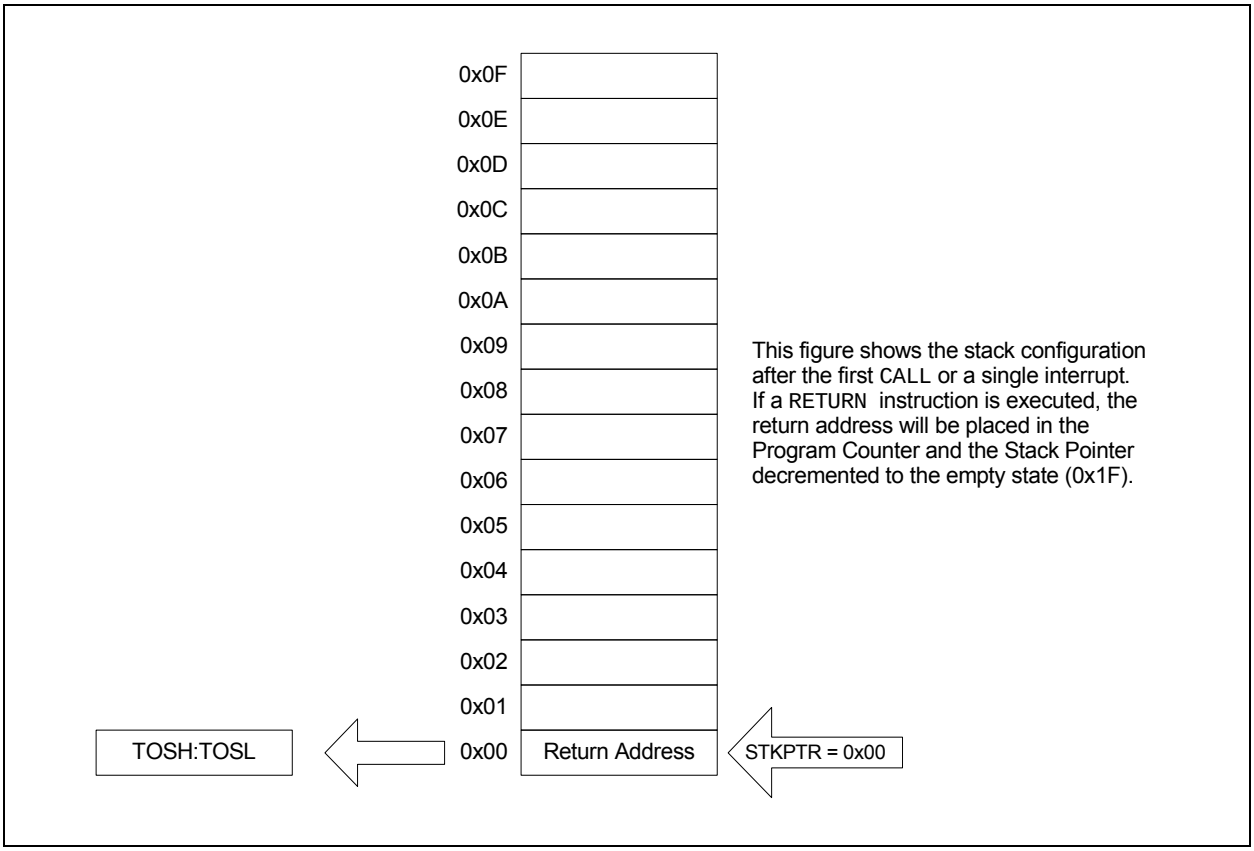


FIGURE 3-7: ACCESSING THE STACK EXAMPLE 3

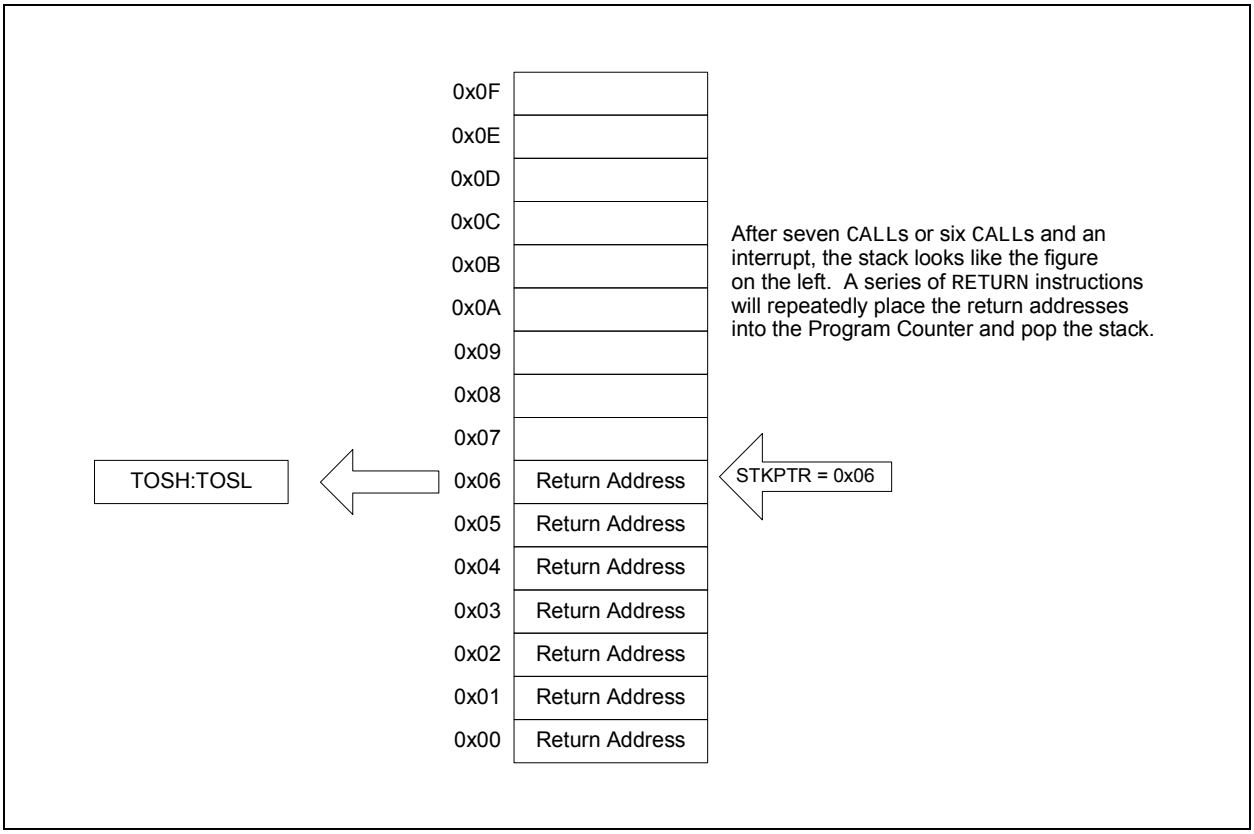
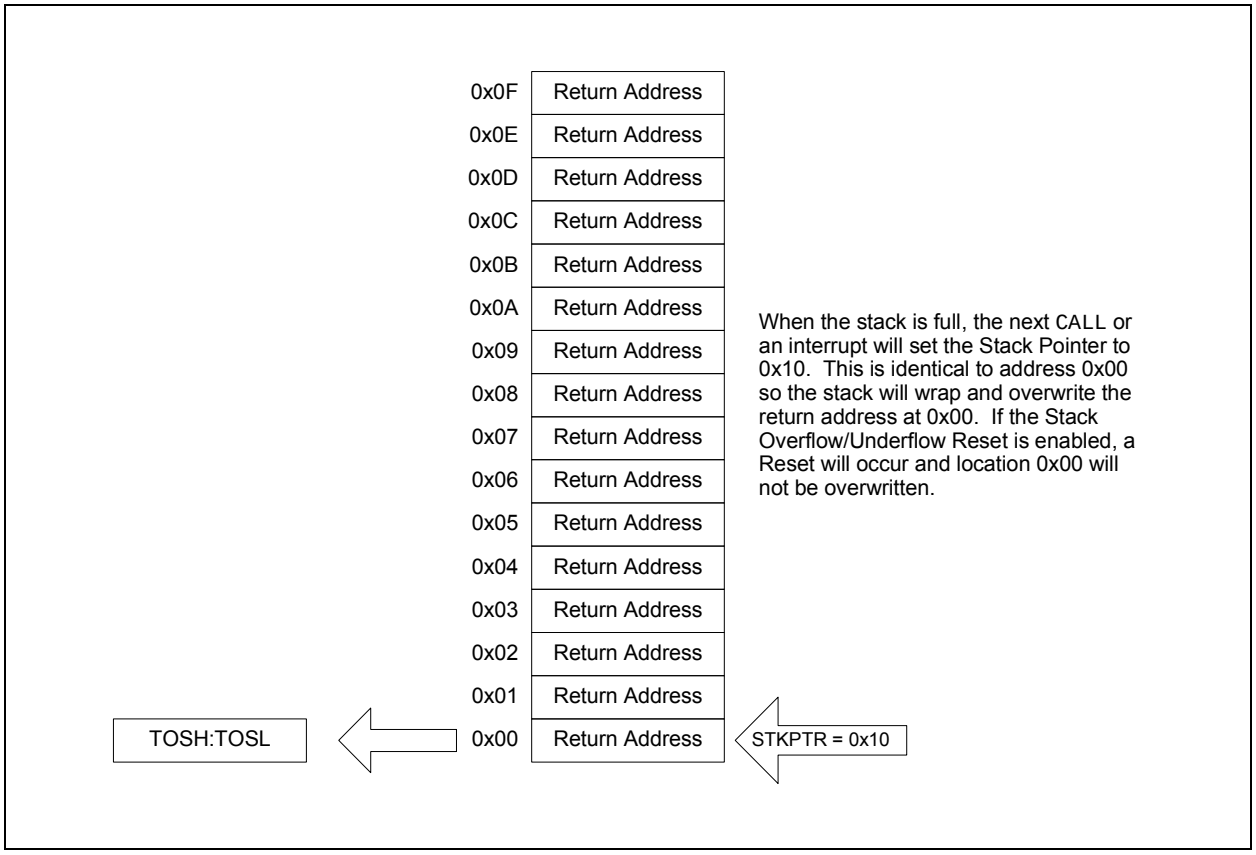


FIGURE 3-8: ACCESSING THE STACK EXAMPLE 4



3.4.2 OVERFLOW/UNDERFLOW RESET

If the STVREN bit in Configuration Word 2 is programmed to '1', the device will be reset if the stack is PUSHed beyond the sixteenth level or POPed beyond the first level, setting the appropriate bits (STKOVF or STKUNF, respectively) in the PCON register.

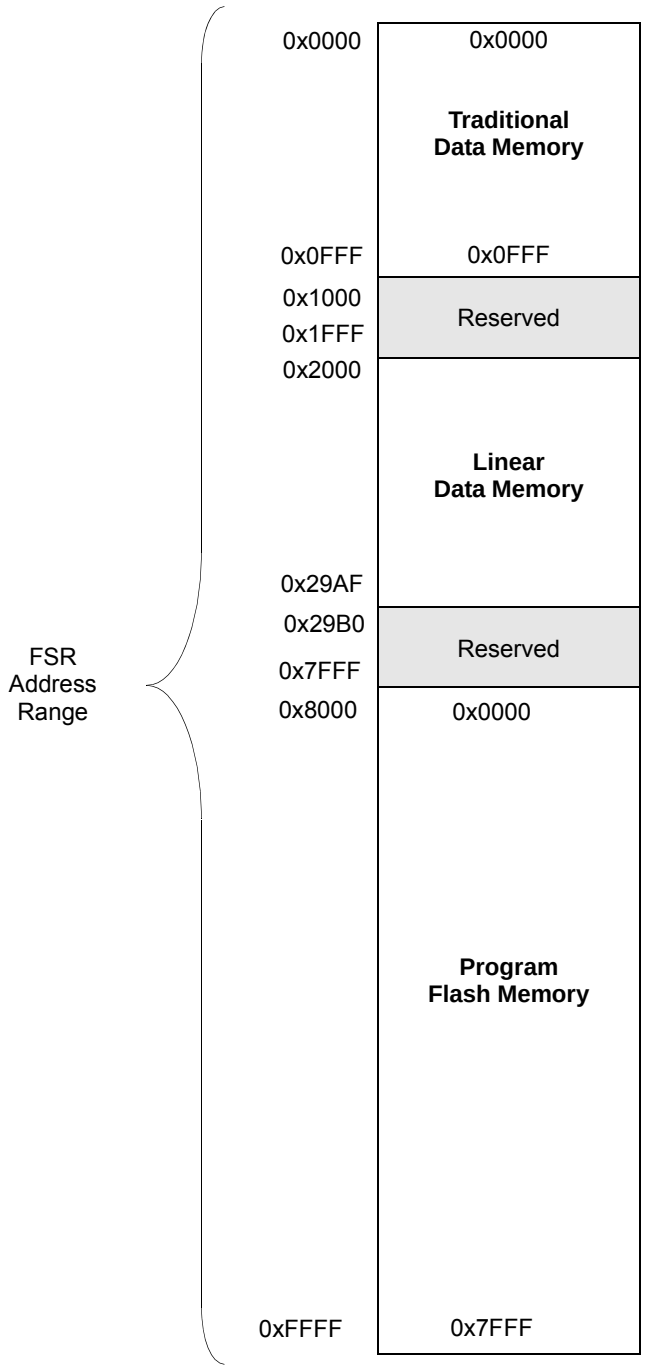
3.5 Indirect Addressing

The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the File Select Registers (FSR). If the FSRn address specifies one of the two INDFn registers, the read will return '0' and the write will not occur (though Status bits may be affected). The FSRn register value is created by the pair FSRnH and FSRnL.

The FSR registers form a 16-bit address that allows an addressing space with 65536 locations. These locations are divided into three memory regions:

- Traditional Data Memory
- Linear Data Memory
- Program Flash Memory

FIGURE 3-9: INDIRECT ADDRESSING

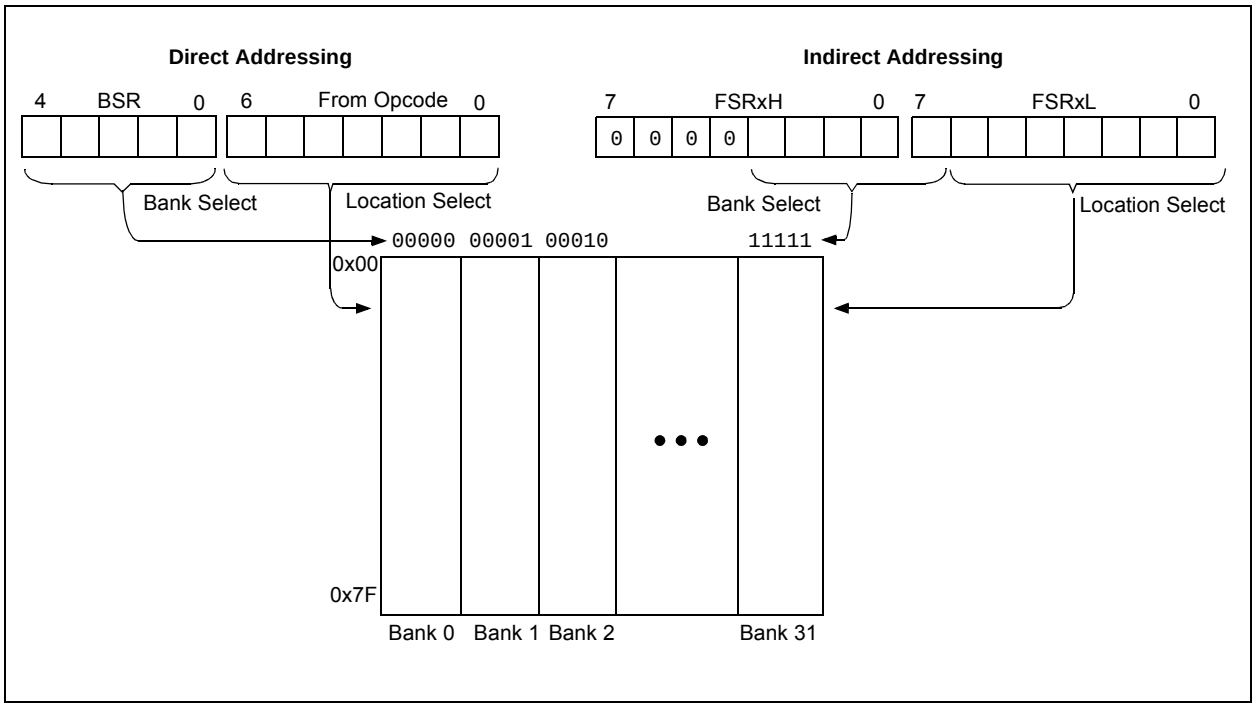


Note: Not all memory regions are completely implemented. Consult device memory tables for memory limits.

3.5.1 TRADITIONAL DATA MEMORY

The traditional data memory is a region from FSR address 0x000 to FSR address 0xFFF. The addresses correspond to the absolute addresses of all SFR, GPR and common registers.

FIGURE 3-10: TRADITIONAL DATA MEMORY MAP



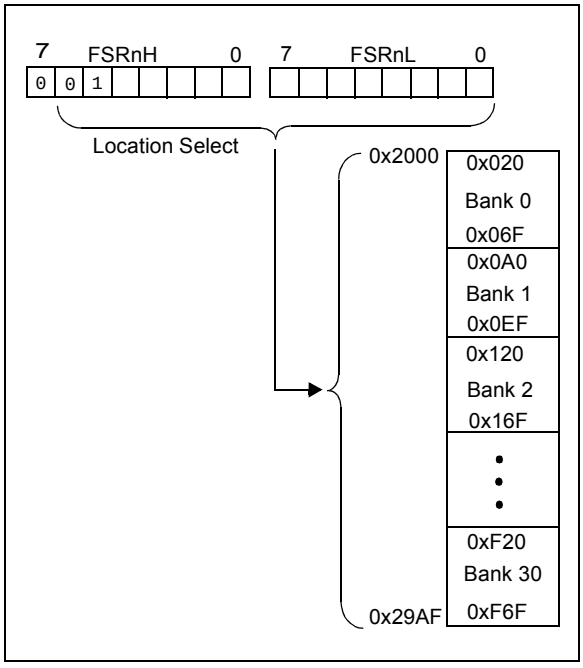
3.5.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

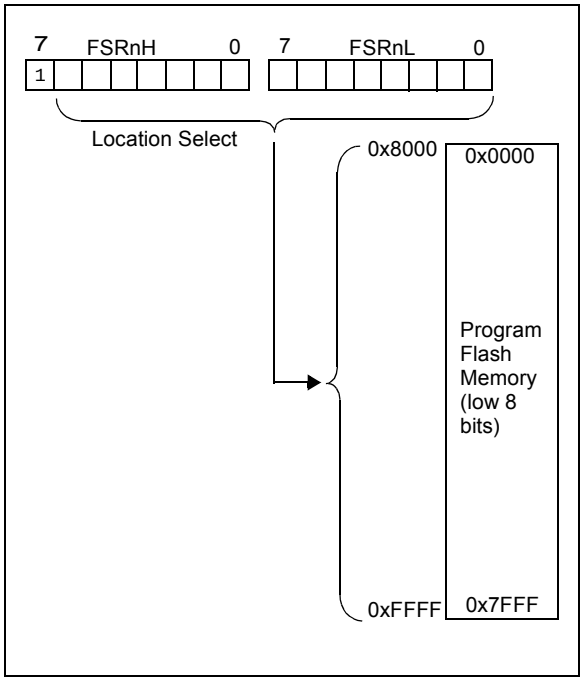
FIGURE 3-11: LINEAR DATA MEMORY MAP



3.5.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-12: PROGRAM FLASH MEMORY MAP



4.0 DEVICE CONFIGURATION

Device Configuration consists of Configuration Word 1 and Configuration Word 2, Code Protection and Device ID.

4.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 at 8007h and Configuration Word 2 at 8008h.

Note:	The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

REGISTER 4-1: CONFIGURATION WORD 1

U-1	U-1	R/P-1	R/P-1	R/P-1	U-1
—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13-12 **Unimplemented:** Read as '1'

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **Unimplemented:** Read as '1'

bit 7 **$\overline{\text{CP}}$:** Code Protection bit
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUE3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

bit 2 **Unimplemented:** Read as '1'

bit 1-0 **FOSC<1:0>:** Oscillator Selection bits
00 = INTOSC oscillator: I/O function on CLKIN pin
01 = ECL: External Clock, Low-Power mode (0-0.5 MHz): device clock supplied to CLKIN pin
10 = ECM: External Clock, Medium-Power mode (0.5-4 MHz): device clock supplied to CLKIN pin
11 = ECH: External Clock, High-Power mode (4-20 MHz): device clock supplied to CLKIN pin

REGISTER 4-2: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
LVP(1)	DEBUG(3)	LPBOR	BORV(2)	STVREN	—
bit 13					bit 8

U-1	U-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1
—	—	—	—	—	—	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
1 = Low-voltage programming enabled
0 = High-voltage on MCLR must be used for programming

bit 12 **DEBUG:** In-Circuit Debugger Mode bit(3)
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **LPBOR:** Low-Power BOR bit
1 = Low-Power BOR is disabled
0 = Low-Power BOR is enabled

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(2)
1 = Brown-out Reset voltage (VBOR), low trip point selected
0 = Brown-out Reset voltage (VBOR), high trip point selected

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8-2 **Unimplemented:** Read as '1'

bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
4 kW Flash memory (PIC16LF1904 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to FFFh may be modified by PMCON control
01 = 000h to 7FFh write-protected, 800h to FFFh may be modified by PMCON control
00 = 000h to FFFh write-protected, no addresses may be modified by PMCON control
8 kW Flash memory (PIC16LF1906/7 only):
11 = Write protection off
10 = 0000h to 01FFh write-protected, 200h to 1FFFh may be modified by PMCON control
01 = 0000h to 0FFFh write-protected, 1000h to 1FFFh may be modified by PMCON control
00 = 0000h to 1FFFh write-protected, no addresses may be modified by PMCON control

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
2: See VBOR parameter for specific trip point voltages.
3: The DEBUG bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

4.2 Code Protection

Code protection allows the device to be protected from unauthorized access. Program memory protection is controlled independently. Internal access to the program memory is unaffected by any code protection setting.

4.2.1 PROGRAM MEMORY PROTECTION

The entire program memory space is protected from external reads and writes by the $\overline{CP}$ bit in Configuration Word 1. When $\overline{CP}$ = 0, external reads and writes of program memory are inhibited and a read will return all '0's. The CPU can continue to read program memory, regardless of the protection bit settings. Writing the program memory is dependent upon the write protection setting. See **Section 4.3 "Write Protection"** for more information.

4.3 Write Protection

Write protection allows the device to be protected from unintended self-writes. Applications, such as boot loader software, can be protected while allowing other regions of the program memory to be modified.

The WRT<1:0> bits in Configuration Word 2 define the size of the program memory block that is protected.

4.4 User ID

Four memory locations (8000h-8003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are readable and writable during normal execution. See **Section 10.4 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations. For more information on checksum calculation, see the **"***PIC16F193X/LF193X/PIC16F194X/LF194X/PIC16LF190X Memory Programming Specification***"** (DS41397).

4.5 Device ID and Revision ID

The memory location 8006h is where the Device ID and Revision ID are stored. The upper nine bits hold the Device ID. The lower five bits hold the Revision ID. See **Section 10.4 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the Device ID and Revision ID.

REGISTER 4-3: DEVICEID: DEVICE ID REGISTER

R	R	R	R	R	R
DEV<8:3>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<2:0>			REV<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '1'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	P = Programmable bit

bit 13-5 **DEV<8:0>:** Device ID bits

Device	DEVICEID<13:0> Values	
	DEV<8:0>	REV<4:0>
PIC16LF1904	10 1100 100	x xxxx
PIC16LF1906	10 1100 011	x xxxx
PIC16LF1907	10 1100 010	x xxxx

bit 4-0 **REV<4:0>:** Revision ID bits

These bits are used to identify the revision (see Table under DEV<8:0> above).

5.0 RESETS

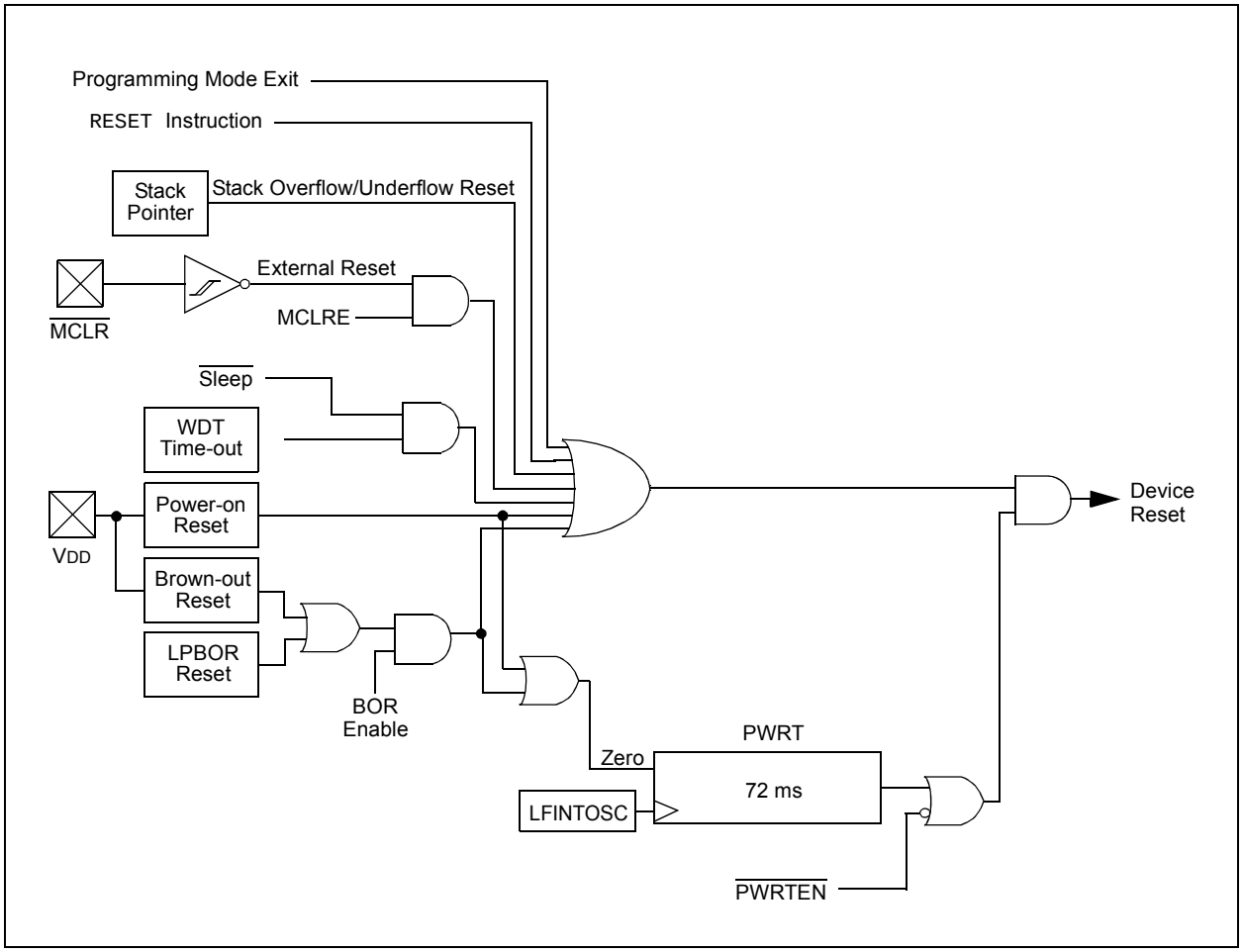
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- Low-Power Brown-out Reset (LPBOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional Power-up Timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



5.1 Power-on Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

5.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Word 1.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

5.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Word 1. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to Table 5-1 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Word 2.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 5-2 for more information.

TABLE 5-1: BOR OPERATING MODES

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Device Operation upon release of POR	Device Operation upon wake- up from Sleep
11	X	X	Active	Waits for BOR ready(1)	
10	X	Awake	Active	Waits for BOR ready	
		Sleep	Disabled		
01	1	X	Active	Waits for BOR ready(1)	
	0	X	Disabled	Begins immediately	
00	X	X	Disabled	Begins immediately	

Note 1: In these specific cases, "release of POR" and "wake-up from Sleep," there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

5.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Word 1 are set to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

5.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Word 1 are set to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

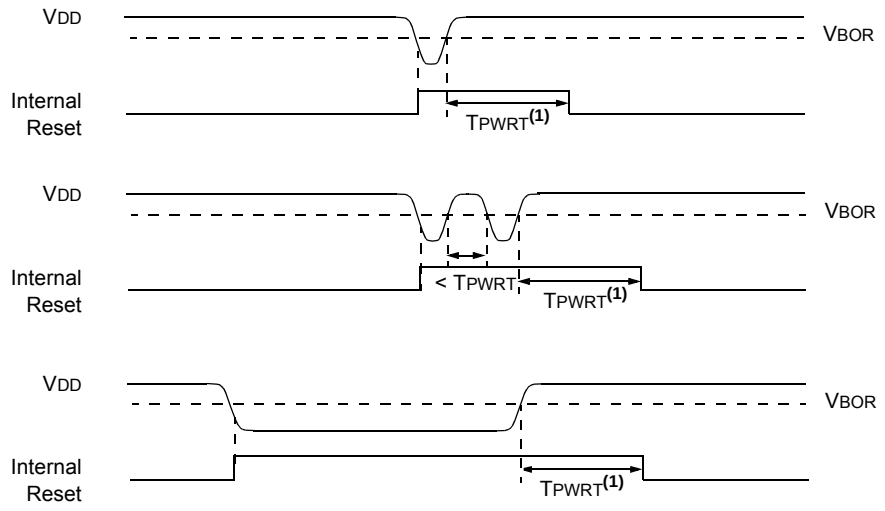
5.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Word 1 are set to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

FIGURE 5-2: BROWN-OUT SITUATIONS



Note 1: TPWRT delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

REGISTER 5-1: BORCON: BROWN-OUT RESET CONTROL REGISTER

R/W-1/u	R/W-0/u	U-0	U-0	U-0	U-0	U-0	R-q/u
SBOREN	BORFS	—	—	—	—	—	BORRDY
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **SBOREN:** Software Brown-out Reset Enable bit
If BOREN <1:0> in Configuration Word 1 ≠ 01:
SBOREN is read/write, but has no effect on the BOR.
If BOREN <1:0> in Configuration Word 1 = 01:
1 = BOR Enabled
0 = BOR Disabled

bit 6 **BORFS:** Brown-out Reset Fast Start bit(1)
If BOREN<1:0> = 11 (Always on) or BOREN<1:0> = 00 (Always off)
BORFS is Read/Write, but has no effect.
If BOREN <1:0> = 10 (Disabled in Sleep) or BOREN<1:0> = 01 (Under software control):
1 = Band gap is forced on always (covers Sleep/wake-up/operating cases)
0 = Band gap operates normally, and may turn off

bit 5-1 **Unimplemented:** Read as '0'

bit 0 **BORRDY:** Brown-out Reset Circuit Ready Status bit
1 = The Brown-out Reset circuit is active
0 = The Brown-out Reset circuit is inactive

5.3 Low-Power Brown-out Reset (LPBOR)

The Low-Power Brown-Out Reset (LPBOR) is an essential part of the Reset subsystem. Refer to Figure 5-1 to see how the BOR interacts with other modules.

The LPBOR is used to monitor the external VDD pin. When too low of a voltage is detected, the device is held in Reset. When this occurs, a register bit ($\overline{BOR}$) is changed to indicate that a BOR Reset has occurred. The same bit is set for both the BOR and the LPBOR. Refer to Register 5-2.

5.3.1 ENABLING LPBOR

The LPBOR is controlled by the $\overline{LPBOR}$ bit of Configuration Word 2. When the device is erased, the LPBOR module defaults to disabled.

5.3.1.1 LPBOR Module Output

The output of the LPBOR module is a signal indicating whether or not a Reset is to be asserted. This signal is to be OR'd together with the Reset signal of the BOR module to provide the generic $\overline{BOR}$ signal, which goes to the PCON register and to the power control block.

5.4 $\overline{MCLR}$

The $\overline{MCLR}$ is an optional external input that can reset the device. The $\overline{MCLR}$ function is controlled by the MCLRE bit of Configuration Word 1 and the LVP bit of Configuration Word 2 (Table 5-2).

TABLE 5-2: $\overline{MCLR}$ CONFIGURATION

MCLRE	LVP	$\overline{MCLR}$
0	0	Disabled
1	0	Enabled
x	1	Enabled

5.4.1 $\overline{MCLR}$ ENABLED

When $\overline{MCLR}$ is enabled and the pin is held low, the device is held in Reset. The $\overline{MCLR}$ pin is connected to VDD through an internal weak pull-up.

The device has a noise filter in the $\overline{MCLR}$ Reset path. The filter will detect and ignore small pulses.

Note:	A Reset does not drive the $\overline{MCLR}$ pin low.

5.4.2 $\overline{MCLR}$ DISABLED

When $\overline{MCLR}$ is disabled, the pin functions as a general purpose input and the internal weak pull-up is under software control. See **Section 11.5 "PORTE Registers"** for more information.

5.5 Watchdog Timer (WDT) Reset

The Watchdog Timer generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the WDT Reset. See **Section 9.0 "Watchdog Timer"** for more information.

5.6 RESET Instruction

A RESET instruction will cause a device Reset. The $\overline{RI}$ bit in the PCON register will be set to '0'. See Table 5-4 for default conditions after a RESET instruction has occurred.

5.7 Stack Overflow/Underflow Reset

The device can reset when the Stack Overflows or Underflows. The STKOVF or STKUNF bits of the PCON register indicate the Reset condition. These Resets are enabled by setting the STVREN bit in Configuration Word 2. See **Section 5.7 "Stack Overflow/Underflow Reset"** for more information.

5.8 Programming Mode Exit

Upon exit of Programming mode, the device will behave as if a POR had just occurred.

5.9 Power-Up Timer

The Power-up Timer optionally delays device execution after a BOR or POR event. This timer is typically used to allow VDD to stabilize before allowing the device to start running.

The Power-up Timer is controlled by the $\overline{PWRTE}$ bit of Configuration Word 1.

5.10 Start-up Sequence

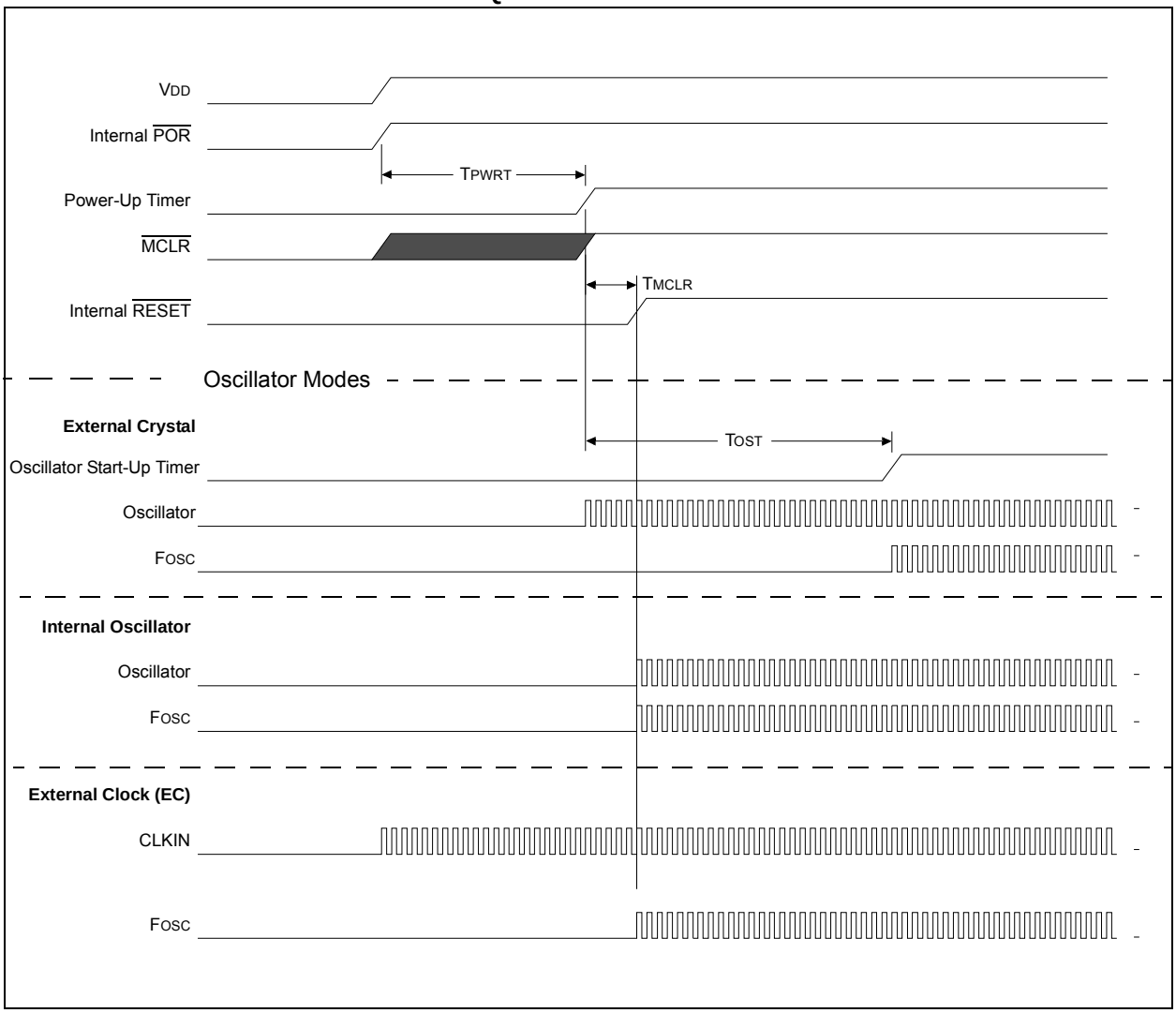
Upon the release of a POR or BOR, the following must occur before the device will begin executing:

1. Power-up Timer runs to completion (if enabled).
2. Oscillator start-up timer runs to completion (if required for oscillator source).
3. $\overline{MCLR}$ must be released (if enabled).

The total time-out will vary based on oscillator configuration and Power-up Timer configuration. See **Section 6.0 "Oscillator Module"** for more information.

The Power-up Timer and oscillator start-up timer run independently of $\overline{MCLR}$ Reset. If $\overline{MCLR}$ is kept low long enough, the Power-up Timer and oscillator start-up timer will expire. Upon bringing $\overline{MCLR}$ high, the device will begin execution immediately (see Figure 5-3). This is useful for testing purposes or to synchronize more than one device operating in parallel.

FIGURE 5-3: RESET START-UP SEQUENCE



5.11 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON registers are updated to indicate the cause of the Reset. Table 5-3 and Table 5-4 show the Reset conditions of these registers.

TABLE 5-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

STKOVF	STKUNF	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	0	1	1	1	0	x	1	1	Power-on Reset
0	0	1	1	1	0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	1	1	1	0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
0	0	u	1	1	u	0	1	1	Brown-out Reset
u	u	0	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	u	0	u	u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	u	0	u	u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep
u	u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 5-4: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	---1 1000	00-1 110x
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	---u uuuu	uu-u 0uuu
$\overline{\text{MCLR}}$ Reset during Sleep	0000h	---1 0uuu	uu-u 0uuu
WDT Reset	0000h	---0 uuuu	uu-0 uuuu
WDT Wake-up from Sleep	PC + 1	---0 0uuu	uu-u uuuu
Brown-out Reset	0000h	---1 1uuu	00-1 11u0
Interrupt Wake-up from Sleep	PC + 1(1)	---1 0uuu	uu-u uuuu
RESET Instruction Executed	0000h	---u uuuu	uu-u u0uu
Stack Overflow Reset (STVREN = 1)	0000h	---u uuuu	1u-u uuuu
Stack Underflow Reset (STVREN = 1)	0000h	---u uuuu	u1-u uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

5.12 Power Control (PCON) Register

The Power Control (PCON) register contains flag bits to differentiate between a:

- Power-on Reset ($\overline{POR}$)
- Brown-out Reset ($\overline{BOR}$)
- Reset Instruction Reset ($\overline{RI}$)
- $\overline{MCLR}$ Reset ($\overline{RMCLR}$)
- Watchdog Timer Reset ($\overline{RWDT}$)
- Stack Underflow Reset (STKUNF)
- Stack Overflow Reset (STKOVF)

The PCON register bits are shown in Register 5-2.

REGISTER 5-2: PCON: POWER CONTROL REGISTER

R/W/HS-0/q	R/W/HS-0/q	U-0	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-q/u	R/W/HC-q/u
STKOVF	STKUNF	—	$\overline{RWDT}$	$\overline{RMCLR}$	$\overline{RI}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:		
HC = Bit is cleared by hardware		HS = Bit is set by hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7 **STKOVF:** Stack Overflow Flag bit
1 = A Stack Overflow occurred
0 = A Stack Overflow has not occurred or set to ‘0’ by firmware

bit 6 **STKUNF:** Stack Underflow Flag bit
1 = A Stack Underflow occurred
0 = A Stack Underflow has not occurred or set to ‘0’ by firmware

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **$\overline{RWDT}$:** Watchdog Timer Reset Flag bit
1 = A Watchdog Timer Reset has not occurred or set to ‘1’ by firmware
0 = A Watchdog Timer Reset has occurred (set to ‘0’ in hardware when a Watchdog Timer Reset)

bit 3 **$\overline{RMCLR}$:** $\overline{MCLR}$ Reset Flag bit
1 = A $\overline{MCLR}$ Reset has not occurred or set to ‘1’ by firmware
0 = A $\overline{MCLR}$ Reset has occurred (set to ‘0’ in hardware when a $\overline{MCLR}$ Reset occurs)

bit 2 **$\overline{RI}$:** RESET Instruction Flag bit
1 = A RESET instruction has not been executed or set to ‘1’ by firmware
0 = A RESET instruction has been executed (set to ‘0’ in hardware upon executing a RESET instruction)

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

TABLE 5-5: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	45
PCON	STKOVF	STKUNF	—	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	49
STATUS	—	—	—	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	21
WDTCON	—	—	WDTPS<4:0>					SWDTEN	75

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Resets.

6.0 OSCILLATOR MODULE

6.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 6-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external clock circuits. In addition, the system clock source can be supplied from one of two internal oscillators, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Fast start-up oscillator allows internal circuits to power up and stabilize before switching to the 16 MHz HFINTOSC

The oscillator module can be configured in one of the following clock modes:

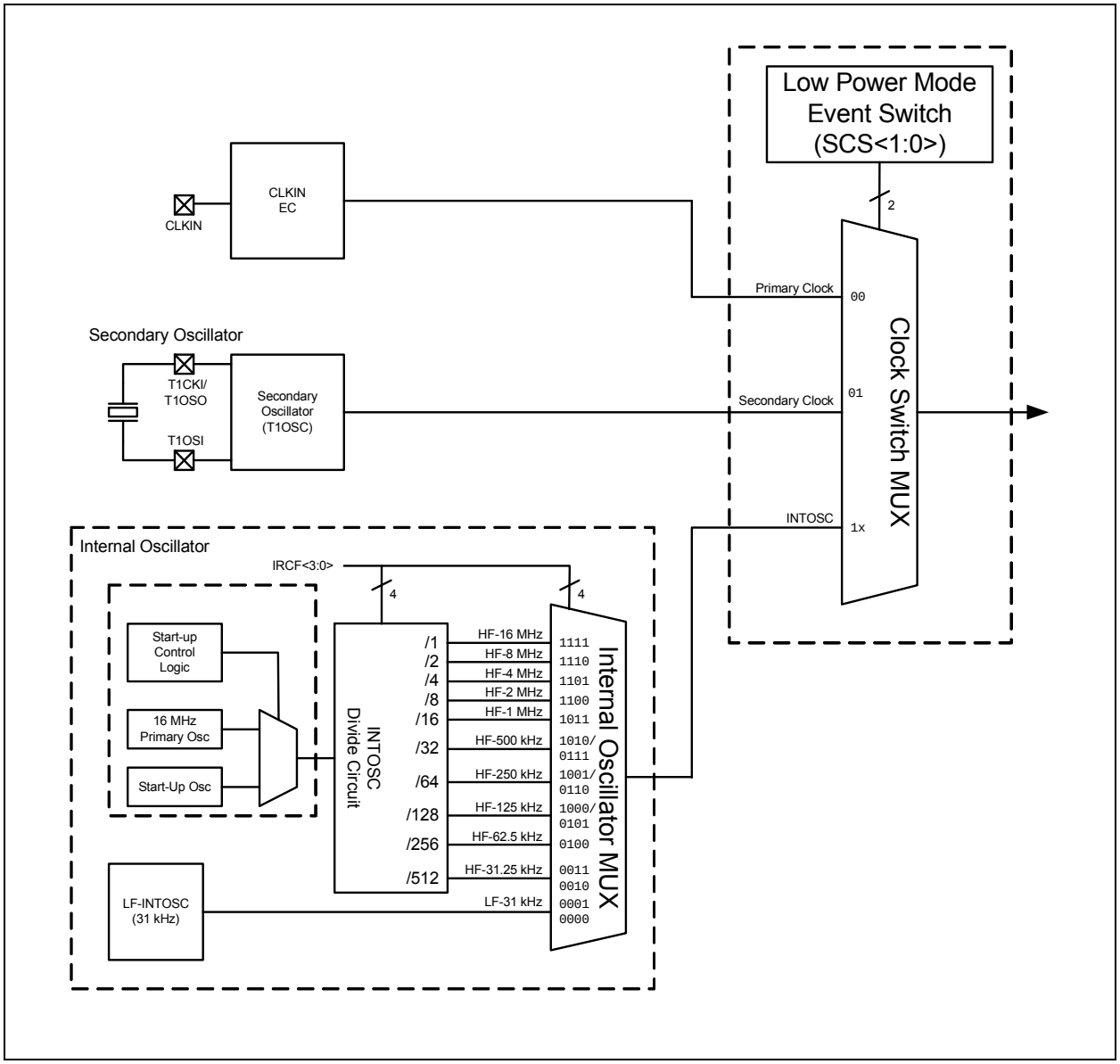
1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium-Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 20 MHz)
4. INTOSC – Internal oscillator (31 kHz to 16 MHz).

Clock Source modes are selected by the FOSC<1:0> bits in the Configuration Word 1. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The EC clock mode relies on an external logic level signal as the device clock source.

The INTOSC internal oscillator block produces a low and high-frequency clock source, designated LFINTOSC and HFINTOSC (see Internal Oscillator Block, Figure 6-1). A wide selection of device clock frequencies may be derived from these two clock sources.

FIGURE 6-1: SIMPLIFIED PIC® MCU CLOCK SOURCE BLOCK DIAGRAM



6.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. An example is: oscillator module (EC mode) circuit.

Internal clock sources are contained internally within the oscillator module. The internal oscillator block has two internal oscillators that are used to generate the internal system clock sources: the 16 MHz High-Frequency Internal Oscillator and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 6.3 "Clock Switching"** for additional information.

6.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<1:0> bits in the Configuration Word 1 to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
  - Secondary oscillator during run-time, or
  - An external clock source determined by the value of the FOSC bits.

See **Section 6.3 "Clock Switching"** for more information.

6.2.1.1 EC Mode

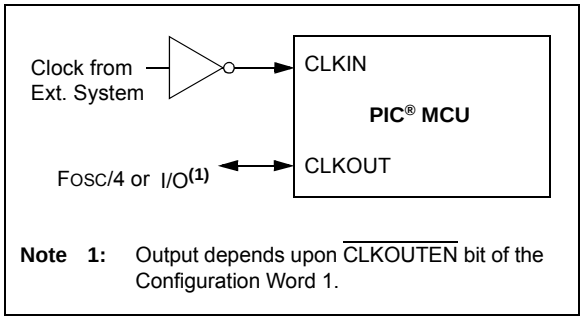
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the CLKIN input. CLKOUT is available for general purpose I/O or CLKOUT. Figure 6-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Word 1:

- High power, 4-20 MHz (FOSC = 11)
- Medium power, 0.5-4 MHz (FOSC = 10)
- Low power, 0-0.5 MHz (FOSC = 01)

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 6-2: EXTERNAL CLOCK (EC) MODE OPERATION



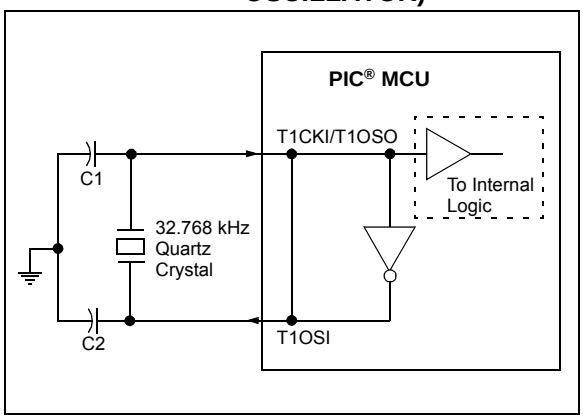
Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Word 1.

6.2.1.2 Secondary Oscillator

The secondary oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1CKI/T1OSO and T1OSI device pins.

The secondary oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 6.3 "Clock Switching"** for more information.

FIGURE 6-3: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)
- TB097, "*Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS*" (DS91097)
- AN1288, "*Design Practices for Low-Power External Oscillators*" (DS01288)

6.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<1:0> bits in Configuration Word 1 to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 6.3 "Clock Switching"** for more information.

In **INTOSC** mode, CLKIN is available for general purpose I/O. CLKOUT is available for general purpose I/O or CLKOUT.

The function of the CLKOUT pin is determined by the state of the CLKOUTEN bit in Configuration Word 1.

The internal oscillator block has two independent oscillators that provides the internal system clock source.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz.
2. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

6.2.2.1 HFINTOSC

The High-Frequency Internal Oscillator (HFINTOSC) is a factory calibrated 16 MHz internal clock source.

The output of the HFINTOSC connects to a postscaler and multiplexer (see Figure 6-1). The frequency derived from the HFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 6.2.2.4 "Internal Oscillator Clock Switch Timing"** for more information.

The HFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<1:0> = 11, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'.

The High-Frequency Internal Oscillator Ready bit (HFIOFR) of the OSCSTAT register indicates when the HFINTOSC is running and can be utilized.

The High-Frequency Internal Oscillator Status Stable bit (HFIOFS) of the OSCSTAT register indicates when the HFINTOSC is running within 0.5% of its final value.

6.2.2.2 LFINTOSC

The Low-Frequency Internal Oscillator (LFINTOSC) is an uncalibrated 31 kHz internal clock source.

The output of the LFINTOSC connects to a multiplexer (see Figure 6-1). Select 31 kHz, via software, using the IRCF<3:0> bits of the OSCCON register. See **Section 6.2.2.4 "Internal Oscillator Clock Switch Timing"** for more information. The LFINTOSC is also the frequency for the Power-up Timer (PWRT) and Watchdog Timer (WDT).

The LFINTOSC is enabled by selecting 31 kHz (IRCF<3:0> bits of the OSCCON register = 000) as the system clock source (SCS bits of the OSCCON register = 1x), or when any of the following are enabled:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired LF frequency, and
- FOSC<1:0> = 01, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'

Peripherals that use the LFINTOSC are:

- Power-up Timer (PWRT)
- Watchdog Timer (WDT)

The Low-Frequency Internal Oscillator Ready bit (LFIOFR) of the OSCSTAT register indicates when the LFINTOSC is running and can be utilized.

6.2.2.3 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The output of the 16 MHz HFINTOSC and 31 kHz LFINTOSC connects to a postscaler and multiplexer (see Figure 6-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register select the frequency output of the internal oscillators. One of the following frequencies can be selected via software:

- 16 MHz
- 8 MHz
- 4 MHz
- 2 MHz
- 1 MHz
- 500 kHz (default after Reset)
- 250 kHz
- 125 kHz
- 62.5 kHz
- 31.25 kHz
- 31 kHz (LFINTOSC)

Note:	Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '0111' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

6.2.2.4 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 6-4). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

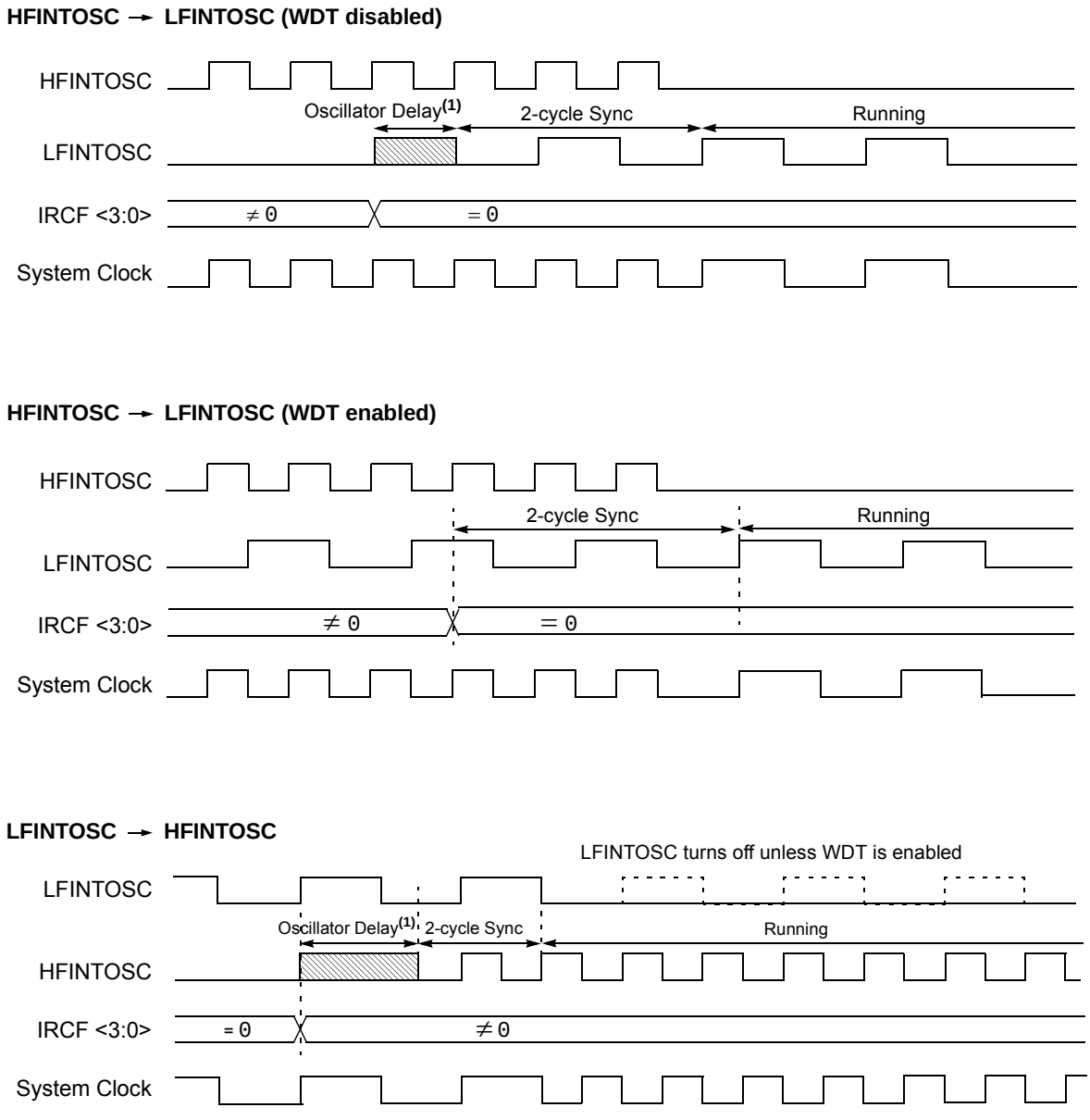
1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 6-4 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 6-2.

Start-up delay specifications are located in the oscillator tables of **Section 22.0 "Electrical Specifications"**.

FIGURE 6-4: INTERNAL OSCILLATOR SWITCH TIMING



Note 1: See Table 6-1, “Oscillator Switching Delays” for more information.

TABLE 6-1: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Oscillator Delay
Any clock source	LFINTOSC	1 cycle of each clock source
	HFINTOSC	2 μs (approx.)
	ECH, ECM, ECL	2 cycles
	Secondary Oscillator	1024 Secondary Oscillator Cycles

6.3 Clock Switching

The system clock source can be switched between external and internal clock sources via software using the System Clock Select (SCS) bits of the OSCCON register. The following clock sources can be selected using the SCS bits:

- Default system oscillator determined by FOSC bits in Configuration Word 1
- Secondary oscillator 32 kHz crystal
- Internal Oscillator Block (INTOSC)

6.3.1 SYSTEM CLOCK SELECT (SCS) BITS

The System Clock Select (SCS) bits of the OSCCON register selects the system clock source that is used for the CPU and peripherals.

- When the SCS bits of the OSCCON register = 00, the system clock source is determined by value of the FOSC<1:0> bits in the Configuration Word 1.
- When the SCS bits of the OSCCON register = 01, the system clock source is the secondary oscillator.
- When the SCS bits of the OSCCON register = 1x, the system clock source is chosen by the internal oscillator frequency selected by the IRCF<3:0> bits of the OSCCON register. After a Reset, the SCS bits of the OSCCON register are always cleared.

When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 6-2.

6.3.2 OSCILLATOR START-UP TIME-OUT STATUS (OSTS) BIT

The Oscillator Start-up Time-out Status (OSTS) bit of the OSCSTAT register indicates whether the system clock is running from the external clock source, as defined by the FOSC<1:0> bits in the Configuration Word 1, or from the internal clock source. The OST does not reflect the status of the secondary oscillator.

6.3.3 SECONDARY OSCILLATOR

The secondary oscillator is a separate crystal oscillator associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSI and T1CKI/T1OSO device pins.

The secondary oscillator is enabled using the T1OSCEN control bit in the T1CON register. See **Section 17.0 “Timer1 Module with Gate Control”** for more information about the Timer1 peripheral.

6.3.4 SECONDARY OSCILLATOR READY (T1OSCR) BIT

The user must ensure that the secondary oscillator is ready to be used before it is selected as a system clock source. The Secondary Oscillator Ready (T1OSCR) bit of the OSCSTAT register indicates whether the secondary oscillator is ready to be used. After the T1OSCR bit is set, the SCS bits can be configured to select the secondary oscillator.

6.4 Oscillator Control Registers

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
—	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘0’

bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
000x = 31 kHz LF
001x = 31.25 kHz
0100 = 62.5 kHz
0101 = 125 kHz
0110 = 250 kHz
0111 = 500 kHz (default upon Reset)
1000 = 125 kHz(1)
1001 = 250 kHz(1)
1010 = 500 kHz(1)
1011 = 1 MHz
1100 = 2 MHz
1101 = 4 MHz
1110 = 8 MHz
1111 = 16 MHz

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Secondary oscillator
00 = Clock determined by FOSC<1:0> in Configuration Word 1.

Note 1: Duplicate frequency derived from HFINTOSC.

REGISTER 6-2: OSCSTAT: OSCILLATOR STATUS REGISTER

R-1/q	U-0	R-q/q	R-0/q	U-0	U-0	R-0/0	R-0/q
T1OSCR	—	OSTS	HFIOFR	—	—	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Conditional

bit 7 **T1OSCR:** Timer1 Oscillator Ready bit
If T1OSCEN = 1:
1 = Timer1 oscillator is ready
0 = Timer1 oscillator is not ready
If T1OSCEN = 0:
1 = Timer1 clock source is always ready

bit 6 **Unimplemented:** Read as '0'

bit 5 **OSTS:** Oscillator Start-up Time-out Status bit
1 = Running from the external clock source (EC)
0 = Running from an internal oscillator (FOSC<1:0> = 00)

bit 4 **HFIOFR:** High-Frequency Internal Oscillator Ready bit
1 = HFINTOSC is ready
0 = HFINTOSC is not ready

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **LFIOFR:** Low-Frequency Internal Oscillator Ready bit
1 = LFINTOSC is ready
0 = LFINTOSC is not ready

bit 0 **HFIOFS:** High-Frequency Internal Oscillator Stable bit
1 = HFINTOSC 16 MHz oscillator is stable and is driving the INTOSC
0 = HFINTOSC 16 MHz oscillator is not stable, the start-up oscillator is driving INTOSC

TABLE 6-2: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	—	IRCF<3:0>				—	SCS<1:0>		58
OSCSTAT	T1OSCR	—	OSTS	HFIOFR	—	—	LFIOFR	HFIOFS	59
T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	139

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

TABLE 6-3: SUMMARY OF CONFIGURATION WORD WITH CLOCK SOURCES

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	39
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

7.0 INTERRUPTS

The interrupt feature allows certain events to preempt normal program flow. Firmware is used to determine the source of the interrupt and act accordingly. Some interrupts can be configured to wake the MCU from Sleep mode.

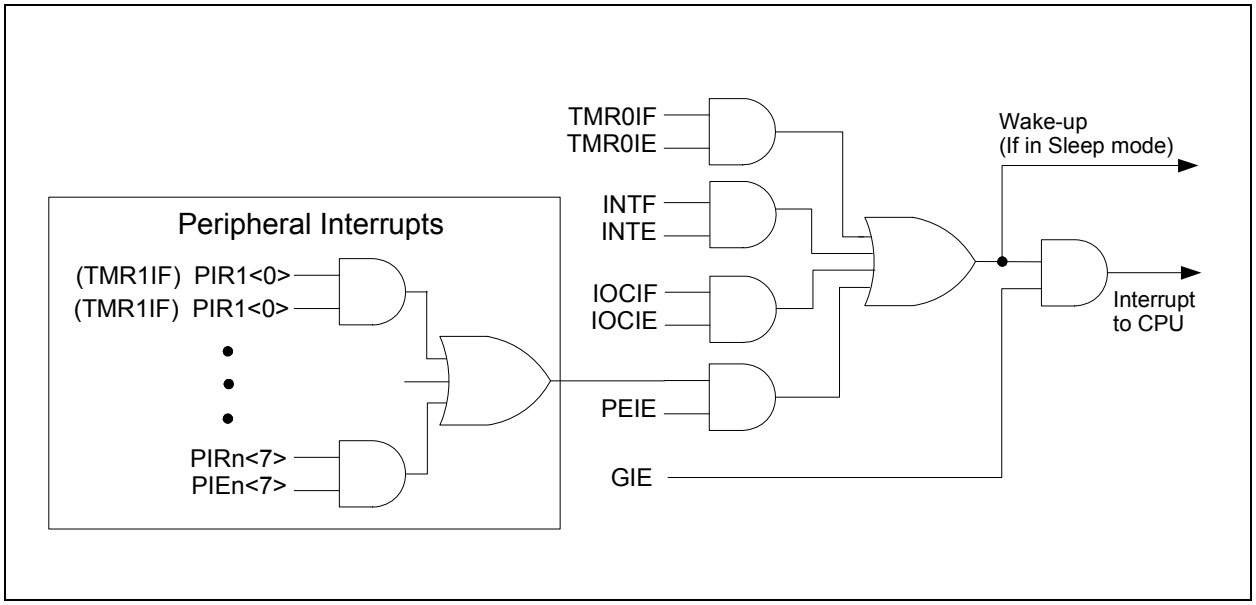
This chapter contains the following information for Interrupts:

- Operation
- Interrupt Latency
- Interrupts During Sleep
- INT Pin
- Automatic Context Saving

Many peripherals produce Interrupts. Refer to the corresponding chapters for details.

A block diagram of the interrupt logic is shown in Figure 7.1.

FIGURE 7-1: INTERRUPT LOGIC



7.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIE1 and PIE2 registers)

The INTCON, PIR1 and PIR2 registers record individual interrupts via interrupt flag bits. Interrupt flag bits will be set, regardless of the status of the GIE, PEIE and individual interrupt enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- Critical registers are automatically saved to the shadow registers (See **Section 7.5 "Automatic Context Saving"**)
- PC is loaded with the interrupt vector 0004h

The firmware within the Interrupt Service Routine (ISR) should determine the source of the interrupt by polling the interrupt flag bits. The interrupt flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any interrupt that occurs while executing the ISR will be recorded through its interrupt flag, but will not cause the processor to redirect to the interrupt vector.

The `RETFIE` instruction exits the ISR by popping the previous address from the stack, restoring the saved context from the shadow registers and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

Note 1:	Individual interrupt flag bits are set, regardless of the state of any other enable bits.
2:	All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

7.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is three or four instruction cycles. For asynchronous interrupts, the latency is three to five instruction cycles, depending on when the interrupt occurs. See Figure 7-2 and Figure 7.3 for more details.

FIGURE 7-2: INTERRUPT LATENCY

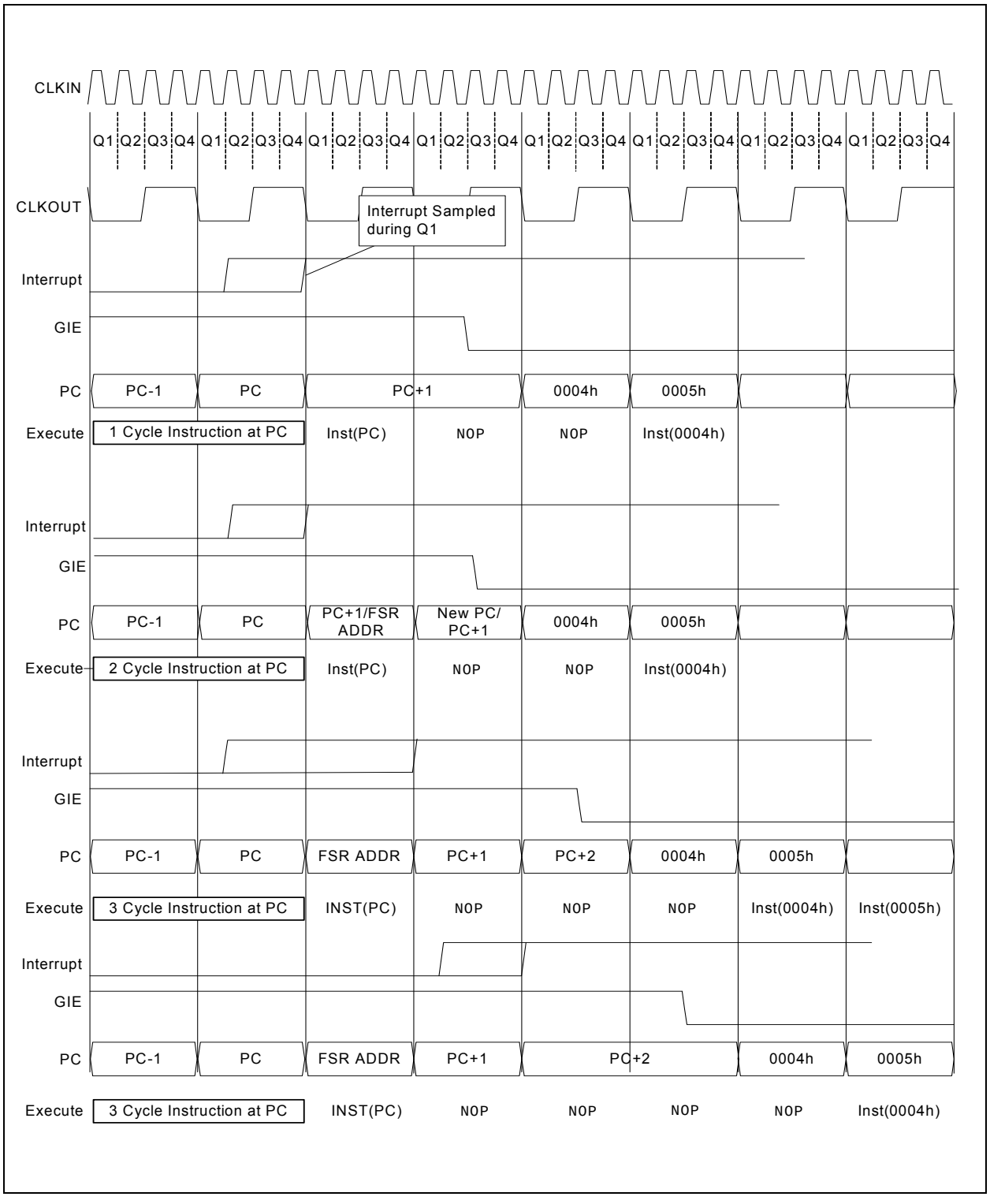
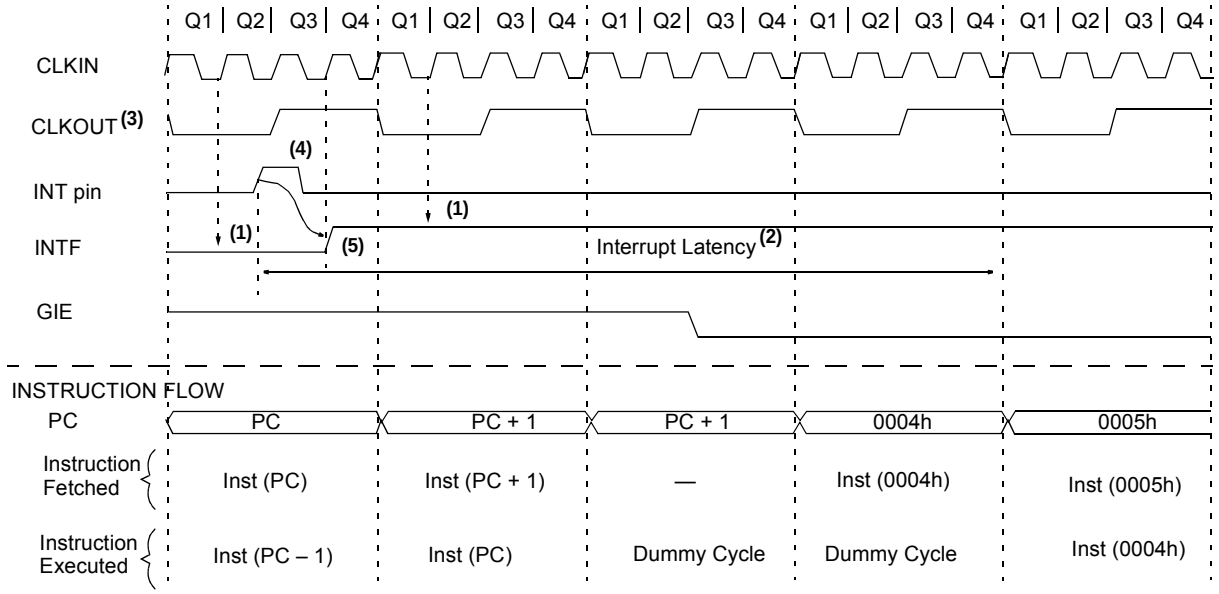


FIGURE 7-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all Oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 22.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

7.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate interrupt enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to **Section 8.0 "Power-Down Mode (Sleep)"** for more details.

7.4 INT Pin

The INT pin can be used to generate an asynchronous edge-triggered interrupt. This interrupt is enabled by setting the INTE bit of the INTCON register. The INTEDG bit of the OPTION_REG register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector.

7.5 Automatic Context Saving

Upon entering an interrupt, the return PC address is saved on the stack. Additionally, the following registers are automatically saved in the shadow registers:

- W register
- STATUS register (except for $\overline{TO}$ and $\overline{PD}$)
- BSR register
- FSR registers
- PCLATH register

Upon exiting the Interrupt Service Routine, these registers are automatically restored. Any modifications to these registers during the ISR will be lost. If modifications to any of these registers are desired, the corresponding shadow register should be modified and the value will be restored when exiting the ISR. The shadow registers are available in Bank 31 and are readable and writable. Depending on the user's application, other registers may also need to be saved.

7.6 Interrupt Control Registers

7.6.1 INTCON REGISTER

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, interrupt-on-change and external INT pin interrupts.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 7-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0
GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all active interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all active peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **TMR0IE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt

bit 4 **INTE:** INT External Interrupt Enable bit
1 = Enables the INT external interrupt
0 = Disables the INT external interrupt

bit 3 **IOCIE:** Interrupt-on-Change Interrupt Enable bit
1 = Enables the interrupt-on-change interrupt
0 = Disables the interrupt-on-change interrupt

bit 2 **TMR0IF:** Timer0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed
0 = TMR0 register did not overflow

bit 1 **INTF:** INT External Interrupt Flag bit
1 = The INT external interrupt occurred
0 = The INT external interrupt did not occur

bit 0 **IOCIF:** Interrupt-on-Change Interrupt Flag bit
1 = When at least one of the interrupt-on-change pins changed state
0 = None of the interrupt-on-change pins have changed state

7.6.2 PIE1 REGISTER

The PIE1 register contains the interrupt enable bits, as shown in Register 7-2.

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 7-2: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	R/W-0/0
TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **TMR1GIE:** Timer1 Gate Interrupt Enable bit
1 = Enables the Timer1 gate acquisition interrupt
0 = Disables the Timer1 gate acquisition interrupt

bit 6 **ADIE:** A/D Converter (ADC) Interrupt Enable bit
1 = Enables the ADC interrupt
0 = Disables the ADC interrupt

bit 5 **RCIE:** USART Receive Interrupt Enable bit
1 = Enables the USART receive interrupt
0 = Disables the USART receive interrupt

bit 4 **TXIE:** USART Transmit Interrupt Enable bit
1 = Enables the USART transmit interrupt
0 = Disables the USART transmit interrupt

bit 3-1 **Unimplemented:** Read as ‘0’

bit 0 **TMR1IE:** Timer1 Overflow Interrupt Enable bit
1 = Enables the Timer1 overflow interrupt
0 = Disables the Timer1 overflow interrupt

.

7.6.3 PIE2 REGISTER

The PIE2 register contains the interrupt enable bits, as shown in Register 7-3.

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 7-3: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2

U-0	U-0	U-0	U-0	U-0	R/W-0/0	U-0	U-0
—	—	—	—	—	LCDIE	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **LCDIE:** LCD Module Interrupt Enable bit
1 = Enables the LCD module interrupt
0 = Disables the LCD module interrupt

bit 1-0 **Unimplemented:** Read as ‘0’

7.6.4 PIR1 REGISTER

The PIR1 register contains the interrupt flag bits, as shown in Register 7-4.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 7-4: PIR1: PERIPHERAL INTERRUPT REQUEST REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	R/W-0/0
TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **TMR1GIF:** Timer1 Gate Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 6 **ADIF:** A/D Converter Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 5 **RCIF:** USART Receive Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 4 **TXIF:** USART Transmit Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 3-1 **Unimplemented:** Read as ‘0’

bit 0 **TMR1IF:** Timer1 Overflow Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

7.6.5 PIR2 REGISTER

The PIR2 register contains the interrupt flag bits, as shown in Register 7-5.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 7-5: PIR2: PERIPHERAL INTERRUPT REQUEST REGISTER 2

U-0	U-0	U-0	U-0	U-0	R/W-0/0	U-0	U-0
—	—	—	—	—	LCDIF	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **LCDIF:** LCD Module Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 1-0 **Unimplemented:** Read as ‘0’

TABLE 7-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	T0CS	T0SE	PSA	PS<2:0>			130
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	66
PIE2	—	—	—	—	—	LCDIE	—	—	67
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	68
PIR2	—	—	—	—	—	LCDIF	—	—	69

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Interrupts.

8.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Secondary oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Secondary oscillator

I/O pins that are high-impedance inputs should be pulled to VDD or VSS externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include the FVR module. See **13.0 "Fixed Voltage Reference (FVR)"** for more information.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 5.11, Determining the Cause of a Reset**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

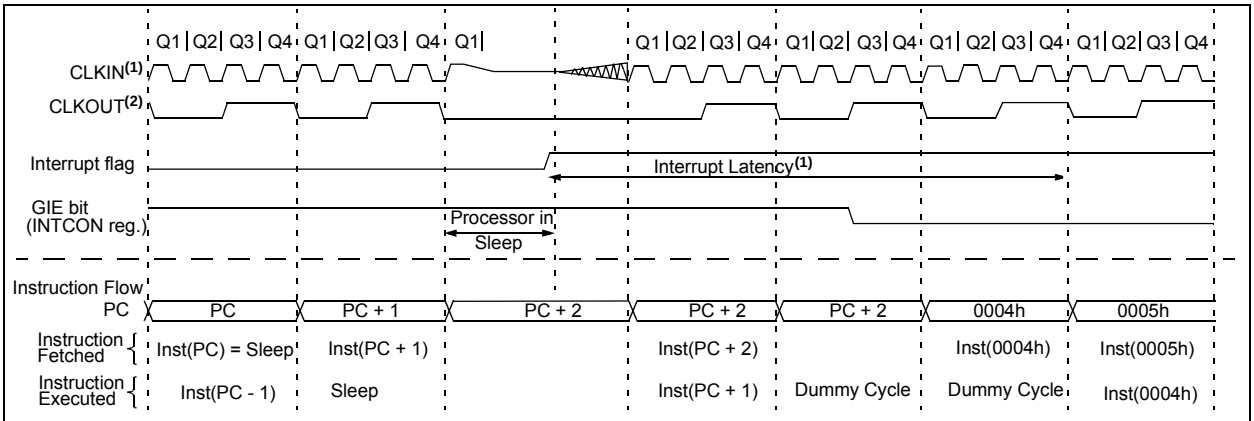
8.1.1 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction
  - SLEEP instruction will execute as a NOP.
  - WDT and WDT prescaler will not be cleared
  - $\overline{TO}$ bit of the STATUS register will not be set
  - $\overline{PD}$ bit of the STATUS register will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction
  - SLEEP instruction will be completely executed
  - Device will immediately wake-up from Sleep
  - WDT and WDT prescaler will be cleared
  - $\overline{TO}$ bit of the STATUS register will be set
  - $\overline{PD}$ bit of the STATUS register will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

FIGURE 8-1: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: GIE = 1 assumed. In this case after wake-up, the processor calls the ISR at 0004h. If GIE = 0, execution will continue in-line.

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH POWER-DOWN MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	110
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	110
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	110
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	66
PIE2	—	—	—	—	—	LCDIE	—	—	67
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	68
PIR2	—	—	—	—	—	LCDIF	—	—	69
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	21
WDTCON	—	—	WDTPS<4:0>					SWDTEN	75

Legend: — = unimplemented location, read as '0'. Shaded cells are not used in Power-down mode.

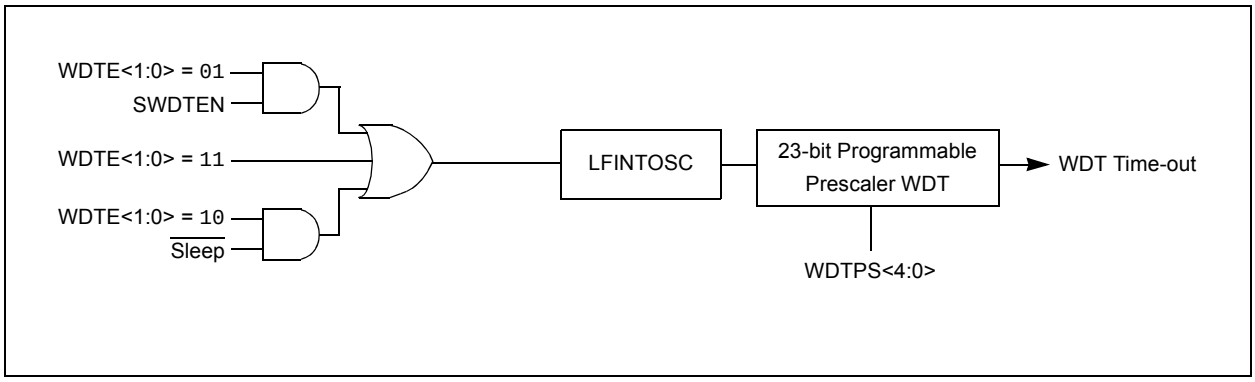
9.0 WATCHDOG TIMER

The Watchdog Timer is a system timer that generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The Watchdog Timer is typically used to recover the system from unexpected events.

The WDT has the following features:

- Independent clock source
- Multiple operating modes
  - WDT is always on
  - WDT is off when in Sleep
  - WDT is controlled by software
  - WDT is always off
- Configurable time-out period is from 1 ms to 256 seconds (typical)
- Multiple Reset conditions
- Operation during Sleep

FIGURE 9-1: WATCHDOG TIMER BLOCK DIAGRAM



9.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1ms. See **Section 22.0 "Electrical Specifications"** for the LFINTOSC tolerances.

9.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 9-1.

9.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to '11', the WDT is always on.

WDT protection is active during Sleep.

9.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

9.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 9-1 for more details.

TABLE 9-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0		Disabled
00	X	X	Disabled

9.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is two seconds.

9.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled
- Oscillator Start-up TImer (OST) is running

See Table 9-2 for more information.

9.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 6.0 "Oscillator Module"** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 "Memory Organization"** and STATUS register (**Register 3-1**) for more information.

TABLE 9-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Change INTOSC divider (IRCF bits)	Unaffected

9.6 Watchdog Control Register

REGISTER 9-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1	R/W-1/1	R/W-0/0
—	—	WDTPS<4:0>					SWDTEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-1 **WDTPS<4:0>:** Watchdog Timer Period Select bits(1)

Bit Value = Prescale Rate

00000 = 1:32 (Interval 1 ms nominal)
00001 = 1:64 (Interval 2 ms nominal)
00010 = 1:128 (Interval 4 ms nominal)
00011 = 1:256 (Interval 8 ms nominal)
00100 = 1:512 (Interval 16 ms nominal)
00101 = 1:1024 (Interval 32 ms nominal)
00110 = 1:2048 (Interval 64 ms nominal)
00111 = 1:4096 (Interval 128 ms nominal)
01000 = 1:8192 (Interval 256 ms nominal)
01001 = 1:16384 (Interval 512 ms nominal)
01010 = 1:32768 (Interval 1s nominal)
01011 = 1:65536 (Interval 2s nominal) (Reset value)
01100 = 1:131072 (2^{17}) (Interval 4s nominal)
01101 = 1:262144 (2^{18}) (Interval 8s nominal)
01110 = 1:524288 (2^{19}) (Interval 16s nominal)
01111 = 1:1048576 (2^{20}) (Interval 32s nominal)
10000 = 1:2097152 (2^{21}) (Interval 64s nominal)
10001 = 1:4194304 (2^{22}) (Interval 128s nominal)
10010 = 1:8388608 (2^{23}) (Interval 256s nominal)

10011 = Reserved. Results in minimum interval (1:32)
•
•
•
11111 = Reserved. Results in minimum interval (1:32)

bit 0 **SWDTEN:** Software Enable/Disable for Watchdog Timer bit

If WDTE<1:0> = 00:
This bit is ignored.
If WDTE<1:0> = 01:
1 = WDT is turned on
0 = WDT is turned off
If WDTE<1:0> = 1x:
This bit is ignored.

Note 1: Times are approximate. WDT time is based on 31 kHz LFINTOSC.

TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	—	IRCF<3:0>				—	SCS<1:0>		58
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	21
WDTCON	—	—	WDTPS<4:0>					SWDTEN	75

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by Watchdog Timer.

TABLE 9-4: SUMMARY OF CONFIGURATION WORD WITH WATCHDOG TIMER

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{CLKOUTEN}$	BOREN<1:0>		—	39
	7:0	$\overline{CP}$	MCLRE	$\overline{PWRTE}$	WDTE<1:0>		—	FOSC<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Watchdog Timer.

10.0 FLASH PROGRAM MEMORY CONTROL

The Flash Program Memory is readable and writable during normal operation over the full VDD range. Program memory is indirectly addressed using Special Function Registers (SFRs). The SFRs used to access program memory are:

- PMCON1
- PMCON2
- PMDATL
- PMDATH
- PMADRL
- PMADRH

When accessing the program memory, the PMDATH:PMDATL register pair forms a 2-byte word that holds the 14-bit data for read/write, and the PMADRH:PMADRL register pair forms a 2-byte word that holds the 15-bit address of the program memory location being read.

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump rated to operate over the operating voltage range of the device.

The Flash Program Memory can be protected in two ways; by code protection ($\overline{CP}$ bit in Configuration Word 1) and write protection (WRT<1:0> bits in Configuration Word 2).

Code protection ($\overline{CP}$ = 0)**(1)**, disables access, reading and writing, to the Flash Program Memory via external device programmers. Code protection does not affect the self-write and erase functionality. Code protection can only be reset by a device programmer performing a Bulk Erase to the device, clearing all Flash Program Memory, Configuration bits and User IDs.

Write protection prohibits self-write and erase to a portion or all of the Flash Program Memory as defined by the bits WRT<1:0>. Write protection does not affect a device programmers ability to read, write or erase the device.

Note 1:	Code protection of the entire Flash Program Memory array is enabled by clearing the $\overline{CP}$ bit of Configuration Word 1.

10.1 PMADRL and PMADRH Registers

The PMADRH:PMADRL register pair can address up to a maximum of 32K words of program memory. When selecting a program address value, the MSB of the address is written to the PMADRH register and the LSB is written to the PMADRL register.

10.1.1 PMCON1 AND PMCON2 REGISTERS

PMCON1 is the control register for Flash Program Memory accesses.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared by hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation to occur. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and execute the appropriate error handling routine.

The PMCON2 register is a write-only register. Attempting to read the PMCON2 register will return all '0's.

To enable writes to the program memory, a specific pattern (the unlock sequence), must be written to the PMCON2 register. The required unlock sequence prevents inadvertent writes to the program memory write latches and Flash Program Memory.

10.2 Flash Program Memory Overview

It is important to understand the Flash Program Memory structure for erase and programming operations. Flash Program Memory is arranged in rows. A row consists of a fixed number of 14-bit program memory words. A row is the minimum size that can be erased by user software.

After a row has been erased, the user can reprogram all or a portion of this row. Data to be written into the program memory row is written to 14-bit wide data write latches. These write latches are not directly accessible to the user, but may be loaded via sequential writes to the PMDATH:PMDATL register pair.

Note:	If the user wants to modify only a portion of a previously programmed row, then the contents of the entire row must be read and saved in RAM prior to the erase. Then, new data and retained data can be written into the write latches to reprogram the row of Flash Program Memory. However, any unprogrammed locations can be written without first erasing the row. In this case, it is not necessary to save and rewrite the other previously programmed locations.

See Table 10-1 for Erase Row size and the number of write latches for Flash program memory.

TABLE 10-1: FLASH MEMORY ORGANIZATION BY DEVICE

Device	Row Erase (words)	Write Latches (words)
PIC16LF1904/6/7	32	32

10.2.1 READING THE FLASH PROGRAM MEMORY

To read a program memory location, the user must:

1. Write the desired address to the PMADRH:PMADRL register pair.
2. Clear the CFGS bit of the PMCON1 register.
3. Then, set control bit RD of the PMCON1 register.

Once the read control bit is set, the program memory Flash controller will use the second instruction cycle to read the data. This causes the second instruction immediately following the "`BSF PMCON1,RD`" instruction to be ignored. The data is available in the very next cycle, in the PMDATH:PMDATL register pair; therefore, it can be read as two bytes in the following instructions.

PMDATH:PMDATL register pair will hold this value until another read or until it is written to by the user.

Note:	The two instructions following a program memory read are required to be `NOP`s. This prevents the user from executing a 2-cycle instruction on the next instruction after the RD bit is set.

FIGURE 10-1: FLASH PROGRAM MEMORY READ FLOWCHART

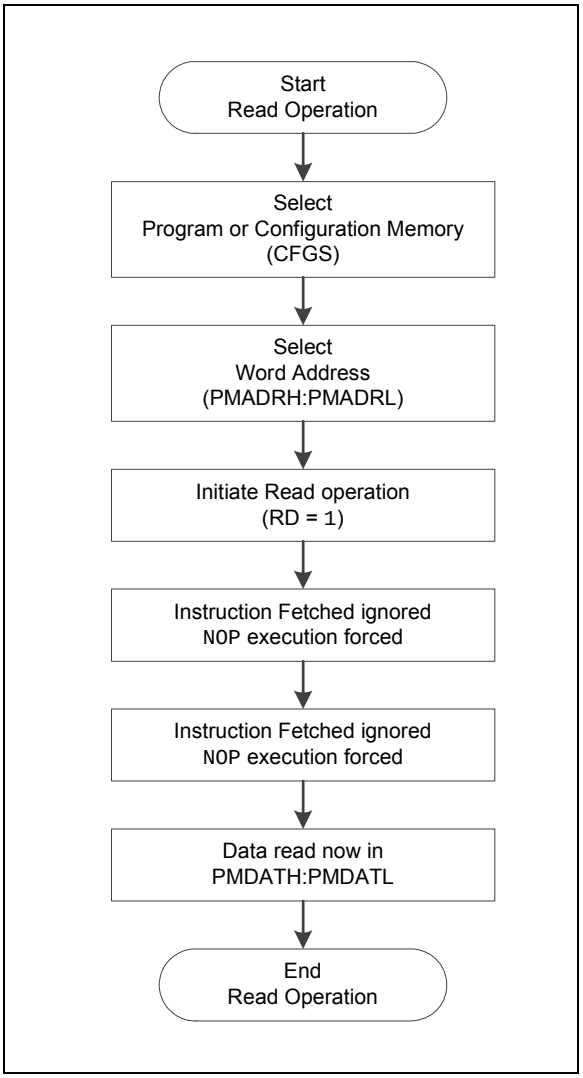
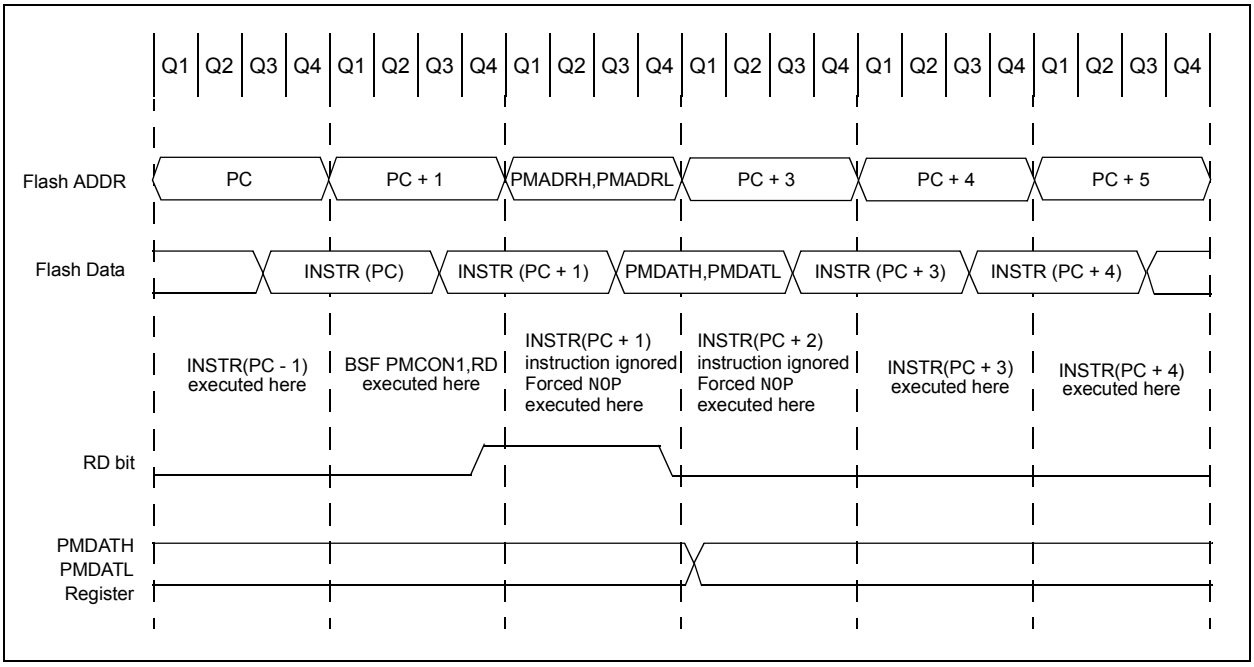


FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWL    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-1)
    NOP                       ; Ignored (Figure 10-1)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

10.2.2 FLASH MEMORY UNLOCK SEQUENCE

The unlock sequence is a mechanism that protects the Flash Program Memory from unintended self-write programming or erasing. The sequence must be executed and completed without interruption to successfully complete any of the following operations:

- Row Erase
- Load program memory write latches
- Write of program memory write latches to program memory
- Write of program memory write latches to User IDs

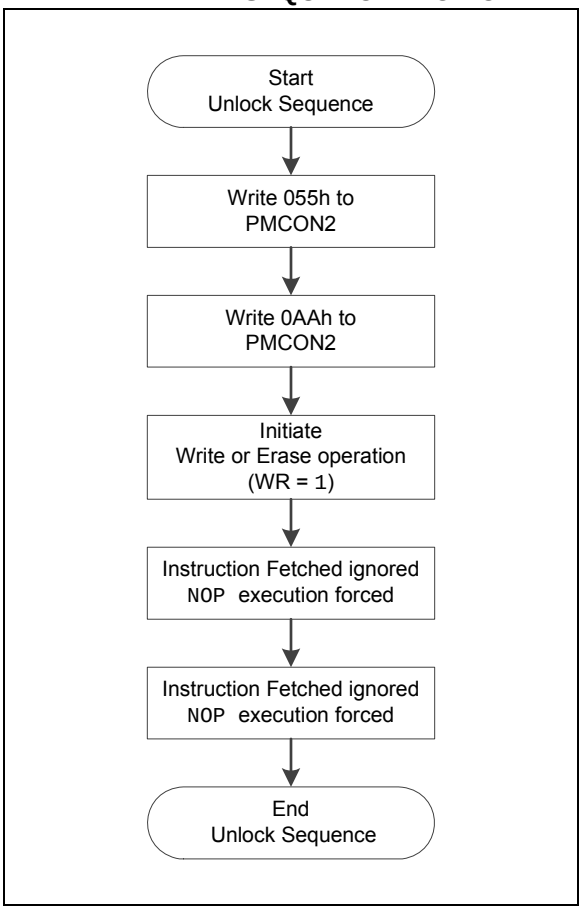
The unlock sequence consists of the following steps:

1. Write 55h to PMCON2
2. Write AAh to PMCON2
3. Set the WR bit in PMCON1
4. NOP instruction
5. NOP instruction

Once the WR bit is set, the processor will always force two NOP instructions. When an Erase Row or Program Row operation is being performed, the processor will stall internal operations (typical 2 ms), until the operation is complete and then resume with the next instruction. When the operation is loading the program memory write latches, the processor will always force the two NOP instructions and continue uninterrupted with the next instruction.

Since the unlock sequence must not be interrupted, global interrupts should be disabled prior to the unlock sequence and re-enabled after the unlock sequence is completed.

FIGURE 10-3: FLASH PROGRAM MEMORY UNLOCK SEQUENCE FLOWCHART



10.2.3 ERASING FLASH PROGRAM MEMORY

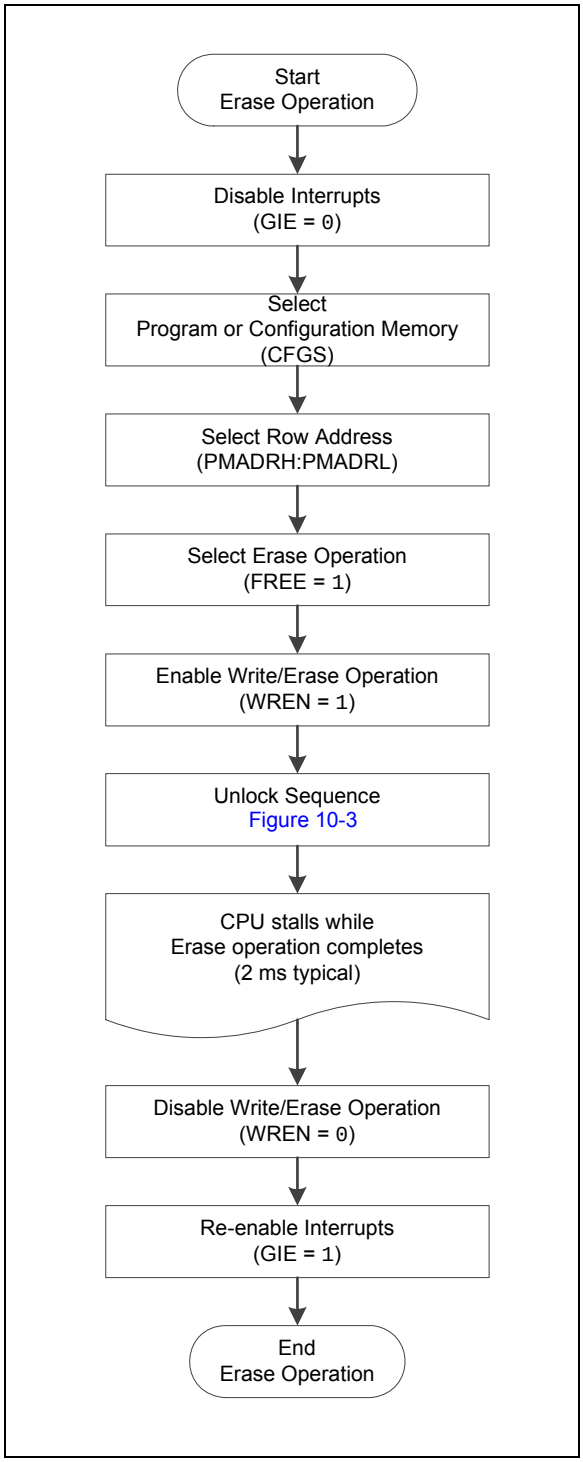
While executing code, program memory can only be erased by rows. To erase a row:

1. Load the PMADRH:PMADRL register pair with any address within the row to be erased.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the FREE and WREN bits of the PMCON1 register.
4. Write 55h, then AAh, to PMCON2 (Flash programming unlock sequence).
5. Set control bit WR of the PMCON1 register to begin the erase operation.

See Example 10-2.

After the "`BSF PMCON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the PMCON1 write instruction.

FIGURE 10-4: FLASH PROGRAM MEMORY ERASE FLOWCHART



EXAMPLE 10-2: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase row is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       PMADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       PMADRH
        BCF         PMCON1,CFGS     ; Not configuration space
        BSF         PMCON1,FREE     ; Specify an erase operation
        BSF         PMCON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       PMCON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       PMCON2          ; Write AAh
        BSF         PMCON1,WR       ; Set WR bit to begin erase
        NOP                         ; NOP instructions are forced as processor starts
        NOP                         ; row erase of program memory.
                                    ;
                                    ; The processor stalls until the erase process is complete
                                    ; after erase processor continues with 3rd instruction

        BCF         PMCON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

10.2.4 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the address in PMADRH:PMADRL of the row to be programmed.
2. Load each write latch with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 10-2 (row writes to program memory with 32 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper ten bits of PMADRH:PMADRL, (PMADRH<6:0>:PMADRL<7:5>) with the lower five bits of PMADRL, (PMADRL<4:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the PMDATH:PMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash Program Memory.

Note:	The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.

1. Set the WREN bit of the PMCON1 register.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash Program Memory.
4. Load the PMADRH:PMADRL register pair with the address of the location to be written.
5. Load the PMDATH:PMDATL register pair with the program memory data to be written.
6. Execute the unlock sequence (**Section 10.2.2 "Flash Memory Unlock Sequence"**). The write latch is now loaded.
7. Increment the PMADRH:PMADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '0', the write sequence will initiate the write to Flash Program Memory.
10. Load the PMDATH:PMDATL register pair with the program memory data to be written.
11. Execute the unlock sequence (**Section 10.2.2 "Flash Memory Unlock Sequence"**). The entire program memory latch content is now written to Flash Program Memory.

Note:	The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

An example of the complete write sequence is shown in Example 10-3. The initial address is loaded into the PMADRH:PMADRL register pair; the data is loaded using indirect addressing.

FIGURE 10-5: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES

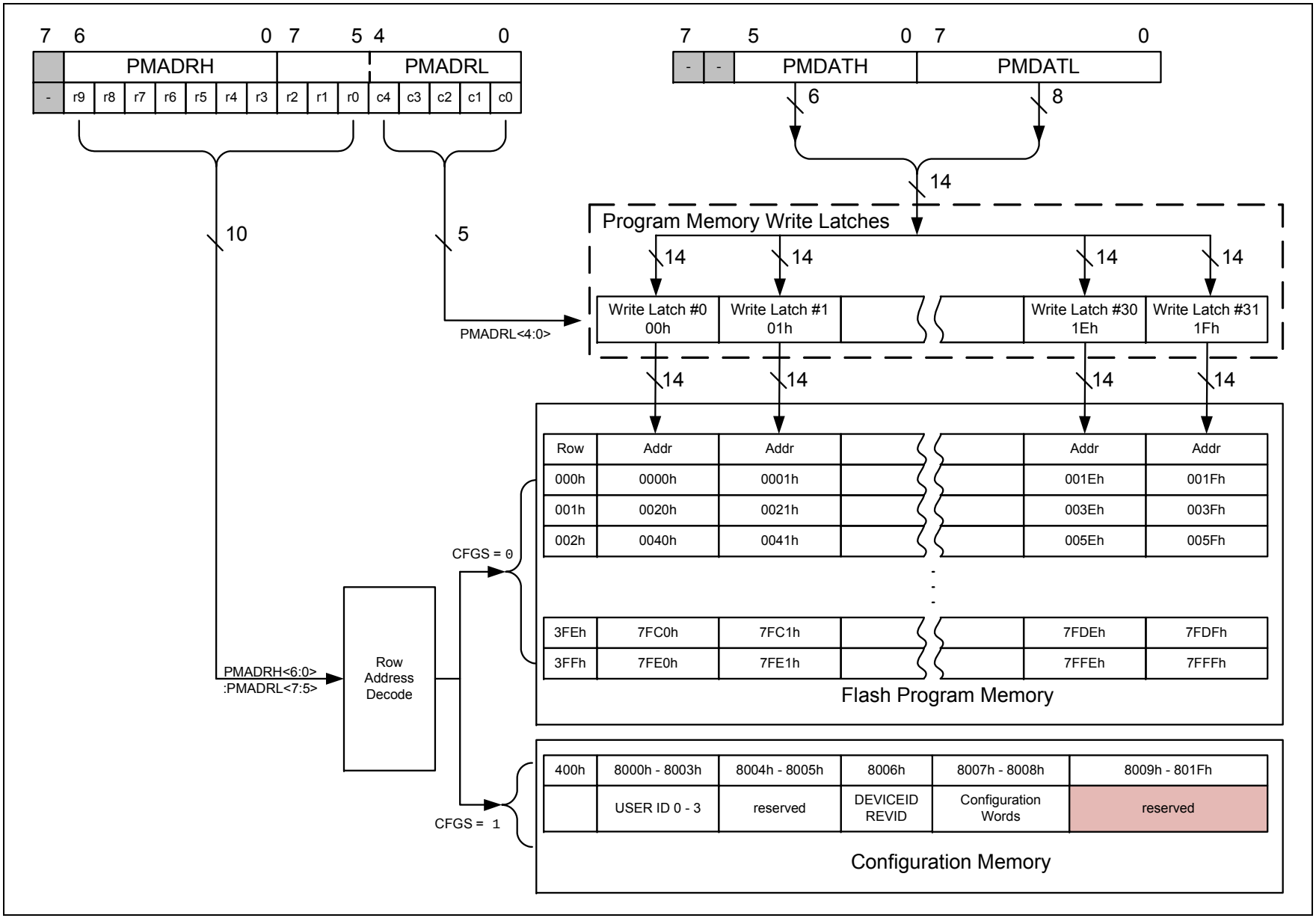
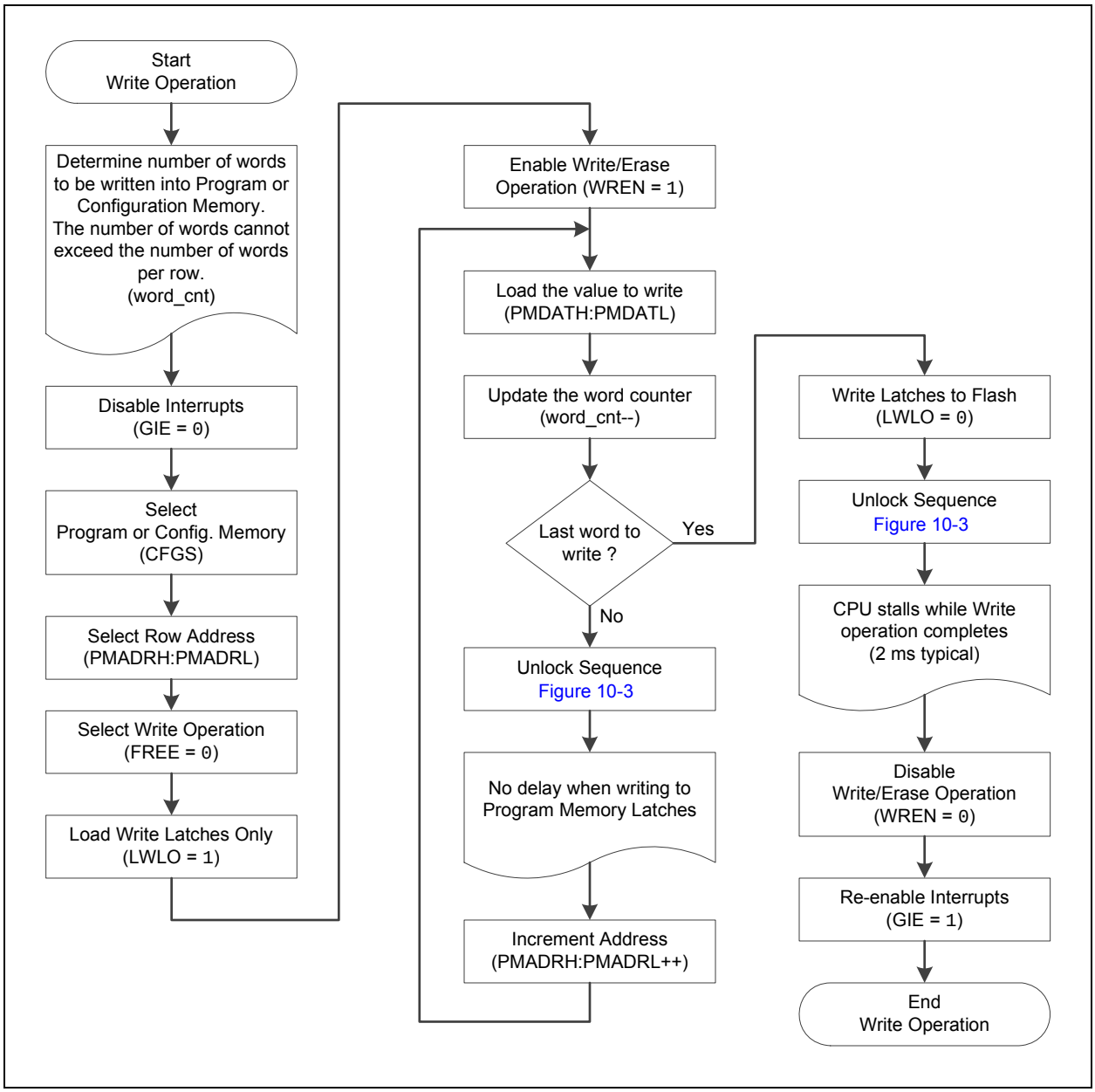


FIGURE 10-6: FLASH PROGRAM MEMORY WRITE FLOWCHART



EXAMPLE 10-3: WRITING TO FLASH PROGRAM MEMORY

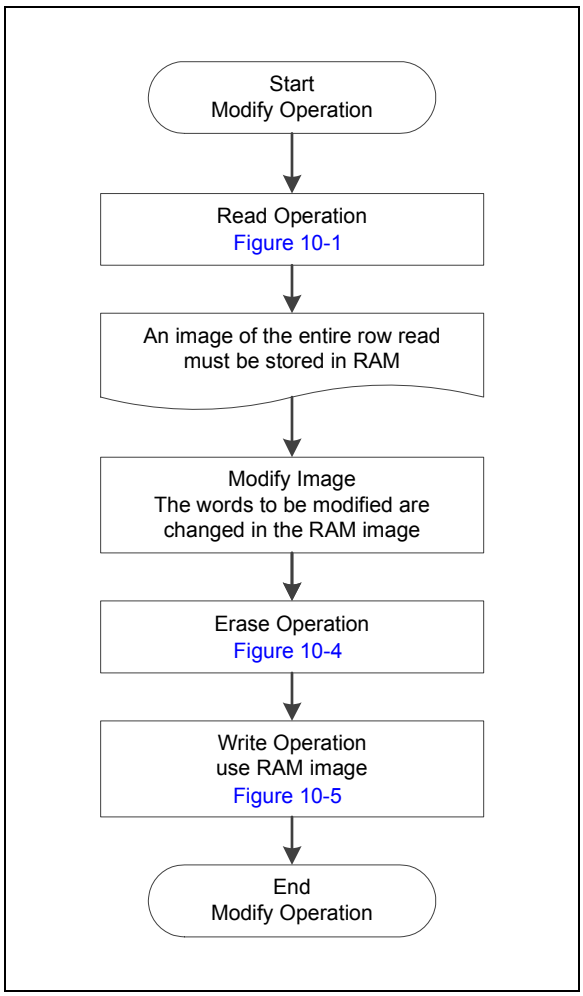
```
; This write routine assumes the following:
; 1. 64 bytes of data are loaded, starting at the address in DATA_ADDR
; 2. Each word of data to be written is made up of two adjacent bytes in DATA_ADDR,
;    stored in little endian format
; 3. A valid starting address (the least significant bits = 00000) is loaded in ADDRH:ADDRL
; 4. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)
;
        BCF         INTCON,GIE     ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRH         ; Bank 3
        MOVF        ADDRH,W        ; Load initial address
        MOVWF       PMADRH         ;
        MOVF        ADDRL,W        ;
        MOVWF       PMADRL         ;
        MOVLW       LOW DATA_ADDR  ; Load initial data address
        MOVWF       FSR0L          ;
        MOVLW       HIGH DATA_ADDR ; Load initial data address
        MOVWF       FSR0H          ;
        BCF         PMCON1,CFGS    ; Not configuration space
        BSF         PMCON1,WREN    ; Enable writes
        BSF         PMCON1,LWLO    ; Only Load Write Latches
LOOP
        MOVIW       FSR0++         ; Load first data byte into lower
        MOVWF       PMDATL         ;
        MOVIW       FSR0++         ; Load second data byte into upper
        MOVWF       PMDATH         ;

        MOVF        PMADRL,W       ; Check if lower bits of address are '00000'
        XORLW       0x1F           ; Check if we're on the last of 32 addresses
        ANDLW       0x1F           ;
        BTFSC       STATUS,Z       ; Exit if last of 32 words,
        GOTO        START_WRITE    ;

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       PMCON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       PMCON2         ; Write AAh
        BSF         PMCON1,WR      ; Set WR bit to begin write
        NOP                        ; NOP instructions are forced as processor
                                   ; loads program memory write latches
        NOP                        ;

        INCF        PMADRL,F       ; Still loading latches Increment address
        GOTO        LOOP           ; Write next latches

START_WRITE
        BCF         PMCON1,LWLO    ; No more loading latches - Actually start Flash program
                                   ; memory write

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       PMCON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       PMCON2         ; Write AAh
        BSF         PMCON1,WR      ; Set WR bit to begin write
        NOP                        ; NOP instructions are forced as processor writes
                                   ; all the program memory write latches simultaneously
        NOP                        ; to program memory.
                                   ; After NOPs, the processor
                                   ; stalls until the self-write process in complete
                                   ; after write processor continues with 3rd instruction
        BCF         PMCON1,WREN    ; Disable writes
        BSF         INTCON,GIE     ; Enable interrupts
```

10.3 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

1. Load the starting address of the row to be modified.
2. Read the existing data from the row into a RAM image.
3. Modify the RAM image to contain the new data to be written into program memory.
4. Load the starting address of the row to be rewritten.
5. Erase the program memory row.
6. Load the write latches with data from the RAM image.
7. Initiate a programming operation.

FIGURE 10-7: FLASH PROGRAM MEMORY MODIFY FLOWCHART



10.4 User ID, Device ID and Configuration Word Access

Instead of accessing program memory, the User ID's, Device ID/Revision ID and Configuration Words can be accessed when CFGS = 1 in the PMCON1 register. This is the region that would be pointed to by PC<15> = 1, but not all addresses are accessible. Different access may exist for reads and writes. Refer to Table 10-2.

When read access is initiated on an address outside the parameters listed in Table 10-2, the PMDATH:PMDATL register pair is cleared, reading back '0's.

TABLE 10-2: USER ID, DEVICE ID AND CONFIGURATION WORD ACCESS (CFGS = 1)

Address	Function	Read Access	Write Access
8000h-8003h	User IDs	Yes	Yes
8006h	Device ID/Revision ID	Yes	No
8007h-8008h	Configuration Words 1 and 2	Yes	No

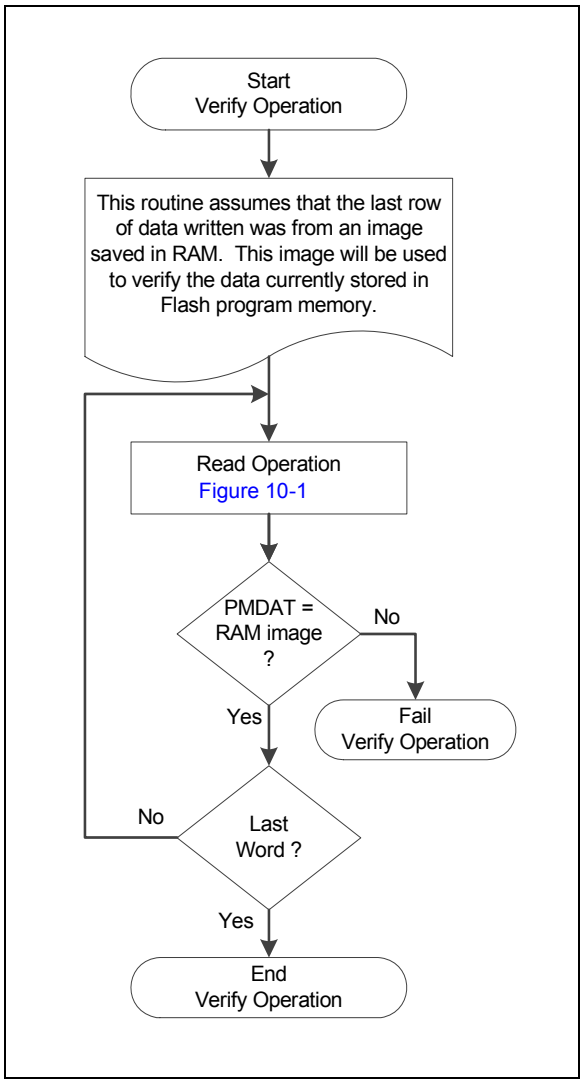
EXAMPLE 10-4: CONFIGURATION WORD AND DEVICE ID ACCESS

```
* This code block will read 1 word of program memory at the memory address:
*   PROG_ADDR_LO (must be 00h-08h) data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select correct Bank
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    CLRF     PMADRH           ; Clear MSB of address

    BSF      PMCON1,CFGS      ; Select Configuration Space
    BCF      INTCON,GIE       ; Disable interrupts
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Executed (See Figure 10-1)
    NOP                       ; Ignored (See Figure 10-1)
    BSF      INTCON,GIE       ; Restore interrupts

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

10.5 Write Verify

It is considered good programming practice to verify that program memory writes agree with the intended value. Since program memory is stored as a full page then the stored program memory contents are compared with the intended data stored in RAM after the last write is complete.

FIGURE 10-8: FLASH PROGRAM MEMORY VERIFY FLOWCHART



10.6 Flash Program Memory Control Registers

REGISTER 10-1: PMDATL: PROGRAM MEMORY DATA LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PMDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMDAT<7:0>**: Read/write value for Least Significant bits of program memory

REGISTER 10-2: PMDATH: PROGRAM MEMORY DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	PMDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PMDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 10-3: PMADRL: PROGRAM MEMORY ADDRESS LOW BYTE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PMADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMADR<7:0>**: Specifies the Least Significant bits for program memory address

REGISTER 10-4: PMADRH: PROGRAM MEMORY ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	PMADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘1’

bit 6-0 **PMADR<14:8>**: Specifies the Most Significant bits for program memory address

REGISTER 10-5: PMCON1: PROGRAM MEMORY CONTROL 1 REGISTER

U-1[1]	R/W-0/0	R/W-0/0	R/W/HC-0/0	R/W/HC-x/q[2]	R/W-0/0	R/S/HC-0/0	R/S/HC-0/0
—	CFGS	LWLO	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **Unimplemented:** Read as '1'

bit 6 **CFGS:** Configuration Select bit
- 1 = Access Configuration, User ID and Device ID registers
- 0 = Access Flash Program Memory

bit 5 **LWLO:** Load Write Latches Only bit[3]
- 1 = Only the addressed program memory write latch is loaded/updated on the next WR command
- 0 = The addressed program memory write latch is loaded/updated and a write of all program memory write latches will be initiated on the next WR command

bit 4 **FREE:** Program Flash Erase Enable bit
- 1 = Performs an erase operation on the next WR command (hardware cleared upon completion)
- 0 = Performs a write operation on the next WR command

bit 3 **WRERR:** Program/Erase Error Flag bit
- 1 = Condition indicates an improper program or erase sequence attempt or termination (bit is set automatically on any set attempt (write '1') of the WR bit).
- 0 = The program or erase operation completed normally.

bit 2 **WREN:** Program/Erase Enable bit
- 1 = Allows program/erase cycles
- 0 = Inhibits programming/erasing of program Flash

bit 1 **WR:** Write Control bit
- 1 = Initiates a program Flash program/erase operation.
  The operation is self-timed and the bit is cleared by hardware once operation is complete.
  The WR bit can only be set (not cleared) in software.
- 0 = Program/erase operation to the Flash is complete and inactive.

bit 0 **RD:** Read Control bit
- 1 = Initiates a program Flash read. Read takes one cycle. RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
- 0 = Does not initiate a program Flash read.

Note 1: Unimplemented bit, read as '1'.
2: The WRERR bit is automatically set by hardware when a program memory write or erase operation is started (WR = 1) .
3: The LWLO bit is ignored during a program memory erase operation (FREE = 1).

REGISTER 10-6: PMCON2: PROGRAM MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
Program Memory Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the PMCON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes.

TABLE 10-3: SUMMARY OF REGISTERS ASSOCIATED WITH FLASH PROGRAM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
PMCON1	—(1)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	91
PMCON2	Program Memory Control Register 2								92
PMADRL	PMADRL<7:0>								90
PMADRH	—(1)	PMADRH<6:0>							90
PMDATL	PMDATL<7:0>								90
PMDATH	—	—	PMDATH<5:0>						90
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the Flash Program Memory module.
Note 1: Unimplemented, read as '1'.

TABLE 10-4: SUMMARY OF CONFIGURATION WORD WITH FLASH PROGRAM MEMORY

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	39
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	—	40
	7:0	—	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the Flash Program Memory.

11.0 I/O PORTS

In general, when a peripheral is enabled on a port pin, that pin cannot be used as a general purpose output. However, the pin can still be read.

Each port has three standard registers for its operation. These registers are:

- TRISx registers (data direction)
- PORTx registers (reads the levels on the pins of the device)
- LATx registers (output latch)

Some ports may have one or more of the following additional registers. These registers are:

- ANSELx (analog select)
- WPUx (weak pull-up)

TABLE 11-1: PORT AVAILABILITY PER DEVICE

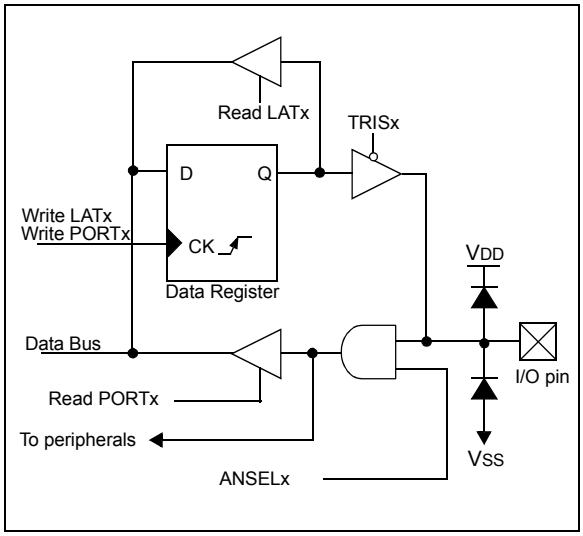
Device	PORTA	PORTB	PORTC	PORTD	PORTE
PIC16LF1906	•	•	•		•
PIC16LF1904/7	•	•	•	•	•

The data latch (LATA register) is useful for read-modify-write operations on the value that the I/O pins are driving.

A write operation to the LATA register has the same affect as a write to the corresponding PORTA register. A read of the LATA register reads of the values held in the I/O port latches, while a read of the PORTA register reads the actual I/O pin value.

Ports that support analog inputs have an associated ANSELx register. When an ANSEL bit is set, the digital input buffer associated with that bit is disabled. Disabling the input buffer prevents analog signal levels on the pin between a logic high and low from causing excessive current in the logic input circuitry. A simplified model of a generic I/O port, without the interfaces to other peripherals, is shown in Figure 11-1.

FIGURE 11-1: GENERIC I/O PORT OPERATION



EXAMPLE 11-1: INITIALIZING PORTA

```
; This code example illustrates
; initializing the PORTA register. The
; other ports are initialized in the same
; manner.

BANKSEL  PORTA        ;
CLRF     PORTA        ;Init PORTA
BANKSEL  LATA         ;Data Latch
CLRF     LATA         ;
BANKSEL  ANSELA       ;
CLRF     ANSELA       ;digital I/O
BANKSEL  TRISA        ;
MOVLW    B'00111000'  ;Set RA<5:3> as inputs
MOVWF    TRISA        ;and set RA<2:0> as
                      ;outputs
```

11.1 PORTA Registers

PORTA is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISA (Register 11-2). Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., disable the output driver). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., enables output driver and puts the contents of the output latch on the selected pin). The exception is RA3, which is input only and its TRIS bit will always read as '1'. Example 11-1 shows how to initialize PORTA.

Reading the PORTA register (Register 11-1) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATA).

The TRISA register (Register 11-2) controls the PORTA pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISA register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

11.1.1 ANSELA REGISTER

The ANSELA register (Register 11-4) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELA bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELA bits has no effect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELA bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

11.1.2 PORTA FUNCTIONS AND OUTPUT PRIORITIES

Each PORTA pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 11-2.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input functions, such as ADC, comparator and CapSense inputs, are not shown in the priority lists. These inputs are active when the I/O pin is set for Analog mode using the ANSELx registers. Digital output functions may control the pin when it is in Analog mode with the priority shown in Table 11-2.

TABLE 11-2: PORTA OUTPUT PRIORITY

Pin Name	Function Priority(1)
RA0	SEG12 (LCD) AN0 RA0
RA1	SEG7 AN1 RA1
RA2	COM2 AN2 RA2
RA3	VREF+ COM3 SEG15 AN3 RA3
RA4	SEG4 T0CKI RA4
RA5	SEG5 AN4 RA5
RA6	CLKOUT SEG1 RA6
RA7	CLKIN SEG2 RA7

Note 1: Priority listed from highest to lowest.

REGISTER 11-1: PORTA: PORTA REGISTER

R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R-x/x	R/W-x/x	R/W-x/x	R/W-x/x
RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RA<7:0>**: PORTA I/O Value bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTA are actually written to the corresponding LATA register. Reads from the PORTA register is return of actual I/O pin values.

REGISTER 11-2: TRISA: PORTA TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **TRISA<7:4>:** PORTA Tri-State Control bits
1 = PORTA pin configured as an input (tri-stated)
0 = PORTA pin configured as an output

bit 3 **TRISA3:** RA3 Port Tri-State Control bit
This bit is always '1' as RA3 is an input only

bit 2-0 **TRISA<2:0>:** PORTA Tri-State Control bits
1 = PORTA pin configured as an input (tri-stated)
0 = PORTA pin configured as an output

REGISTER 11-3: LATA: PORTA DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **LATA<7:0>**: RA<7:4> Output Latch Value bits(1)

Note 1: Writes to PORTA are actually written to the corresponding LATA register. Reads from the PORTA register is return of actual I/O pin values.

REGISTER 11-4: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	R/W-1/1	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **ANSA5**: Analog Select between Analog or Digital Function on pins RA5, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **ANSA<3:0>**: Analog Select between Analog or Digital Function on pins RA<3:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

TABLE 11-3: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	96
LATA	LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	95
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			130
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	95
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	95

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

TABLE 11-4: SUMMARY OF CONFIGURATION WORD WITH PORTA

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	39
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by PORTA.

11.2 PORTB Registers

PORTB is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISB (Register 11-6). Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTB register (Register 11-5) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATB).

The TRISB register (Register 11-6) controls the PORTB pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISB register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

11.2.1 ANSELB REGISTER

The ANSELB register (Register 11-8) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELB bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELB bits has no effect on digital output functions. A pin with TRIS clear and ANSELB set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELB bits default to the Analog mode after reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

11.2.2 PORTB FUNCTIONS AND OUTPUT PRIORITIES

Each PORTB pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 11-5.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in Table 11-5.

TABLE 11-5: PORTB OUTPUT PRIORITY

Pin Name	Function Priority(1)
RB0	SEG0 AN12 INT IOC RB0
RB1	SEG24 AN10 VLCD1 IOC RB1
RB2	SEG25 AN8 VLCD2 IOC RB2
RB3	SEG26 AN9 VLCD3 IOC RB3
RB4	COM0 AN11 IOC RB4
RB5	COM1 AN13 IOC RB5
RB6	ICDCLK SEG14 IOC RB6
RB7	ICDDAT SEG13 IOC RB7

Note 1: Priority listed from highest to lowest.

REGISTER 11-5: PORTB: PORTB REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **RB<7:0>**: PORTB General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTB are actually written to the corresponding LATB register. Reads from the PORTB register is return of actual I/O pin values.

REGISTER 11-6: TRISB: PORTB TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **TRISB<7:0>:** PORTB Tri-State Control bits
1 = PORTB pin configured as an input (tri-stated)
0 = PORTB pin configured as an output

REGISTER 11-7: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **LATB<7:0>**: PORTB Output Latch Value bits(1)

Note 1: Writes to PORTB are actually written to the corresponding LATB register. Reads from the PORTB register is return of actual I/O pin values.

REGISTER 11-8: ANSELB: PORTB ANALOG SELECT REGISTER

U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **ANSB<5:0>**: Analog Select between Analog or Digital Function on pins RB<5:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 11-9: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **WPUB<7:0>**: Weak Pull-up Register bits
1 = Pull-up enabled
0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

TABLE 11-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	99
LATB	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	98
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	98
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	98
WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	99

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTB.

11.3 PORTC Registers

PORTC is an 8-bit wide bidirectional port. The corresponding data direction register is TRISC (Register 11-6). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTC register (Register 11-5) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATC).

The TRISC register (Register 11-6) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

11.3.1 PORTC FUNCTIONS AND OUTPUT PRIORITIES

Each PORTC pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 11-7.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in Table 11-7.

TABLE 11-7: PORTC OUTPUT PRIORITY

Pin Name	Function Priority(1)
RC0	T1OSO T1CKI RC0
RC1	T1OSI RC1
RC2	SEG2 RC2
RC3	SEG6 RC3
RC4	SEG11 T1G RC4
RC5	SEG10 RC5
RC6	SEG9 RC6 TX/CK
RC7	SEG8 RC7 RX/DT

Note 1: Priority listed from highest to lowest.

REGISTER 11-10: PORTC: PORTC REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTC are actually written to the corresponding LATC register. Reads from the PORTC register is return of actual I/O pin values.

REGISTER 11-11: TRISC: PORTC TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits
1 = PORTC pin configured as an input (tri-stated)
0 = PORTC pin configured as an output

REGISTER 11-12: LATC: PORTC DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATC<7:0>**: PORTC Output Latch Value bits(1)

Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

TABLE 11-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	98
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	98
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	98

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

11.4 PORTD Registers (PIC16LF1904/7 only)

PORTD is a 8-bit wide, bidirectional port. The corresponding data direction register is TRISD (Register 11-14). Setting a TRISD bit (= 1) will make the corresponding PORTD pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISD bit (= 0) will make the corresponding PORTD pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTD register (Register 11-13) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATD).

The TRISD register (Register 11-14) controls the PORTD pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISD register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

11.4.1 PORTD FUNCTIONS AND OUTPUT PRIORITIES

Each PORTD pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 11-9.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in Table 11-9.

TABLE 11-9: PORTD OUTPUT PRIORITY

Pin Name	Function Priority(1)
RD0	RD0
RD1	RD1
RD2	RD2
RD3	RD3
RD4	RD4
RD5	RD5
RD6	RD6
RD7	RD7

Note 1: Priority listed from highest to lowest.

REGISTER 11-13: PORTD: PORTD REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RD<7:0>**: PORTD General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTD are actually written to the corresponding LATD register. Reads from the PORTD register is return of actual I/O pin values.

REGISTER 11-14: TRISD: PORTD TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISD7	TRISD6	TRISD5	TRISD4	TRISD5	TRISD5	TRISD5	TRISD4
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISD<7:0>:** PORTD Tri-State Control bits
1 = PORTD pin configured as an input (tri-stated)
0 = PORTD pin configured as an output

REGISTER 11-15: LATD: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATD<7:0>**: PORTD Output Latch Value bits(1)

Note 1: Writes to PORTD are actually written to the corresponding LATD register. Reads from the PORTD register is return of actual I/O pin values.

TABLE 11-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD(1)

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
LATD	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	104
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	104
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	104

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTD.

Note 1: PIC16LF1904/7 only.

11.5 PORTE Registers

RE3 is input only, and also functions as $\overline{MCLR}$. The $\overline{MCLR}$ feature can be disabled via a configuration fuse. RE3 also supplies the programming voltage. The TRIS bit for RE3 (TRISE3) always reads '1'.

11.5.1 PORTE FUNCTIONS AND OUTPUT PRIORITIES

No output priorities, RE3 is an input only pin.

REGISTER 11-16: PORTE: PORTE REGISTER

U-0	U-0	U-0	U-0	R-x/u	U-0	U-0	U-0
—	—	—	—	RE3	RE2(1)	RE1(1)	RE0(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **Unimplemented**: Read as '0'

bit 3-0 **RE<3:0>**: PORTE Input Pin bit(1)
1 = Port pin is > V_{IH}
0 = Port pin is < V_{IL}

2: RE<2:0> are not implemented on the PIC16LF1906. Read as '0'. Writes to RE<2:0> are actually written to the corresponding LATE register. Reads from the PORTE register is the return of actual I/O pin values.

REGISTER 11-17: TRISE: PORTE TRI-STATE REGISTER

U-0	U-0	U-0	U-0	U-1(1)	R/W-1/1(2)	R/W-1/1(2)	R/W-1/1(2)
—	—	—	—	—	TRISE2	TRISE1	TRISE0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **Unimplemented**: Read as '0'

bit 3 **Unimplemented**: Read as '1'

bit 2-0 **TRISE<2:0>:** PORTE Tri-State Control bits(2)
1 = Port output driver is disabled
0 = Port output driver is enabled

Note 1: Unimplemented, read as '1'.

2: TRISE<2:0> are not implemented on the PIC16LF1906. Read as '0'.

REGISTER 11-18: LATE: PORTE DATA LATCH REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	LATE2(2)	LATE1(2)	LATE0(2)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **LATE<2:0>**: PORTE Output Latch Value bits(1)

Note 1: Writes to PORTE are actually written to the corresponding LATE register. Reads from the PORTE register is return of actual I/O pin values.

2: LATE<2:0> are not implemented on the PIC16LF1906. Read as '0'.

REGISTER 11-19: ANSELE: PORTE ANALOG SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	—	—	ANSE2(2)	ANSE1(2)	ANSE0(2)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **ANSE<2:0>**: Analog Select between Analog or Digital Function on pins RE<2:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

2: ANSE<2:0> are not implemented on the PIC16LF1906. Read as '0'.

REGISTER 11-20: WPUE: WEAK PULL-UP PORTE REGISTER

U-0	U-0	U-0	U-0	R/W-1/1	U-0	U-0	U-0
—	—	—	—	WPUE3	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **WPUE3:** Weak Pull-up Register bit
1 = Pull-up enabled
0 = Pull-up disabled

bit 2-0 **Unimplemented:** Read as '0'

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

TABLE 11-11: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON	121
ANSELE	—	—	—	—	—	ANSE2(2)	ANSE1(2)	ANSE0(2)	99
LATE	—	—	—	—	—	LATE2(2)	LATE1(2)	LATE0(2)	106
PORTE	—	—	—	—	RE3	RE2(2)	RE1(2)	RE0(2)	106
TRISE	—	—	—	—	—(1)	TRISE2(2)	TRISE1(2)	TRISE0(2)	106
WPUE	—	—	—	—	WPUE3	—	—	—	108

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTE.
Note 1: Unimplemented, read as '1'.
2: PIC16LF1904/7 only.

12.0 INTERRUPT-ON-CHANGE

The PORTB pins can be configured to operate as Interrupt-On-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual PORTB pin, or combination of PORTB pins, can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 12-1 is a block diagram of the IOC module.

12.1 Enabling the Module

To allow individual PORTB pins to generate an interrupt, the IOCIE bit of the INTCON register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

12.2 Individual Pin Configuration

For each PORTB pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated IOCBPx bit of the IOCBP register is set. To enable a pin to detect a falling edge, the associated IOCBNx bit of the IOCBN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting both the IOCBPx bit and the IOCBNx bit of the IOCBP and IOCBN registers, respectively.

12.3 Interrupt Flags

The IOCBFx bits located in the IOCBF register are status flags that correspond to the interrupt-on-change pins of PORTB. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the INTCON register reflects the status of all IOCBFx bits.

12.4 Clearing Interrupt Flags

The individual status flags, (IOCBFx bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

EXAMPLE 12-1:

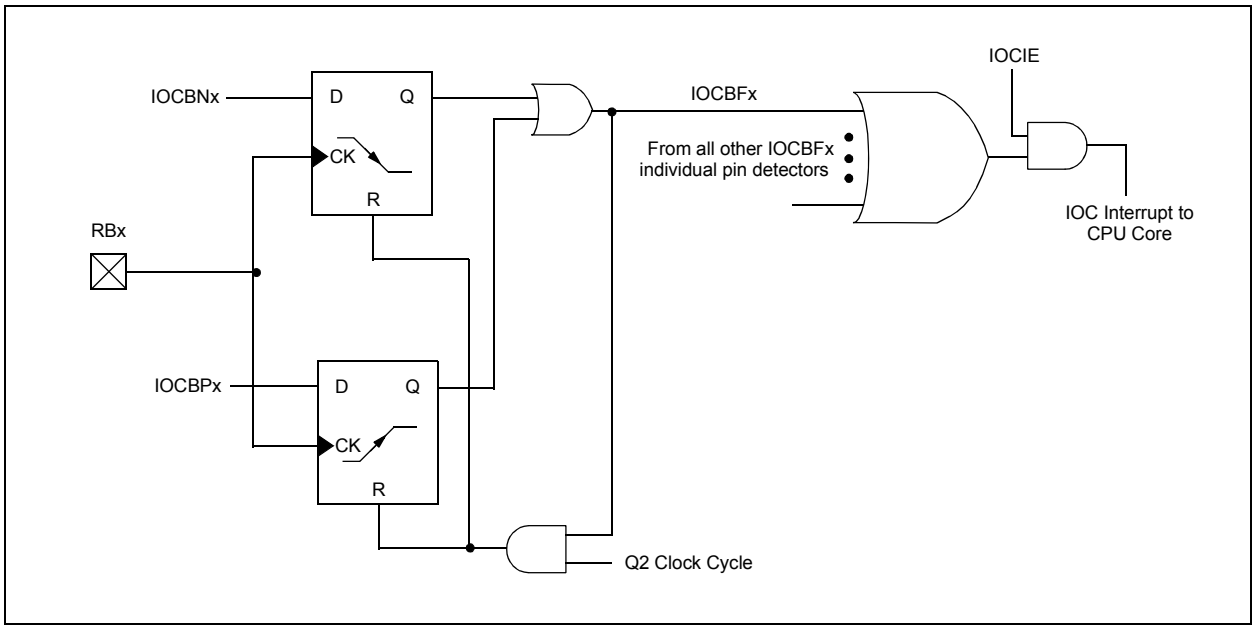
```
MOVLW  0xff
XORWF  IOCBF, W
ANDWF  IOCBF, F
```

12.5 Operation in Sleep

The interrupt-on-change interrupt sequence will wake the device from Sleep mode, if the IOCIE bit is set.

If an edge is detected while in Sleep mode, the IOCBF register will be updated prior to the first instruction executed out of Sleep.

FIGURE 12-1: INTERRUPT-ON-CHANGE BLOCK DIAGRAM



12.6 Interrupt-On-Change Registers

REGISTER 12-1: IOCBP: INTERRUPT-ON-CHANGE POSITIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **IOCBP<7:0>:** Interrupt-on-Change Positive Edge Enable bits

1 = Interrupt-on-Change enabled on the pin for a positive going edge. Associated Status bit and interrupt flag will be set upon detecting an edge.

0 = Interrupt-on-Change disabled for the associated pin.

REGISTER 12-2: IOCBN: INTERRUPT-ON-CHANGE NEGATIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **IOCBN<7:0>:** Interrupt-on-Change Negative Edge Enable bits

1 = Interrupt-on-Change enabled on the pin for a negative going edge. Associated Status bit and interrupt flag will be set upon detecting an edge.

0 = Interrupt-on-Change disabled for the associated pin.

REGISTER 12-3: IOCBF: INTERRUPT-ON-CHANGE FLAG REGISTER

R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0
IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HS - Bit is set in hardware

bit 7-0 **IOCBF<7:0>:** Interrupt-on-Change Flag bits

1 = An enabled change was detected on the associated pin.
Set when IOCBPx = 1 and a rising edge was detected on RBx, or when IOCBNx = 1 and a falling edge was detected on RBx.

0 = No change was detected, or the user cleared the detected change.

TABLE 12-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	99
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	110
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	110
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	110
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	98

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupt-on-change.

13.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference (FVR) is a stable voltage reference, independent of VDD, with 1.024V or 2.048V selectable output levels. The output of the FVR can be configured as the FVR input channel on the ADC.

The FVR can be enabled by setting the FVREN bit of the FVRCON register.

13.1 Independent Gain Amplifiers

The output of the FVR supplied to the ADC is routed through two independent programmable gain amplifiers. Each amplifier can be configured to amplify the reference voltage by 1x or 2x, to produce the two possible voltage levels.

The ADFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the ADC module. Reference **Section 15.0 "Analog-to-Digital Converter (ADC) Module"** for additional information.

13.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRRDY bit of the FVRCON register will be set. See **Section 22.0 "Electrical Specifications"** for the minimum delay requirement.

FIGURE 13-1: VOLTAGE REFERENCE BLOCK DIAGRAM

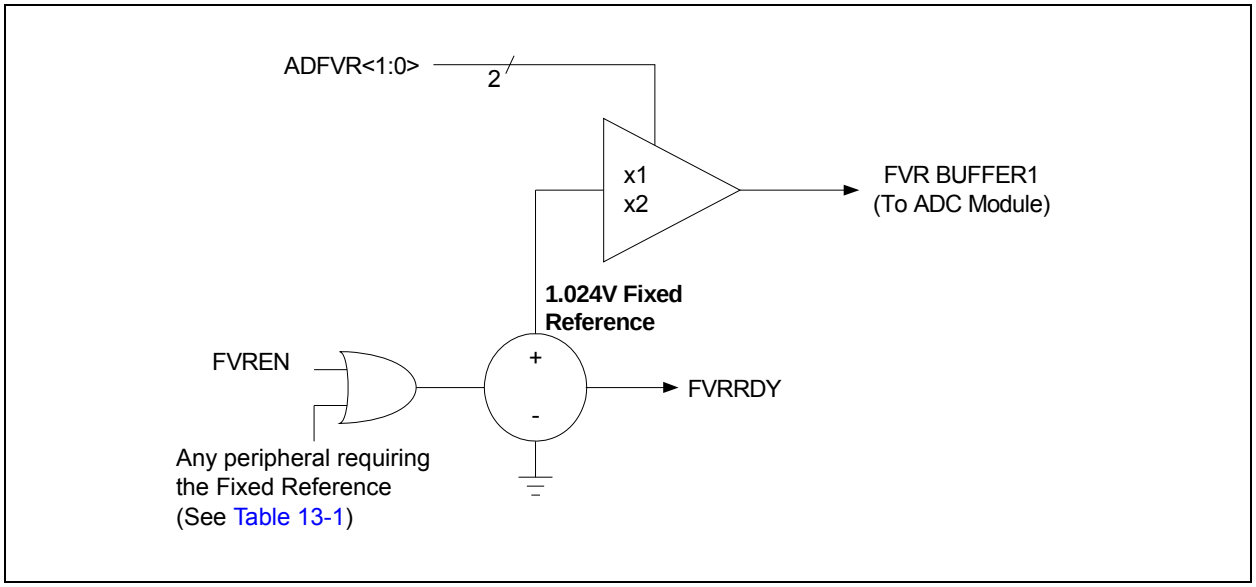


TABLE 13-1: PERIPHERALS REQUIRING THE FIXED VOLTAGE REFERENCE (FVR)

Peripheral	Conditions	Description
HFINTOSC	FOSC<2:0> = 100 and IRCF<3:0> = 000x	INTOSC is active and device is not in Sleep.
BOR	BOREN<1:0> = 11	BOR always enabled.
	BOREN<1:0> = 10 and BORFS = 1	BOR disabled in Sleep mode, BOR Fast Start enabled.
	BOREN<1:0> = 01 and BORFS = 1	BOR under software control, BOR Fast Start enabled.

13.3 FVR Control Registers

REGISTER 13-1: FVRCON: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0/0	R-q/q	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
FVREN	FVRRDY(1)	TSEN	TSRNG	—	—	ADFVR<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **FVREN:** Fixed Voltage Reference Enable bit
0 = Fixed Voltage Reference is disabled
1 = Fixed Voltage Reference is enabled

bit 6 **FVRRDY:** Fixed Voltage Reference Ready Flag bit(1)
0 = Fixed Voltage Reference output is not ready or not enabled
1 = Fixed Voltage Reference output is ready for use

bit 5 **TSEN:** Temperature Indicator Enable bit
0 = Temperature Indicator is disabled
1 = Temperature Indicator is enabled

bit 4 **TSRNG:** Temperature Indicator Range Selection bit
0 = $V_{OUT} = V_{DD} - 2V_T$ (Low Range)
1 = $V_{OUT} = V_{DD} - 4V_T$ (High Range)

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **ADFVR<1:0>:** ADC Fixed Voltage Reference Selection bit
00 = ADC Fixed Voltage Reference Peripheral output is off.
01 = ADC Fixed Voltage Reference Peripheral output is 1x (1.024V)
10 = ADC Fixed Voltage Reference Peripheral output is 2x (2.048V)(2)
11 = Reserved

Note 1: FVRRDY will output the true state of the band gap.
2: Fixed Voltage Reference output cannot exceed V_{DD}.

TABLE 13-2: SUMMARY OF REGISTERS ASSOCIATED WITH FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR1	ADFVR0	113

Legend: Shaded cells are not used with the Fixed Voltage Reference.

14.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between of -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

14.1 Circuit Operation

Figure 14-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 14-1 describes the output characteristics of the temperature indicator.

EQUATION 14-1: VOUT RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

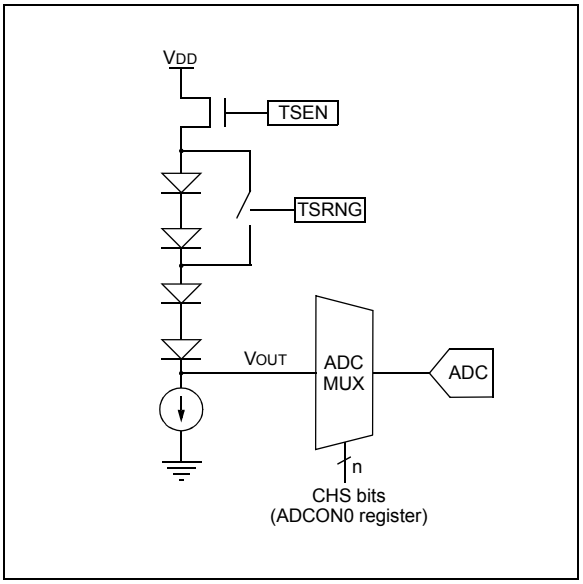
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 13.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 14-1: TEMPERATURE CIRCUIT DIAGRAM



14.2 Minimum Operating VDD vs. Minimum Sensing Temperature

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 14-1 shows the recommended minimum VDD vs. range setting.

TABLE 14-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

14.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 15.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

14.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 µs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 µs between sequential conversions of the temperature indicator output.

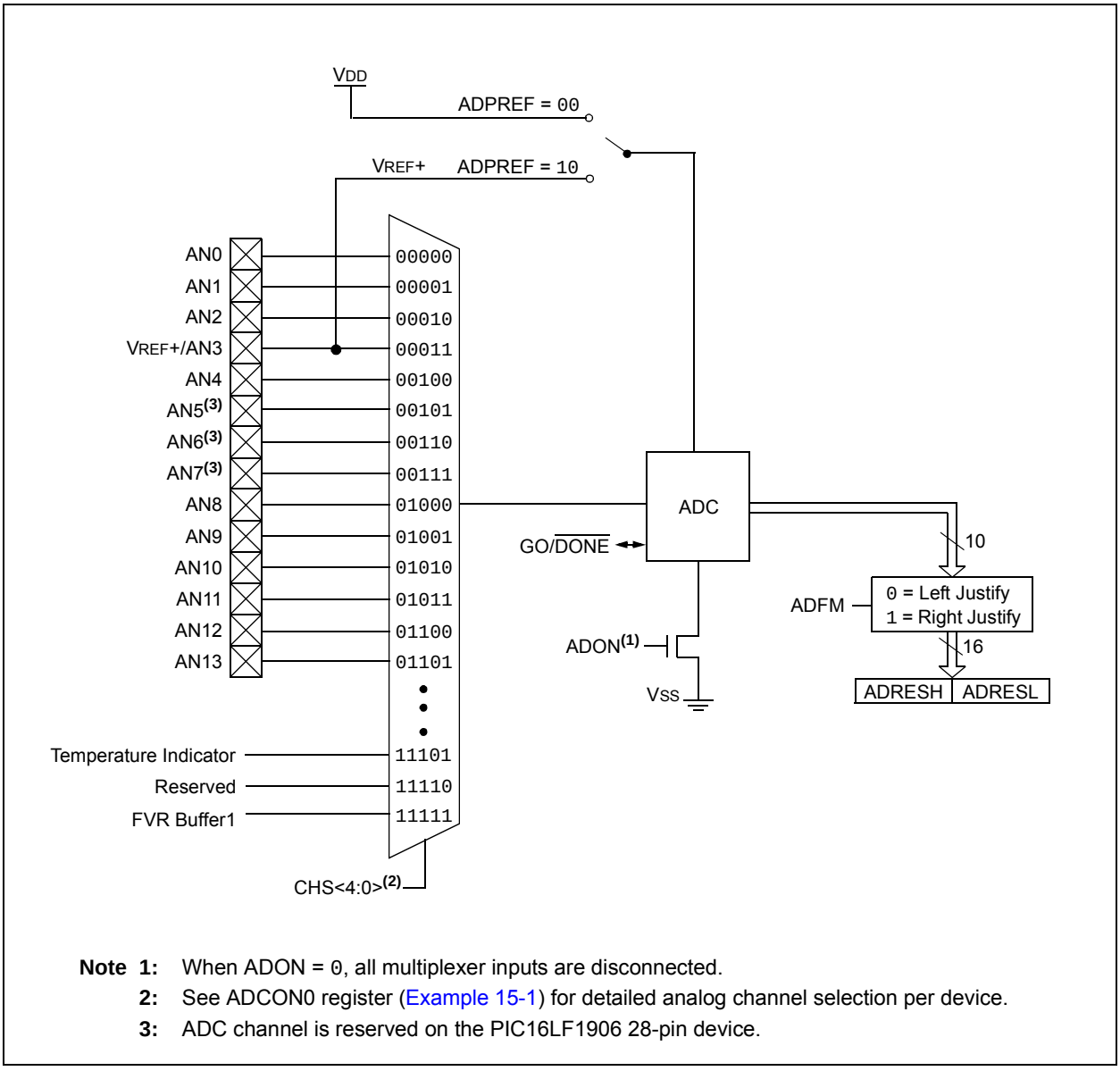
15.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 15-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 15-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.
2: See ADCON0 register (Example 15-1) for detailed analog channel selection per device.
3: ADC channel is reserved on the PIC16LF1906 28-pin device.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are up to 11 channel selections available:

- AN<13:0> pins
- Temperature Indicator
- FVR (Fixed Voltage Reference) Output

Refer to **Section 13.0 "Fixed Voltage Reference (FVR)"** and **Section 14.0 "Temperature Indicator Module"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- VREF+ pin
- VDD

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11.5 TAD periods as shown in Figure 15-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in **Section 22.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**16 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
F_{OSC}/2	000	100 ns(2)	125 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
F_{OSC}/4	100	200 ns(2)	250 ns(2)	500 ns(2)	1.0 μs	4.0 μs
F_{OSC}/8	001	400 ns(2)	0.5 μs(2)	1.0 μs	2.0 μs	8.0 μs(3)
F_{OSC}/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs(3)
F_{OSC}/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs(3)	32.0 μs(3)
F_{OSC}/64	110	3.2 μs	4.0 μs	8.0 μs(3)	16.0 μs(3)	64.0 μs(3)
F_{RC}	x11	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)

Legend: Shaded cells are outside of recommended range.

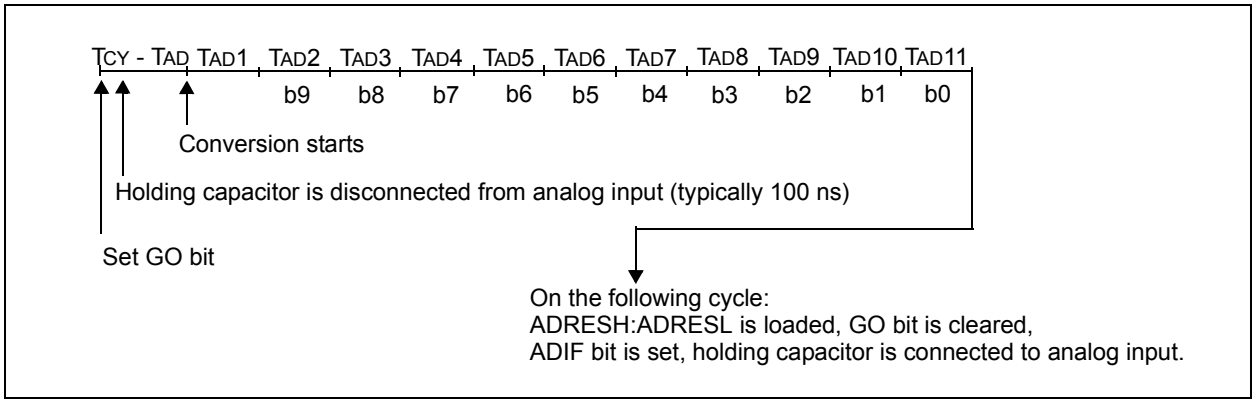
Note 1: The F_{RC} source has a typical T_{AD} time of 1.6 μs for V_{DD}.

2: These values violate the minimum required T_{AD} time.

3: For faster conversion times, the selection of another clock source is recommended.

4: The ADC clock period (T_{AD}) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock F_{OSC}. However, the F_{RC} clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



15.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC Interrupt Flag is the ADIF bit in the PIR1 register. The ADC Interrupt Enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

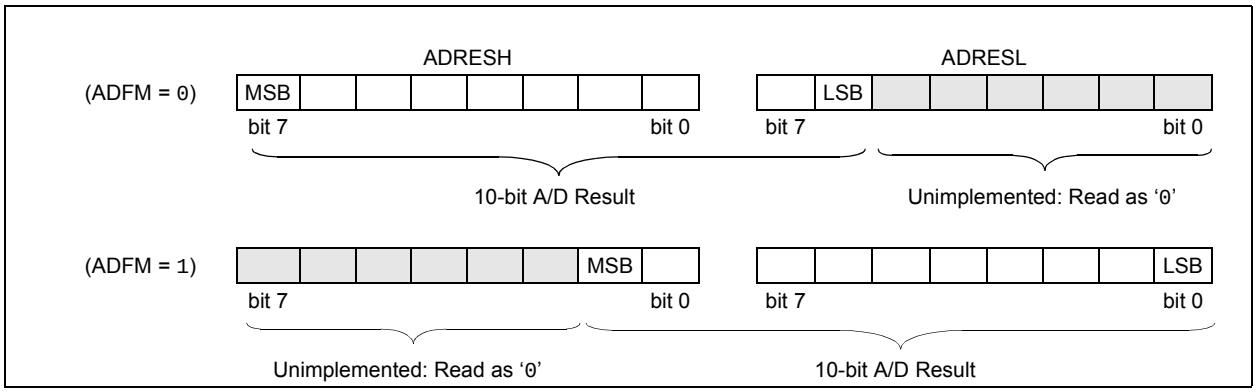
This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the GIE and PEIE bits of the INTCON register must be disabled. If the GIE and PEIE bits of the INTCON register are enabled, execution will switch to the Interrupt Service Routine.

15.1.6 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON1 register controls the output format.

Figure 15-3 shows the two output formats.

FIGURE 15-3: 10-BIT A/D CONVERSION RESULT FORMAT



15.2 ADC Operation

15.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/$\overline{\text{DONE}}$ bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note:	The GO/$\overline{\text{DONE}}$ bit should not be set in the same instruction that turns on the ADC. Refer to **Section 15.2.5 "A/D Conversion Procedure"**.

15.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/$\overline{\text{DONE}}$ bit
- Set the ADIF Interrupt Flag bit
- Update the ADRESH and ADRESL registers with new conversion result

15.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRESH and ADRESL registers will be updated with the partially complete Analog-to-Digital conversion sample. Incomplete bits will match the last bit converted.

Note:	A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

15.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

15.2.5 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (Refer to the TRIS register)
   - Configure pin as analog (Refer to the ANSEL register)
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt(1)
4. Wait the required acquisition time(2).
5. Start conversion by setting the GO/$\overline{\text{DONE}}$ bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/$\overline{\text{DONE}}$ bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 15.3 "A/D Acquisition Requirements"**.

EXAMPLE 15-1: A/D CONVERSION

```
;This code block configures the ADC
;for polling, Vdd and Vss references, Frc
;clock and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL   ADCON1       ;
MOVLW     B'11110000'  ;Right justify, Frc
                       ;clock
MOVWF     ADCON1       ;Vdd and Vss Vref
BANKSEL   TRISA        ;
BSF       TRISA,0      ;Set RA0 to input
BANKSEL   ANSEL        ;
BSF       ANSEL,0      ;Set RA0 to analog
BANKSEL   ADCON0       ;
MOVLW     B'00000001'  ;Select channel AN0
MOVWF     ADCON0       ;Turn ADC On
CALL      SampleTime   ;Acquisiton delay
BSF       ADCON0,ADGO  ;Start conversion
BTFSC     ADCON0,ADGO  ;Is conversion done?
GOTO      $-1          ;No, test again
BANKSEL   ADRESH       ;
MOVF      ADRESH,W     ;Read upper 2 bits
MOVWF     RESULTHI     ;store in GPR space
BANKSEL   ADRESL       ;
MOVF      ADRESL,W     ;Read lower 8 bits
MOVWF     RESULTLO     ;Store in GPR space
```

15.2.6 ADC REGISTER DEFINITIONS

The following registers are used to control the operation of the ADC.

REGISTER 15-1: ADCON0: A/D CONTROL REGISTER 0

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-2 **CHS<4:0>:** Analog Channel Select bits

00000 = AN0
00001 = AN1
00010 = AN2
00011 = AN3
00100 = AN4
00101 = AN5(3)
00110 = AN6(3)
00111 = AN7(3)
01000 = AN8
01001 = AN9
01010 = AN10
01011 = AN11
01100 = AN12
01101 = AN13
01110 = Reserved. No channel connected.
•
•
•
11100 = Reserved. No channel connected.
11101 = Temperature Indicator(2)
11110 = Reserved. No channel connected.
11111 = FVR (Fixed Voltage Reference) Buffer 1 Output(1)

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle.
This bit is automatically cleared by hardware when the A/D conversion has completed.
0 = A/D conversion completed/not in progress

bit 0 **ADON:** ADC Enable bit

1 = ADC is enabled
0 = ADC is disabled and consumes no operating current

Note 1: See **Section 13.0 "Fixed Voltage Reference (FVR)"** for more information.
2: See **Section 14.0 "Temperature Indicator Module"** for more information.
3: ADC channel is reserved on the PIC16LF1906 28-pin device.

REGISTER 15-2: ADCON1: A/D CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
ADFM	ADCS<2:0>			—	—	ADPREF<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ADFM:** A/D Result Format Select bit
- 1 = Right justified. Six Most Significant bits of ADRESH are set to '0' when the conversion result is loaded.
- 0 = Left justified. Six Least Significant bits of ADRESL are set to '0' when the conversion result is loaded.

bit 6-4 **ADCS<2:0>:** A/D Conversion Clock Select bits
- 000 = FOSC/2
- 001 = FOSC/8
- 010 = FOSC/32
- 011 = FRC (clock supplied from a dedicated RC oscillator)
- 100 = FOSC/4
- 101 = FOSC/16
- 110 = FOSC/64
- 111 = FRC (clock supplied from a dedicated RC oscillator)

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **ADPREF<1:0>:** A/D Positive Voltage Reference Configuration bits
- 00 = VREF+ is connected to VDD
- 01 = Reserved
- 10 = VREF+ is connected to external VREF+ pin(1)
- 11 = Reserved

Note 1: When selecting the FVR or the VREF+ pin as the source of the positive reference, be aware that a minimum voltage specification exists. See **Section 22.0 "Electrical Specifications"** for details.

REGISTER 15-3: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<9:2>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<9:2>**: ADC Result Register bits
Upper eight bits of 10-bit conversion result

REGISTER 15-4: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<1:0>		—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **ADRES<1:0>**: ADC Result Register bits
Lower two bits of 10-bit conversion result

bit 5-0 **Reserved**: Do not use.

REGISTER 15-5: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 1

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	—	ADRES<9:8>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Reserved**: Do not use.

bit 1-0 **ADRES<9:8>**: ADC Result Register bits
Upper two bits of 10-bit conversion result

REGISTER 15-6: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 1

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<7:0>**: ADC Result Register bits
Lower eight bits of 10-bit conversion result

15.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 15-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 15-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 15-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 15-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -12.5pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.715\mu s$$

Therefore:

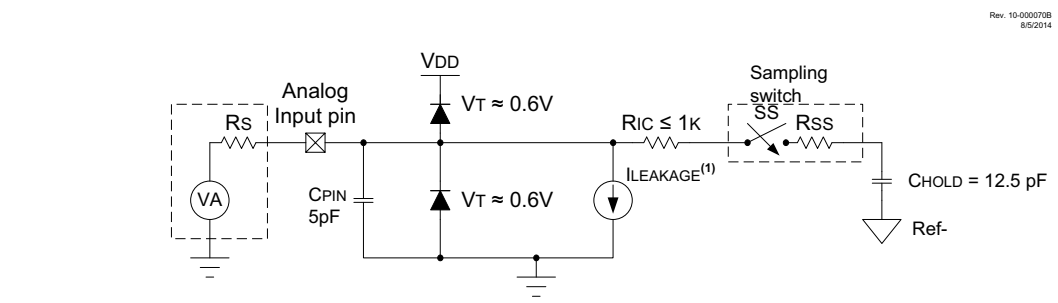
$$T_{ACQ} = 2\mu s + 1.715\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.96\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

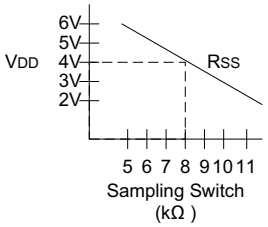
2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

FIGURE 15-4: ANALOG INPUT MODEL



Legend: CHOLD = Sample/Hold Capacitance
CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to varies injunctions
RIC = Interconnect Resistance
RSS = Resistance of Sampling switch
SS = Sampling Switch
VT = Threshold Voltage



Note 1: Refer to **Section 22.0 "Electrical Specifications"**.

FIGURE 15-5: ADC TRANSFER FUNCTION

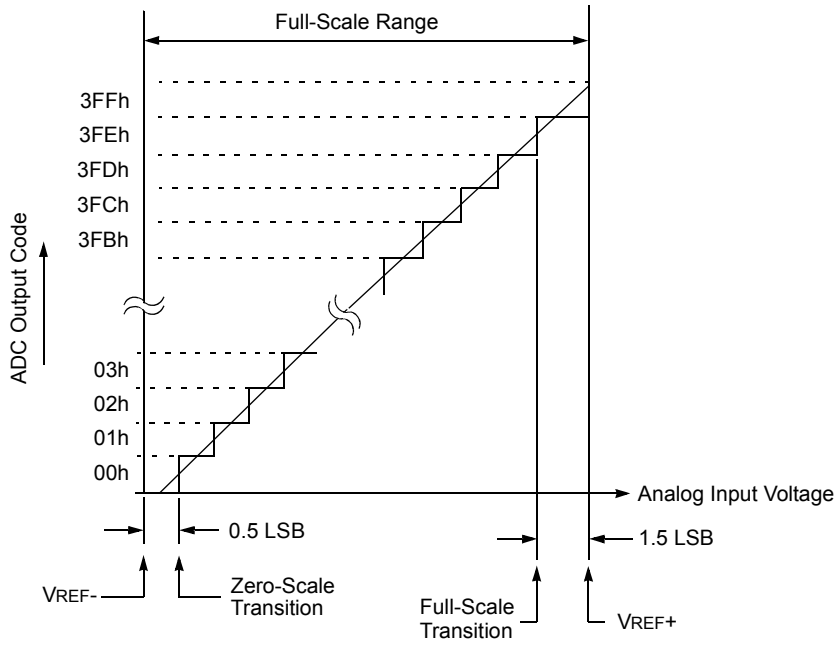


TABLE 15-2: SUMMARY OF REGISTERS ASSOCIATED WITH ADC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS4	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	121
ADCON1	ADFM	ADCS2	ADCS1	ADCS0	—	—	ADPREF1	ADPREF0	122
ADRESH	A/D Result Register High								123, 124
ADRESL	A/D Result Register Low								123, 124
ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	96
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	99
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	68
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	95
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	98
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR1	ADFVR0	113

Legend: x = unknown, u = unchanged, – = unimplemented read as '0', q = value depends on condition. Shaded cells are not used for ADC module.

16.0 TIMER0 MODULE

The Timer0 module is an 8-bit timer/counter with the following features:

- 8-bit timer/counter register (TMR0)
- 8-bit prescaler (independent of Watchdog Timer)
- Programmable internal or external clock source
- Programmable external clock edge selection
- Interrupt on overflow
- TMR0 can be used to gate Timer1

Figure 16-1 is a block diagram of the Timer0 module.

16.1 Timer0 Operation

The Timer0 module can be used as either an 8-bit timer or an 8-bit counter.

16.1.1 8-BIT TIMER MODE

The Timer0 module will increment every instruction cycle, if used without a prescaler. 8-Bit Timer mode is selected by clearing the TMR0CS bit of the OPTION_REG register.

When TMR0 is written, the increment is inhibited for two instruction cycles immediately following the write.

Note:	The value written to the TMR0 register can be adjusted, in order to account for the two instruction cycle delay when TMR0 is written.

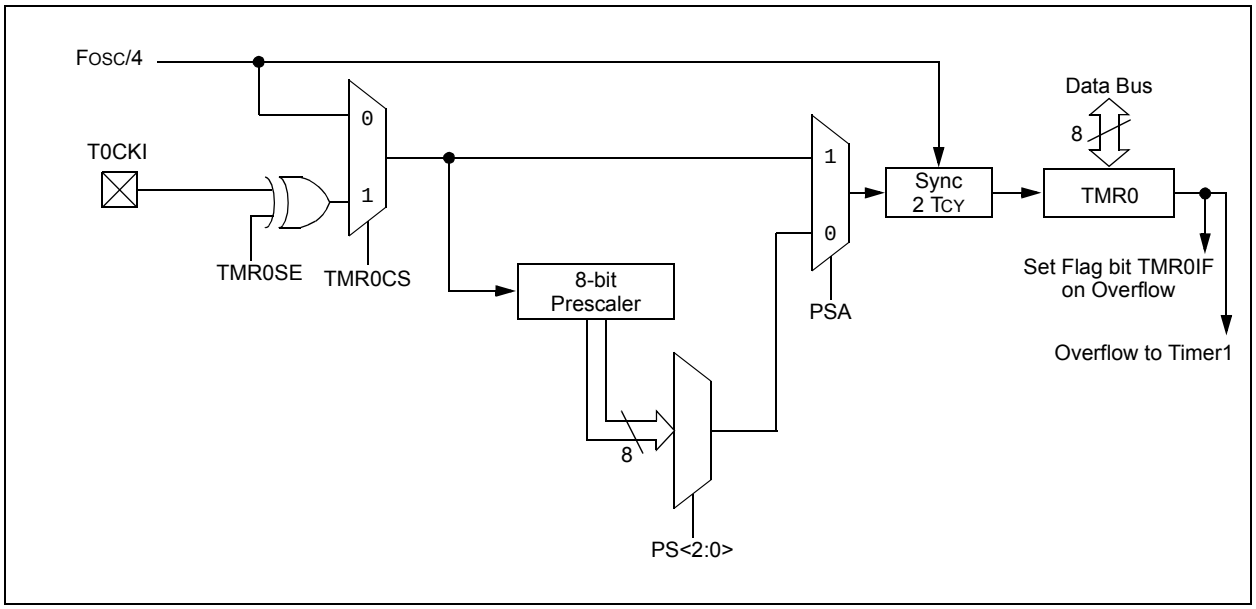
16.1.2 8-BIT COUNTER MODE

In 8-Bit Counter mode, the Timer0 module will increment on every rising or falling edge of the T0CKI pin.

8-Bit Counter mode using the T0CKI pin is selected by setting the TMR0CS bit in the OPTION_REG register to '1'.

The rising or falling transition of the incrementing edge is determined by the TMR0SE bit in the OPTION_REG register.

FIGURE 16-1: BLOCK DIAGRAM OF THE TIMER0



16.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A software programmable prescaler is available for exclusive use with Timer0. The prescaler is enabled by clearing the PSA bit of the OPTION_REG register.

Note:	The Watchdog Timer (WDT) uses its own independent prescaler.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION_REG register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be disabled by setting the PSA bit of the OPTION_REG register.

The prescaler is not readable or writable. All instructions writing to the TMR0 register will clear the prescaler.

16.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The TMR0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The TMR0IF bit can only be cleared in software. The Timer0 interrupt enable is the TMR0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

16.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in **Section 22.0 "Electrical Specifications"**.

16.1.6 OPERATION DURING SLEEP

Timer0 cannot operate while the processor is in Sleep mode. The contents of the TMR0 register will remain unchanged while the processor is in Sleep mode.

REGISTER 16-1: OPTION_REG: OPTION REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **$\overline{\text{WPUEN}}$:** Weak Pull-up Enable bit
1 = All weak pull-ups are disabled (except $\overline{\text{MCLR}}$, if it is enabled)
0 = Weak pull-ups are enabled by individual WPUx latch values

bit 6 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of INT pin
0 = Interrupt on falling edge of INT pin

bit 5 **TMR0CS:** Timer0 Clock Source Select bit
1 = Transition on T0CKI pin
0 = Internal instruction cycle clock (FOSC/4)

bit 4 **TMR0SE:** Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on T0CKI pin
0 = Increment on low-to-high transition on T0CKI pin

bit 3 **PSA:** Prescaler Assignment bit
1 = Prescaler is not assigned to the Timer0 module
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS<2:0>:** Prescaler Rate Select bits

Bit Value	Timer0 Rate
000	1 : 2
001	1 : 4
010	1 : 8
011	1 : 16
100	1 : 32
101	1 : 64
110	1 : 128
111	1 : 256

TABLE 16-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER0

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			130
TMR0	Timer0 Module Register								128*
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	95

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the Timer0 module.
* Page provides register information.

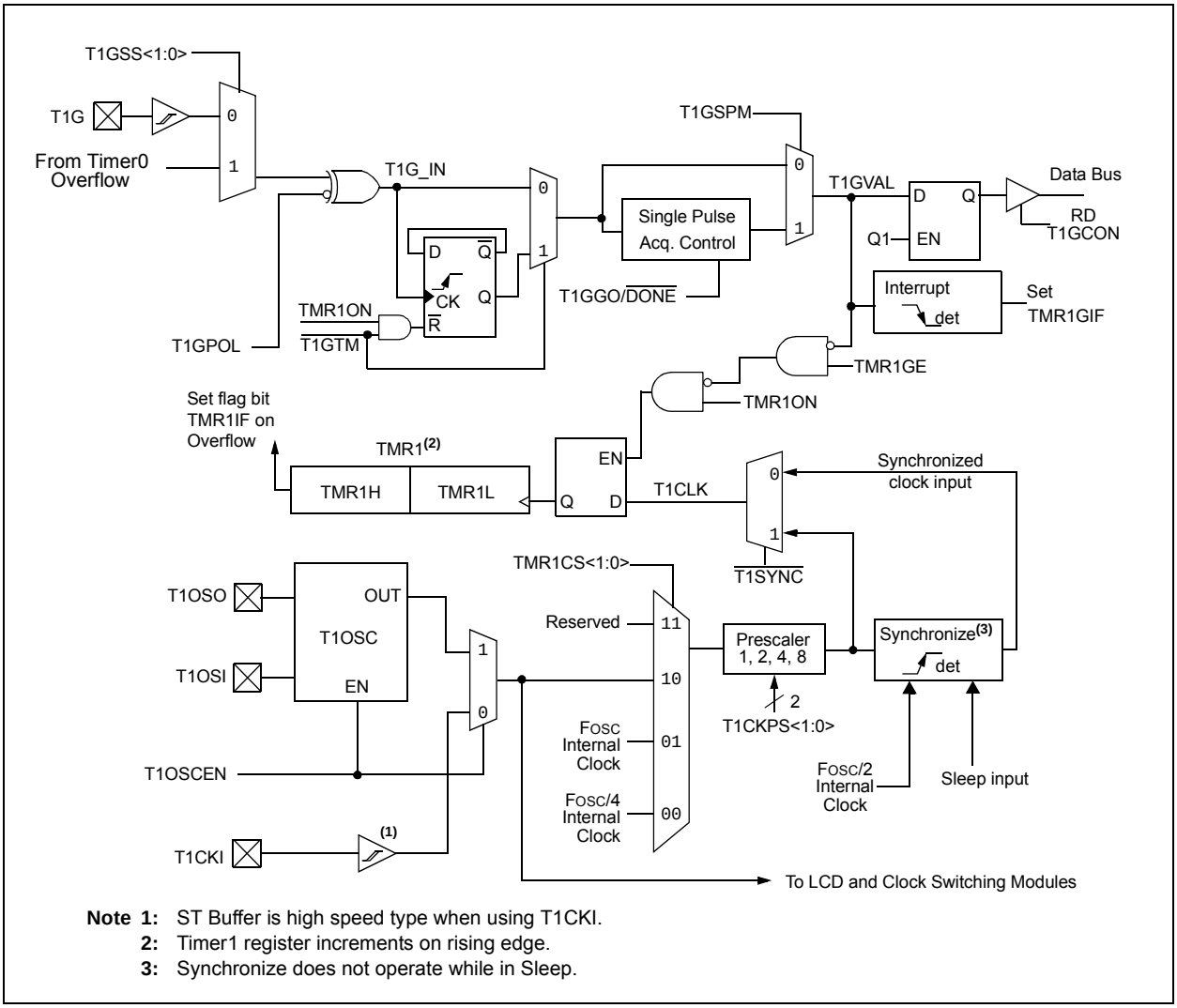
17.0 TIMER1 MODULE WITH GATE CONTROL

The Timer1 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMR1H:TMR1L)
- Programmable internal or external clock source
- 2-bit prescaler
- Dedicated 32 kHz oscillator circuit
- Multiple Timer1 gate (count enable) sources
- Interrupt on overflow
- Wake-up on overflow (external clock, Asynchronous mode only)
- Selectable Gate Source Polarity
- Gate Toggle mode
- Gate Single-pulse mode
- Gate Value Status
- Gate Event Interrupt

Figure 17-1 is a block diagram of the Timer1 module.

FIGURE 17-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.

17.1 Timer1 Operation

The Timer1 module is a 16-bit incrementing counter which is accessed through the TMR1H:TMR1L register pair. Writes to TMR1H or TMR1L directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1 is enabled by configuring the TMR1ON and TMR1GE bits in the T1CON and T1GCON registers, respectively. Table 17-1 displays the Timer1 enable selections.

TABLE 17-1: TIMER1 ENABLE SELECTIONS

TMR1ON	TMR1GE	Timer1 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

17.2 Clock Source Selection

The TMR1CS<1:0> and T1OSCEN bits of the T1CON register are used to select the clock source for Timer1. Table 17-2 displays the clock source selections.

17.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected, the TMR1H:TMR1L register pair will increment on multiples of FOSC as determined by the Timer1 prescaler.

When the FOSC internal clock source is selected, the Timer1 register value will increment by four counts every instruction clock cycle. Due to this condition, a 2 LSB error in resolution will occur when reading the Timer1 value. To utilize the full resolution of Timer1, an asynchronous input signal must be used to gate the Timer1 clock input.

The following asynchronous source may be used:

- Asynchronous event on the T1G pin to Timer1 gate

17.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When enabled to count, Timer1 is incremented on the rising edge of the external clock input T1CKI or the capacitive sensing oscillator signal. Either of these external clock sources can be synchronized to the microcontroller system clock or they can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1 enabled after POR
- Write to TMR1H or TMR1L
- Timer1 is disabled
- Timer1 is disabled (TMR1ON = 0) when T1CKI is high then Timer1 is enabled (TMR1ON = 1) when T1CKI is low.

TABLE 17-2: CLOCK SOURCE SELECTIONS

TMR1CS1	TMR1CS0	T1OSCEN	Clock Source
0	0	x	Instruction Clock (FOSC/4)
0	1	x	System Clock (FOSC)
1	0	0	External Clocking on T1CKI Pin
1	0	1	Osc. Circuit on T1OSI/T1OSO Pins
1	1	x	Reserved

17.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

17.4 Timer1 Oscillator

A dedicated low-power 32.768 kHz oscillator circuit is built-in between pins T1OSI (input) and T1OSO. This internal circuit is to be used in conjunction with an external 32.768 kHz crystal.

The oscillator circuit is enabled by setting the T1OSCEN bit of the T1CON register. The oscillator will continue to run during Sleep.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to using Timer1. A suitable delay similar to the OST delay can be implemented in software by clearing the TMR1IF bit then presetting the TMR1H:TMR1L register pair to FC00h. The TMR1IF flag will be set when 1024 clock cycles have elapsed, thereby indicating that the oscillator is running and reasonably stable.

17.5 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer increments asynchronously to the internal phase clocks. If the external clock source is selected then the timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 17.5.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce an additional increment.

17.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TMR1L register pair.

17.6 Timer1 Gate

Timer1 can be configured to count freely or the count can be enabled and disabled using Timer1 gate circuitry. This is also referred to as Timer1 Gate Enable.

Timer1 gate can also be driven by multiple selectable sources.

17.6.1 TIMER1 GATE ENABLE

The Timer1 Gate Enable mode is enabled by setting the TMR1GE bit of the T1GCON register. The polarity of the Timer1 Gate Enable mode is configured using the T1GPOL bit of the T1GCON register.

When Timer1 Gate Enable mode is enabled, Timer1 will increment on the rising edge of the Timer1 clock source. When Timer1 Gate Enable mode is disabled, no incrementing will occur and Timer1 will hold the current count. See Figure 17-3 for timing details.

TABLE 17-3: TIMER1 GATE ENABLE SELECTIONS

T1CLK	T1GPOL	T1G	Timer1 Operation
↑	0	0	Counts
↑	0	1	Holds Count
↑	1	0	Holds Count
↑	1	1	Counts

17.6.2 TIMER1 GATE SOURCE SELECTION

The Timer1 gate source can be selected from one of four different sources. Source selection is controlled by the T1GSS bits of the T1GCON register. The polarity for each available source is also selectable. Polarity selection is controlled by the T1GPOL bit of the T1GCON register.

TABLE 17-4: TIMER1 GATE SOURCES

T1GSS	Timer1 Gate Source
00	Timer1 Gate Pin
01	Overflow of Timer0 (TMR0 increments from FFh to 00h)

17.6.2.1 T1G Pin Gate Operation

The T1G pin is one source for Timer1 gate control. It can be used to supply an external source to the Timer1 gate circuitry.

17.6.2.2 Timer0 Overflow Gate Operation

When Timer0 increments from FFh to 00h, a low-to-high pulse will automatically be generated and internally supplied to the Timer1 gate circuitry.

17.6.3 TIMER1 GATE TOGGLE MODE

When Timer1 Gate Toggle mode is enabled, it is possible to measure the full-cycle length of a Timer1 gate signal, as opposed to the duration of a single level pulse.

The Timer1 gate source is routed through a flip-flop that changes state on every incrementing edge of the signal. See Figure 17-4 for timing details.

Timer1 Gate Toggle mode is enabled by setting the T1GTM bit of the T1GCON register. When the T1GTM bit is cleared, the flip-flop is cleared and held clear. This is necessary in order to control which edge is measured.

Note:	Enabling Toggle mode at the same time as changing the gate polarity may result in indeterminate operation.

17.6.4 TIMER1 GATE SINGLE-PULSE MODE

When Timer1 Gate Single-Pulse mode is enabled, it is possible to capture a single pulse gate event. Timer1 Gate Single-Pulse mode is first enabled by setting the T1GSPM bit in the T1GCON register. Next, the T1GGO/$\overline{\text{DONE}}$ bit in the T1GCON register must be set. The Timer1 will be fully enabled on the next incrementing edge. On the next trailing edge of the pulse, the T1GGO/$\overline{\text{DONE}}$ bit will automatically be cleared. No other gate events will be allowed to increment Timer1 until the T1GGO/$\overline{\text{DONE}}$ bit is once again set in software. See Figure 17-5 for timing details.

If the Single Pulse Gate mode is disabled by clearing the T1GSPM bit in the T1GCON register, the T1GGO/$\overline{\text{DONE}}$ bit should also be cleared.

Enabling the Toggle mode and the Single-Pulse mode simultaneously will permit both sections to work together. This allows the cycle times on the Timer1 gate source to be measured. See Figure 17-6 for timing details.

17.6.5 TIMER1 GATE VALUE STATUS

When Timer1 Gate Value Status is utilized, it is possible to read the most current level of the gate control value. The value is stored in the T1GVAL bit in the T1GCON register. The T1GVAL bit is valid even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

17.6.6 TIMER1 GATE EVENT INTERRUPT

When Timer1 Gate Event Interrupt is enabled, it is possible to generate an interrupt upon the completion of a gate event. When the falling edge of T1GVAL occurs, the TMR1GIF flag bit in the PIR1 register will be set. If the TMR1GIE bit in the PIE1 register is set, then an interrupt will be recognized.

The TMR1GIF flag bit operates even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

17.7 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit of the PIR1 register is set. To enable the interrupt on rollover, you must set these bits:

- TMR1ON bit of the T1CON register
- TMR1IE bit of the PIE1 register
- PEIE bit of the INTCON register
- GIE bit of the INTCON register

The interrupt is cleared by clearing the TMR1IF bit in the Interrupt Service Routine.

Note:	The TMR1H:TMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

17.8 Timer1 Operation During Sleep

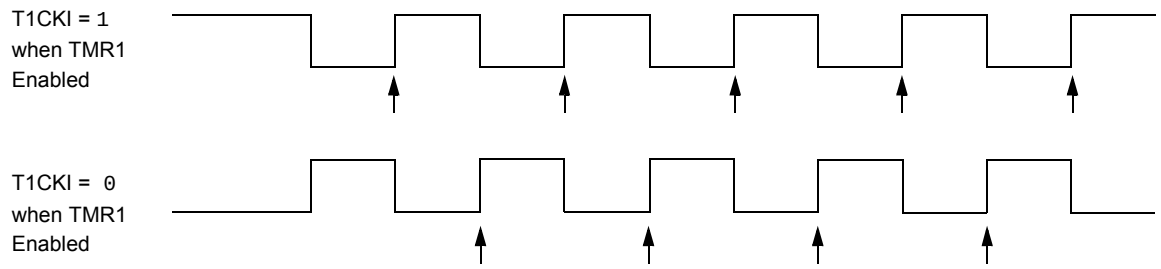
Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To set up the timer to wake the device:

- TMR1ON bit of the T1CON register must be set
- TMR1IE bit of the PIE1 register must be set
- PEIE bit of the INTCON register must be set
- $\overline{\text{T1SYNC}}$ bit of the T1CON register must be set
- TMR1CS bits of the T1CON register must be configured
- T1OSCEN bit of the T1CON register must be configured

The device will wake-up on an overflow and execute the next instructions. If the GIE bit of the INTCON register is set, the device will call the Interrupt Service Routine.

Timer1 oscillator will continue to operate in Sleep regardless of the $\overline{\text{T1SYNC}}$ bit setting.

FIGURE 17-2: TIMER1 INCREMENTING EDGE



Note 1: Arrows indicate counter increments.

2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the clock.

FIGURE 17-3: TIMER1 GATE ENABLE MODE

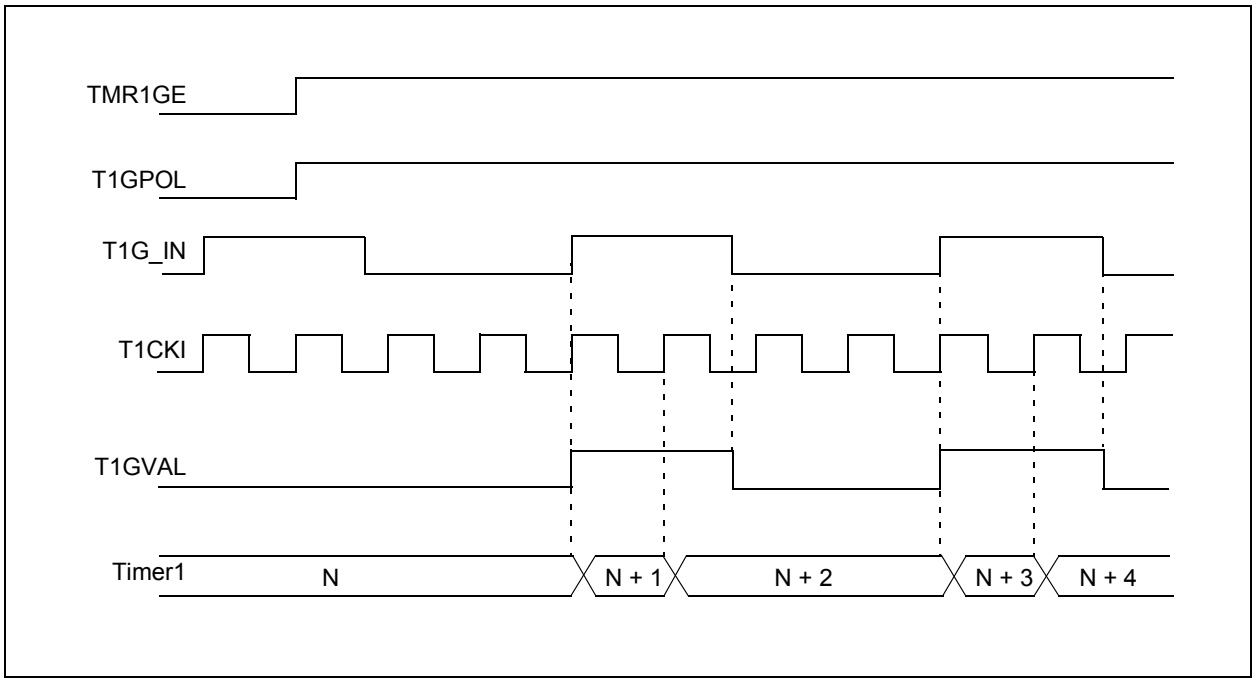


FIGURE 17-4: TIMER1 GATE TOGGLE MODE

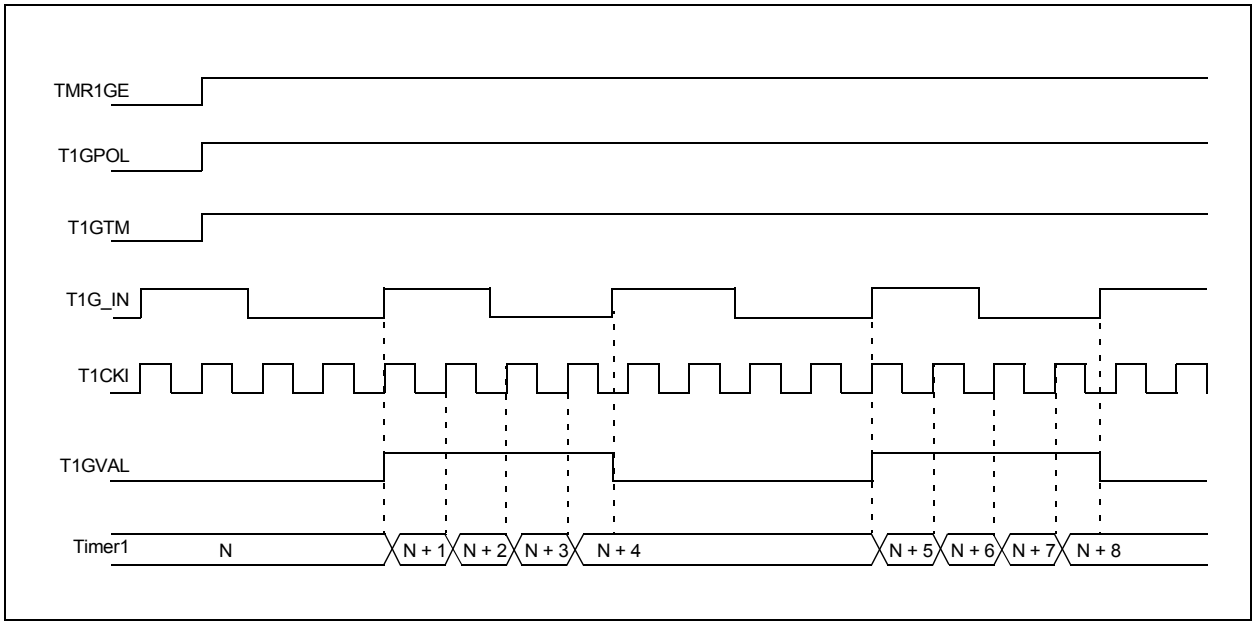


FIGURE 17-5: TIMER1 GATE SINGLE-PULSE MODE

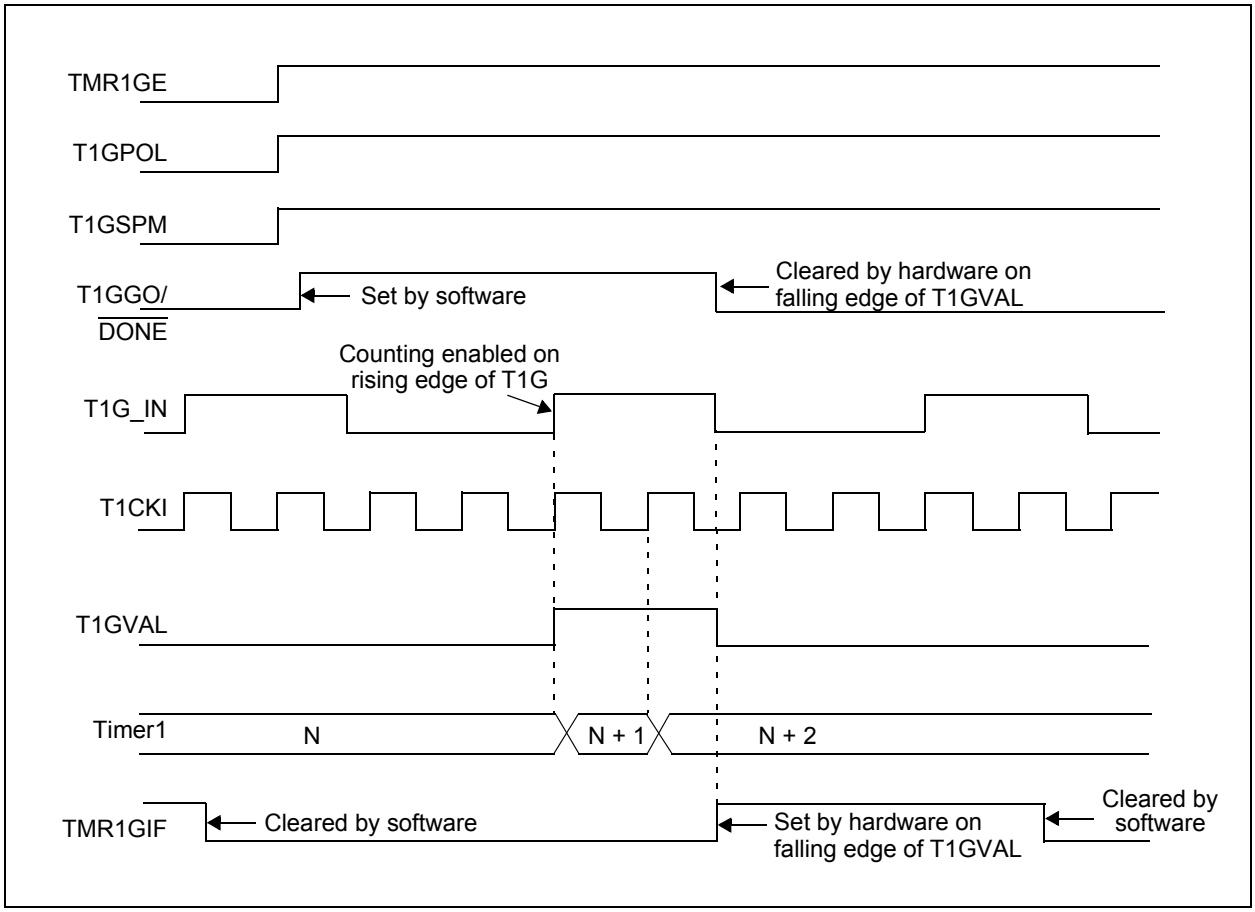
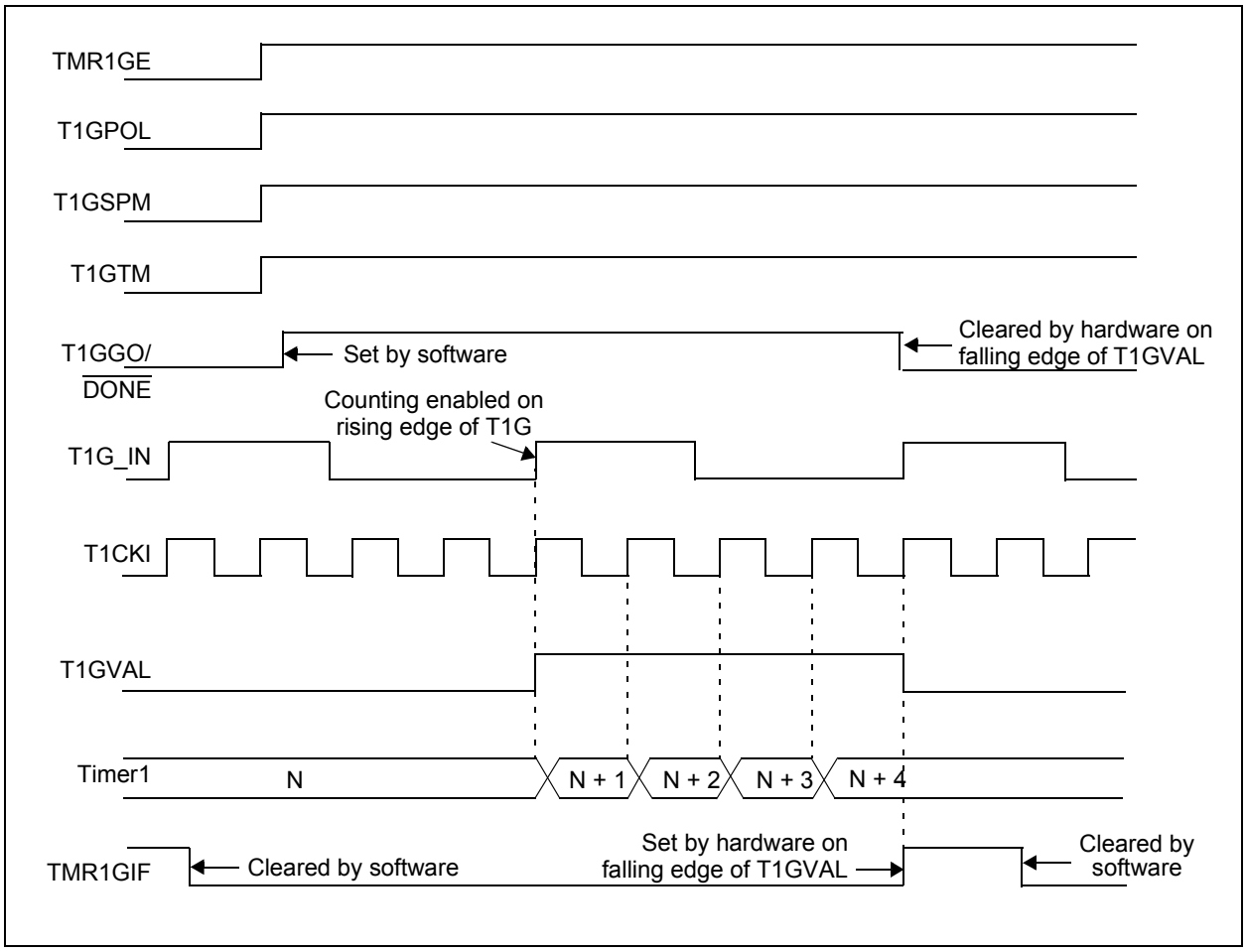


FIGURE 17-6: TIMER1 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE



17.9 Timer1 Control Register

The Timer1 Control register (T1CON), shown in Register 17-1, is used to control Timer1 and select the various features of the Timer1 module.

REGISTER 17-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	U-0	R/W-0/u
TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **TMR1CS<1:0>:** Timer1 Clock Source Select bits
- 11 = Reserved
- 10 = Timer1 clock source is pin or oscillator:
  - If T1OSCEN = 0:
  - External clock from T1CKI pin (on the rising edge)
  - If T1OSCEN = 1:
  - Crystal oscillator on T1OSI/T1OSO pins
- 01 = Timer1 clock source is system clock (FOSC)
- 00 = Timer1 clock source is instruction clock (FOSC/4)

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
- 11 = 1:8 Prescale value
- 10 = 1:4 Prescale value
- 01 = 1:2 Prescale value
- 00 = 1:1 Prescale value

bit 3 **T1OSCEN:** LP Oscillator Enable Control bit
- 1 = Dedicated Timer1 oscillator circuit enabled
- 0 = Dedicated Timer1 oscillator circuit disabled

bit 2 **$\overline{\text{T1SYNC}}$:** Timer1 External Clock Input Synchronization Control bit

TMR1CS<1:0> = 1X
- 1 = Do not synchronize external clock input
- 0 = Synchronize external clock input with system clock (FOSC)

TMR1CS<1:0> = 0X

This bit is ignored. Timer1 uses the internal clock when TMR1CS<1:0> = 1X.

bit 1 **Unimplemented:** Read as '0'

bit 0 **TMR1ON:** Timer1 On bit
- 1 = Enables Timer1
- 0 = Stops Timer1
  - Clears Timer1 gate flip-flop

17.10 Timer1 Gate Control Register

The Timer1 Gate Control register (T1GCON), shown in Register 17-2, is used to control Timer1 gate.

REGISTER 17-2: T1GCON: TIMER1 GATE CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W/HC-0/u	R-x/x	R/W-0/u	R/W-0/u
TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **TMR1GE:** Timer1 Gate Enable bit

If TMR1ON = 0:
This bit is ignored
If TMR1ON = 1:
1 = Timer1 counting is controlled by the Timer1 gate function
0 = Timer1 counts regardless of Timer1 gate function

bit 6 **T1GPOL:** Timer1 Gate Polarity bit

1 = Timer1 gate is active-high (Timer1 counts when gate is high)
0 = Timer1 gate is active-low (Timer1 counts when gate is low)

bit 5 **T1GTM:** Timer1 Gate Toggle Mode bit

1 = Timer1 Gate Toggle mode is enabled
0 = Timer1 Gate Toggle mode is disabled and toggle flip-flop is cleared
Timer1 gate flip-flop toggles on every rising edge.

bit 4 **T1GSPM:** Timer1 Gate Single-Pulse Mode bit

1 = Timer1 gate Single-Pulse mode is enabled and is controlling Timer1 gate
0 = Timer1 gate Single-Pulse mode is disabled

bit 3 **T1GGO/$\overline{\text{DONE}}$:** Timer1 Gate Single-Pulse Acquisition Status bit

1 = Timer1 gate single-pulse acquisition is ready, waiting for an edge
0 = Timer1 gate single-pulse acquisition has completed or has not been started

bit 2 **T1GVAL:** Timer1 Gate Current State bit

Indicates the current state of the Timer1 gate that could be provided to TMR1H:TMR1L.
Unaffected by Timer1 Gate Enable (TMR1GE).

bit 1-0 **T1GSS<1:0>:** Timer1 Gate Source Select bits

00 = Timer1 gate pin
01 = Timer0 overflow output
10 = Reserved
11 = Reserved

TABLE 17-5: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	68
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								135*
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								135*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	101
T1CON	TMR1CS1	TMR1CS0	T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	139
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	$\overline{\text{T1GGO}}$/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	140

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the Timer1 module.

* Page provides register information.

18.0 ENHANCED UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (EUSART)

The Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART) module is a serial I/O communications peripheral. It contains all the clock generators, shift registers and data buffers necessary to perform an input or output serial data transfer independent of device program execution. The EUSART, also known as a Serial Communications Interface (SCI), can be configured as a full-duplex asynchronous system or half-duplex synchronous system. Full-Duplex mode is useful for communications with peripheral systems, such as CRT terminals and personal computers. Half-Duplex Synchronous mode is intended for communications with peripheral devices, such as A/D or D/A integrated circuits, serial EEPROMs or other microcontrollers. These devices typically do not have internal clocks for baud rate generation and require the external clock signal provided by a master synchronous device.

The EUSART module includes the following capabilities:

- Full-duplex asynchronous transmit and receive
- Two-character input buffer
- One-character output buffer
- Programmable 8-bit or 9-bit character length
- Address detection in 9-bit mode
- Input buffer overrun error detection
- Received character framing error detection
- Half-duplex synchronous master
- Half-duplex synchronous slave
- Programmable clock and data polarity

The EUSART module implements the following additional features, making it ideally suited for use in Local Interconnect Network (LIN) bus systems:

- Automatic detection and calibration of the baud rate
- Wake-up on Break reception
- 13-bit Break character transmit

Block diagrams of the EUSART transmitter and receiver are shown in Figure 18-1 and Figure 18-2.

FIGURE 18-1: EUSART TRANSMIT BLOCK DIAGRAM

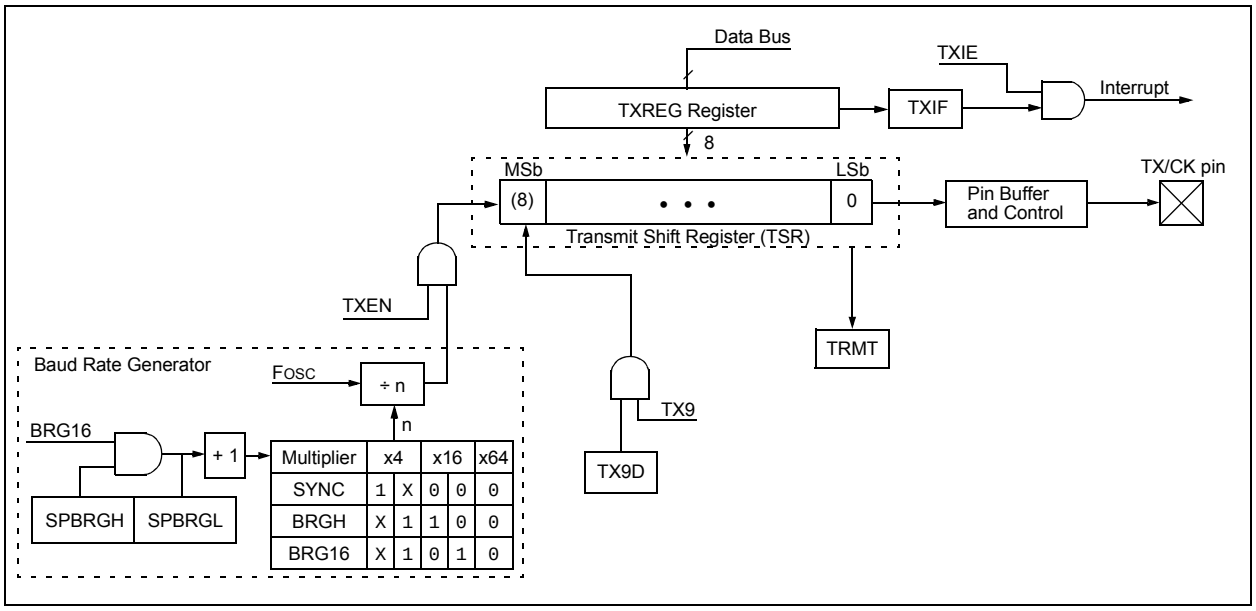
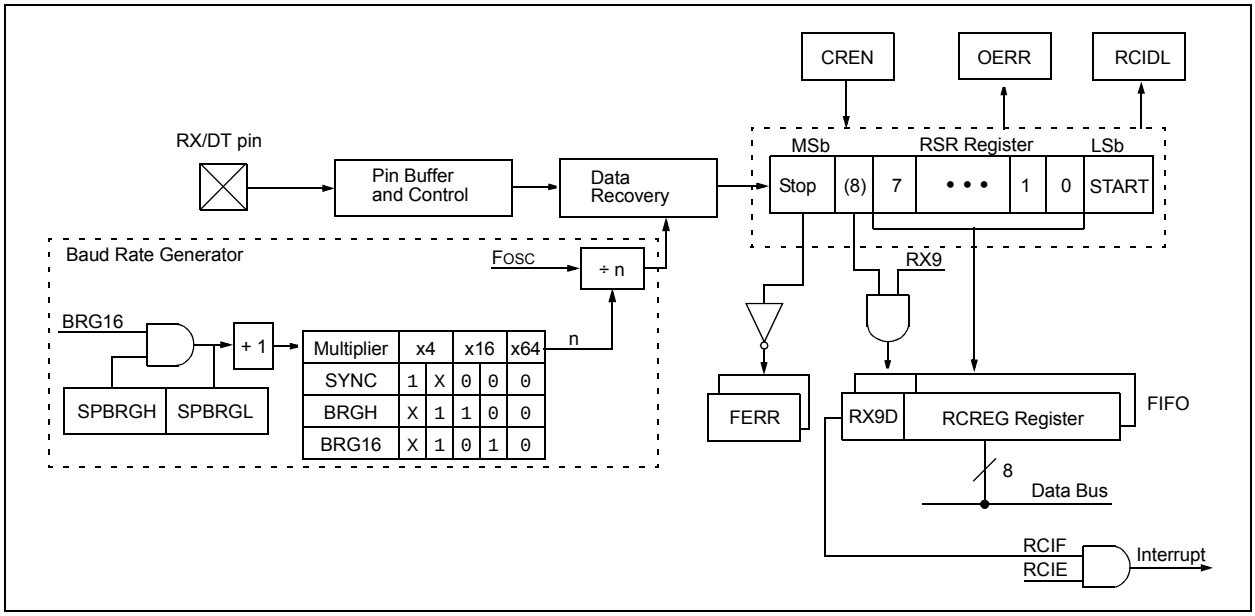


FIGURE 18-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 18-1, Register 18-2 and Register 18-3, respectively.

For all modes of EUSART operation, the TRIS control bits corresponding to the RX/DT and TX/CK pins should be set to '1'. The EUSART control will automatically reconfigure the pin from input to output, as needed.

When the receiver or transmitter section is not enabled then the corresponding RX/DT or TX/CK pin may be used for general purpose input and output.

18.1 EUSART Asynchronous Mode

The EUSART transmits and receives data using the standard non-return-to-zero (NRZ) format. NRZ is implemented with two levels: a VOH Mark state which represents a '1' data bit, and a VOL Space state which represents a '0' data bit. NRZ refers to the fact that consecutively transmitted data bits of the same value stay at the output level of that bit without returning to a neutral level between each bit transmission. An NRZ transmission port idles in the Mark state. Each character transmission consists of one Start bit followed by eight or nine data bits and is always terminated by one or more Stop bits. The Start bit is always a space and the Stop bits are always marks. The most common data format is eight bits. Each transmitted bit persists for a period of 1/(Baud Rate). An on-chip dedicated 8-bit/16-bit Baud Rate Generator is used to derive standard baud rate frequencies from the system oscillator. See Table 18-5 for examples of baud rate configurations.

The EUSART transmits and receives the LSb first. The EUSART's transmitter and receiver are functionally independent, but share the same data format and baud rate. Parity is not supported by the hardware, but can be implemented in software and stored as the ninth data bit.

18.1.1 EUSART ASYNCHRONOUS TRANSMITTER

The EUSART transmitter block diagram is shown in Figure 18-1. The heart of the transmitter is the serial Transmit Shift Register (TSR), which is not directly accessible by software. The TSR obtains its data from the transmit buffer, which is the TXREG register.

18.1.1.1 Enabling the Transmitter

The EUSART transmitter is enabled for asynchronous operations by configuring the following three control bits:

- TXEN = 1
- SYNC = 0
- SPEN = 1

All other EUSART control bits are assumed to be in their default state.

Setting the TXEN bit of the TXSTA register enables the transmitter circuitry of the EUSART. Clearing the SYNC bit of the TXSTA register configures the EUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the EUSART. The programmer must set the corresponding TRIS bit to configure the TX/CK I/O pin as an output. If the TX/CK pin is shared with an analog peripheral, the analog I/O function must be disabled by clearing the corresponding ANSEL bit.

Note:	The TXIF transmitter interrupt flag is set when the TXEN enable bit is set.

18.1.1.2 Transmitting Data

A transmission is initiated by writing a character to the TXREG register. If this is the first character, or the previous character has been completely flushed from the TSR, the data in the TXREG is immediately transferred to the TSR register. If the TSR still contains all or part of a previous character, the new character data is held in the TXREG until the Stop bit of the previous character has been transmitted. The pending character in the TXREG is then transferred to the TSR in one TCY immediately following the Stop bit transmission. The transmission of the Start bit, data bits and Stop bit sequence commences immediately following the transfer of the data to the TSR from the TXREG.

18.1.1.3 Transmit Data Polarity

The polarity of the transmit data can be controlled with the SCKP bit of the BAUDCON register. The default state of this bit is '0' which selects high true transmit Idle and data bits. Setting the SCKP bit to '1' will invert the transmit data resulting in low true Idle and data bits. The SCKP bit controls transmit data polarity only in Asynchronous mode. In Synchronous mode the SCKP bit has a different function. See **Section 18.5.1.2 "Clock Polarity"**.

18.1.1.4 Transmit Interrupt Flag

The TXIF interrupt flag bit of the PIR1 register is set whenever the EUSART transmitter is enabled and no character is being held for transmission in the TXREG. In other words, the TXIF bit is only clear when the TSR is busy with a character and a new character has been queued for transmission in the TXREG. The TXIF flag bit is not cleared immediately upon writing TXREG. TXIF becomes valid in the second instruction cycle following the write execution. Polling TXIF immediately following the TXREG write will return invalid results. The TXIF bit is read-only, it cannot be set or cleared by software.

The TXIF interrupt can be enabled by setting the TXIE interrupt enable bit of the PIE1 register. However, the TXIF flag bit will be set whenever the TXREG is empty, regardless of the state of the TXIE enable bit.

To use interrupts when transmitting data, set the TXIE bit only when there is more data to send. Clear the TXIE interrupt enable bit upon writing the last character of the transmission to the TXREG.

18.1.1.5 TSR Status

The TRMT bit of the TXSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user needs to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

18.1.1.6 Transmitting 9-Bit Characters

The EUSART supports 9-bit character transmissions. When the TX9 bit of the TXSTA register is set, the EUSART will shift 9 bits out for each character transmitted. The TX9D bit of the TXSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the eight Least Significant bits into the TXREG. All nine bits of data will be transferred to the TSR shift register immediately after the TXREG is written.

A special 9-bit Address mode is available for use with multiple receivers. See **Section 18.1.2.7 "Address Detection"** for more information on the Address mode.

18.1.1.7 Asynchronous Transmission Set-up:

1. Initialize the SPBRGH:SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 18.4 "EUSART Baud Rate Generator (BRG)"**).
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
4. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the eight Least Significant data bits are an address when the receiver is set for address detection.
5. Set the SCKP control bit if inverted transmit data polarity is desired.
6. Enable the transmission by setting the TXEN control bit. This will cause the TXIF interrupt bit to be set.
7. If interrupts are desired, set the TXIE interrupt enable bit. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
8. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
9. Load 8-bit data into the TXREG register. This will start the transmission.

FIGURE 18-3: ASYNCHRONOUS TRANSMISSION

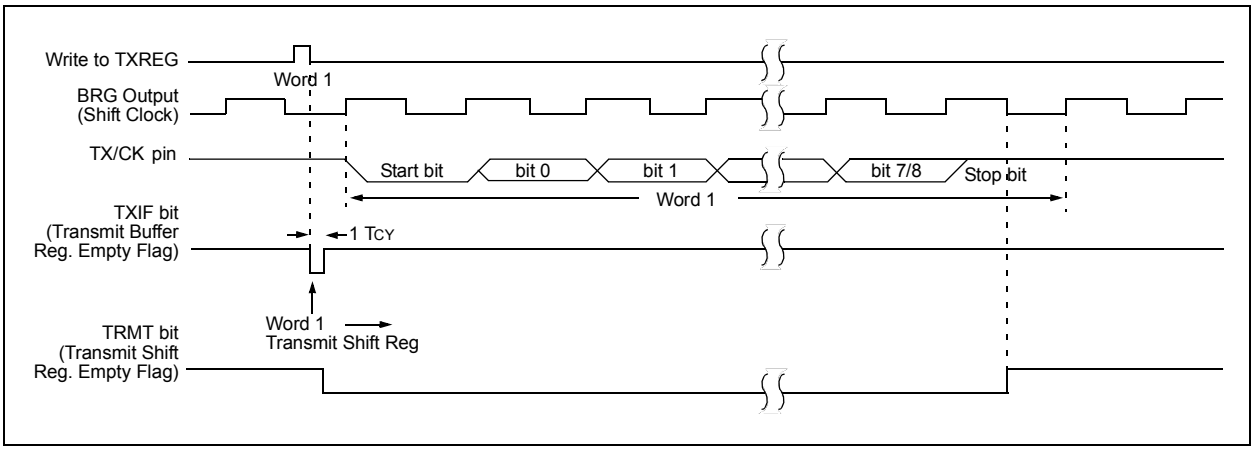
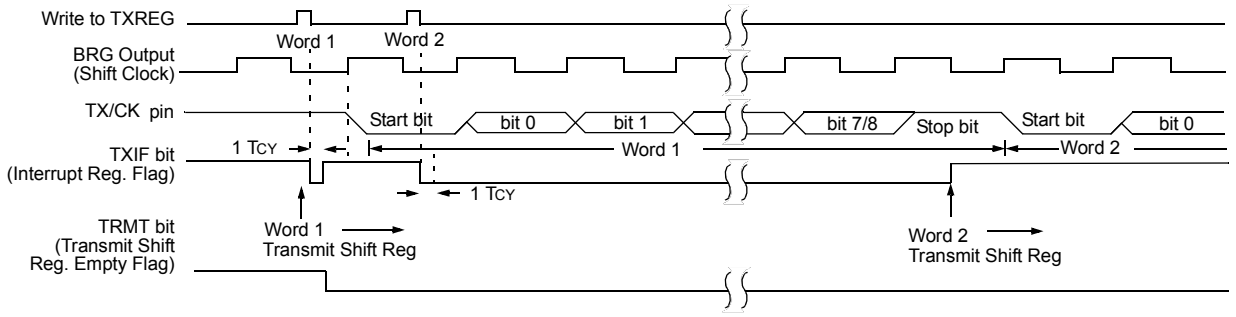


FIGURE 18-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 18-1: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TXREG	EUSART Transmit Register								144*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for asynchronous transmission.
* Page provides register information.
Note 1: PIC16LF1904/7 only.

18.1.2 EUSART ASYNCHRONOUS RECEIVER

The Asynchronous mode would typically be used in RS-232 systems. The receiver block diagram is shown in Figure 18-2. The data is received on the RX/DT pin and drives the data recovery block. The data recovery block is actually a high-speed shifter operating at 16 times the baud rate, whereas the serial Receive Shift Register (RSR) operates at the bit rate. When all eight or nine bits of the character have been shifted in, they are immediately transferred to a two character First-In-First-Out (FIFO) memory. The FIFO buffering allows reception of two complete characters and the start of a third character before software must start servicing the EUSART receiver. The FIFO and RSR registers are not directly accessible by software. Access to the received data is via the RCREG register.

18.1.2.1 Enabling the Receiver

The EUSART receiver is enabled for asynchronous operation by configuring the following three control bits:

- CREN = 1
- SYNC = 0
- SPEN = 1

All other EUSART control bits are assumed to be in their default state.

Setting the CREN bit of the RCSTA register enables the receiver circuitry of the EUSART. Clearing the SYNC bit of the TXSTA register configures the EUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the EUSART. The programmer must set the corresponding TRIS bit to configure the RX/DT I/O pin as an input.

Note 1:	If the RX/DT function is on an analog pin, the corresponding ANSEL bit must be cleared for the receiver to function.

If the RX/DT pin is shared with an analog peripheral the analog I/O function must be disabled by clearing the corresponding ANSEL bit.

18.1.2.2 Receiving Data

The receiver data recovery circuit initiates character reception on the falling edge of the first bit. The first bit, also known as the Start bit, is always a zero. The data recovery circuit counts one-half bit time to the center of the Start bit and verifies that the bit is still a zero. If it is not a zero then the data recovery circuit aborts character reception, without generating an error, and resumes looking for the falling edge of the Start bit. If the Start bit zero verification succeeds then the data recovery circuit counts a full bit time to the center of the next bit. The bit is then sampled by a majority detect circuit and the resulting '0' or '1' is shifted into the RSR. This repeats until all data bits have been sampled and shifted into the RSR. One final bit time is measured and the level sampled. This is the Stop bit, which is always a '1'. If the data recovery circuit samples a '0' in the Stop bit position then a framing error is set for this character, otherwise the framing error is cleared for this character. See **Section 18.1.2.4 "Receive Framing Error"** for more information on framing errors.

Immediately after all data bits and the Stop bit have been received, the character in the RSR is transferred to the EUSART receive FIFO and the RCIF interrupt flag bit of the PIR1 register is set. The top character in the FIFO is transferred out of the FIFO by reading the RCREG register.

Note:	If the receive FIFO is overrun, no additional characters will be received until the overrun condition is cleared. See **Section 18.1.2.5 "Receive Overrun Error"** for more information on overrun errors.

18.1.2.3 Receive Interrupts

The RCIF interrupt flag bit of the PIR1 register is set whenever the EUSART receiver is enabled and there is an unread character in the receive FIFO. The RCIF interrupt flag bit is read-only, it cannot be set or cleared by software.

RCIF interrupts are enabled by setting the following bits:

- RCIE interrupt enable bit of the PIE1 register
- PEIE peripheral interrupt enable bit of the INTCON register
- GIE global interrupt enable bit of the INTCON register

The RCIF interrupt flag bit will be set when there is an unread character in the FIFO, regardless of the state of interrupt enable bits.

18.1.2.4 Receive Framing Error

Each character in the receive FIFO buffer has a corresponding framing error Status bit. A framing error indicates that a Stop bit was not seen at the expected time. The framing error status is accessed via the FERR bit of the RCSTA register. The FERR bit represents the status of the top unread character in the receive FIFO. Therefore, the FERR bit must be read before reading the RCREG.

The FERR bit is read-only and only applies to the top unread character in the receive FIFO. A framing error (FERR = 1) does not preclude reception of additional characters. It is not necessary to clear the FERR bit. Reading the next character from the FIFO buffer will advance the FIFO to the next character and the next corresponding framing error.

The FERR bit can be forced clear by clearing the SPEN bit of the RCSTA register which resets the EUSART. Clearing the CREN bit of the RCSTA register does not affect the FERR bit. A framing error by itself does not generate an interrupt.

Note:	If all receive characters in the receive FIFO have framing errors, repeated reads of the RCREG will not clear the FERR bit.

18.1.2.5 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated If a third character, in its entirety, is received before the FIFO is accessed. When this happens the OERR bit of the RCSTA register is set. The characters already in the FIFO buffer can be read but no additional characters will be received until the error is cleared. The error must be cleared by either clearing the CREN bit of the RCSTA register or by resetting the EUSART by clearing the SPEN bit of the RCSTA register.

18.1.2.6 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set, the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth and Most Significant data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

18.1.2.7 Address Detection

A special Address Detection mode is available for use when multiple receivers share the same transmission line, such as in RS-485 systems. Address detection is enabled by setting the ADDEN bit of the RCSTA register.

Address detection requires 9-bit character reception. When address detection is enabled, only characters with the ninth data bit set will be transferred to the receive FIFO buffer, thereby setting the RCIF interrupt bit. All other characters will be ignored.

Upon receiving an address character, user software determines if the address matches its own. Upon address match, user software must disable address detection by clearing the ADDEN bit before the next Stop bit occurs. When user software detects the end of the message, determined by the message protocol used, software places the receiver back into the Address Detection mode by setting the ADDEN bit.

18.1.2.8 Asynchronous Reception Set-up:

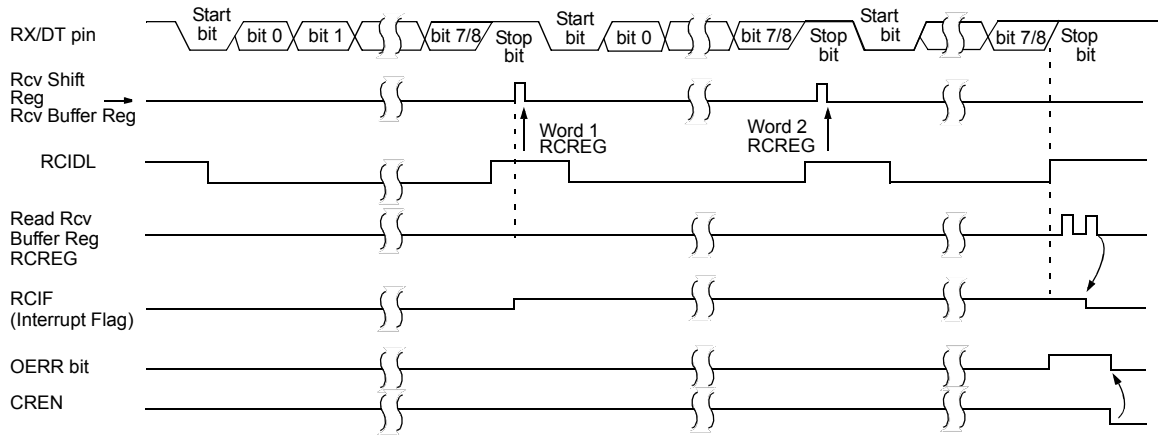
1. Initialize the SPBRGH:SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 18.4 "EUSART Baud Rate Generator (BRG)"**).
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. Enable the serial port by setting the SPEN bit and the RX/DT pin TRIS bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE interrupt enable bit and set the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RCSTA register to get the error flags and, if 9-bit data reception is enabled, the ninth data bit.
9. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

18.1.2.9 9-bit Address Detection Mode Set-up

This mode would typically be used in RS-485 systems. To set up an asynchronous reception with address detect enable:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 18.4 "EUSART Baud Rate Generator (BRG)"**).
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE interrupt enable bit and set the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the ninth bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RCSTA register to get the error flags. The ninth data bit will always be set.
10. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

FIGURE 18-5: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX/DT input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

TABLE 18-2: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCREG	EUSART Receive Register								147*
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	101
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for asynchronous reception.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

18.2 Clock Accuracy with Asynchronous Operation

The factory calibrates the internal oscillator block output (INTOSC). However, the INTOSC frequency may drift as VDD or temperature changes, and this directly affects the asynchronous baud rate.

The Auto-Baud Detect feature (see **Section 18.4.1 "Auto-Baud Detect"**) can be used to compensate for changes in the INTOSC frequency.

There may not be fine enough resolution when adjusting the Baud Rate Generator to compensate for a gradual change in the peripheral clock frequency.

18.3 Register Definitions: EUSART Control

REGISTER 18-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don't care

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** Ninth bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode.

REGISTER 18-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RX/DT and TX/CK pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave
Don't care

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enable interrupt and load the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 8-bit (RX9 = 0):
Don't care

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

REGISTER 18-3: BAUDCON: BAUD RATE CONTROL REGISTER

R-0/0	R-1/1	U-0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0
ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ABDOVF:** Auto-Baud Detect Overflow bit
Asynchronous mode:
1 = Auto-baud timer overflowed
0 = Auto-baud timer did not overflow
Synchronous mode:
Don't care

bit 6 **RCIDL**: Receive Idle Flag bit
Asynchronous mode:
1 = Receiver is Idle
0 = Start bit has been received and the receiver is receiving
Synchronous mode:
Don't care

bit 5 **Unimplemented:** Read as '0'

bit 4 **SCKP**: Synchronous Clock Polarity Select bit
Asynchronous mode:
1 = Transmit inverted data to the TX/CK pin
0 = Transmit non-inverted data to the TX/CK pin
Synchronous mode:
1 = Data is clocked on rising edge of the clock
0 = Data is clocked on falling edge of the clock

bit 3 **BRG16:** 16-bit Baud Rate Generator bit
1 = 16-bit Baud Rate Generator is used
0 = 8-bit Baud Rate Generator is used

bit 2 **Unimplemented:** Read as '0'

bit 1 **WUE:** Wake-up Enable bit
Asynchronous mode:
1 = Receiver is waiting for a falling edge. No character will be received, byte RCIF will be set. WUE will automatically clear after RCIF is set.
0 = Receiver is operating normally
Synchronous mode:
Don't care

bit 0 **ABDEN**: Auto-Baud Detect Enable bit
Asynchronous mode:
1 = Auto-Baud Detect mode is enabled (clears when auto-baud is complete)
0 = Auto-Baud Detect mode is disabled
Synchronous mode:
Don't care

18.4 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDCON register selects 16-bit mode.

The SPBRGH:SPBRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXSTA register and the BRG16 bit of the BAUDCON register. In Synchronous mode, the BRGH bit is ignored.

Example 18-1 provides a sample calculation for determining the desired baud rate, actual baud rate, and baud rate % error.

Typical baud rates and error values for various Asynchronous modes have been computed for your convenience and are shown in Table 18-5. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPBRGH, SPBRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is Idle before changing the system clock.

EXAMPLE 18-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate = \frac{FOSC}{64([SPBRGH:SPBRG] + 1)}$$

Solving for SPBRGH:SPBRGL:

$$SPBRGH: SPBRGL = \frac{\frac{FOSC}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$ActualBaudRate = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Baud\ Rate\ \%\ Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

TABLE 18-3: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n+1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n+1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n+1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH, SPBRGL register pair

TABLE 18-4: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented, read as '0'. Shaded bits are not used by the BRG.

* Page provides register information.

TABLE 18-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	1221	1.73	255	1200	0.00	239	1202	0.16	207	1200	0.00	143
2400	2404	0.16	129	2400	0.00	119	2404	0.16	103	2400	0.00	71
9600	9470	-1.36	32	9600	0.00	29	9615	0.16	25	9600	0.00	17
10417	10417	0.00	29	10286	-1.26	27	10417	0.00	23	10165	-2.42	16
19.2k	19.53k	1.73	15	19.20k	0.00	14	19.23k	0.16	12	19.20k	0.00	8
57.6k	—	—	—	57.60k	0.00	7	—	—	—	57.60k	0.00	2
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	300	0.16	207	300	0.00	191	300	0.16	51
1200	1202	0.16	103	1202	0.16	51	1200	0.00	47	1202	0.16	12
2400	2404	0.16	51	2404	0.16	25	2400	0.00	23	—	—	—
9600	9615	0.16	12	—	—	—	9600	0.00	5	—	—	—
10417	10417	0.00	11	10417	0.00	5	—	—	—	—	—	—
19.2k	—	—	—	—	—	—	19.20k	0.00	2	—	—	—
57.6k	—	—	—	—	—	—	57.60k	0.00	0	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	—	—	—
9600	9615	0.16	129	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	10417	0.00	119	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	56.82k	-1.36	21	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	113.64k	-1.36	10	115.2k	0.00	9	111.1k	-3.55	8	115.2k	0.00	5

TABLE 18-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	-0.01	4166	300.0	0.00	3839	300.03	0.01	3332	300.0	0.00	2303
1200	1200	-0.03	1041	1200	0.00	959	1200.5	0.04	832	1200	0.00	575
2400	2399	-0.03	520	2400	0.00	479	2398	-0.08	416	2400	0.00	287
9600	9615	0.16	129	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	10417	0.00	119	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	56.818	-1.36	21	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	113.636	-1.36	10	115.2k	0.00	9	111.11k	-3.55	8	115.2k	0.00	5

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	299.9	-0.02	1666	300.1	0.04	832	300.0	0.00	767	300.5	0.16	207
1200	1199	-0.08	416	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19.23k	0.16	25	19.23k	0.16	12	19.20k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

TABLE 18-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

18.4.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCON register starts the auto-baud calibration sequence (Figure 18.4.2). While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRGL begins counting up using the BRG counter clock as shown in Table 18-6. The fifth rising edge will occur on the RX/DT pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH:SPBRGL register pair, the ABDEN bit is automatically cleared, and the RCIF interrupt flag is set. A read operation on the RCREG needs to be performed to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRGL register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 18-6. During ABD, both the SPBRGH and SPBRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 18.4.3 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

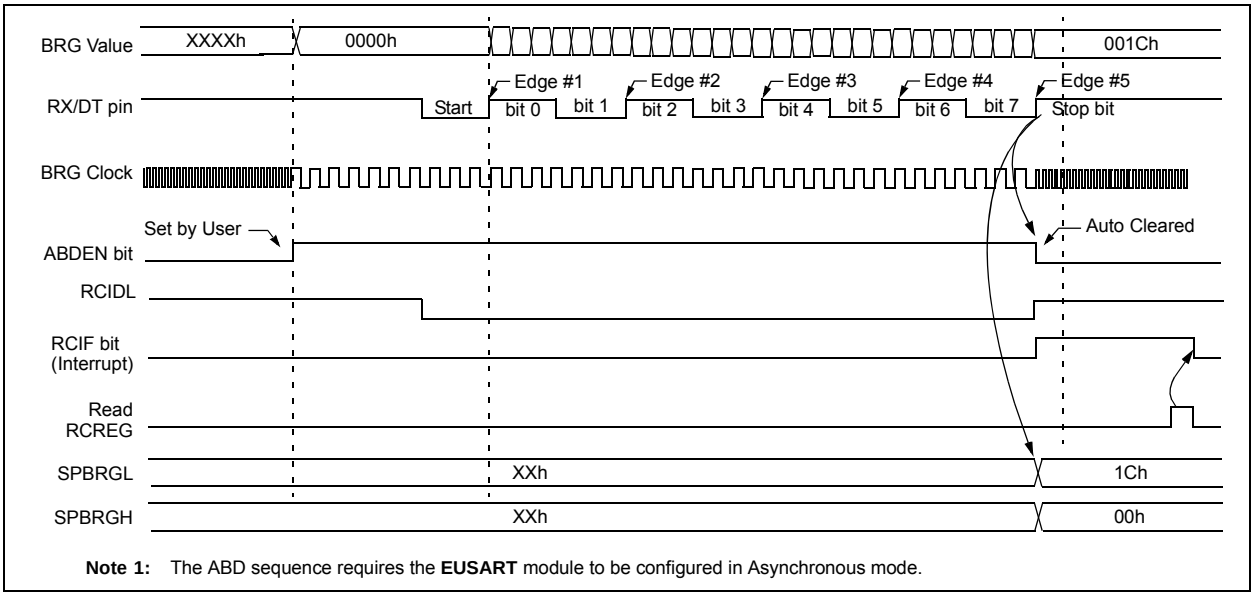
3: During the auto-baud process, the auto-baud counter starts counting at 1. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRGL register pair.

TABLE 18-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SPBRGL and SPBRGH registers are both used as a 16-bit counter, independent of BRG16 setting.

FIGURE 18-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode.

18.4.2 AUTO-BAUD OVERFLOW

During the course of automatic baud detection, the ABDOVF bit of the BAUDCON register will be set if the baud rate counter overflows before the fifth rising edge is detected on the RX pin. The ABDOVF bit indicates that the counter has exceeded the maximum count that can fit in the 16 bits of the SPBRGH:SPBRGL register pair. After the ABDOVF has been set, the counter continues to count until the fifth rising edge is detected on the RX/DT pin. Upon detecting the fifth RX/DT edge, the hardware will set the RCIF interrupt flag and clear the ABDEN bit of the BAUDCON register. The RCIF flag can be subsequently cleared by reading the RCREG. The ABDOVF flag can be cleared by software directly.

To terminate the auto-baud process before the RCIF flag is set, clear the ABDEN bit then clear the ABDOVF bit. The ABDOVF bit will remain set if the ABDEN bit is not cleared first.

18.4.3 AUTO-WAKE-UP ON BREAK

During Sleep mode, all clocks to the EUSART are suspended. Because of this, the Baud Rate Generator is inactive and a proper character reception cannot be performed. The Auto-Wake-up feature allows the controller to wake-up due to activity on the RX/DT line. This feature is available only in Asynchronous mode.

The Auto-Wake-up feature is enabled by setting the WUE bit of the BAUDCON register. Once set, the normal receive sequence on RX/DT is disabled, and the EUSART remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a wake-up signal character for the LIN protocol.)

The EUSART module generates an RCIF interrupt coincident with the wake-up event. The interrupt is generated synchronously to the Q clocks in normal CPU operating modes (Figure 18-7), and asynchronously if the device is in Sleep mode (Figure 18-8). The interrupt condition is cleared by reading the RCREG register.

The WUE bit is automatically cleared by the low-to-high transition on the RX line at the end of the Break. This signals to the user that the Break event is over. At this point, the EUSART module is in Idle mode waiting to receive the next character.

18.4.3.1 Special Considerations

Break Character

To avoid character errors or character fragments during a wake-up event, the wake-up character must be all zeros.

When the wake-up is enabled the function works independent of the low time on the data stream. If the WUE bit is set and a valid non-zero character is received, the low time from the Start bit to the first rising edge will be interpreted as the wake-up event. The remaining bits in the character will be received as a fragmented character and subsequent characters can result in framing or overrun errors.

Therefore, the initial character in the transmission must be all ‘0’s. This must be ten or more bit times, 13-bit times recommended for LIN bus, or any number of bit times for standard RS-232 devices.

Oscillator Startup Time

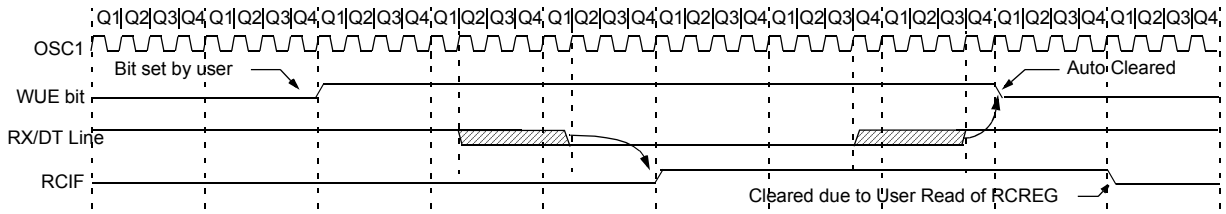
Oscillator start-up time must be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or wake-up signal) character must be of sufficient length, and be followed by a sufficient interval, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

WUE Bit

The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared by hardware by a rising edge on RX/DT. The interrupt condition is then cleared by software by reading the RCREG register and discarding its contents.

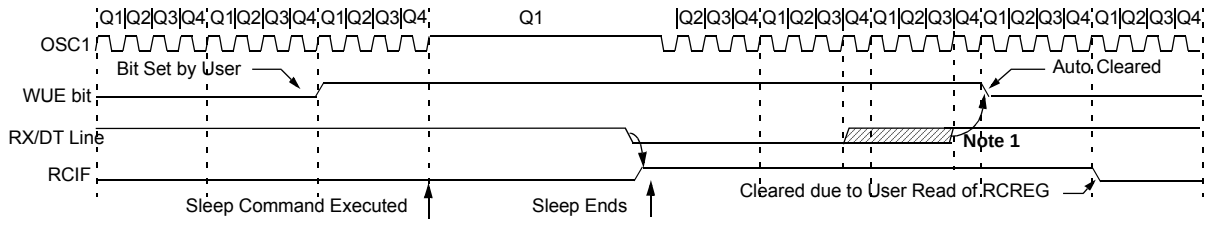
To ensure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process before setting the WUE bit. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

FIGURE 18-7: AUTO-WAKE-UP BIT (WUE) TIMING DURING NORMAL OPERATION



Note 1: The **EUSART** remains in Idle while the WUE bit is set.

FIGURE 18-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



Note 1: If the wake-up event requires long oscillator warm-up time, the automatic clearing of the WUE bit can occur while the `stposc` signal is still active. This sequence should not depend on the presence of Q clocks.

2: The **EUSART** remains in Idle while the WUE bit is set.

18.4.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 '0' bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 18-9 for the timing of the Break character sequence.

18.4.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

18.4.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the Received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

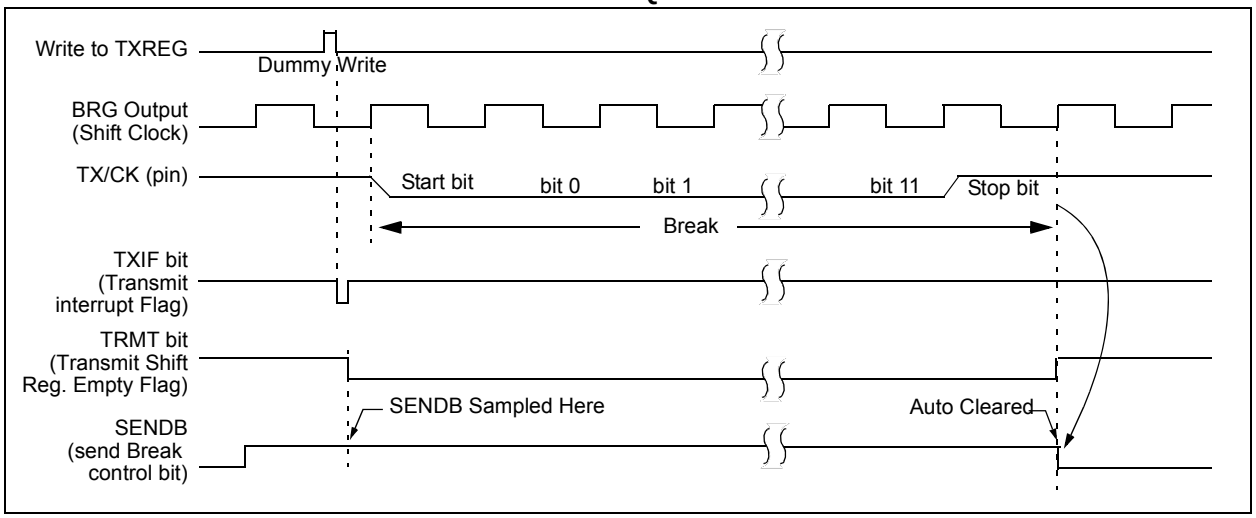
A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in **Section 18.4.3 "Auto-Wake-up on Break"**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCON register before placing the EUSART in Sleep mode.

FIGURE 18-9: SEND BREAK CHARACTER SEQUENCE



18.5 EUSART Synchronous Mode

Synchronous serial communications are typically used in systems with a single master and one or more slaves. The master device contains the necessary circuitry for baud rate generation and supplies the clock for all devices in the system. Slave devices can take advantage of the master clock by eliminating the internal clock generation circuitry.

There are two signal lines in Synchronous mode: a bidirectional data line and a clock line. Slaves use the external clock supplied by the master to shift the serial data into and out of their respective receive and transmit shift registers. Since the data line is bidirectional, synchronous operation is half-duplex only. Half-duplex refers to the fact that master and slave devices can receive and transmit data but not both simultaneously. The EUSART can operate as either a master or slave device.

Start and Stop bits are not used in synchronous transmissions.

18.5.1 SYNCHRONOUS MASTER MODE

The following bits are used to configure the EUSART for synchronous master operation:

- SYNC = 1
- CSRC = 1
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TXSTA register configures the device for synchronous operation. Setting the CSRC bit of the TXSTA register configures the device as a master. Clearing the SREN and CREN bits of the RCSTA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RCSTA register enables the EUSART. If the RX/DT or TX/CK pins are shared with an analog peripheral the analog I/O functions must be disabled by clearing the corresponding ANSEL bits.

The TRIS bits corresponding to the RX/DT and TX/CK pins should be set.

18.5.1.1 Master Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a master transmits the clock on the TX/CK line. The TX/CK pin output driver is automatically enabled when the EUSART is configured for synchronous transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One clock cycle is generated for each data bit. Only as many clock cycles are generated as there are data bits.

18.5.1.2 Clock Polarity

A clock polarity option is provided for Microwire compatibility. Clock polarity is selected with the SCKP bit of the BAUDCON register. Setting the SCKP bit sets the clock Idle state as high. When the SCKP bit is set, the data changes on the falling edge of each clock and is sampled on the rising edge of each clock. Clearing the SCKP bit sets the Idle state as low. When the SCKP bit is cleared, the data changes on the rising edge of each clock and is sampled on the falling edge of each clock.

18.5.1.3 Synchronous Master Transmission

Data is transferred out of the device on the RX/DT pin. The RX/DT and TX/CK pin output drivers are automatically enabled when the EUSART is configured for synchronous master transmit operation.

A transmission is initiated by writing a character to the TXREG register. If the TSR still contains all or part of a previous character the new character data is held in the TXREG until the last bit of the previous character has been transmitted. If this is the first character, or the previous character has been completely flushed from the TSR, the data in the TXREG is immediately transferred to the TSR. The transmission of the character commences immediately following the transfer of the data to the TSR from the TXREG.

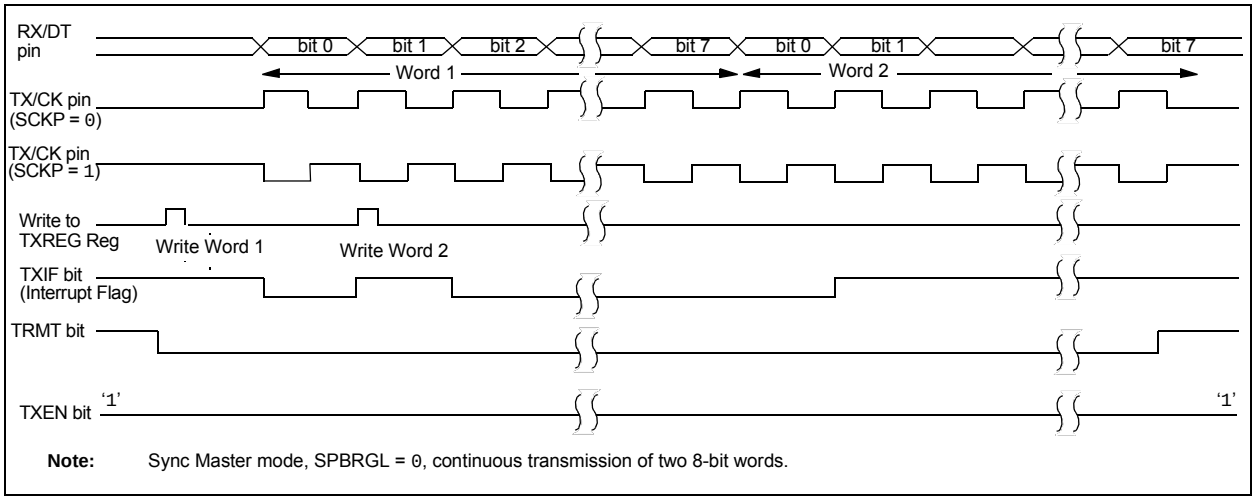
Each data bit changes on the leading edge of the master clock and remains valid until the subsequent leading clock edge.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

18.5.1.4 Synchronous Master Transmission Set-up:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 18.4 “EUSART Baud Rate Generator (BRG)”**).
2. Set the RX/DT and TX/CK TRIS controls to ‘1’.
3. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC. Set the TRIS bits corresponding to the RX/DT and TX/CK I/O pins.
4. Disable Receive mode by clearing bits SREN and CREN.
5. Enable Transmit mode by setting the TXEN bit.
6. If 9-bit transmission is desired, set the TX9 bit.
7. If interrupts are desired, set the TXIE, GIE and PEIE interrupt enable bits.
8. If 9-bit transmission is selected, the ninth bit should be loaded in the TX9D bit.
9. Start transmission by loading data to the TXREG register.

FIGURE 18-10: SYNCHRONOUS TRANSMISSION



Note: Sync Master mode, SPBRGL = 0, continuous transmission of two 8-bit words.

FIGURE 18-11: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)

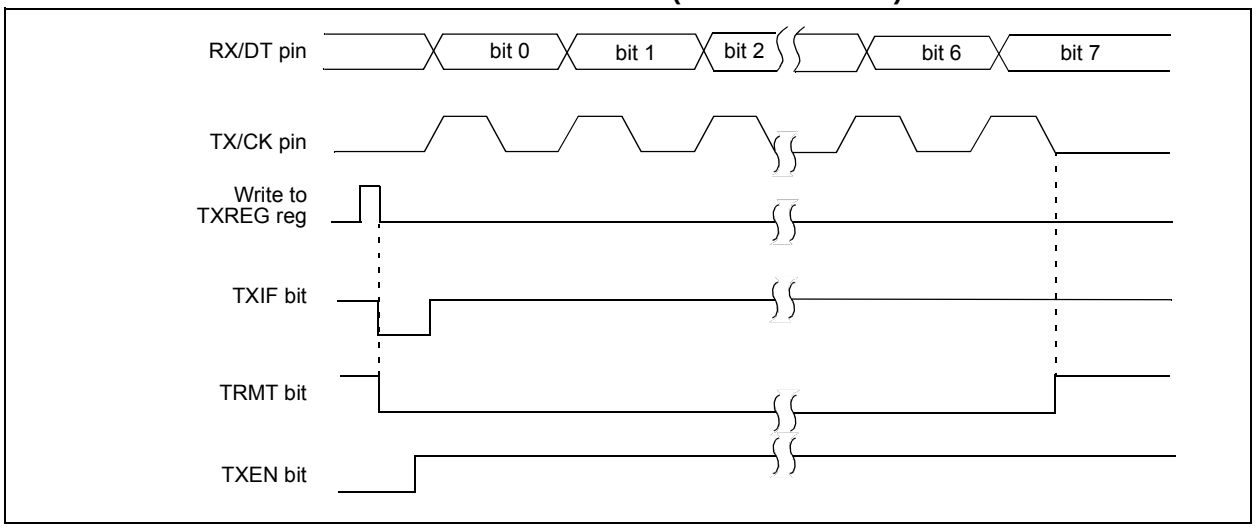


TABLE 18-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	98
TRISG	—	—	—	TRISG4	TRISG3	TRISG2	TRISG1	TRISG0	98
TXREG	EUSART Transmit Register								144*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous master transmission.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

18.5.1.5 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver must be disabled by setting the corresponding TRIS bits when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are un-read characters in the receive FIFO.

18.5.1.6 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver must be disabled by setting the associated TRIS bit when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

18.5.1.7 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG.

If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

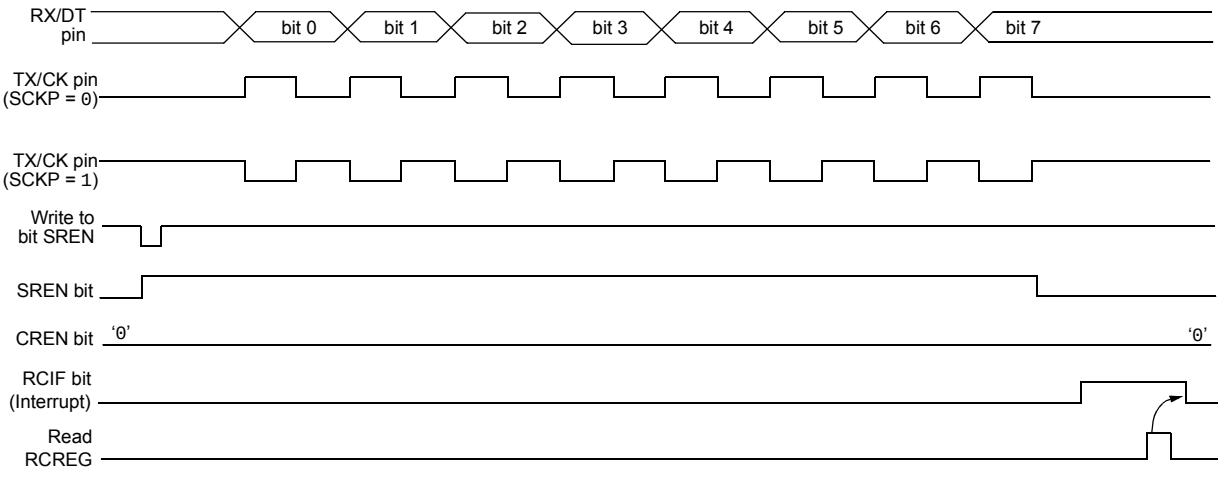
18.5.1.8 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

18.5.1.9 Synchronous Master Reception Set-up:

1. Initialize the SPBRGH, SPBRGL register pair for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
2. Set the RX/DT and TX/CK TRIS controls to ‘1’.
3. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC. Disable RX/DT and TX/CK output drivers by setting the corresponding TRIS bits.
4. Ensure bits CREN and SREN are clear.
5. If using interrupts, set the GIE and PEIE bits of the INTCON register and set RCIE.
6. If 9-bit reception is desired, set bit RX9.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF will be set when reception of a character is complete. An interrupt will be generated if the enable bit RCIE was set.
9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RCREG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

FIGURE 18-12: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates Sync Master mode with bit SREN = 1 and bit BRGH = 0.

TABLE 18-8: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCREG	EUSART Receive Register								147*
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous master reception.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

18.5.2 SYNCHRONOUS SLAVE MODE

The following bits are used to configure the EUSART for Synchronous slave operation:

- SYNC = 1
- CSRC = 0
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TXSTA register configures the device for synchronous operation. Clearing the CSRC bit of the TXSTA register configures the device as a slave. Clearing the SREN and CREN bits of the RCSTA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RCSTA register enables the EUSART. If the RX/DT or TX/CK pins are shared with an analog peripheral the analog I/O functions must be disabled by clearing the corresponding ANSEL bits.

RX/DT and TX/CK pin output drivers must be disabled by setting the corresponding TRIS bits.

18.5.2.1 EUSART Synchronous Slave Transmit

The operation of the Synchronous Master and Slave modes are identical (see **Section 18.5.1.3 "Synchronous Master Transmission"**), except in the case of the Sleep mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

1. The first character will immediately transfer to the TSR register and transmit.
2. The second word will remain in TXREG register.
3. The TXIF bit will not be set.
4. After the first character has been shifted out of TSR, the TXREG register will transfer the second character to the TSR and the TXIF bit will now be set.
5. If the PEIE and TXIE bits are set, the interrupt will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will call the Interrupt Service Routine.

18.5.2.2 Synchronous Slave Transmission Set-up:

1. Set the SYNC and SPEN bits and clear the CSRC bit.
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. Clear the CREN and SREN bits.
4. If using interrupts, ensure that the GIE and PEIE bits of the INTCON register are set and set the TXIE bit.
5. If 9-bit transmission is desired, set the TX9 bit.
6. Enable transmission by setting the TXEN bit.
7. If 9-bit transmission is selected, insert the Most Significant bit into the TX9D bit.
8. Start transmission by writing the Least Significant eight bits to the TXREG register.

TABLE 18-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	98
TXREG	EUSART Transmit Register								144*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous slave transmission.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

18.5.2.3 EUSART Synchronous Slave Reception

The operation of the Synchronous Master and Slave modes is identical (**Section 18.5.1.5 "Synchronous Master Reception"**), with the following exceptions:

- Sleep
- CREN bit is always set, therefore the receiver is never Idle
- SREN bit, which is a "don't care" in Slave mode

A character may be received while in Sleep mode by setting the CREN bit prior to entering Sleep. Once the word is received, the RSR register will transfer the data to the RCREG register. If the RCIE enable bit is set, the interrupt generated will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will branch to the interrupt vector.

18.5.2.4 Synchronous Slave Reception Set-up:

1. Set the SYNC and SPEN bits and clear the CSRC bit.
2. Set the RX/DT and TX/CK TRIS controls to '1'.
3. If using interrupts, ensure that the GIE and PEIE bits of the INTCON register are set and set the RCIE bit.
4. If 9-bit reception is desired, set the RX9 bit.
5. Set the CREN bit to enable reception.
6. The RCIF bit will be set when reception is complete. An interrupt will be generated if the RCIE bit was set.
7. If 9-bit mode is enabled, retrieve the Most Significant bit from the RX9D bit of the RCSTA register.
8. Retrieve the eight Least Significant bits from the receive FIFO by reading the RCREG register.
9. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

TABLE 18-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	—	TMR1IF	68
RCREG	EUSART Receive Register								147*
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous slave reception.

* Page provides register information.

19.0 LIQUID CRYSTAL DISPLAY (LCD) DRIVER MODULE

The Liquid Crystal Display (LCD) driver module generates the timing control to drive a static or multiplexed LCD panel. In the PIC16LF1904/6/7 device, the module drives the panels of up to four commons and up to 116 total segments. The LCD module also provides control of the LCD pixel data.

The LCD driver module supports:

- Direct driving of LCD panel
- Three LCD clock sources with selectable prescaler
- Up to four common pins:
  - Static (1 common)
  - 1/2 multiplex (2 commons)
  - 1/3 multiplex (3 commons)
  - 1/4 multiplex (4 commons)
- 19 Segment pins (PIC16LF1906 only)
- 29 Segment pins (PIC16LF1904/7 only)
- Static, 1/2 or 1/3 LCD Bias

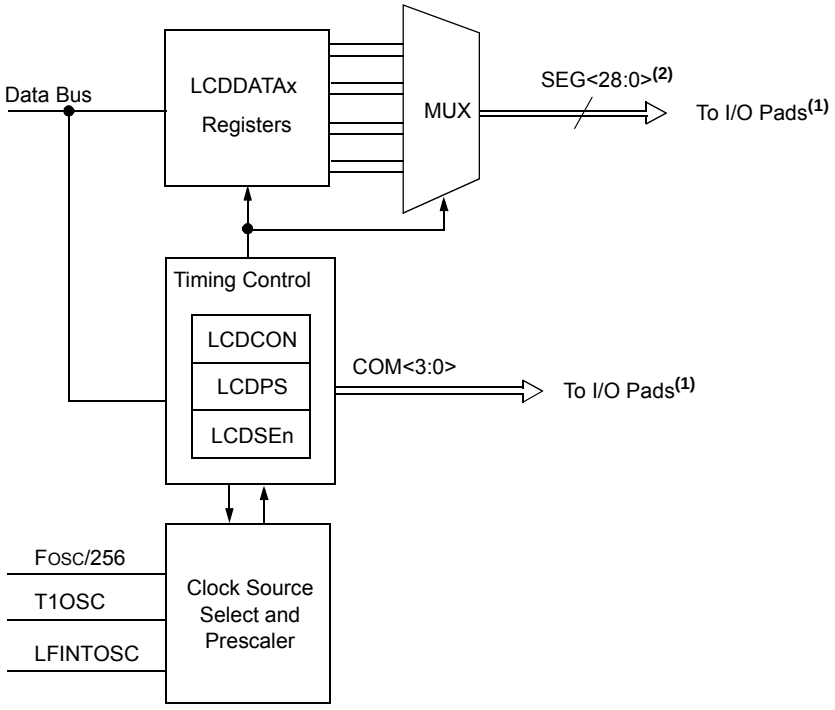
Note:	COM3 and SEG15 share the same physical pin on the PIC16LF1906, therefore SEG15 is not available when using 1/4 multiplex displays.

19.1 LCD Registers

The module contains the following registers:

- LCD Control register (LCDCON)
- LCD Phase register (LCDPS)
- LCD Reference Ladder register (LCDRL)
- LCD Contrast Control register (LCDCST)
- LCD Reference Voltage Control register (LCDREF)
- Up to 4 LCD Segment Enable registers (LCDSEn)
- Up to 16 LCD data registers (LCDDATAn)

FIGURE 19-1: LCD DRIVER MODULE BLOCK DIAGRAM



Note 1: These are not directly connected to the I/O pads, but may be tri-stated, depending on the configuration of the LCD module.

2: COM3 and SEG15 share the same physical pin, therefore SEG15 is not available when using 1/4 multiplex displays. For the PIC16LF1906 device only.

TABLE 19-1: LCD SEGMENT AND DATA REGISTERS

Device	# of LCD Registers	
	Segment Enable	Data
PIC16LF1904/7	3	16
PIC16LF1906	4	12

The LCDCON register (Register 19-1) controls the operation of the LCD driver module. The LCDPS register (Register 19-2) configures the LCD clock source prescaler and the type of waveform; Type-A or Type-B. The LCDSEn registers (Register 19-5) configure the functions of the port pins.

The following LCDSEn registers are available:

- LCDSE0 SE<7:0>
- LCDSE1 SE<15:8>
- LCDSE2 SE<23:16>(1)
- LCDSE3 SE<28:24>(1) (SE<26:24>(2))

Once the module is initialized for the LCD panel, the individual bits of the LCDDATAn registers are cleared/set to represent a clear/dark pixel, respectively:

- LCDDATA0 SEG<7:0>COM0
- LCDDATA1 SEG<15:8>COM0
- LCDDATA2 SEG<23:16>COM0(1)
- LCDDATA3 SEG<7:0>COM1
- LCDDATA4 SEG<15:8>COM1
- LCDDATA5 SEG<23:16>COM1(1)
- LCDDATA6 SEG<7:0>COM2
- LCDDATA7 SEG<15:8>COM2
- LCDDATA8 SEG<23:16>COM2(1)
- LCDDATA9 SEG<7:0>COM3
- LCDDATA10 SEG<15:8>COM3
- LCDDATA11 SEG<23:16>COM3(1)
- LCDDATA12 SEG<28:24>COM0(1) (SEG<26:24>)(2)
- LCDDATA15 SEG<28:24>COM1(1) (SEG<26:24>)(2)
- LCDDATA18 SEG<28:24>COM2(1) (SEG<26:24>)(2)
- LCDDATA21 SEG<28:24>COM3(1) (SEG<26:24>)(2)

Note 1: PIC16LF1904/7 only.

2: PIC16LF1906 only.

As an example, LCDDATAn is detailed in Register 19-6.

Once the module is configured, the LCDEN bit of the LCDCON register is used to enable or disable the LCD module. The LCD panel can also operate during Sleep by clearing the SLPEN bit of the LCDCON register.

REGISTER 19-1: LCDCON: LIQUID CRYSTAL DISPLAY (LCD) CONTROL REGISTER

R/W-0/0	R/W-0/0	R/C-0/0	U-0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1
LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **LCDEN:** LCD Driver Enable bit
1 = LCD driver module is enabled
0 = LCD driver module is disabled

bit 6 **SLPEN:** LCD Driver Enable in Sleep Mode bit
1 = LCD driver module is disabled in Sleep mode
0 = LCD driver module is enabled in Sleep mode

bit 5 **WERR:** LCD Write Failed Error bit
1 = LCDDATAn register written while the WA bit of the LCDPS register = 0 (must be cleared in software)
0 = No LCD write error

bit 4 **Unimplemented:** Read as '0'

bit 3-2 **CS<1:0>:** Clock Source Select bits
00 = FOSC/256
01 = T1OSC (Timer1)
1x = LFINTOSC (31 kHz)

bit 1-0 **LMUX<1:0>:** Commons Select bits

LMUX<1:0>	Multiplex	Maximum Number of Pixels		Bias
		PIC16LF1906	PIC16LF1904/7	
00	Static (COM0)	19	29	Static
01	1/2 (COM<1:0>)	38	58	1/2 or 1/3
10	1/3 (COM<2:0>)	57	87	1/2 or 1/3
11	1/4 (COM<3:0>)	72(1)	116	1/3

Note 1: On these devices, COM3 and SEG15 are shared on one pin, limiting the device from driving 72 segments.

REGISTER 19-2: LCDPS: LCD PHASE REGISTER

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1
WFT	BIASMD	LCDA	WA	LP<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **WFT:** Waveform Type bit
1 = Type-B phase changes on each frame boundary
0 = Type-A phase changes within each common type

bit 6 **BIASMD:** Bias Mode Select bit
When LMUX<1:0> = 00:
0 = Static Bias mode (do not set this bit to '1')
When LMUX<1:0> = 01:
1 = 1/2 Bias mode
0 = 1/3 Bias mode
When LMUX<1:0> = 10:
1 = 1/2 Bias mode
0 = 1/3 Bias mode
When LMUX<1:0> = 11:
0 = 1/3 Bias mode (do not set this bit to '1')

bit 5 **LCDA:** LCD Active Status bit
1 = LCD driver module is active
0 = LCD driver module is inactive

bit 4 **WA:** LCD Write Allow Status bit
1 = Writing to the LCDDATAn registers is allowed
0 = Writing to the LCDDATAn registers is not allowed

bit 3-0 **LP<3:0>:** LCD Prescaler Selection bits
1111 = 1:16
1110 = 1:15
1101 = 1:14
1100 = 1:13
1011 = 1:12
1010 = 1:11
1001 = 1:10
1000 = 1:9
0111 = 1:8
0110 = 1:7
0101 = 1:6
0100 = 1:5
0011 = 1:4
0010 = 1:3
0001 = 1:2
0000 = 1:1

REGISTER 19-3: LCDREF: LCD REFERENCE VOLTAGE CONTROL REGISTER

R/W-0/0	U-0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0
LCDIRE	—	LCDIRI	—	VLCD3PE	VLCD2PE	VLCD1PE	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **LCDIRE:** LCD Internal Reference Enable bit
1 = Internal LCD Reference is enabled and connected to the Internal Contrast Control circuit
0 = Internal LCD Reference is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5 **LCDIRI:** LCD Internal Reference Ladder Idle Enable bit
Allows the Internal FVR buffer to shut down when the LCD Reference Ladder is in power mode 'B'
1 = When the LCD Reference Ladder is in power mode 'B', the LCD Internal FVR buffer is disabled.
0 = The LCD Internal FVR Buffer ignores the LCD Reference Ladder Power mode.

bit 4 **Unimplemented:** Read as '0'

bit 3 **VLCD3PE:** VLCD3 Pin Enable bit
1 = The VLCD3 pin is connected to the internal bias voltage LCDBIAS3**(1)**
0 = The VLCD3 pin is not connected

bit 2 **VLCD2PE:** VLCD2 Pin Enable bit
1 = The VLCD2 pin is connected to the internal bias voltage LCDBIAS2**(1)**
0 = The VLCD2 pin is not connected

bit 1 **VLCD1PE:** VLCD1 Pin Enable bit
1 = The VLCD1 pin is connected to the internal bias voltage LCDBIAS1**(1)**
0 = The VLCD1 pin is not connected

bit 0 **Unimplemented:** Read as '0'

Note 1: Normal pin controls of TRISx and ANSELx are unaffected.

REGISTER 19-4: LCDCST: LCD CONTRAST CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	—	LCDCST<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	C = Only clearable bit

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-0 **LCDCST<2:0>:** LCD Contrast Control bits
Selects the resistance of the LCD contrast control resistor ladder
Bit Value = Resistor ladder
000 = Minimum Resistance (Maximum contrast). Resistor ladder is shorted.
001 = Resistor ladder is at 1/7th of maximum resistance
010 = Resistor ladder is at 2/7th of maximum resistance
011 = Resistor ladder is at 3/7th of maximum resistance
100 = Resistor ladder is at 4/7th of maximum resistance
101 = Resistor ladder is at 5/7th of maximum resistance
110 = Resistor ladder is at 6/7th of maximum resistance
111 = Resistor ladder is at maximum resistance (Minimum contrast).

REGISTER 19-5: LCDSEn: LCD SEGMENT ENABLE REGISTERS

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
SEn	SEn	SEn	SEn	SEn	SEn	SEn	SEn
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **SEn:** Segment Enable bits
1 = Segment function of the pin is enabled
0 = I/O function of the pin is enabled

REGISTER 19-6: LCDDATAn: LCD DATA REGISTERS

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
SEGx-COMy	SEGx-COMy	SEGx-COMy	SEGx-COMy	SEGx-COMy	SEGx-COMy	SEGx-COMy	SEGx-COMy
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **SEGx-COMy:** Pixel On bits
1 = Pixel on (dark)
0 = Pixel off (clear)

19.2 LCD Clock Source Selection

The LCD module has three possible clock sources:

- FOSC/256
- T1OSC
- LFINTOSC

The first clock source is the system clock divided by 256 (FOSC/256). This divider ratio is chosen to provide about 1 kHz output when the system clock is 8 MHz. The divider is not programmable. Instead, the LCD prescaler bits LP<3:0> of the LCDPS register are used to set the LCD frame clock rate.

The second clock source is the T1OSC. This also gives about 1 kHz when a 32.768 kHz crystal is used with the Timer1 oscillator. To use the Timer1 oscillator as a clock source, the T1OSCEN bit of the T1CON register should be set.

The third clock source is the 31 kHz LFINTOSC, which provides approximately 1 kHz output.

The second and third clock sources may be used to continue running the LCD while the processor is in Sleep.

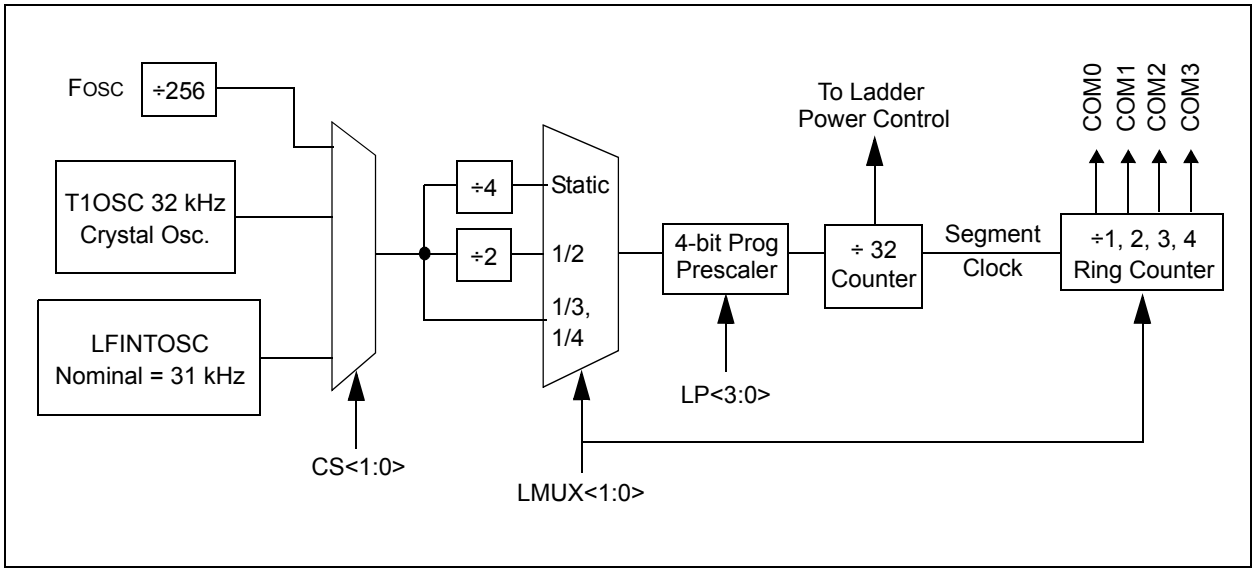
Using bits CS<1:0> of the LCDCON register can select any of these clock sources.

19.2.1 LCD PRESCALER

A 4-bit counter is available as a prescaler for the LCD clock. The prescaler is not directly readable or writable; its value is set by the LP<3:0> bits of the LCDPS register, which determine the prescaler assignment and prescale ratio.

The prescale values are selectable from 1:1 through 1:16.

FIGURE 19-2: LCD CLOCK GENERATION



19.3 LCD Bias Voltage Generation

The LCD module can be configured for one of three bias types:

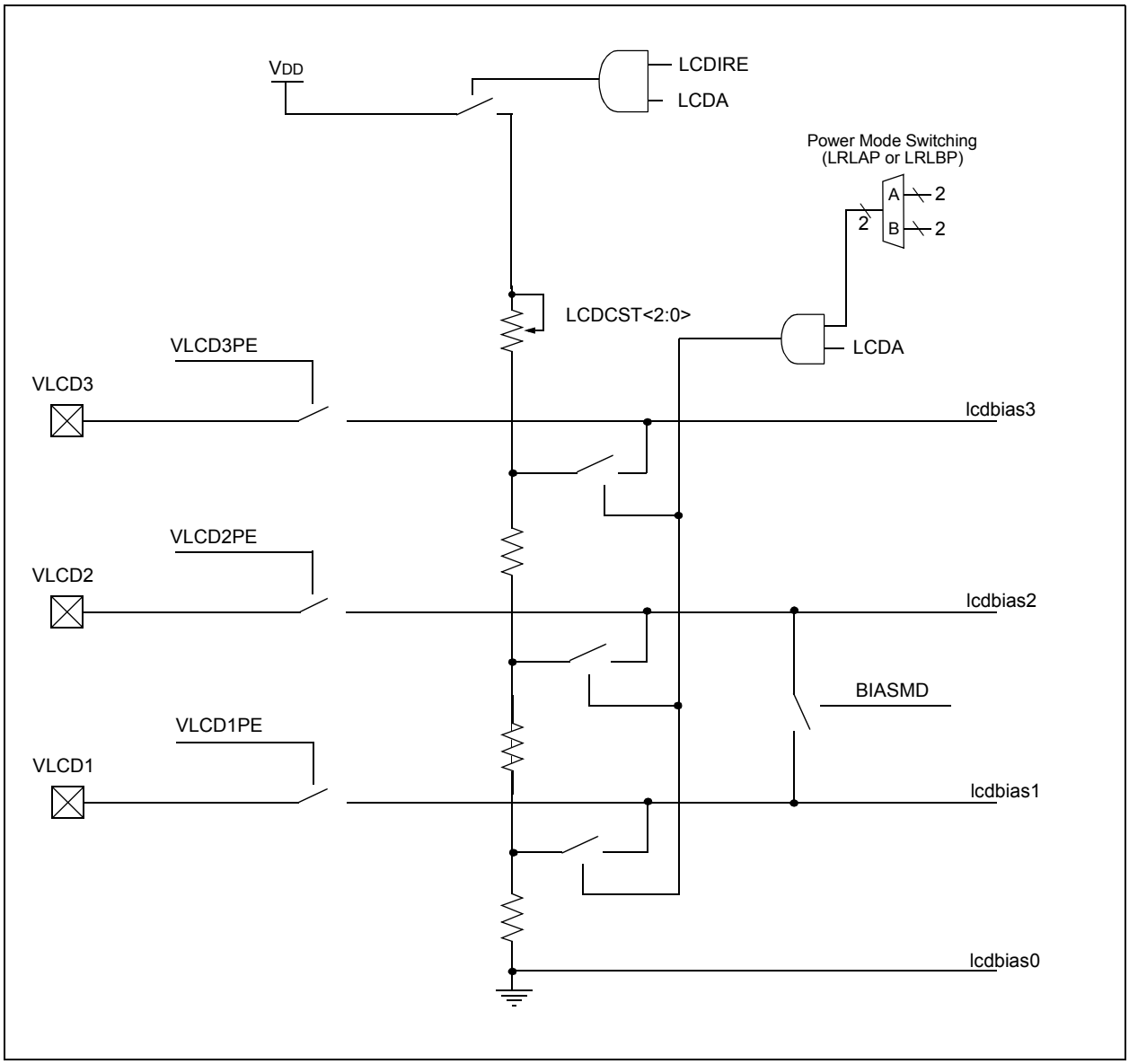
- Static Bias (2 voltage levels: VSS and VLCD)
- 1/2 Bias (3 voltage levels: VSS, 1/2 VLCD and VLCD)
- 1/3 Bias (4 voltage levels: VSS, 1/3 VLCD, 2/3 VLCD and VLCD)

TABLE 19-2: LCD BIAS VOLTAGES

	Static Bias	1/2 Bias	1/3 Bias
LCD Bias 0	VSS	VSS	VSS
LCD Bias 1	—	1/2 VDD	1/3 VDD
LCD Bias 2	—	1/2 VDD	2/3 VDD
LCD Bias 3	VLCD3	VLCD3	VLCD3

So that the user is not forced to place external components and use up to three pins for bias voltage generation, internal contrast control and an internal reference ladder are provided internally to the PIC16LF1904/6/7. Both of these features may be used in conjunction with the external VLCD<3:1> pins, to provide maximum flexibility. Refer to Figure 19-3.

FIGURE 19-3: LCD BIAS VOLTAGE GENERATION BLOCK DIAGRAM



19.4 LCD Bias Internal Reference Ladder

The internal reference ladder can be used to divide the LCD bias voltage two or three equally spaced voltages that will be supplied to the LCD segment pins. To create this, the reference ladder consists of three matched resistors. Refer to Figure 19-3.

19.4.1 BIAS MODE INTERACTION

When in 1/2 Bias mode (BIASMD = 1), then the middle resistor of the ladder is shorted out so that only two voltages are generated. The current consumption of the ladder is higher in this mode, with the one resistor removed.

TABLE 19-3: LCD INTERNAL LADDER POWER MODES (1/3 BIAS)

Power Mode	Nominal Resistance of Entire Ladder	Nominal IDD
Low	3 Mohm	1 µA
Medium	300 kohm	10 µA
High	30 kohm	100 µA

19.4.2 POWER MODES

The internal reference ladder may be operated in one of three power modes. This allows the user to trade off LCD contrast for power in the specific application. The larger the LCD glass, the more capacitance is present on a physical LCD segment, requiring more current to maintain the same contrast level.

Three different power modes are available, LP, MP and HP. The internal reference ladder can also be turned off for applications that wish to provide an external ladder or to minimize power consumption. Disabling the internal reference ladder results in all of the ladders being disconnected, allowing external voltages to be supplied.

Whenever the LCD module is inactive (LCDA = 0), the internal reference ladder will be turned off.

19.4.3 AUTOMATIC POWER MODE SWITCHING

As an LCD segment is electrically only a capacitor, current is drawn only during the interval where the voltage is switching. To minimize total device current, the LCD internal reference ladder can be operated in a different power mode for the transition portion of the duration. This is controlled by the LCDRL Register (Register 19-7).

The LCDRL register allows switching between two power modes, designated ‘A’ and ‘B’. ‘A’ Power mode is active for a programmable time, beginning at the time when the LCD segments transition. ‘B’ Power mode is the remaining time before the segments or commons change again. The LRLAT<2:0> bits select how long, if any, that the ‘A’ Power mode is active. Refer to Figure 19-4.

To implement this, the 5-bit prescaler used to divide the 32 kHz clock down to the LCD controller’s 1 kHz base rate is used to select the power mode.

FIGURE 19-4: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE A

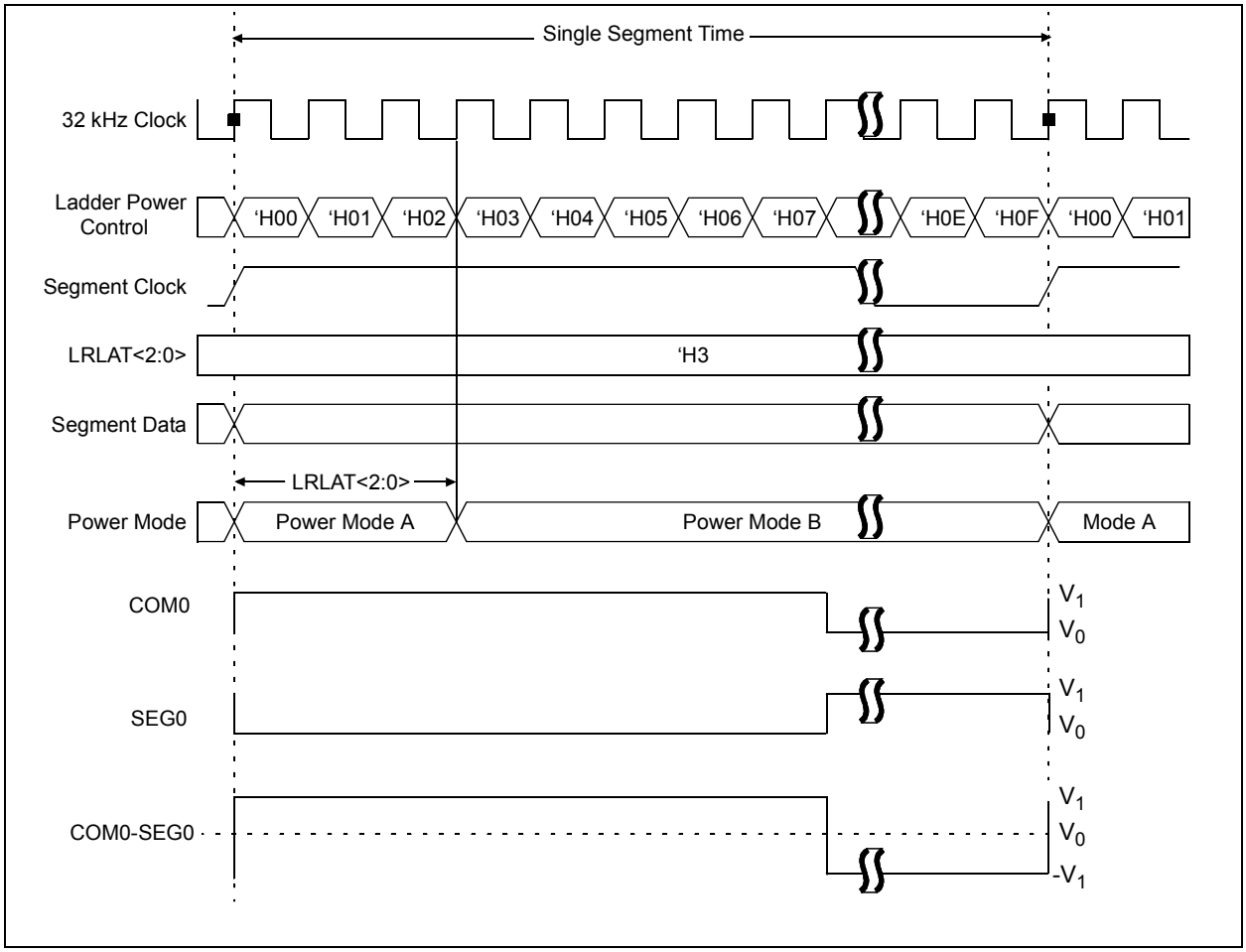


FIGURE 19-5: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE A WAVEFORM (1/2 MUX, 1/2 BIAS DRIVE)

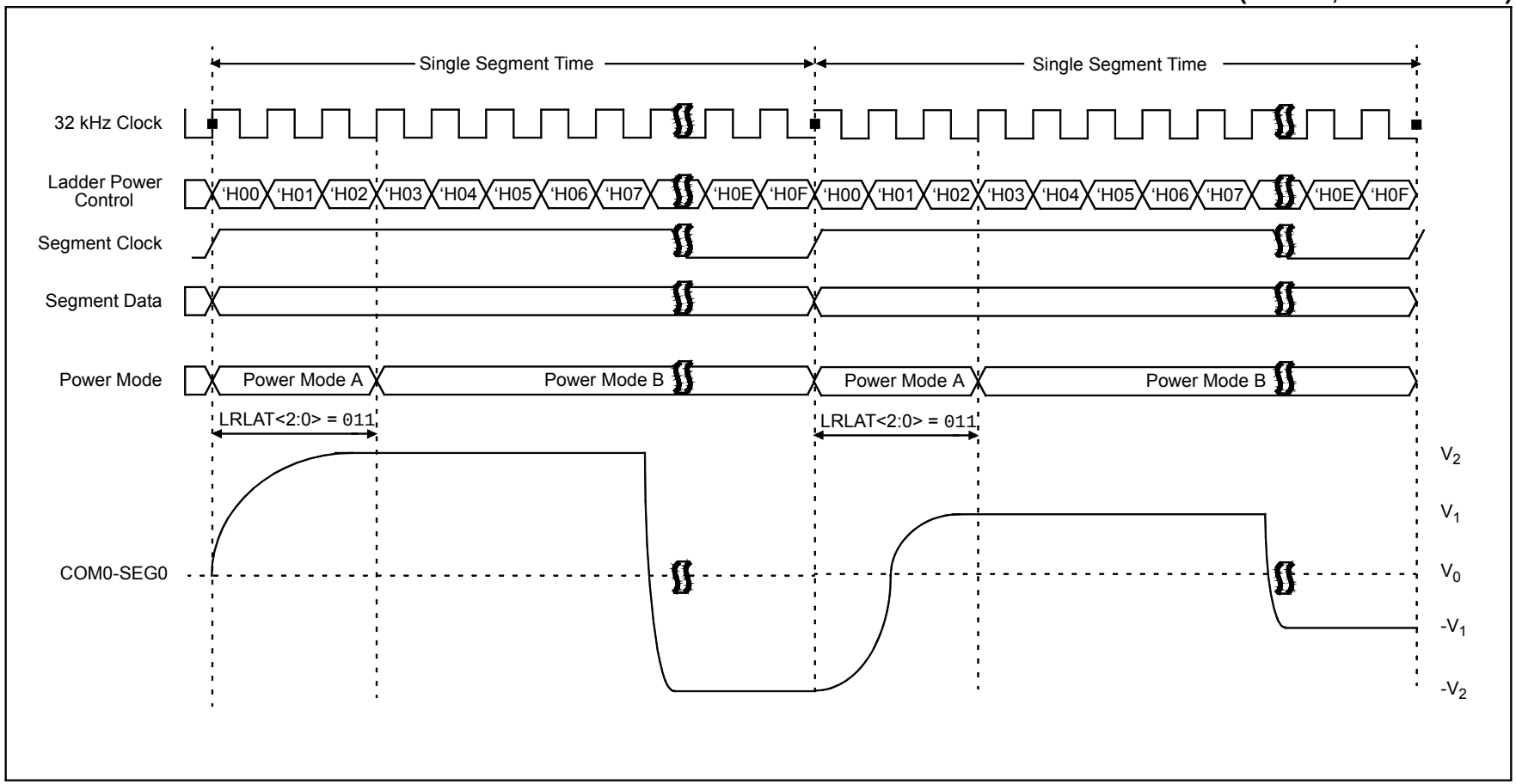
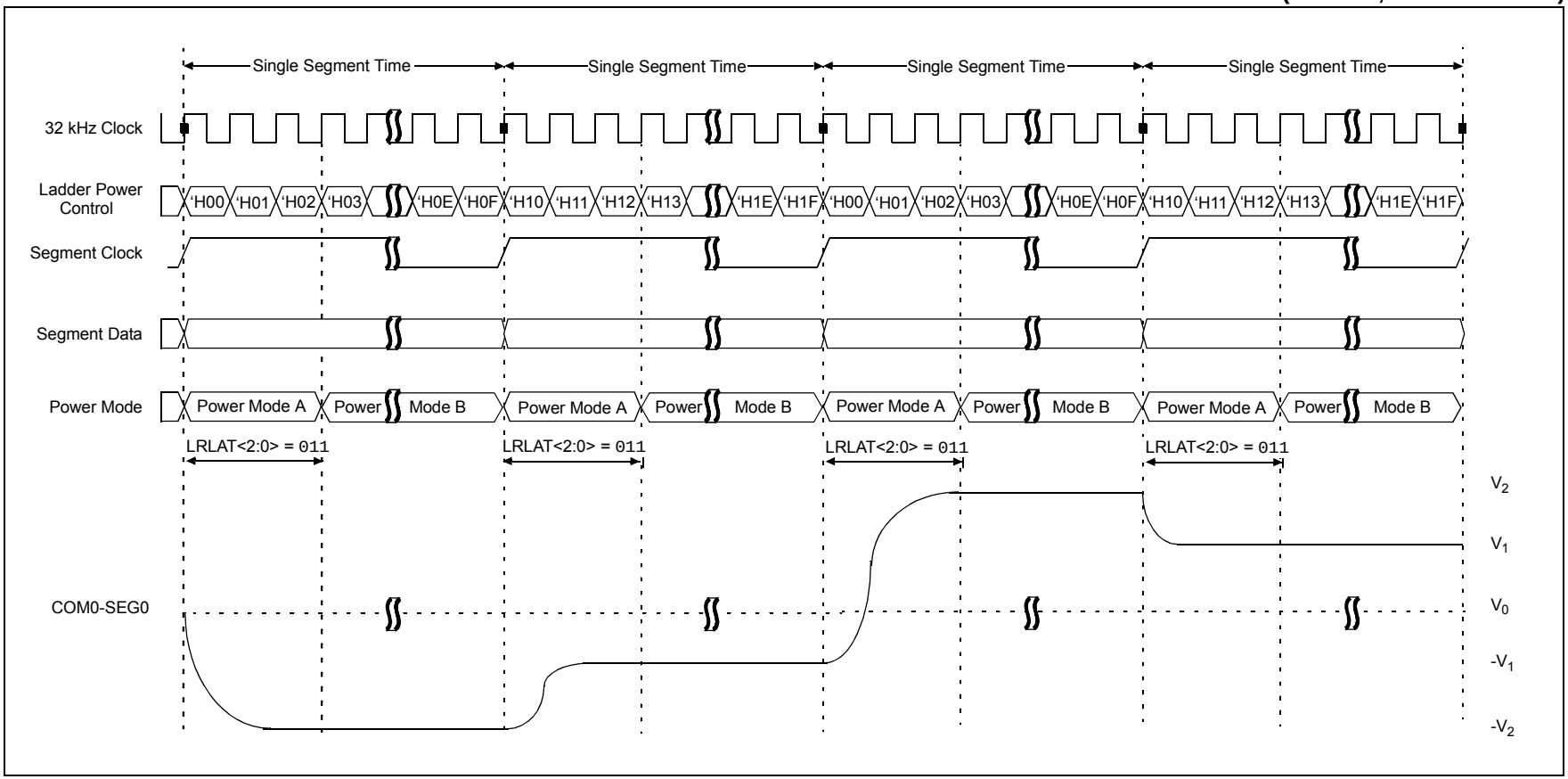


FIGURE 19-6: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE B WAVEFORM (1/2 MUX, 1/2 BIAS DRIVE)



REGISTER 19-7: LCDRL: LCD REFERENCE LADDER CONTROL REGISTERS

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
LRLAP<1:0>		LRLBP<1:0>		—	LRLAT<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **LRLAP<1:0>:** LCD Reference Ladder A Time Power Control bits
During Time interval A (Refer to Figure 19-4):
00 = Internal LCD Reference Ladder is powered down and unconnected
01 = Internal LCD Reference Ladder is powered in low-power mode
10 = Internal LCD Reference Ladder is powered in medium-power mode
11 = Internal LCD Reference Ladder is powered in high-power mode

bit 5-4 **LRLBP<1:0>:** LCD Reference Ladder B Time Power Control bits
During Time interval B (Refer to Figure 19-4):
00 = Internal LCD Reference Ladder is powered down and unconnected
01 = Internal LCD Reference Ladder is powered in low-power mode
10 = Internal LCD Reference Ladder is powered in medium-power mode
11 = Internal LCD Reference Ladder is powered in high-power mode

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **LRLAT<2:0>:** LCD Reference Ladder A Time Interval Control bits
Sets the number of 32 kHz clocks that the A Time interval power mode is active

For type A waveforms (WFT = 0):

000 = Internal LCD Reference Ladder is always in ‘B’ Power mode
001 = Internal LCD Reference Ladder is in ‘A’ Power mode for 1 clock and ‘B’ Power mode for 15 clocks
010 = Internal LCD Reference Ladder is in ‘A’ Power mode for 2 clocks and ‘B’ Power mode for 14 clocks
011 = Internal LCD Reference Ladder is in ‘A’ Power mode for 3 clocks and ‘B’ Power mode for 13 clocks
100 = Internal LCD Reference Ladder is in ‘A’ Power mode for 4 clocks and ‘B’ Power mode for 12 clocks
101 = Internal LCD Reference Ladder is in ‘A’ Power mode for 5 clocks and ‘B’ Power mode for 11 clocks
110 = Internal LCD Reference Ladder is in ‘A’ Power mode for 6 clocks and ‘B’ Power mode for 10 clocks
111 = Internal LCD Reference Ladder is in ‘A’ Power mode for 7 clocks and ‘B’ Power mode for 9 clocks

For type B waveforms (WFT = 1):

000 = Internal LCD Reference Ladder is always in ‘B’ Power mode.
001 = Internal LCD Reference Ladder is in ‘A’ Power mode for 1 clock and ‘B’ Power mode for 31 clocks
010 = Internal LCD Reference Ladder is in ‘A’ Power mode for 2 clocks and ‘B’ Power mode for 30 clocks
011 = Internal LCD Reference Ladder is in ‘A’ Power mode for 3 clocks and ‘B’ Power mode for 29 clocks
100 = Internal LCD Reference Ladder is in ‘A’ Power mode for 4 clocks and ‘B’ Power mode for 28 clocks
101 = Internal LCD Reference Ladder is in ‘A’ Power mode for 5 clocks and ‘B’ Power mode for 27 clocks
110 = Internal LCD Reference Ladder is in ‘A’ Power mode for 6 clocks and ‘B’ Power mode for 26 clocks
111 = Internal LCD Reference Ladder is in ‘A’ Power mode for 7 clocks and ‘B’ Power mode for 25 clocks

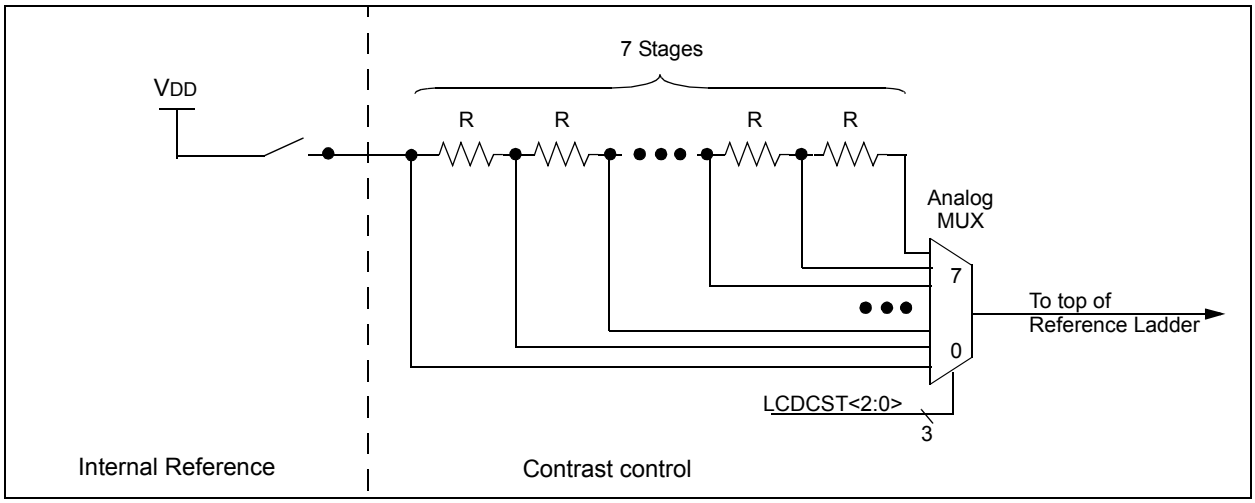
19.4.4 CONTRAST CONTROL

The LCD contrast control circuit consists of a seven-tap resistor ladder, controlled by the LCDCST bits. Refer to Figure 19-7.

The contrast control circuit is used to decrease the output voltage of the signal source by a total of approximately 10%, when LCDCST = 111.

Whenever the LCD module is inactive (LCDA = 0), the contrast control ladder will be turned off (open).

FIGURE 19-7: INTERNAL REFERENCE AND CONTRAST CONTROL BLOCK DIAGRAM



19.4.5 INTERNAL REFERENCE

Under firmware control, an internal reference for the LCD bias voltages can be enabled. When enabled, the source of this voltage can be VDD. When no internal reference is selected, the LCD contrast control circuit is disabled and LCD bias must be provided externally.

Whenever the LCD module is inactive (LCDA = 0), the internal reference will be turned off.

When the internal reference is enabled and the Fixed Voltage Reference is selected, the LCDIRI bit can be used to minimize power consumption by tying into the LCD reference ladder automatic power mode switching. When LCDIRI = 1 and the LCD reference ladder is in Power mode 'B', the LCD internal FVR buffer is disabled.

Note:	The LCD module automatically turns on the Fixed Voltage Reference when needed.

19.4.6 VLCD<3:1> PINS

The VLCD<3:1> pins provide the ability for an external LCD bias network to be used instead of the internal ladder. Use of the VLCD<3:1> pins does not prevent use of the internal ladder. Each VLCD pin has an independent control in the LCDREF register (Register 19-3), allowing access to any or all of the LCD Bias signals. This architecture allows for maximum flexibility in different applications

For example, the VLCD<3:1> pins may be used to add capacitors to the internal reference ladder, increasing the drive capacity.

For applications where the internal contrast control is insufficient, the firmware can choose to only enable the VLCD3 pin, allowing an external contrast control circuit to use the internal reference divider.

19.5 LCD Multiplex Types

The LCD driver module can be configured into one of four multiplex types:

- Static (only COM0 is used)
- 1/2 multiplex (COM<1:0> are used)
- 1/3 multiplex (COM<2:0> are used)
- 1/4 multiplex (COM<3:0> are used)

The LMUX<1:0> bit setting of the LCDCON register decides which of the LCD common pins are used (see Table 19-4 for details).

If the pin is a digital I/O, the corresponding TRIS bit controls the data direction. If the pin is a COM drive, then the TRIS setting of that pin is overridden.

TABLE 19-4: COMMON PIN USAGE

Multiplex	LMUX <1:0>	COM3	COM2	COM1	COM1
Static	00	Unused	Unused	Unused	Active
1/2	01	Unused	Unused	Active	Active
1/3	10	Unused	Active	Active	Active
1/4	11	Active	Active	Active	Active

19.6 Segment Enables

The LCDSEn registers are used to select the pin function for each segment pin. The selection allows each pin to operate as either an LCD segment driver or as one of the pin's alternate functions. To configure the pin as a segment pin, the corresponding bits in the LCDSEn registers must be set to '1'.

If the pin is a digital I/O, the corresponding TRIS bit controls the data direction. Any bit set in the LCDSEn registers overrides any bit settings in the corresponding TRIS register.

Note:	On a Power-on Reset, these pins are configured as normal I/O, not LCD pins.

19.7 Pixel Control

The LCDDATAx registers contain bits which define the state of each pixel. Each bit defines one unique pixel.

Register 19-6 shows the correlation of each bit in the LCDDATAx registers to the respective common and segment signals.

Any LCD pixel location not being used for display can be used as general purpose RAM.

19.8 LCD Frame Frequency

The rate at which the COM and SEG outputs change is called the LCD frame frequency.

TABLE 19-5: FRAME FREQUENCY FORMULAS

Multiplex	Frame Frequency(2) =
Static	Clock source(1)/(4 x (LCD Prescaler) x 32 x 1))
1/2	Clock source(1)/(2 x (LCD Prescaler) x 32 x 2))
1/3	Clock source(1)/(1 x (LCD Prescaler) x 32 x 3))
1/4	Clock source(1)/(1 x (LCD Prescaler) x 32 x 4))

Note 1: Clock source is FOSC/256, T1OSC or LFINTOSC.

2: See Figure 19-2.

TABLE 19-6: APPROXIMATE FRAME FREQUENCY (IN Hz) USING FOSC @ 8 MHz, TIMER1 @ 32.768 kHz OR LFINTOSC

LP<3:0>	Static	1/2	1/3	1/4
2	122	122	162	122
3	81	81	108	81
4	61	61	81	61
5	49	49	65	49
6	41	41	54	41
7	35	35	47	35

19.9 LCD Waveform Generation

LCD waveforms are generated so that the net AC voltage across the dark pixel should be maximized and the net AC voltage across the clear pixel should be minimized. The net DC voltage across any pixel should be zero.

The COM signal represents the time slice for each common, while the SEG contains the pixel data.

The pixel signal (COM-SEG) will have no DC component and it can take only one of the two RMS values. The higher RMS value will create a dark pixel and a lower RMS value will create a clear pixel.

As the number of commons increases, the delta between the two RMS values decreases. The delta represents the maximum contrast that the display can have.

The LCDs can be driven by two types of waveform: Type-A and Type-B. In Type-A waveform, the phase changes within each common type, whereas in Type-B waveform, the phase changes on each frame boundary. Thus, Type-A waveform maintains 0 VDC over a single frame, whereas Type-B waveform takes two frames.

Note 1:	If Sleep has to be executed with LCD Sleep disabled (LCDCON<SLPEN> is '1'), then care must be taken to execute Sleep only when VDC on all the pixels is '0'.
2:	When the LCD clock source is FOSC/256, if Sleep is executed, irrespective of the LCDCON<SLPEN> setting, the LCD immediately goes into Sleep. Thus, take care to see that VDC on all pixels is '0' when Sleep is executed.

Figure 19-8 through Figure 19-18 provide waveforms for static, half-multiplex, 1/3-multiplex and 1/4-multiplex drives for Type-A and Type-B waveforms.

FIGURE 19-8: TYPE-A/TYPE-B WAVEFORMS IN STATIC DRIVE

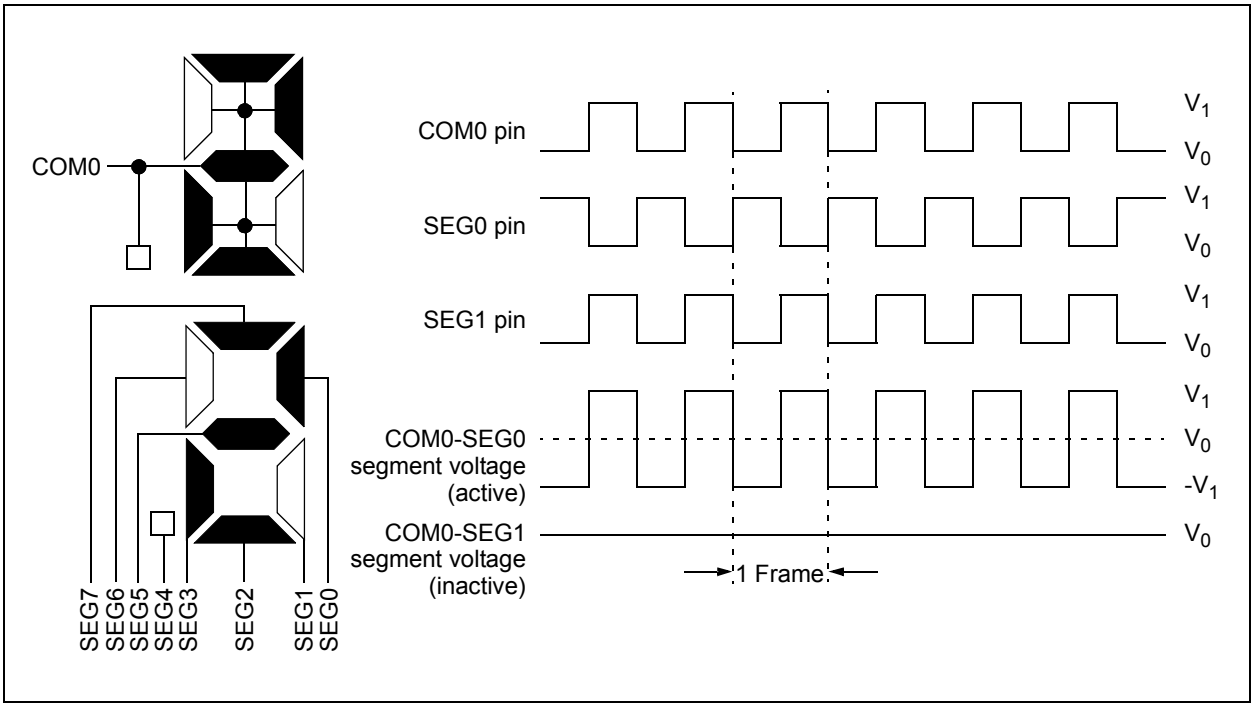
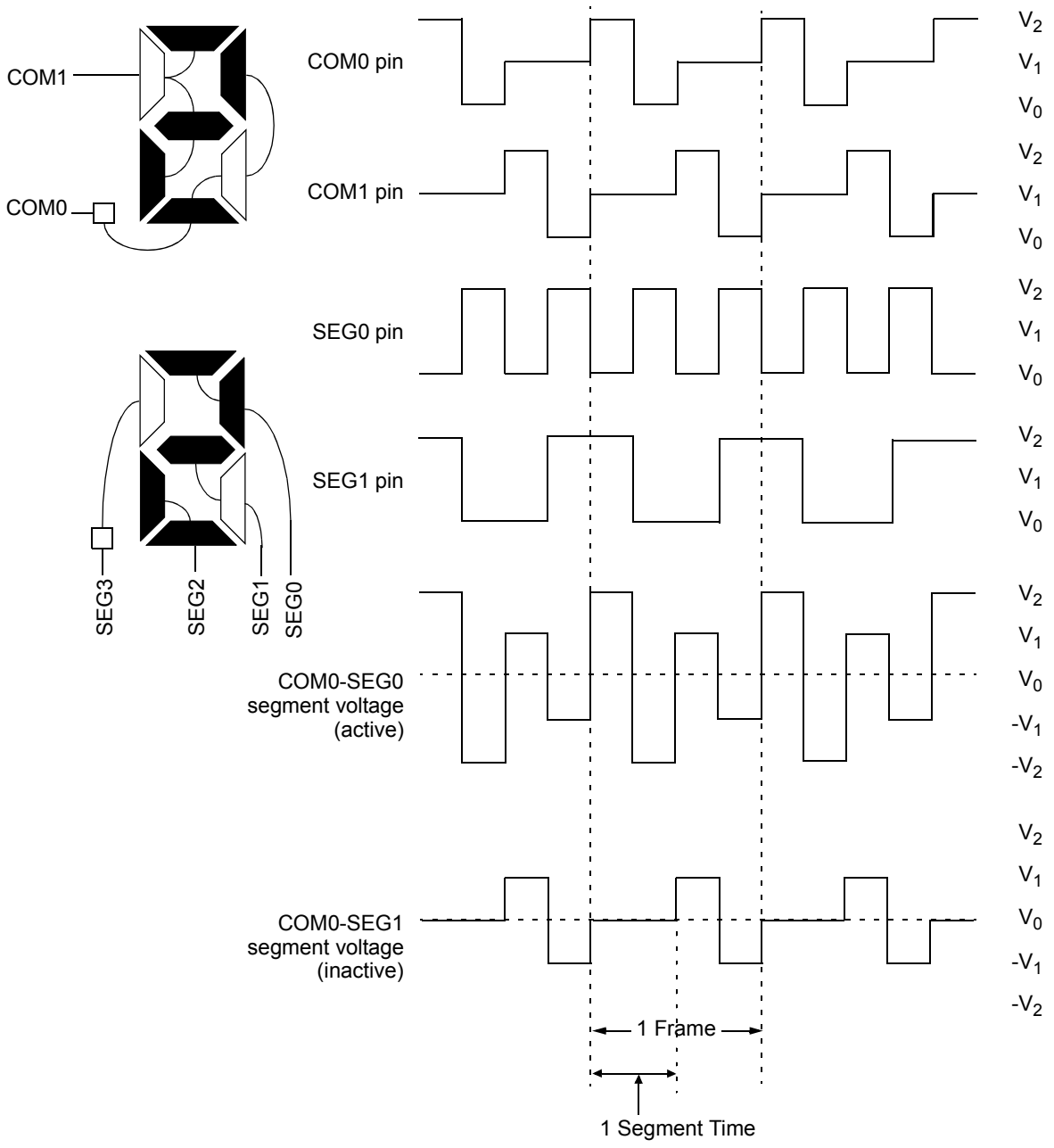
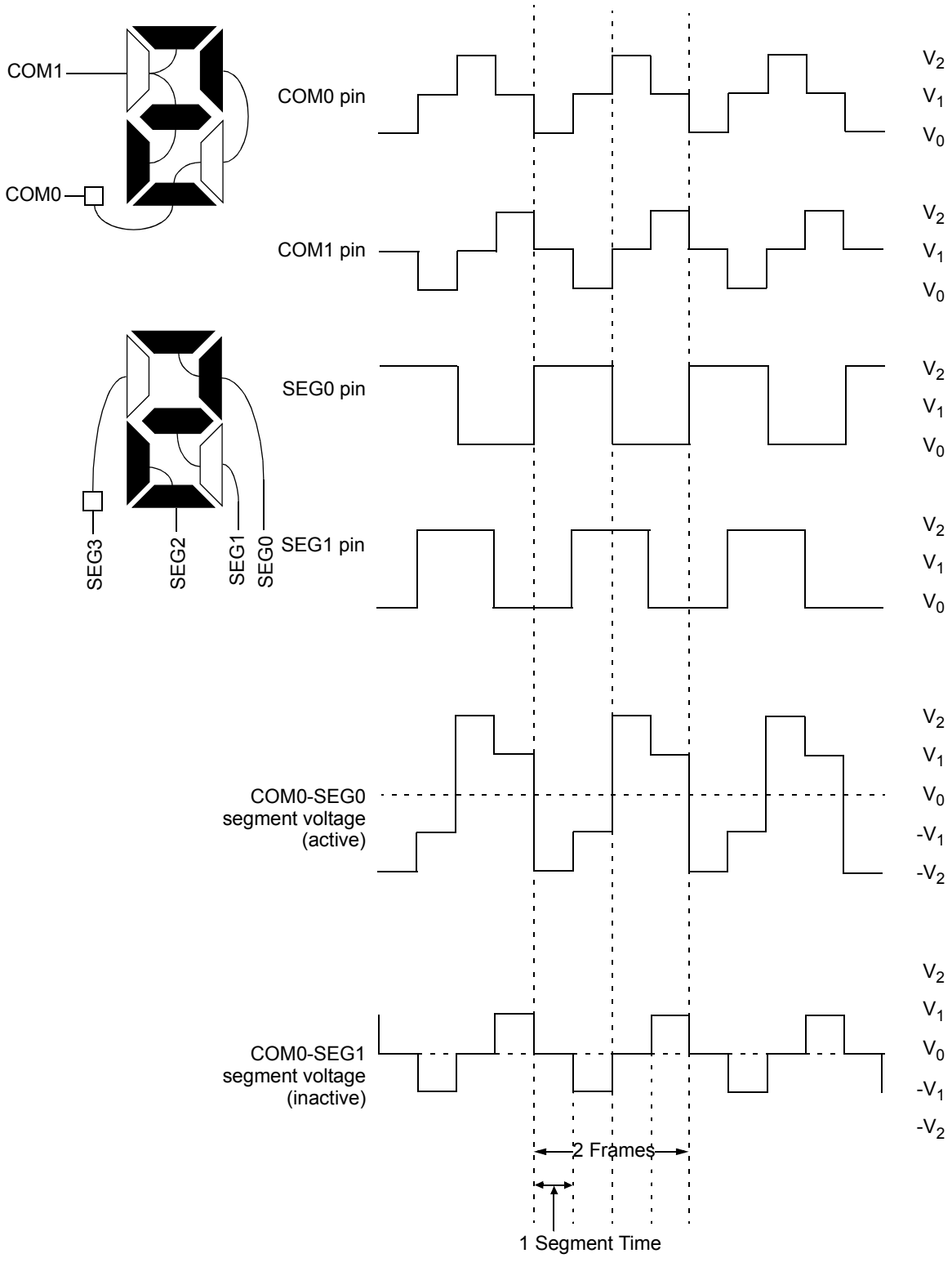


FIGURE 19-9: TYPE-A WAVEFORMS IN 1/2 MUX, 1/2 BIAS DRIVE



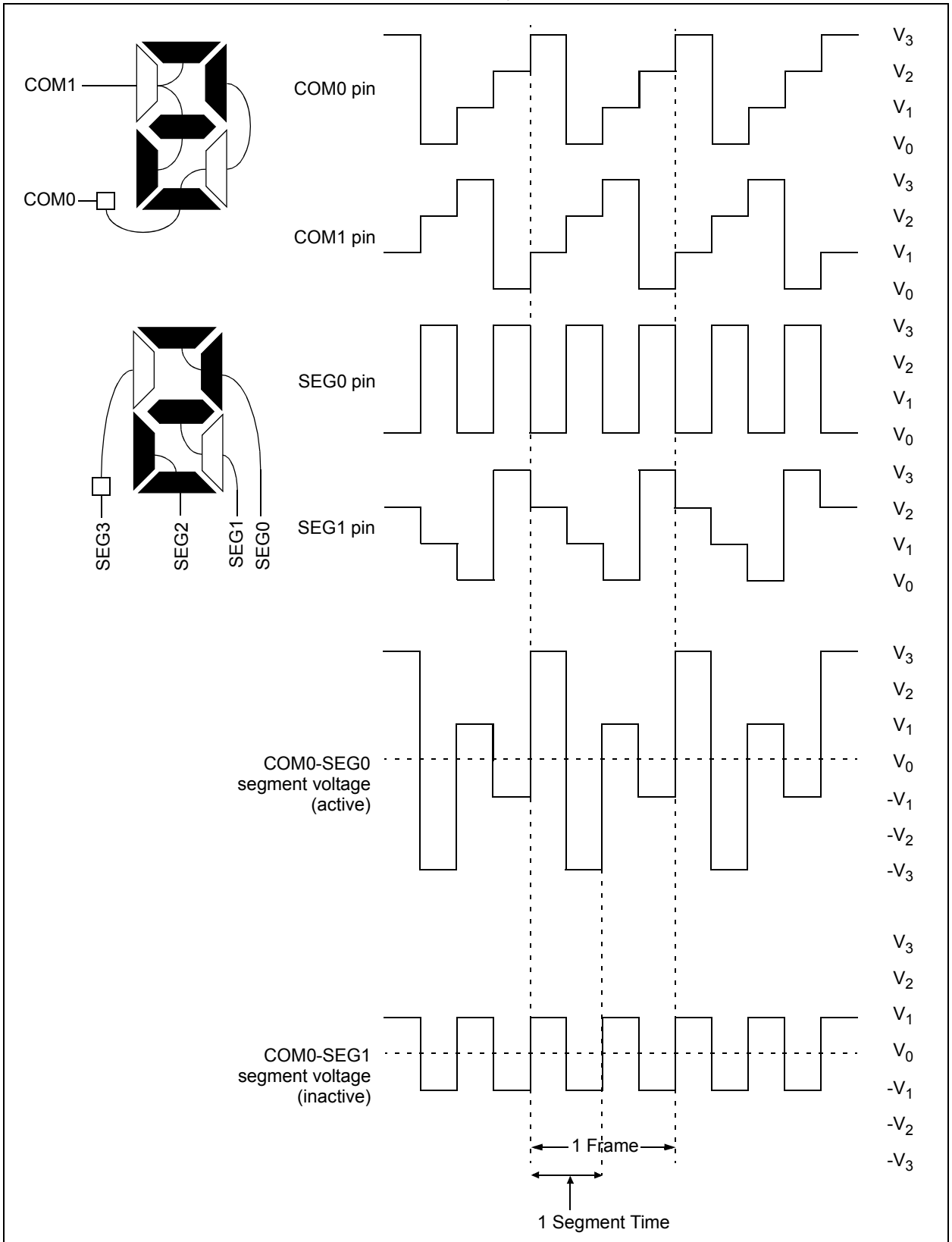
Note: 1 Frame = 2 single segment times.

FIGURE 19-10: TYPE-B WAVEFORMS IN 1/2 MUX, 1/2 BIAS DRIVE



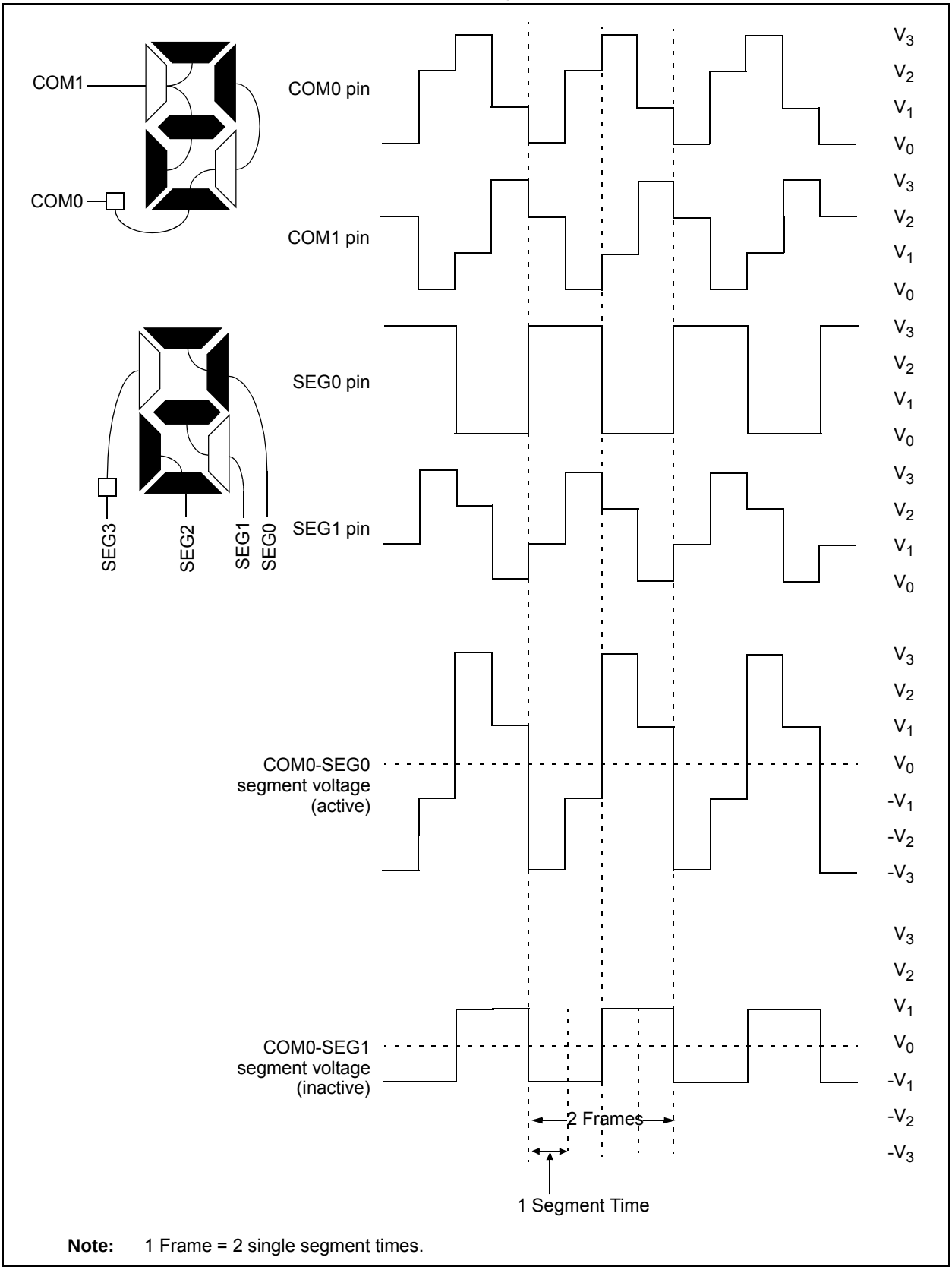
Note: 1 Frame = 2 single segment times.

FIGURE 19-11: TYPE-A WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE



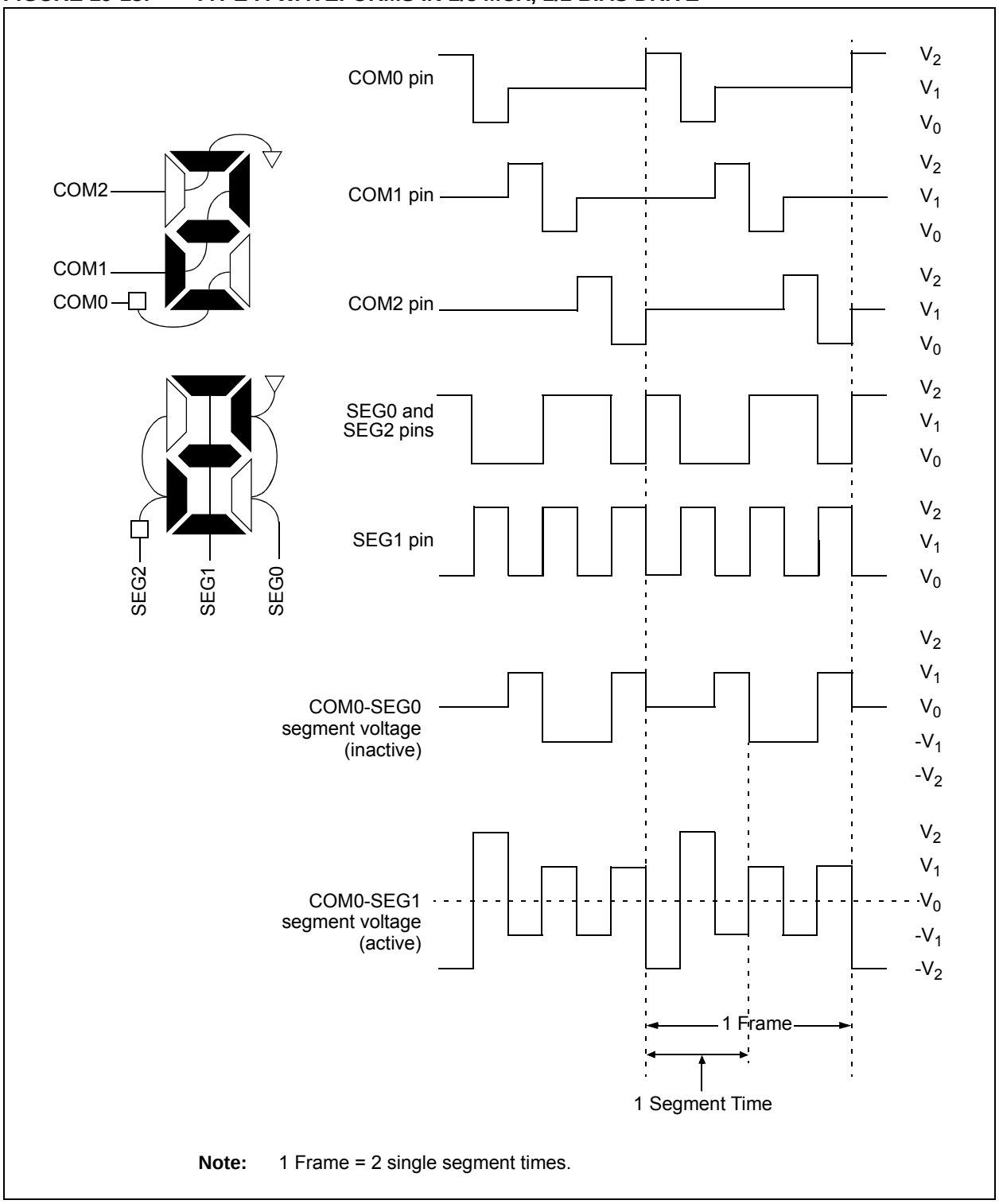
Note: 1 Frame = 2 single segment times.

FIGURE 19-12: TYPE-B WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE



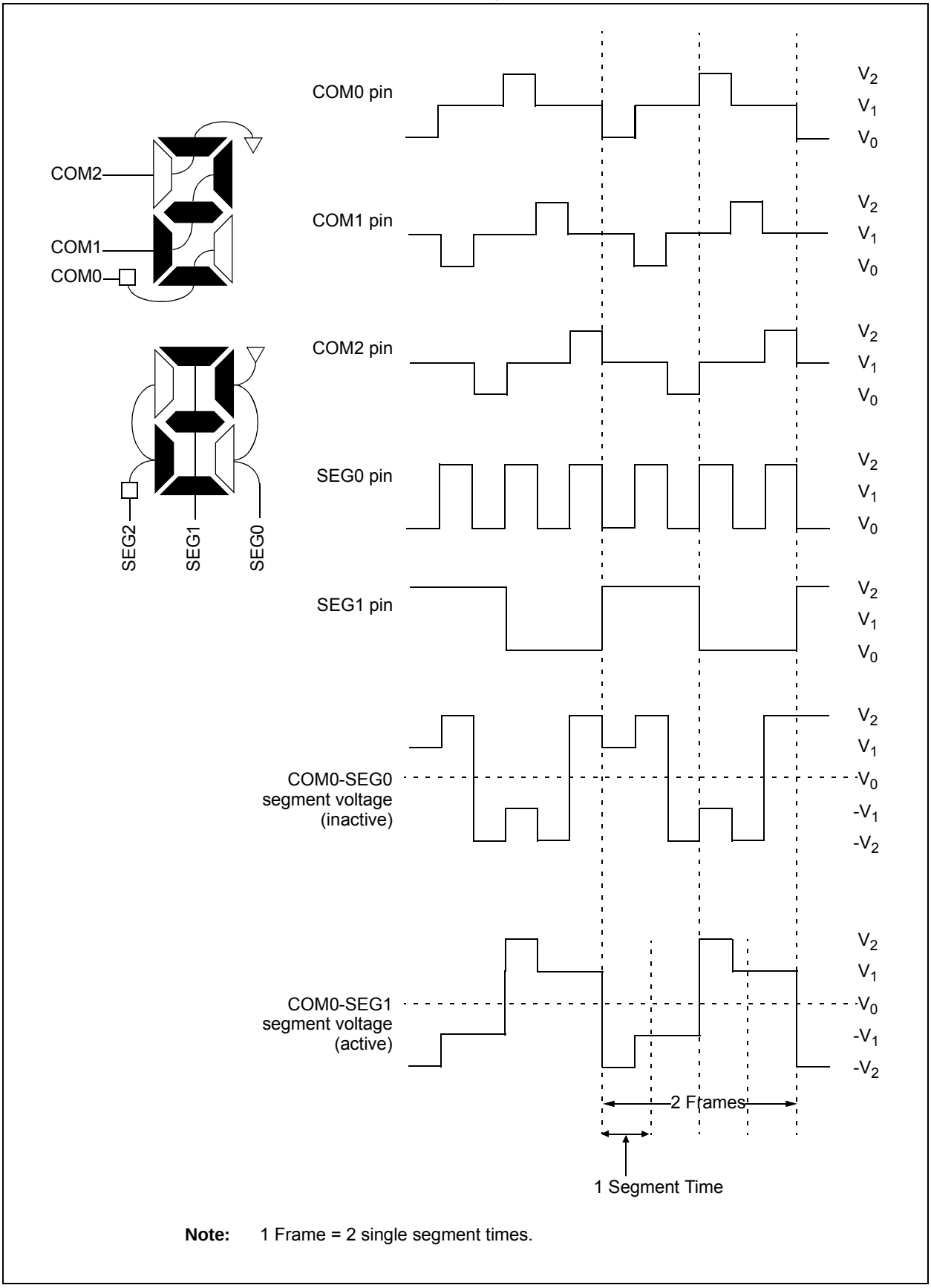
Note: 1 Frame = 2 single segment times.

FIGURE 19-13: TYPE-A WAVEFORMS IN 1/3 MUX, 1/2 BIAS DRIVE



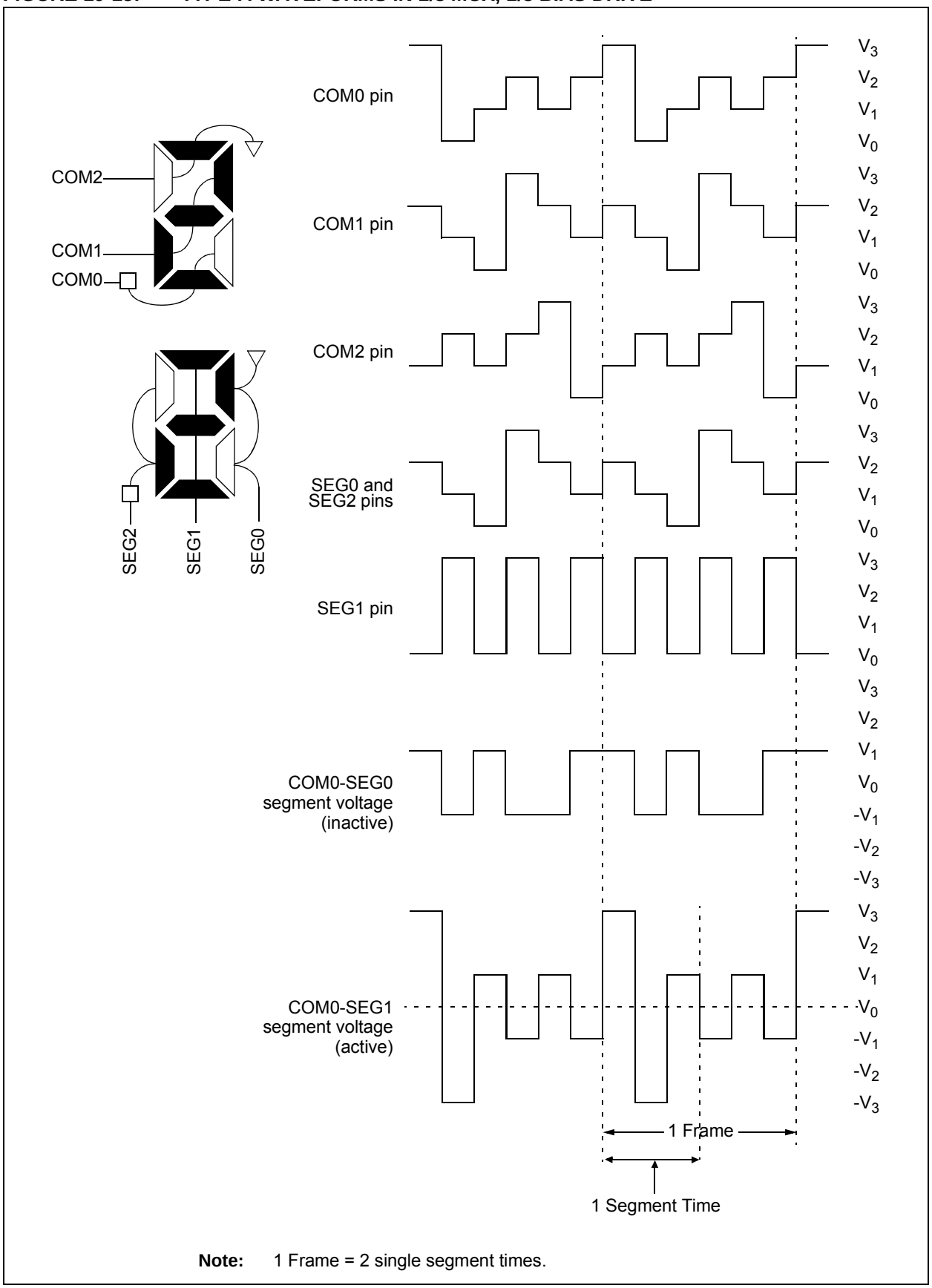
Note: 1 Frame = 2 single segment times.

FIGURE 19-14: TYPE-B WAVEFORMS IN 1/3 MUX, 1/2 BIAS DRIVE



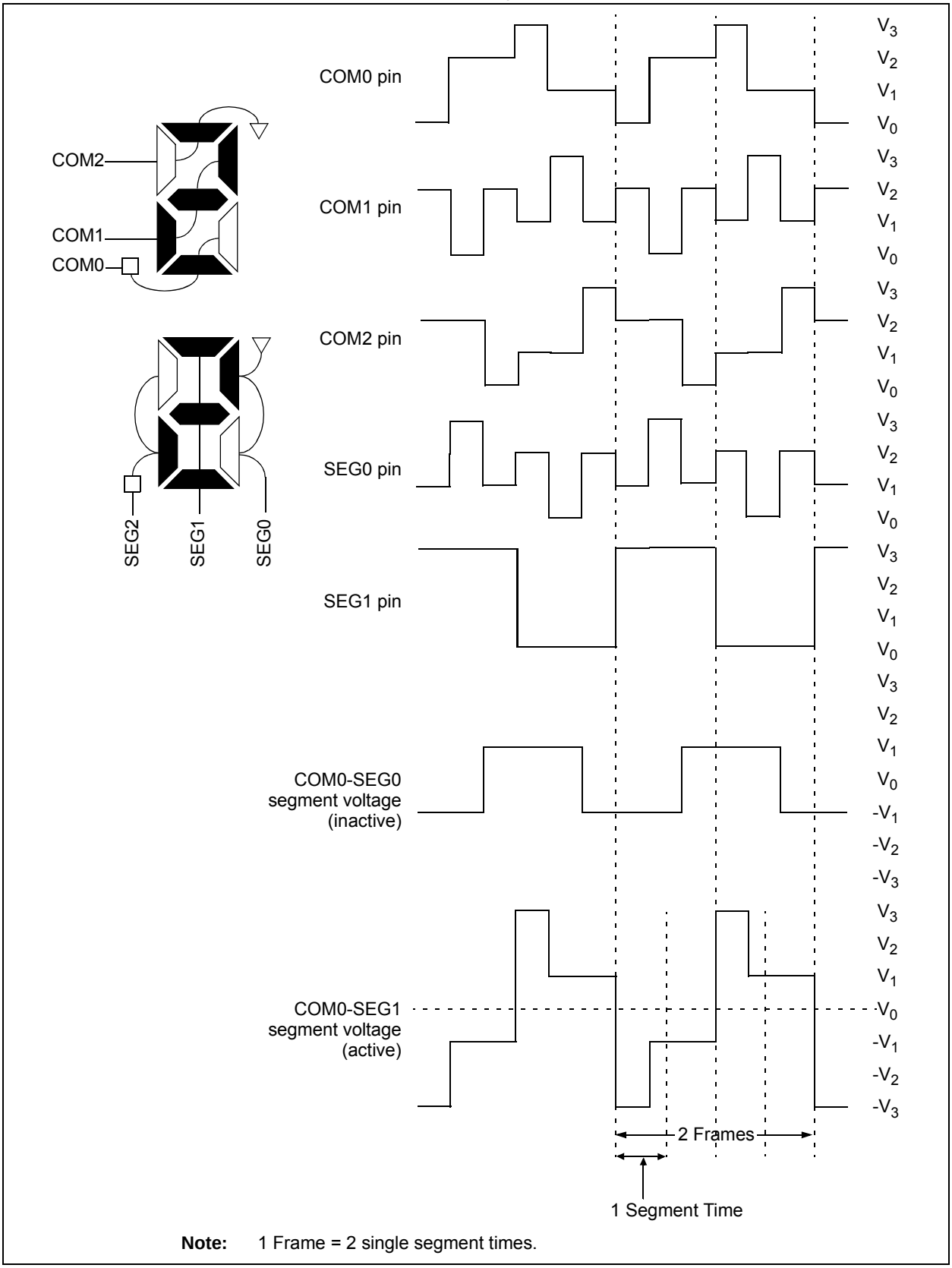
Note: 1 Frame = 2 single segment times.

FIGURE 19-15: TYPE-A WAVEFORMS IN 1/3 MUX, 1/3 BIAS DRIVE



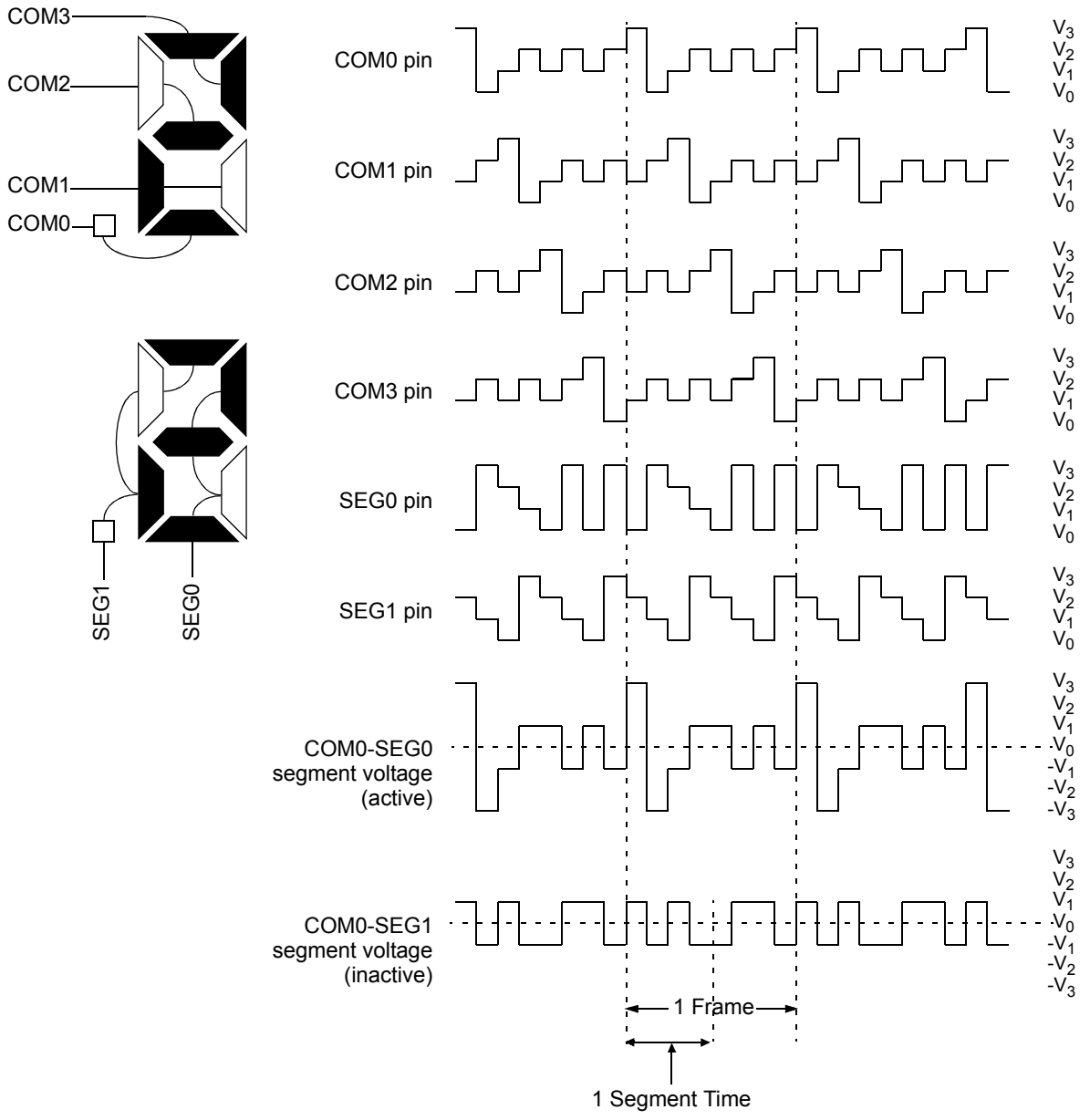
Note: 1 Frame = 2 single segment times.

FIGURE 19-16: TYPE-B WAVEFORMS IN 1/3 MUX, 1/3 BIAS DRIVE



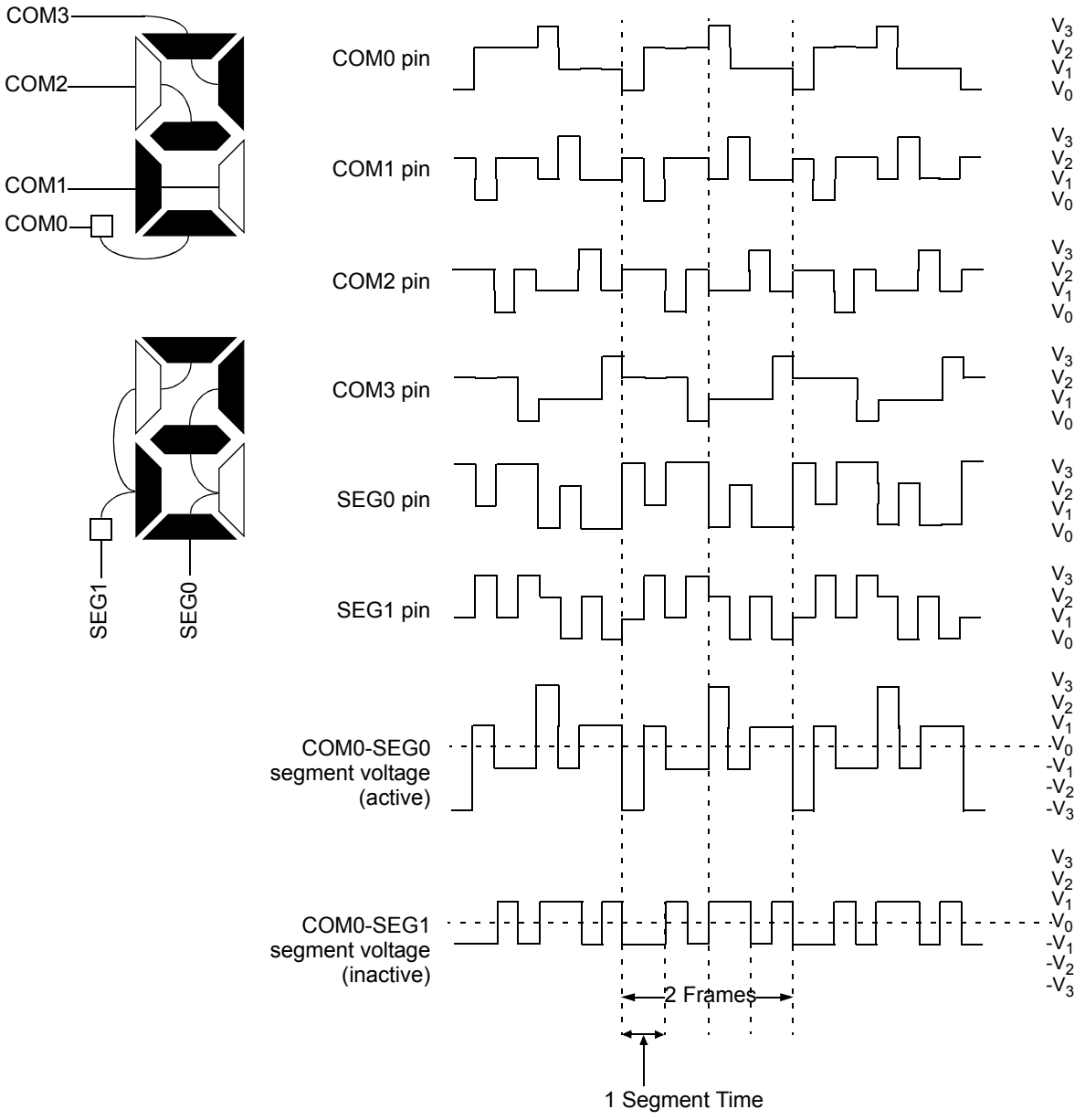
Note: 1 Frame = 2 single segment times.

FIGURE 19-17: TYPE-A WAVEFORMS IN 1/4 MUX, 1/3 BIAS DRIVE



Note: 1 Frame = 2 single segment times.

FIGURE 19-18: TYPE-B WAVEFORMS IN 1/4 MUX, 1/3 BIAS DRIVE



Note: 1 Frame = 2 single segment times.

19.10 LCD Interrupts

The LCD module provides an interrupt in two cases. An interrupt when the LCD controller goes from active to inactive controller. An interrupt also provides unframe boundaries for Type B waveform. The LCD timing generation provides an interrupt that defines the LCD frame timing.

19.10.1 LCD INTERRUPT ON MODULE SHUTDOWN

An LCD interrupt is generated when the module completes shutting down (LCDA goes from '1' to '0').

19.10.2 LCD FRAME INTERRUPTS

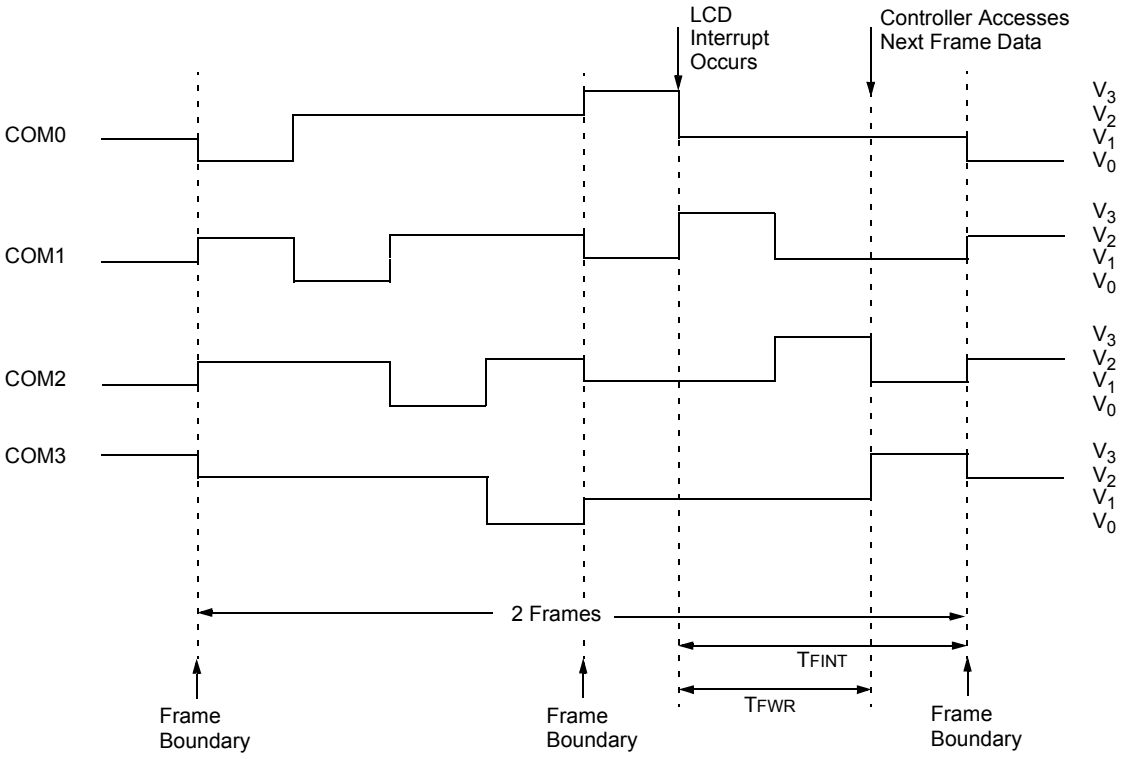
A new frame is defined to begin at the leading edge of the COM0 common signal. The interrupt will be set immediately after the LCD controller completes accessing all pixel data required for a frame. This will occur at a fixed interval before the frame boundary (TFINT), as shown in Figure 19-19. The LCD controller will begin to access data for the next frame within the interval from the interrupt to when the controller begins to access data after the interrupt (TFWR). New data must be written within TFWR, as this is when the LCD controller will begin to access the data for the next frame.

When the LCD driver is running with Type-B waveforms and the LMUX<1:0> bits are not equal to '00' (static drive), there are some additional issues that must be addressed. Since the DC voltage on the pixel takes two frames to maintain zero volts, the pixel data must not change between subsequent frames. If the pixel data were allowed to change, the waveform for the odd frames would not necessarily be the complement of the waveform generated in the even frames and a DC component would be introduced into the panel. Therefore, when using Type-B waveforms, the user must synchronize the LCD pixel updates to occur within a subframe after the frame interrupt.

To correctly sequence writing while in Type-B, the interrupt will only occur on complete phase intervals. If the user attempts to write when the write is disabled, the WERR bit of the LCDCON register is set and the write does not occur.

Note:	The LCD frame interrupt is not generated when the Type-A waveform is selected and when the Type-B with no multiplex (static) is selected.

FIGURE 19-19: WAVEFORMS AND INTERRUPT TIMING IN QUARTER-DUTY CYCLE DRIVE (EXAMPLE – TYPE-B, NON-STATIC)



$T_{FWR} = T_{FRAME}/2*(LMUX<1:0> + 1) + T_{CY}/2$

$T_{FINT} = (T_{FWR}/2 – (2\ T_{CY} + 40\ ns)) \rightarrow \text{minimum} = 1.5(T_{FRAME}/4) – (2\ T_{CY} + 40\ ns)$
$(T_{FWR}/2 – (1\ T_{CY} + 40\ ns)) \rightarrow \text{maximum} = 1.5(T_{FRAME}/4) – (1\ T_{CY} + 40\ ns)$

19.11 Operation During Sleep

The LCD module can operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Setting the SLPEN bit allows the LCD module to go to Sleep. Clearing the SLPEN bit allows the module to continue to operate during Sleep.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will cease all functions and go into a very low-current Consumption mode. The module will stop operation immediately and drive the minimum LCD voltage on both segment and common lines. Figure 19-20 shows this operation.

The LCD module can be configured to operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Clearing SLPEN and correctly configuring the LCD module clock will allow the LCD module to operate during Sleep. Setting SLPEN and correctly executing the LCD module shutdown will disable the LCD module during Sleep and save power.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will immediately cease all functions, drive the outputs to Vss and go into a very low-current mode. The SLEEP instruction should only be executed after the LCD module has been disabled and the current cycle completed, thus ensuring that there are no DC voltages on the glass. To disable the LCD module, clear the LCDEN bit. The LCD module will complete the disabling process after the current frame, clear the LCDA bit and optionally cause an interrupt.

The steps required to properly enter Sleep with the LCD disabled are:

- Clear LCDEN
- Wait for LCDA = 0 either by polling or by interrupt
- Execute SLEEP

If SLPEN = 0 and SLEEP is executed while the LCD module clock source is FOSC/4, then the LCD module will halt with the pin driving the last LCD voltage pattern. Prolonged exposure to a fixed LCD voltage pattern will cause damage to the LCD glass. To prevent LCD glass damage, either perform the proper LCD module shutdown prior to Sleep, or change the LCD module clock to allow the LCD module to continue operation during Sleep.

If a SLEEP instruction is executed and SLPEN = 0 and the LCD module clock is either T1OSC or LFINTOSC, the module will continue to display the current contents of the LCDDATA registers. While in Sleep, the LCD data cannot be changed. If the LCDIE bit is set, the device will wake from Sleep on the next LCD frame boundary. The LCD module current consumption will not decrease in this mode; however, the overall device power consumption will be lower due to the shutdown of the CPU and other peripherals.

Table 19-7 shows the status of the LCD module during a Sleep while using each of the three available clock sources.

Note:	When the LCDEN bit is cleared, the LCD module will be disabled at the completion of frame. At this time, the port pins will revert to digital functionality. To minimize power consumption due to floating digital inputs, the LCD pins should be driven low using the PORT and TRIS registers.

If a SLEEP instruction is executed and SLPEN = 0, the module will continue to display the current contents of the LCDDATA registers. To allow the module to continue operation while in Sleep, the clock source must be either the LFINTOSC or T1OSC external oscillator. While in Sleep, the LCD data cannot be changed. The LCD module current consumption will not decrease in this mode; however, the overall consumption of the device will be lower due to shut down of the core and other peripheral functions.

Table 19-7 shows the status of the LCD module during Sleep while using each of the three available clock sources:

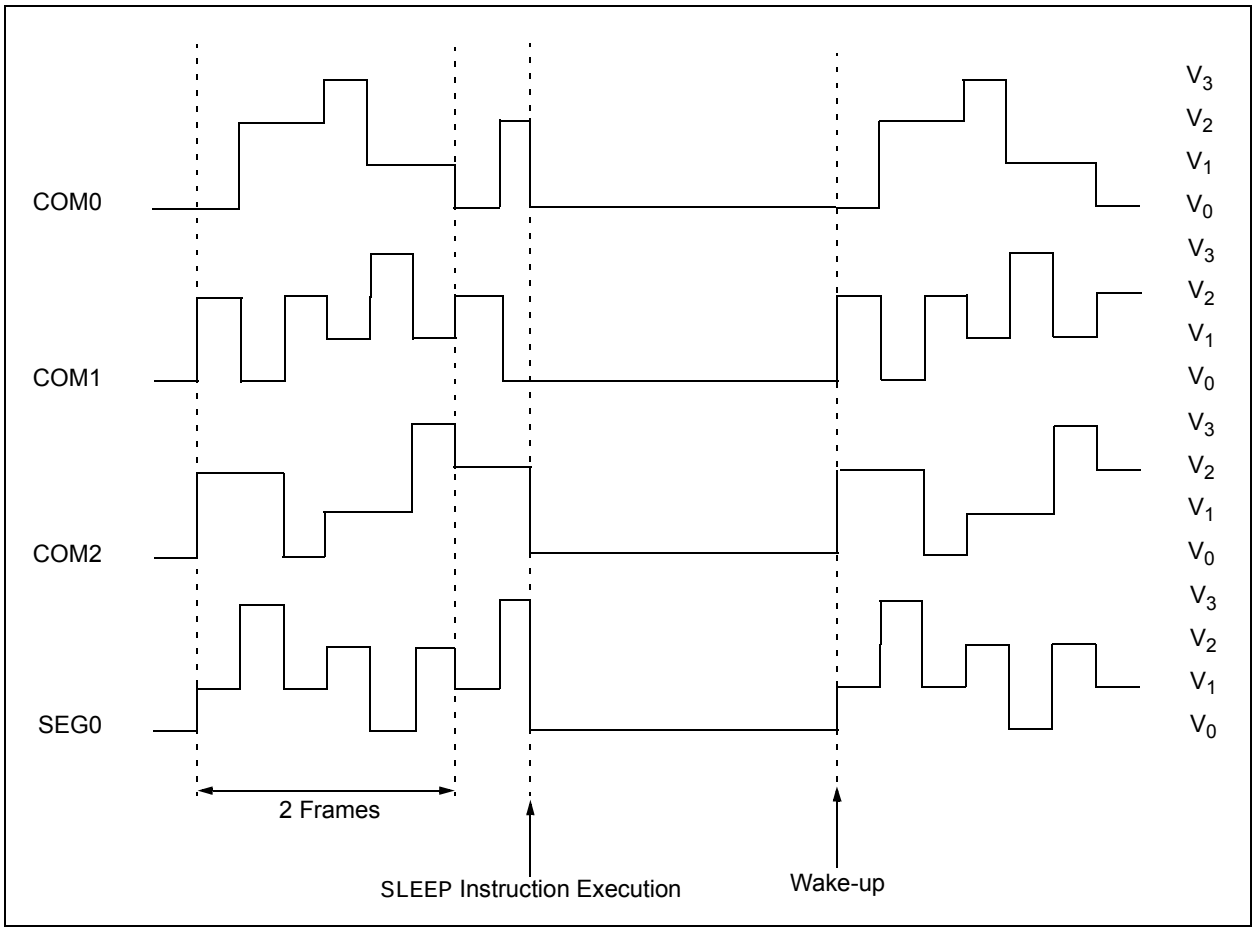
TABLE 19-7: LCD MODULE STATUS DURING SLEEP

Clock Source	SLPEN	Operational During Sleep
T1OSC	0	Yes
	1	No
LFINTOSC	0	Yes
	1	No
FOSC/4	0	No
	1	No

Note:	The LFINTOSC or external T1OSC oscillator must be used to operate the LCD module during Sleep.

If LCD interrupts are being generated (Type-B waveform with a Multiplex mode not static) and LCDIE = 1, the device will awaken from Sleep on the next frame boundary.

FIGURE 19-20: SLEEP ENTRY/EXIT WHEN SLPEN = 1



19.12 Configuring the LCD Module

The following is the sequence of steps to configure the LCD module.

1. Select the frame clock prescale using bits LP<3:0> of the LCDPS register.
2. Configure the appropriate pins to function as segment drivers using the LCDSEn registers.
3. Configure the LCD module for the following using the LCDCON register:
   - Multiplex and Bias mode, bits LMUX<1:0>
   - Timing source, bits CS<1:0>
   - Sleep mode, bit SLPEN
4. Write initial values to pixel data registers, LCDDATA0 through LCDDATA21.
5. Clear LCD Interrupt Flag, LCDIF bit of the PIR2 register and if desired, enable the interrupt by setting bit LCDIE of the PIE2 register.
6. Configure bias voltages by setting the LCDRL, LCDREF and the associated ANSELx registers as needed.
7. Enable the LCD module by setting bit LCDEN of the LCDCON register.

19.13 Disabling the LCD Module

To disable the LCD module, write all '0's to the LCDCON register.

19.14 LCD Current Consumption

When using the LCD module the current consumption consists of the following three factors:

- Oscillator Selection
- LCD Bias Source
- Capacitance of the LCD segments

The current consumption of just the LCD module can be considered negligible compared to these other factors.

19.14.1 OSCILLATOR SELECTION

The current consumed by the clock source selected must be considered when using the LCD module. See **Section 22.0 "Electrical Specifications"** for oscillator current consumption information.

19.14.2 LCD BIAS SOURCE

The LCD bias source, internal or external, can contribute significantly to the current consumption. Use the highest possible resistor values while maintaining contrast to minimize current.

19.14.3 CAPACITANCE OF THE LCD SEGMENTS

The LCD segments which can be modeled as capacitors which must be both charged and discharged every frame. The size of the LCD segment and its technology determines the segment's capacitance.

TABLE 19-8: SUMMARY OF REGISTERS ASSOCIATED WITH LCD OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
LCDCON	LCDEN	SLPEN	WERR	—	CS1	CS0	LMUX<1:0>		173
LCDCST	—	—	—	—	—	LCDCST<2:0>			176
LCDDATA0	SEG7 COM0	SEG6 COM0	SEG5 COM0	SEG4 COM0	SEG3 COM0	SEG2 COM0	SEG1 COM0	SEG0 COM0	177
LCDDATA1	SEG15 COM0	SEG14 COM0	SEG13 COM0	SEG12 COM0	SEG11 COM0	SEG10 COM0	SEG9 COM0	SEG8 COM0	177
LCDDATA2(1)	SEG23 COM0	SEG22 COM0	SEG21 COM0	SEG20 COM0	SEG19 COM0	SEG18 COM0	SEG17 COM0	SEG16 COM0	177
LCDDATA3	SEG7 COM1	SEG6 COM1	SEG5 COM1	SEG4 COM1	SEG3 COM1	SEG2 COM1	SEG1 COM1	SEG0 COM1	177
LCDDATA4	SEG15 COM1	SEG14 COM1	SEG13 COM1	SEG12 COM1	SEG11 COM1	SEG10 COM1	SEG9 COM1	SEG8 COM1	177
LCDDATA5(1)	SEG23 COM1	SEG22 COM1	SEG21 COM1	SEG20 COM1	SEG19 COM1	SEG18 COM1	SEG17 COM1	SEG16 COM1	177
LCDDATA6	SEG7 COM2	SEG6 COM2	SEG5 COM2	SEG4 COM2	SEG3 COM2	SEG2 COM2	SEG1 COM2	SEG0 COM2	177
LCDDATA7	SEG15 COM2	SEG14 COM2	SEG13 COM2	SEG12 COM2	SEG11 COM2	SEG10 COM2	SEG9 COM2	SEG8 COM2	177
LCDDATA8(1)	SEG23 COM2	SEG22 COM2	SEG21 COM2	SEG20 COM2	SEG19 COM2	SEG18 COM2	SEG17 COM2	SEG16 COM2	177
LCDDATA9	SEG7 COM3	SEG6 COM3	SEG5 COM3	SEG4 COM3	SEG3 COM3	SEG2 COM3	SEG1 COM3	SEG0 COM3	177
LCDDATA10	SEG15 COM3	SEG14 COM3	SEG13 COM3	SEG12 COM3	SEG11 COM3	SEG10 COM3	SEG9 COM3	SEG8 COM3	177
LCDDATA11(1)	SEG23 COM3	SEG22 COM3	SEG20 COM3	SEG19 COM3	SEG18 COM3	SEG17 COM3	SEG16 COM3	SEG15 COM3	177
LCDDATA12	—	—	—	SEG28 COM0	SEG27 COM0	SEG26 COM0	SEG25 COM0	SEG24 COM0	177
LCDDATA15	—	—	—	SEG28 COM1	SEG27 COM1	SEG26 COM1	SEG25 COM1	SEG24 COM1	177
LCDDATA18	—	—	—	SEG28 COM2	SEG27 COM2	SEG26 COM2	SEG25 COM2	SEG24 COM2	177
LCDDATA21	—	—	—	SEG28 COM3	SEG27 COM3	SEG26 COM3	SEG25 COM3	SEG24 COM3	177
LCDPS	WFT	BIASMD	LCDA	WA	LP<3:0>				174
LCDREF	LCDIRE	—	LCDIRI	—	VLCD3PE	VLCD2PE	VLCD1PE	—	175
LCDRL	LRLAP<1:0>		LRLBP<1:0>		—	LRLAT<2:0>			184
LCDSE0	SE<7:0>								177
LCDSE1	SE<15:8>								177
LCDSE2	SE<23:16>								177
LCDSE3	—	—	—	SE<28:24>					177
PIE2	—	—	—	—	—	LCDIE	—	—	67
PIR2	—	—	—	—	—	LCDIF	—	—	69
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	139

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the LCD module.

Note 1: PIC16LF1904/7 only.

20.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process, allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- $\overline{MCLR}$/VPP
- VDD
- VSS

In Program/Verify mode the program memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the **"***PIC16F193X/LF193X/PIC16F194X/LF194X/PIC16LF190X Memory Programming Specification***"** (DS41397).

20.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on $\overline{MCLR}$/VPP to VIHH.

20.2 Low-Voltage Programming Entry Mode

The Low-Voltage Programming Entry mode allows the PIC® Flash MCUs to be programmed using VDD only, without high voltage. When the LVP bit of Configuration Words is set to '1', the low-voltage ICSP programming entry is enabled. To disable the Low-Voltage ICSP mode, the LVP bit must be programmed to '0'.

Entry into the Low-Voltage Programming Entry mode requires the following steps:

1. $\overline{MCLR}$ is brought to VIL.
2. A 32-bit key sequence is presented on ICSPDAT, while clocking ICSPCLK.

Once the key sequence is complete, $\overline{MCLR}$ must be held at VIL for as long as Program/Verify mode is to be maintained.

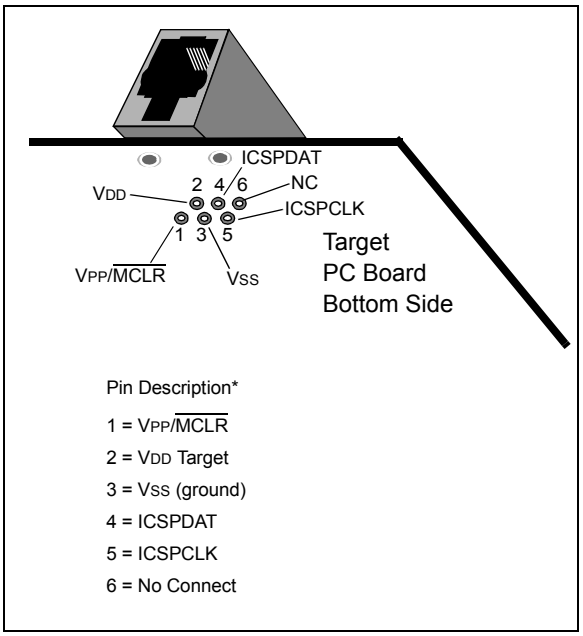
If low-voltage programming is enabled (LVP = 1), the $\overline{MCLR}$ Reset function is automatically enabled and cannot be disabled. See **Section 5.4 "MCLR"** for more information.

The LVP bit can only be reprogrammed to '0' by using the High-Voltage Programming mode.

20.3 Common Programming Interfaces

Connection to a target device is typically done through an ICSP™ header. A commonly found connector on development tools is the RJ-11 in the 6P6C (6-pin, 6 connector) configuration. See Figure 20-1.

FIGURE 20-1: ICD RJ-11 STYLE CONNECTOR INTERFACE

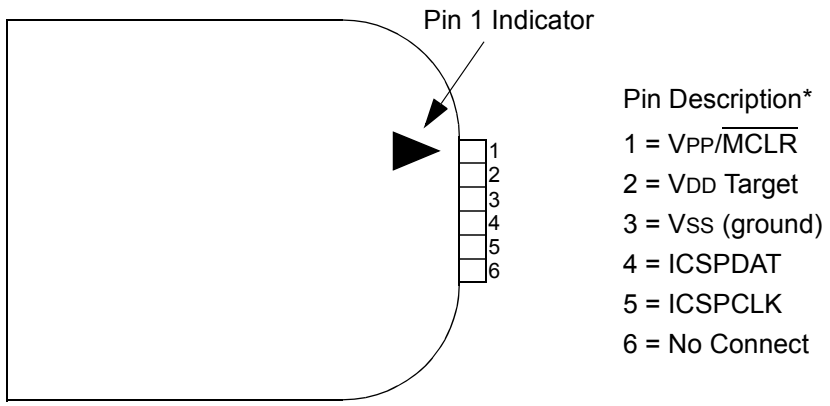


Another connector often found in use with the PICkit™ programmers is a standard 6-pin header with 0.1 inch spacing. Refer to Figure 20-2.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

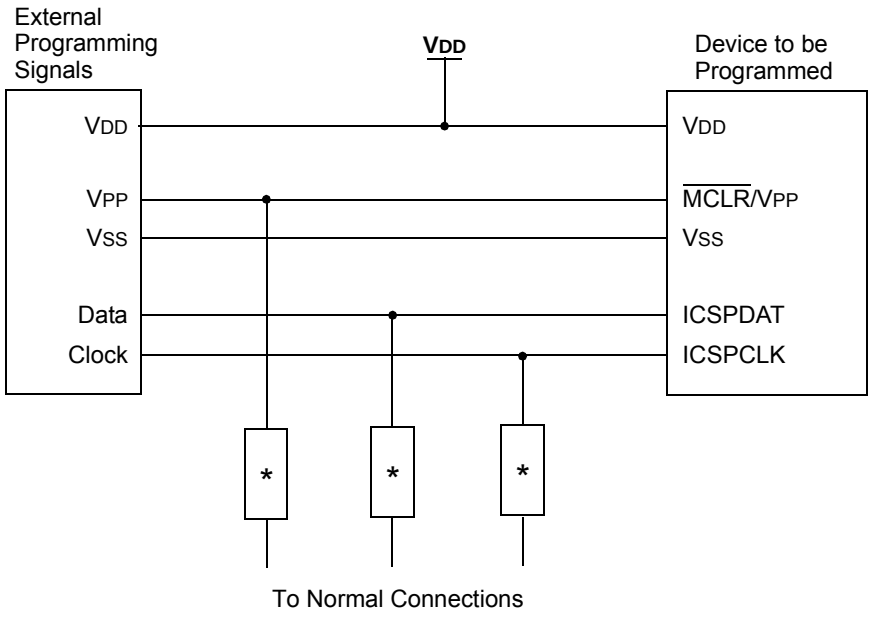
It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 20-3 for more information.

FIGURE 20-2: PICkit™ PROGRAMMER STYLE CONNECTOR INTERFACE



* The 6-pin header (0.100" spacing) accepts 0.025" square pins.

FIGURE 20-3: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

21.0 INSTRUCTION SET SUMMARY

Each PIC16 instruction is a 14-bit word containing the operation code (opcode) and all required operands. The opcodes are broken into three broad categories.

- Byte Oriented
- Bit Oriented
- Literal and Control

The literal and control category contains the most varied instruction word format.

Table 21-3 lists the instructions recognized by the MPASM™ assembler.

All instructions are executed within a single instruction cycle, with the following exceptions, which may take two or three cycles:

- Subroutine takes two cycles (CALL, CALLW)
- Returns from interrupts or subroutines take two cycles (RETURN, RETLW, RETFIE)
- Program branching takes two cycles (GOTO, BRA, BRW, BTFSS, BTFSC, DECFSZ, INCSFZ)
- One additional instruction cycle will be used when any instruction references an indirect file register and the file select register is pointing to program memory.

One instruction cycle consists of 4 oscillator cycles; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution rate of 1 MHz.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

21.1 Read-Modify-Write Operations

Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

TABLE 21-1: OPCODE FIELD DESCRIPTIONS

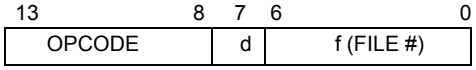
Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
n	FSR or INDF number. (0-1)
mm	Pre-post increment-decrement mode selection

TABLE 21-2: ABBREVIATION DESCRIPTIONS

Field	Description
PC	Program Counter
$\overline{TO}$	Time-out bit
C	Carry bit
DC	Digit carry bit
Z	Zero bit
$\overline{PD}$	Power-down bit

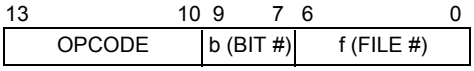
FIGURE 21-1: GENERAL FORMAT FOR INSTRUCTIONS

Byte-oriented file register operations



d = 0 for destination W
d = 1 for destination f
f = 7-bit file register address

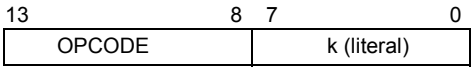
Bit-oriented file register operations



b = 3-bit bit address
f = 7-bit file register address

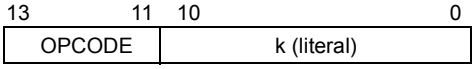
Literal and control operations

General



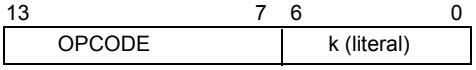
k = 8-bit immediate value

CALL and GOTO instructions only



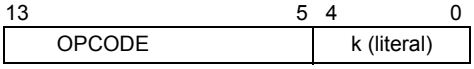
k = 11-bit immediate value

MOVLP instruction only



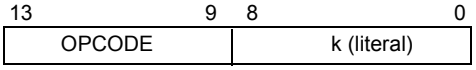
k = 7-bit immediate value

MOVLB instruction only



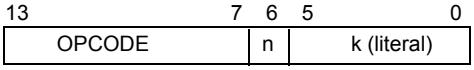
k = 5-bit immediate value

BRA instruction only



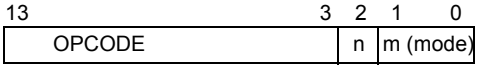
k = 9-bit immediate value

FSR Offset instructions



n = appropriate FSR
k = 6-bit immediate value

FSR Increment instructions



n = appropriate FSR
m = 2-bit mode value

OPCODE only

TABLE 21-3: PIC16LF1904/6/7 ENHANCED INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C, DC, Z	2
ADDWFC	f, d	Add with Carry W and f	1	11	1101	dfff	ffff	C, DC, Z	2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	2
ASRF	f, d	Arithmetic Right Shift	1	11	0111	dfff	ffff	C, Z	2
LSLF	f, d	Logical Left Shift	1	11	0101	dfff	ffff	C, Z	2
LSRF	f, d	Logical Right Shift	1	11	0110	dfff	ffff	C, Z	2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	–	Clear W	1	00	0001	0000	00xx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	2
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	2
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	2
MOVWF	f	Move W to f	1	00	0000	1fff	ffff		2
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C, DC, Z	2
SUBWFB	f, d	Subtract with Borrow W from f	1	11	1011	dfff	ffff	C, DC, Z	2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	2
BYTE ORIENTED SKIP OPERATIONS									
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1, 2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1, 2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		2
BIT-ORIENTED SKIP OPERATIONS									
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		1, 2
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		1, 2
LITERAL OPERATIONS									
ADDLW	k	Add literal and W	1	11	1110	kkkk	kkkk	C, DC, Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLB	k	Move literal to BSR	1	00	0000	001k	kkkk		
MOVLP	k	Move literal to PCLATH	1	11	0001	1kkk	kkkk		
MOVLW	k	Move literal to W	1	11	0000	kkkk	kkkk		
SUBLW	k	Subtract W from literal	1	11	1100	kkkk	kkkk	C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

TABLE 21-3: PIC16LF1904/6/7 ENHANCED INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
CONTROL OPERATIONS						
BRA	k	Relative Branch	2	11 001k kkkk kkkk		
BRW	–	Relative Branch with W	2	00 0000 0000 1011		
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk		
CALLW	–	Call Subroutine with W	2	00 0000 0000 1010		
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
RETFIE	k	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 0100 kkkk kkkk		
RETURN	–	Return from Subroutine	2	00 0000 0000 1000		
INHERENT OPERATIONS						
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000		
OPTION	–	Load OPTION_REG register with W	1	00 0000 0110 0010		
RESET	–	Software device Reset	1	00 0000 0000 0001		
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff		
C-COMPILER OPTIMIZED						
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk kkkk	Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 1nmm		**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk kkkk		**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

21.2 Instruction Descriptions

ADDFSR — Add Literal to FSRn

Syntax:	[*label*] ADDFSR FSRn, k
Operands:	-32 ≤ k ≤ 31 n ∈ [0, 1]
Operation:	FSR(n) + k → FSR(n)
Status Affected:	None
Description:	The signed 6-bit literal ‘k’ is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h - FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

ADDLW — Add literal and W

Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal ‘k’ and the result is placed in the W register.

ADDWF — Add W and f

Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

ADDWFC — ADD W and CARRY bit to f

Syntax:	[*label*] ADDWFC f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) + (C) → dest
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location ‘f’. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed in data memory location ‘f’.

ANDLW — AND literal with W

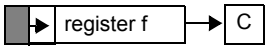
Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND’ed with the 8-bit literal ‘k’. The result is placed in the W register.

ANDWF — AND W with f

Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

ASRF — Arithmetic Right Shift

Syntax:	[*label*] ASRF f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f<7>)→ dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register ‘f’ are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’.



BCF **Bit Clear f**

Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BRA **Relative Branch**

Syntax:	[*label*] BRA label [*label*] BRA $+k
Operands:	-256 ≤ label - PC + 1 ≤ 255 -256 ≤ k ≤ 255
Operation:	(PC) + 1 + k → PC
Status Affected:	None
Description:	Add the signed 9-bit literal 'k' to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + k. This instruction is a 2-cycle instruction. This branch has a limited range.

BRW **Relative Branch with W**

Syntax:	[*label*] BRW
Operands:	None
Operation:	(PC) + (W) → PC
Status Affected:	None
Description:	Add the contents of W (unsigned) to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + (W). This instruction is a 2-cycle instruction.

BSF **Bit Set f**

Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSC **Bit Test f, Skip if Clear**

Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

BTFSS **Bit Test f, Skip if Set**

Syntax:	[*label*] BTFSS f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.

CALL **Call Subroutine**

Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<6:3>) → PC<14:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The 11-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a 2-cycle instruction.

CALLW **Subroutine Call With W**

Syntax:	[*label*] CALLW
Operands:	None
Operation:	(PC) +1 → TOS, (W) → PC<7:0>, (PCLATH<6:0>) → PC<14:8>
Status Affected:	None
Description:	Subroutine call with W. First, the return address (PC + 1) is pushed onto the return stack. Then, the contents of W is loaded into PC<7:0>, and the contents of PCLATH into PC<14:8>. CALLW is a 2-cycle instruction.

CLRF **Clear f**

Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register ‘f’ are cleared and the Z bit is set.

CLRW **Clear W**

Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT **Clear Watchdog Timer**

Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF **Complement f**

Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(\bar{f}) \rightarrow$ (destination)
Status Affected:	Z
Description:	The contents of register ‘f’ are complemented. If ‘d’ is ‘0’, the result is stored in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

DECF **Decrement f**

Syntax:	[*label*] DECF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

DECFSZ **Decrement f, Skip if 0**

Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.

GOTO **Unconditional Branch**

Syntax:	[*label*] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	k → PC<10:0> PCLATH<6:3> → PC<14:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

INCF **Increment f**

Syntax:	[*label*] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

INCFSZ **Increment f, Skip if 0**

Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

IORLW **Inclusive OR literal with W**

Syntax:	[*label*] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.

IORWF **Inclusive OR W with f**

Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .OR. (f) → (destination)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

LSLF **Logical Left Shift**

Syntax: [*label*] LSLF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<7>) → C
(f<6:0>) → dest<7:1>
0 → dest<0>

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the left through the Carry flag. A '0' is shifted into the LSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

LSRF **Logical Right Shift**

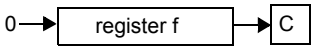
Syntax: [*label*] LSRF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: 0 → dest<7>
(f<7:1>) → dest<6:0>,
(f<0>) → C,

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the right through the Carry flag. A '0' is shifted into the MSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Description: The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:

```
MOVF    FSR, 0
```

After Instruction
W = value in FSR register
Z = 1

MOVIW **Move INDFn to W**

Syntax: [*label*] MOVIW ++FSRn
[*label*] MOVIW --FSRn
[*label*] MOVIW FSRn++
[*label*] MOVIW FSRn--
[*label*] MOVIW k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: INDFn → W
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)
- Unchanged

Status Affected: Z

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

MOVLB **Move literal to BSR**

Syntax: [*label*] MOVLB k

Operands: 0 ≤ k ≤ 15

Operation: k → BSR

Status Affected: None

Description: The 5-bit literal 'k' is loaded into the Bank Select Register (BSR).

MOVLP **Move literal to PCLATH**

Syntax: [*label*] MOVLP k

Operands: 0 ≤ k ≤ 127

Operation: k → PCLATH

Status Affected: None

Description: The 7-bit literal 'k' is loaded into the PCLATH register.

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W)

Status Affected: None

Description: The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 127

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION_REG
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

MOVWI **Move W to INDFn**

Syntax: [*label*] MOVWI ++FSRn
[*label*] MOVWI --FSRn
[*label*] MOVWI FSRn++
[*label*] MOVWI FSRn--
[*label*] MOVWI k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: W → INDFn
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)

Unchanged

Status Affected: None

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

The increment/decrement operation on FSRn WILL NOT affect any Status bits.

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Description: No operation.

Words: 1

Cycles: 1

Example:
```
NOP
```

OPTION **Load OPTION_REG Register with W**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION_REG

Status Affected: None

Description: Move data from W register to OPTION_REG register.

Words: 1

Cycles: 1

Example:
```
OPTION
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

RESET **Software Reset**

Syntax: [*label*] RESET

Operands: None

Operation: Execute a device Reset. Resets the $\overline{RI}$ flag of the PCON register.

Status Affected: None

Description: This instruction provides a way to execute a hardware Reset by software.

RETFIE **Return from Interrupt**

Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None
Description:	Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a 2-cycle instruction.
Words:	1
Cycles:	2
Example:	`RETFIE` After Interrupt PC = TOS GIE = 1

RETLW **Return with literal in W**

Syntax:	[*label*] RETLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the 8-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.
Words:	1
Cycles:	2

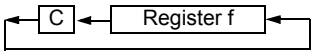
Example:	`CALL TABLE;W contains table`
	`;offset value`
	`;W now has table value`
	`TABLE`
	`ADDWF PC ;W = offset`
	`RETLW k1 ;Begin table`
	`RETLW k2 ;`
	`RETLW kn ; End of table`
	Before Instruction
	W = 0x07
	After Instruction
	W = value of k8

RETURN **Return from Subroutine**

Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.

RLF **Rotate Left f through Carry**

Syntax:	[*label*] RLF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	See description below
Status Affected:	C
Description:	The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	`RLF REG1,0` Before Instruction REG1 = 1110 0110 C = 0 After Instruction REG1 = 1110 0110 W = 1100 1100 C = 1



RRF **Rotate Right f through Carry**

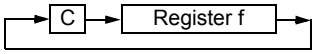
Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.



SLEEP **Enter Sleep mode**

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: The power-down Status bit, $\overline{PD}$ is cleared. Time-out Status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into Sleep mode with the oscillator stopped.

SUBLW **Subtract W from literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (2's complement method) from the 8-bit literal 'k'. The result is placed in the W register.

C = 0	W > k
C = 1	W ≤ k
DC = 0	W<3:0> > k<3:0>
DC = 1	W<3:0> ≤ k<3:0>

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f.

C = 0	W > f
C = 1	W ≤ f
DC = 0	W<3:0> > f<3:0>
DC = 1	W<3:0> ≤ f<3:0>

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) – (W) – ($\overline{B}$) → dest

Status Affected: C, DC, Z

Description: Subtract W and the BORROW flag (CARRY) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

SWAPF **Swap Nibbles in f**

Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (destination<7:4>), (f<7:4>) → (destination<3:0>)
Status Affected:	None
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in register 'f'.

TRIS **Load TRIS Register with W**

Syntax:	[*label*] TRIS f
Operands:	$5 \le f \le 7$
Operation:	(W) → TRIS register 'f'
Status Affected:	None
Description:	Move data from W register to TRIS register. When 'f' = 5, TRISA is loaded. When 'f' = 6, TRISB is loaded. When 'f' = 7, TRISC is loaded.

XORLW **Exclusive OR literal with W**

Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the 8-bit literal 'k'. The result is placed in the W register.

XORWF **Exclusive OR W with f**

Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

NOTES:

22.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on pins with respect to V_{SS}
- on V_{DD} ..... -0.3V to +4.0V
- on $\overline{MCLR}$ ..... -0.3V to +9.0V
- on all other pins ..... -0.3V to (V_{DD} + 0.3V)

Total power dissipation(1) ..... 800 mW
Maximum current
- out of V_{SS} pin
  - -40°C ≤ T_A ≤ +85°C for industrial ..... 300 mA
  - -40°C ≤ T_A ≤ +125°C for extended ..... 95 mA
- into V_{DD} pin
  - -40°C ≤ T_A ≤ +85°C for industrial ..... 250 mA
  - -40°C ≤ T_A ≤ +125°C for extended ..... 70 mA

Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA
Maximum output current
- sunk by any I/O pin ..... 25 mA
- sourced by any I/O pin ..... 25 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

22.1 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: $V_{DDMIN} \le V_{DD} \le V_{DDMAX}$
Operating Temperature: $T_{A\_MIN} \le T_A \le T_{A\_MAX}$

V_{DD} — Operating Supply Voltage(2)

- V_{DDMIN} (Fosc ≤ 16 MHz) ..... +1.8V
- V_{DDMIN} (Fosc ≤ 20 MHz) ..... +2.3V
- V_{DDMAX} ..... +3.6V

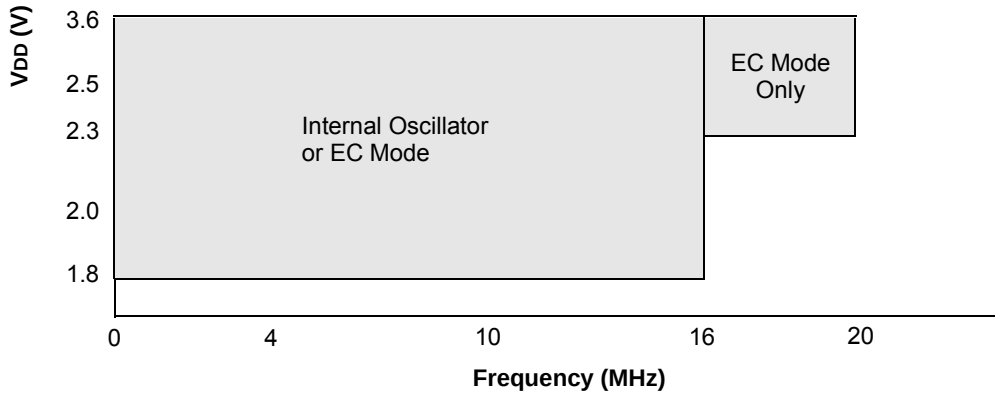
T_A — Operating Ambient Temperature Range

Industrial Temperature
- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +85°C

Extended Temperature
- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +125°C

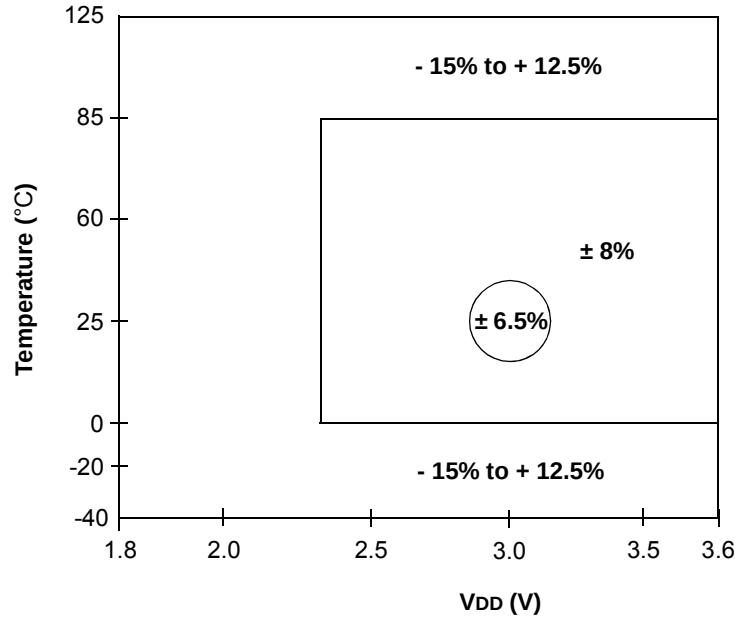
Note 1: Maximum current rating requires even load distribution across I/O pins. Maximum current rating may be limited by the device package power dissipation characterizations, see **Section TABLE 22-6: “Thermal Considerations”** to calculate device specifications.
2: See Parameter D001, DS Characteristics: Supply Voltage.

FIGURE 22-1: VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.
2: Refer to Table 22-7 for each Oscillator mode's supported frequencies.

FIGURE 22-2: HFINTOSC FREQUENCY ACCURACY OVER DEVICE VDD AND TEMPERATURE



22.2 DC Characteristics

TABLE 22-1: SUPPLY VOLTAGE

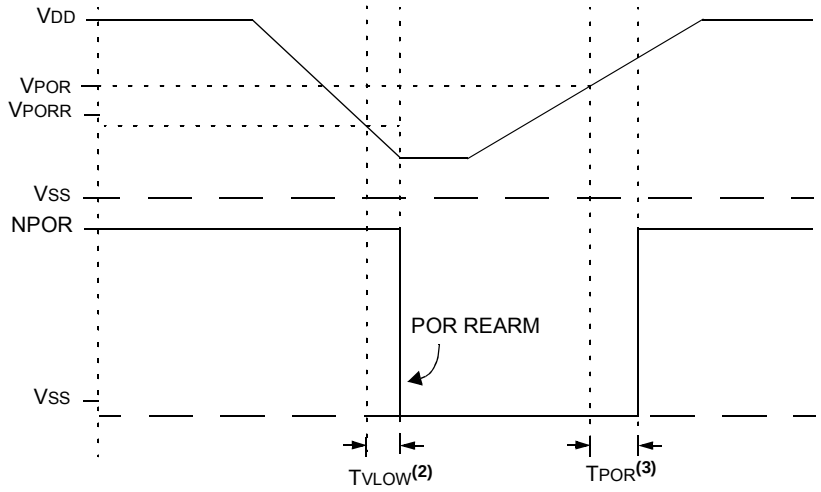
PIC16LF1904/6/7			Standard Operating Conditions (unless otherwise stated)				
Param. No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD		1.8 2.3	— —	3.6 3.6	V V	FOSC ≤ 16 MHz FOSC ≤ 20 MHz (EC mode only)
D002*	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	Device in Sleep mode
D002A*	VPOR*	**Power-on Reset Release Voltage**	1.54	1.64	1.74	V	
D002B*	VPORR*	**Power-on Reset Rearm Voltage**	—	1.7	—	V	Device in Sleep mode
D003	VADFVR	**Fixed Voltage Reference Voltage for ADC, Initial Accuracy**	6 7 7 8	— — — —	4 4 6 6	%	1.024V, VDD ≥ 1.8V, 85°C 1.024V, VDD ≥ 1.8V, 125°C 2.048V, VDD ≥ 2.5V, 85°C 2.048V, VDD ≥ 2.5V, 125°C
D003A	VCDAFVR	**Fixed Voltage Reference Voltage for Comparator and DAC, Initial Accuracy**	7 8 8 9	— — — —	5 5 7 7	%	1.024V, VDD ≥ 1.8V, 85°C 1.024V, VDD ≥ 1.8V, 125°C 2.048V, VDD ≥ 2.5V, 85°C 2.048V, VDD ≥ 2.5V, 125°C
D003B	VLCDFVR	**Fixed Voltage Reference Voltage for LCD Bias, Initial Accuracy**	9 9.5	— —	9 9	%	3.072V, VDD ≥ 3.6V, 85°C 3.072V, VDD ≥ 3.6V, 125°C
D003C*	TCVFVR	**Temperature Coefficient, Fixed Voltage Reference**	—	-130	—	ppm/°C	
D003D*	ΔVFVR/ ΔVIN	**Line Regulation, Fixed Voltage Reference**	—	0.270	—	%/V	
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 5.1 "Power-on Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

FIGURE 22-3: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.

2: TPOR 1 μs typical.

3: TVLOW 2.7 μs typical.

TABLE 22-2: SUPPLY CURRENT (I_{DD})(1,2)

PIC16LF1904/6/7			Standard Operating Conditions (unless otherwise stated)				
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
	Supply Current (I_{DD})(1, 2)						
D010		—	58	75	µA	1.8	F_{OSC} = 1 MHz EC Oscillator mode High Power mode
		—	115	140	µA	3.0	
		—	133	176	µA	3.6	
D011		—	130	200	µA	1.8	F_{OSC} = 4 MHz EC Oscillator mode High Power mode
		—	245	300	µA	3.0	
		—	290	350	µA	3.6	
D012		—	218	275	µA	1.8	F_{OSC} = 500 kHz HFINTOSC mode
		—	283	375	µA	3.0	
		—	314	395	µA	3.6	
D013		—	233	325	µA	1.8	F_{OSC} = 1 MHz HFINTOSC mode
		—	309	425	µA	3.0	
		—	347	475	µA	3.6	
D014		—	305	360	µA	1.8	F_{OSC} = 4 MHz HFINTOSC mode
		—	433	520	µA	3.0	
		—	500	600	µA	3.6	
D015		—	395	480	µA	1.8	F_{OSC} = 8 MHz HFINTOSC mode
		—	600	720	µA	3.0	
		—	700	850	µA	3.6	
D016		—	567	670	µA	1.8	F_{OSC} = 16 MHz HFINTOSC mode
		—	915	1100	µA	3.0	
		—	1087	1300	µA	3.6	
D017		—	2.7	7.2	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +125°C
		—	4.5	9.7	µA	3.0	
		—	5.2	12.0	µA	3.6	
D017A		—	2.7	6.5	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +85°C
		—	4.5	9.0	µA	3.0	
		—	5.2	11.0	µA	3.6	
D018		—	2.4	6.7	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +125°C
		—	4.2	9.2	µA	3.0	
		—	4.8	11.5	µA	3.6	
D018A		—	2.4	6.0	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +85°C
		—	4.2	8.5	µA	3.0	
		—	4.8	10.5	µA	3.6	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: FVR and BOR are disabled.

TABLE 22-3: POWER-DOWN CURRENTS (I_{PD})

PIC16LF1904/6/7		Standard Operating Conditions (unless otherwise stated)						
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
	Power-down Base Current (I_{PD})(2)							
D023		—	0.15	1.0	3.0	µA	1.8	WDT, BOR, FVR, and T1OSC disabled, all Peripherals Inactive
		—	0.16	2.0	4.0	µA	3.0	
		—	0.65	3.0	5.0	µA	3.6	
D024		—	0.27	2.0	4.0	µA	1.8	WDT Current **(Note 1)**
		—	0.56	3.0	5.0	µA	3.0	
		—	0.75	4.0	6.0	µA	3.6	
D025		—	17.5	31	35	µA	1.8	FVR current
		—	17.7	33	38	µA	3.0	
		—	17.8	35	41	µA	3.6	
D026		—	0.15	2.30	3.56	µA	3.0	LPBOR current
		—	0.21	3.40	4.70	µA	3.6	
D027		—	7.0	10	12	µA	3.0	BOR Current
		—	7.5	12	14	µA	3.6	
D028		—	0.50	2.0	4.0	µA	1.8	T1OSC Current
		—	0.60	3.0	5.0	µA	3.0	
		—	0.70	4.0	6.0	µA	3.6	
D029		—	0.40	2.0	4.0	µA	1.8	ADC Current **(Note 1, Note 3)**, no conversion in progress
		—	0.70	3.0	5.0	µA	3.0	
		—	0.90	4.0	6.0	µA	3.6	
D030		—	—	250	—	µA	1.8	ADC Current **(Note 1, Note 3)**, conversion in progress
		—	—	250	—	µA	3.0	
		—	—	250	—	µA	3.6	
D031	LCD Bias Ladder							
	Low power	—	1	2	6	µA	1.8	
	Medium Power	—	10	13	21	µA	3.0	
	High Power	—	100	111	120	µA	3.6	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{DD} or I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD}.

3: A/D oscillator source is FRC.

TABLE 22-4: I/O PORTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
	VIL	**Input Low Voltage**					
		I/O PORT:					
D032		with TTL buffer	—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 3.6V
D033		with Schmitt Trigger buffer	—	—	0.2 VDD	V	1.8V ≤ VDD ≤ 3.6V
D034		$\overline{MCLR}$, OSC1	—	—	0.2 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:					
D040		with TTL buffer	0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 3.6V
D041		with Schmitt Trigger buffer	0.8 VDD	—	—	V	1.8V ≤ VDD ≤ 3.6V
D042		$\overline{MCLR}$	0.8 VDD	—	—	V	
	IIL	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance @ 85°C
				± 5	± 1000	nA	125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD @ 85°C
	IPUR	**Weak Pull-up Current**					
D070*			25	100	200	µA	VDD = 3.3V, VPIN = VSS
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL = 6mA, VDD = 3.3V IOL = 1.8mA, VDD = 1.8V
	VOH	**Output High Voltage**					
D090		I/O ports	VDD - 0.7	—	—	V	IOH = 3mA, VDD = 3.3V IOH = 1mA, VDD = 1.8V
		Capacitive Loading Specs on Output Pins					
D101*	CIO	All I/O pins	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

TABLE 22-5: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Program Memory Programming Specifications					
D110	VIHH	Voltage on $\overline{MCLR}$/VPP/RE3 pin	8.0	—	9.0	V	**(Note 2)**
D111	IDDP	Supply Current during Programming	—	—	10	mA	
D112		VDD for Bulk Erase	2.7	—	VDD max.	V	
D113	VPEW	VDD for Write or Row Erase	VDD min.	—	VDD max.	V	
D114	IPPPGM	Current on $\overline{MCLR}$/VPP during Erase/Write	—	—	1.0	mA	
D115	IDDPGM	Current on VDD during Erase/Write	—		5.0	mA	
		Program Flash Memory					
D121	EP	Cell Endurance	1K	10K	—	E/W	-40°C to +85°C (**Note 1**)
D122	VPR	VDD for Read	VDD min.	—	VDD max.	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Required only if single-supply programming is disabled.

TABLE 22-6: THERMAL CONSIDERATIONS

Standard Operating Conditions (unless otherwise stated)					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θ_{JA}	Thermal Resistance Junction to Ambient	60	°C/W	28-pin SPDIP package
			80	°C/W	28-pin SOIC package
			90	°C/W	28-pin SSOP package
			27.5	°C/W	28-pin UQFN 4x4mm package
			47.2	°C/W	40-pin PDIP package
			41.0	°C/W	40-pin UQFN 5x5mm package
			46.0	°C/W	44-pin TQFP package
TH02	θ_{JC}	Thermal Resistance Junction to Case	31.4	°C/W	28-pin SPDIP package
			24	°C/W	28-pin SOIC package
			24	°C/W	28-pin SSOP package
			24	°C/W	28-pin UQFN 4x4mm package
			24.7	°C/W	40-pin PDIP package
			50.5	°C/W	40-pin UQFN 5x5mm package
			14.5	°C/W	44-pin TQFP package
TH03	T_{JMAX}	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	$PD = P_{INTERNAL} + P_{I/O}$
TH05	$P_{INTERNAL}$	Internal Power Dissipation	—	W	$P_{INTERNAL} = I_{DD} \times V_{DD}$ (1)
TH06	$P_{I/O}$	I/O Power Dissipation	—	W	$P_{I/O} = \Sigma (I_{OL} * V_{OL}) + \Sigma (I_{OH} * (V_{DD} - V_{OH}))$
TH07	P_{DER}	Derated Power	—	W	$P_{DER} = P_{DMAX} (T_J - T_A)/\theta_{JA}$ (2)

Note 1: I_{DD} is current to run the chip alone without driving any load on the output pins.
2: T_A = Ambient Temperature
3: T_J = Junction Temperature

22.3 AC Characteristics

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

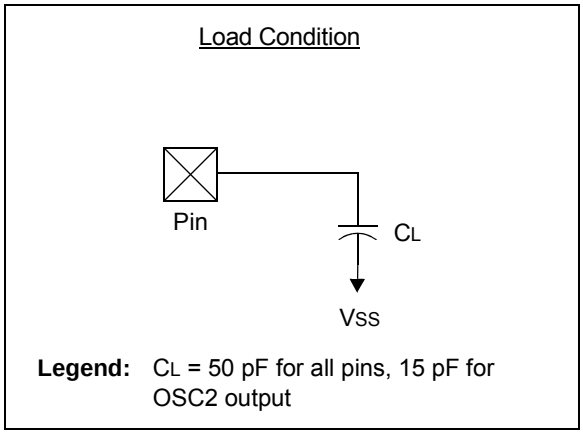
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 22-4: LOAD CONDITIONS



Legend: CL = 50 pF for all pins, 15 pF for OSC2 output

TABLE 22-7: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS01	FOSC	External CLKIN Frequency(1)	DC	—	0.5	MHz	External Clock (ECL)
			DC	—	4	MHz	External Clock (ECM)
			DC	—	20	MHz	External Clock (ECH)
OS02	TOSC	External CLKIN Period(1)	50	—	∞	ns	External Clock (EC)
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

TABLE 22-8: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated)								
Param. No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±8%	—	16	—	MHz	0°C ≤ TA ≤ +85°C
			±6.5%	—	16	—	MHz	VDD = 3.0V @ +25°C
OS10A*	TIOSC ST	HFINTOSC 16 MHz	—	—	5	15	µs	VDD = 2.0V, -40°C to +85°C
		Oscillator Wake-up from Sleep Start-up Time	—	—	5	15	µs	VDD = 3.0V, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

FIGURE 22-5: CLKOUT AND I/O TIMING

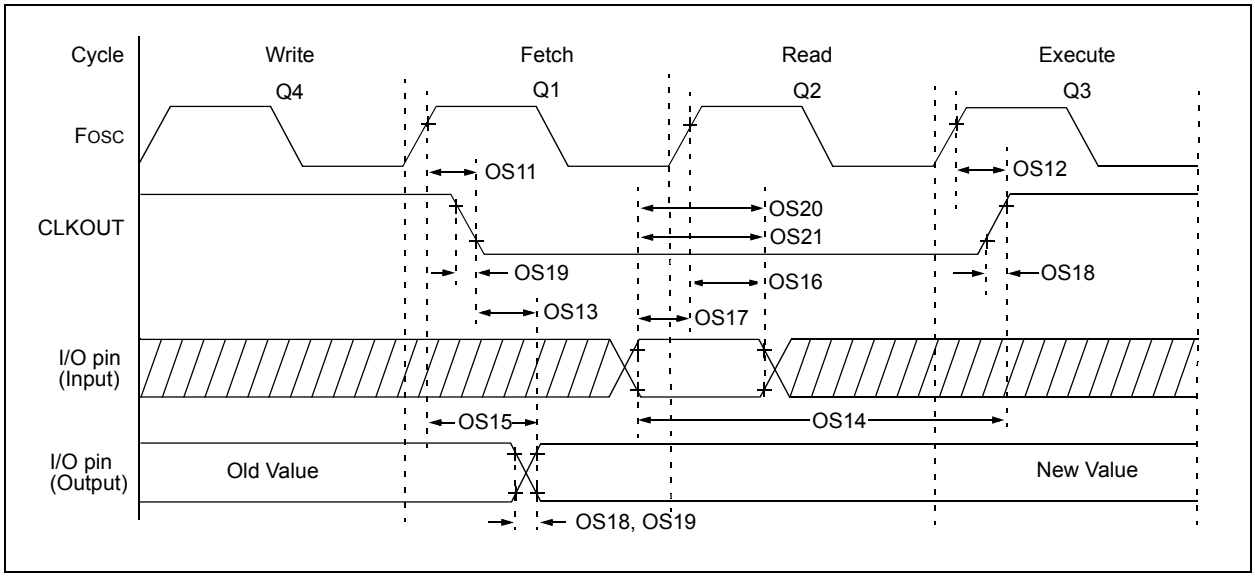


TABLE 22-9: CLKOUT AND I/O TIMING PARAMETERS

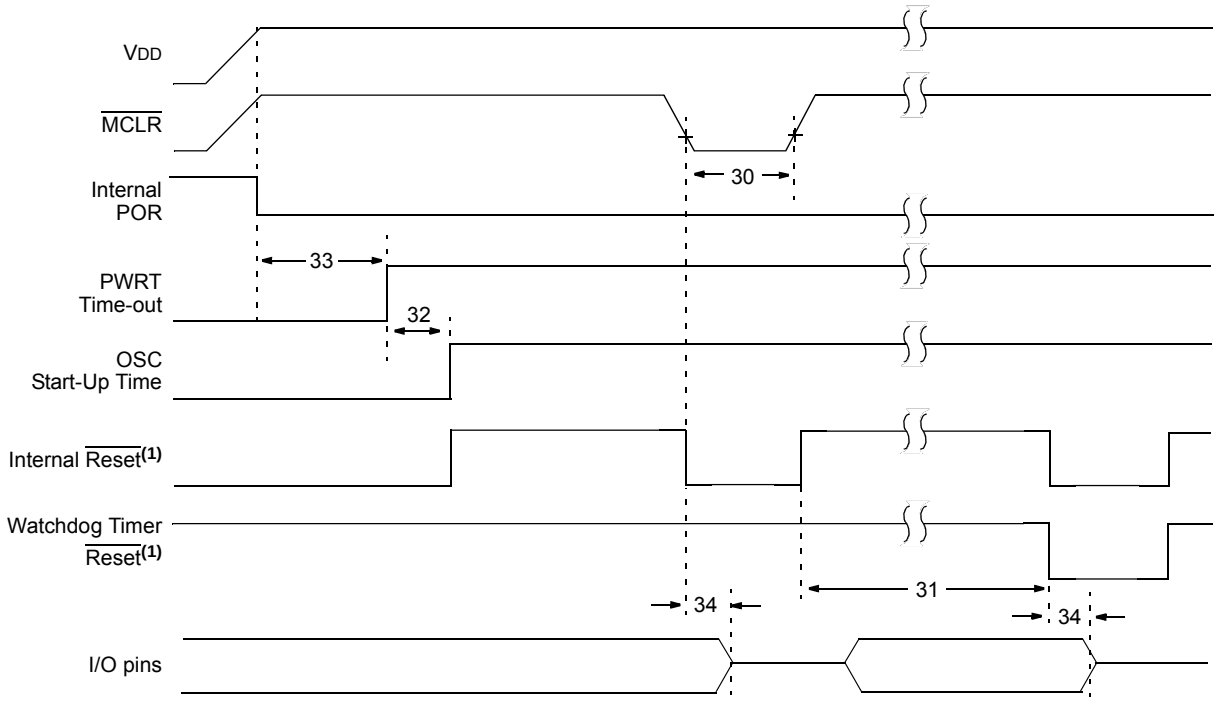
Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18	TioR	Port output rise time	— —	40 15	72 32	ns	VDD = 1.8V VDD = 3.3-5.0V
OS19	TioF	Port output fall time	— —	28 15	55 30	ns	VDD = 1.8V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

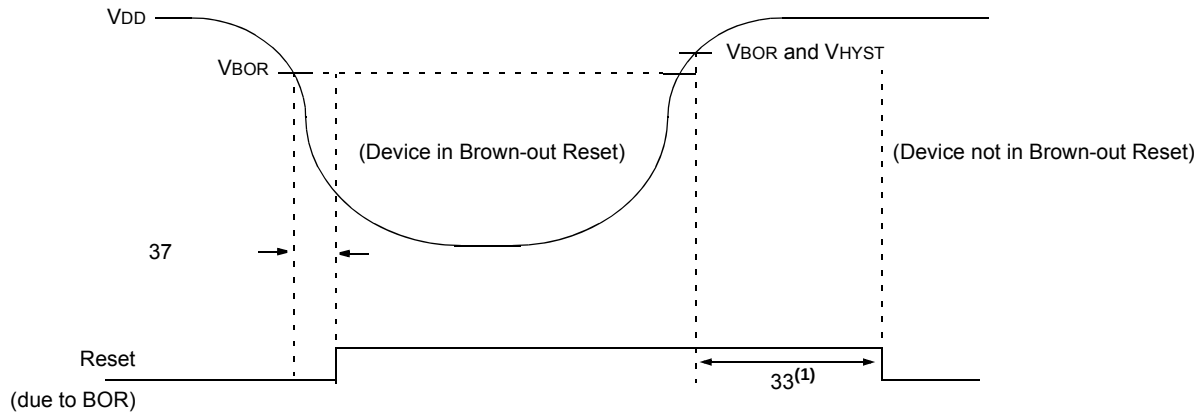
Note 1: Measurements are taken in EC mode where CLKOUT output is 4 x TOSC.

FIGURE 22-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note 1: Asserted low.

FIGURE 22-7: BROWN-OUT RESET TIMING AND CHARACTERISTICS



Note 1: 64 ms delay only if $\overline{\text{PWRTE}}$ bit in the Configuration Word register is programmed to '0'.
2 ms delay if $\overline{\text{PWRTE}}$ = 0 and VREGEN = 1.

FIGURE 22-8: MINIMUM PULSE WIDTH FOR LPBOR DETECTION

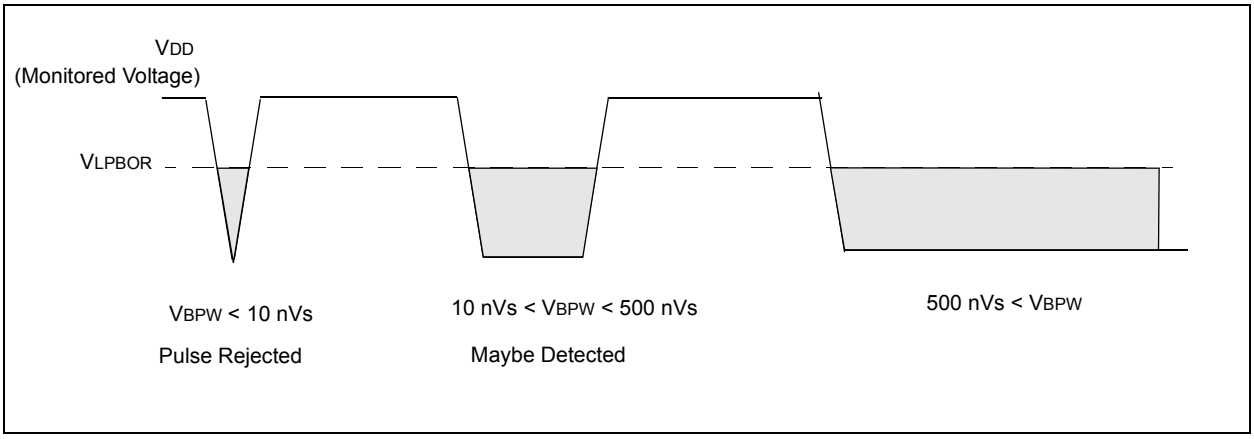


TABLE 22-10: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{MCLR}$ Pulse Width (low)	2 5	— —	— —	µs µs	VDD = 3.0V, -40°C to +85°C VDD = 3.0V
31	FWDTLP	Low Frequency Internal Oscillator Frequency	19	33	52	kHz	
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	Tosc	**(Note 2)**
33*	TPWRT	Power-up Timer Period, $\overline{PWRTE}$ = 0	—	2048	—	Tosc	Clocked by LFINTOSC
34*	TIOZ	I/O High-Impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	—	2.0	µs	
35	VBOR	Brown-out Reset Voltage: BORV = 0 BORV = 1	2.55 1.80	2.70 1.90	2.85 2.05	V V	
35A*	VHYST	Brown-out Reset Hysteresis	25 —	50 —	75 100	mV mV	-40°C to +85°C -40°C to +125°C
35B*	TBORDC	Brown-out Reset DC Response Time	1 —	3 —	5 10	µs µs	VDD ≤ VBOR, -40°C to +85°C VDD ≤ VBOR
35C	TBORAC	Brown-out Reset AC Response Time	—	100	—	ns	Transient Response immunity for a noise spike that goes from VDD to VSS and back with 10 ns rise and fall times. Guidance only.
36	TFVRS	Fixed Voltage Reference Turn-on Time	—	—	5	µs	Turn on to specified stability
37	VLPBOR	Low-Power Brown-out Reset Voltage	1.85	1.95	2.10	V	-40°C to +85°C
38*	VZPHYST	Zero-Power Brown-out Reset Hysteresis	0	25	60	mV	-40°C to +85°C
39*	TZPBPW	Zero-Power Brown-out Reset AC Response Time for BOR detection	10	—	500	nVs	VDD ≤ VBOR, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Period of the slower clock.

3: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

FIGURE 22-9: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

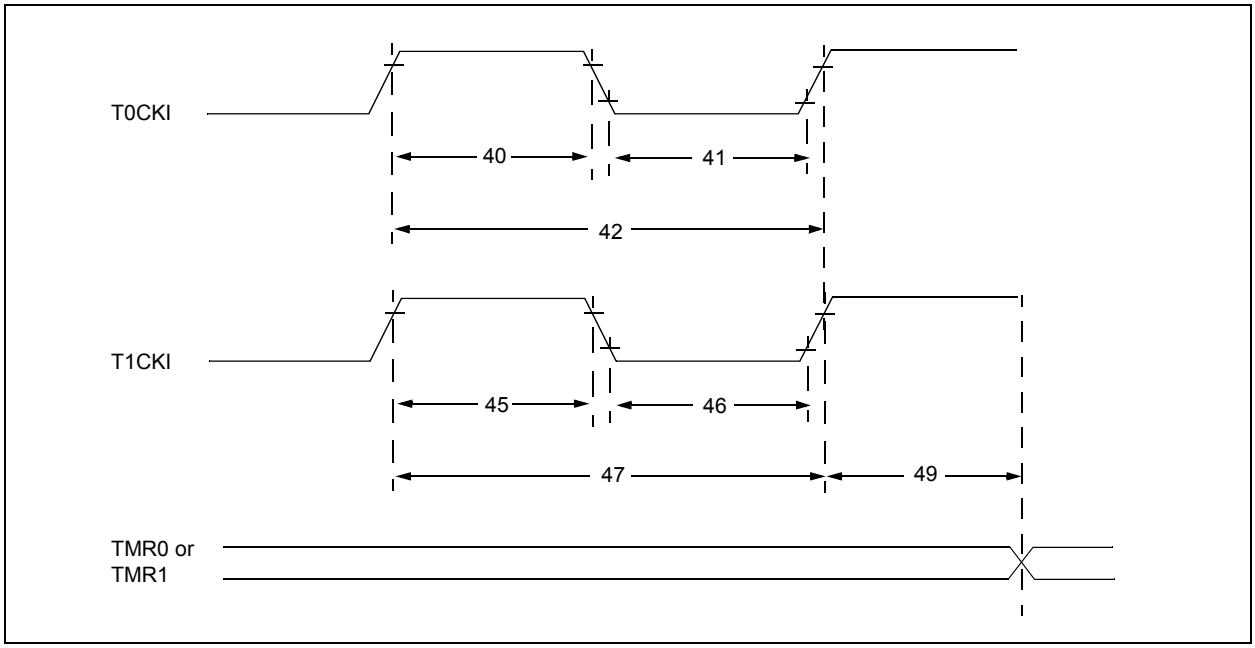


TABLE 22-11: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or TCY + 40 N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or TCY + 40 N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
48	FT1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 22-12: PIC16LF1904/6/7 A/D CONVERTER (ADC) CHARACTERISTICS:

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10	bit	
AD02	EIL	Integral Error	—	±1	±1.7	LSb	VREF = 3.0V
AD03	EDL	Differential Error	—	±1	±1	LSb	No missing codes VREF = 3.0V
AD04	EOFF	Offset Error	—	±1	±2	LSb	VREF = 3.0V
AD05	EGN	Gain Error	—	±1	±1.5	LSb	VREF = 3.0V
AD06	VREF	Reference Voltage(3)	1.8	—	VDD	V	VREF = (VRPOS - VRNEG)
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	Can go higher if external 0.01µF capacitor is present on input pin.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF, VDD pin or FVREF, whichever is selected as reference input.

4: When ADC is off, it will not consume any current other than leakage current. The power-down current specification includes any such leakage from the ADC module.

TABLE 22-13: PIC16LF1902/3 A/D CONVERSION REQUIREMENTS

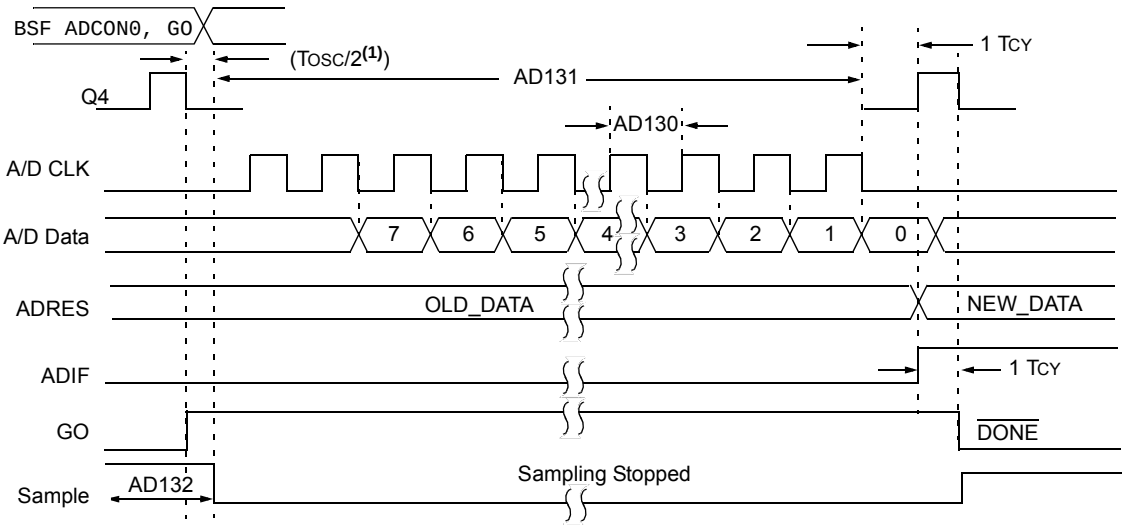
Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	ADC Clock Period (TADC)	1.0	—	6.0	µs	FOSC-based
		ADC Internal FRC Oscillator Period (TFRC)	1.0	2.0	6.0	µs	ADCS<2:0> = x11 (ADC FRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	5.0	—	µs	
AD133*	THCD	Holding Capacitor Disconnect Time	— —	1/2 TAD 1/2 TAD + 1TCY	— —		FOSC-based ADCS<2:0> = x11 (ADC FRC mode)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

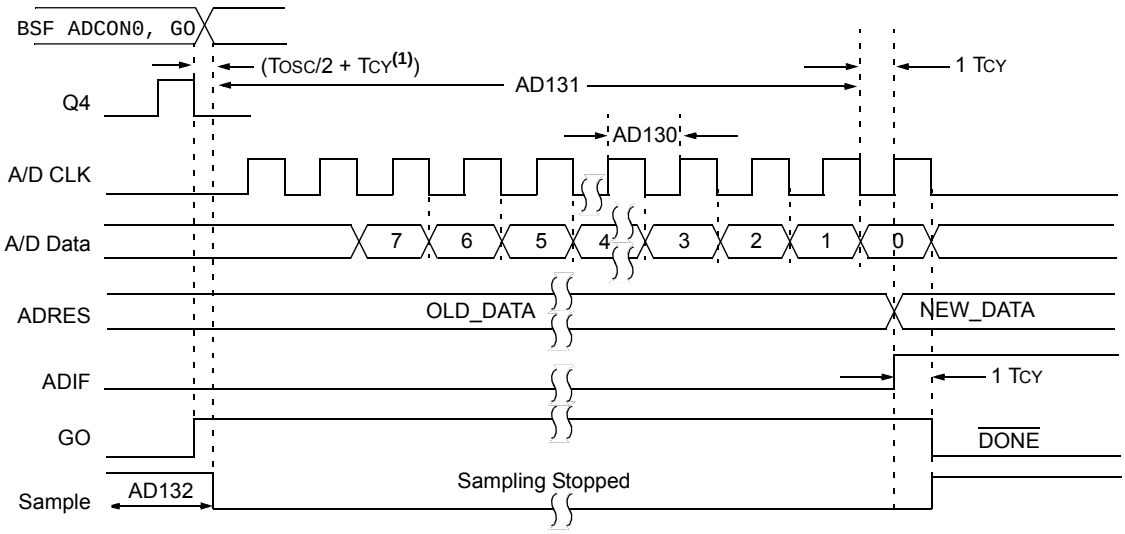
Note 1: The ADRES register may be read on the following TCY cycle.

FIGURE 22-10: PIC16LF1904/6/7 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 22-11: PIC16LF1904/6/7 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

23.0 DC AND AC CHARACTERISTICS GRAPHS AND CHARTS

Graphs and charts are not available at this time.

24.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

24.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

24.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

24.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

24.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

24.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

24.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

24.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

24.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

24.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

24.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

24.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

24.12 Third-Party Development Tools

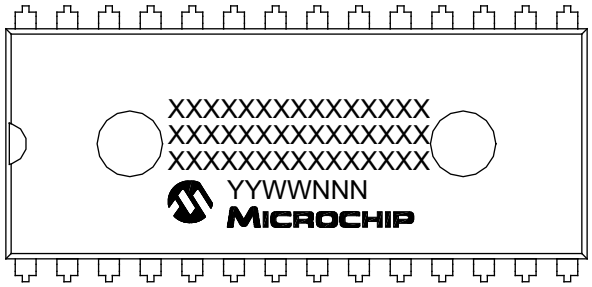
Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

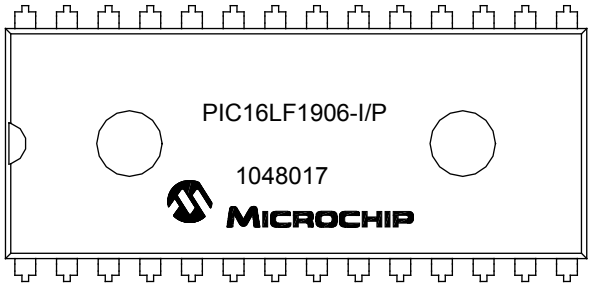
25.0 PACKAGING INFORMATION

25.1 Package Marking Information

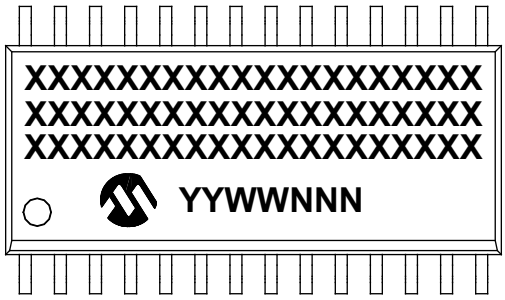
28-Lead PDIP (600 mil)



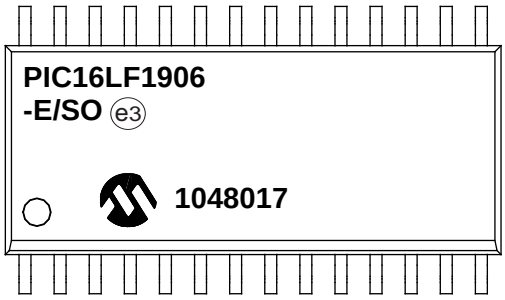
Example



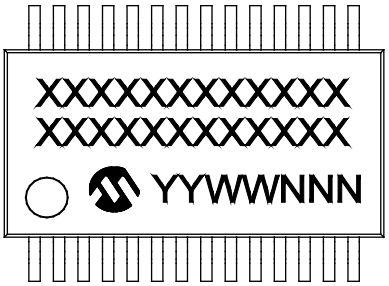
28-Lead SOIC (7.50 mm)



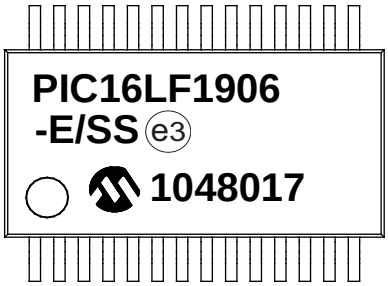
Example



28-Lead SSOP (5.30 mm)



Example

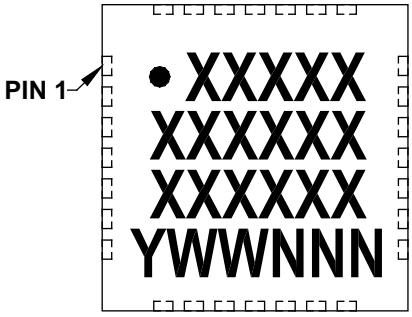


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

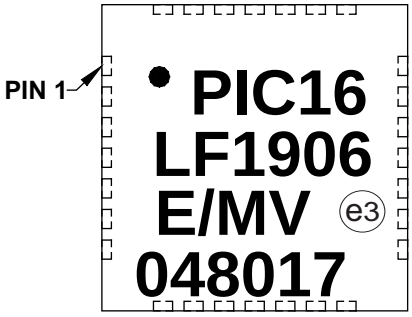
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

Package Marking Information (Continued)

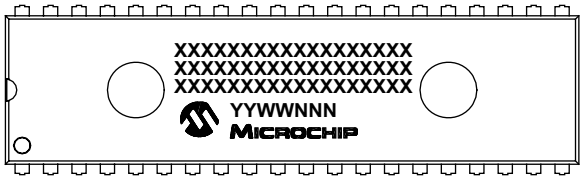
28-Lead UQFN (4x4x0.5 mm)



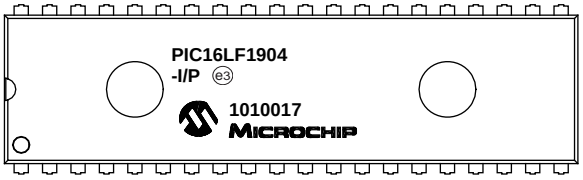
Example



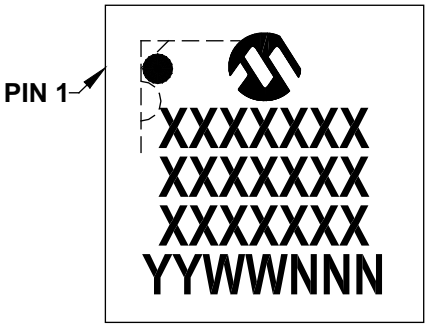
40-Lead PDIP (600 mil)



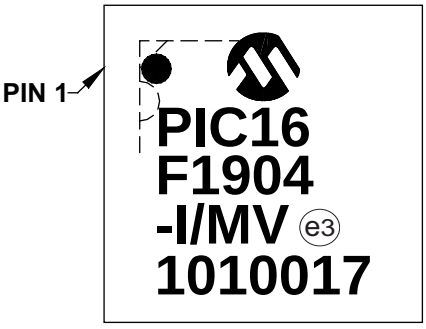
Example



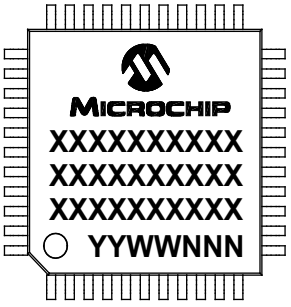
40-Lead UQFN (5x5x0.5 mm)



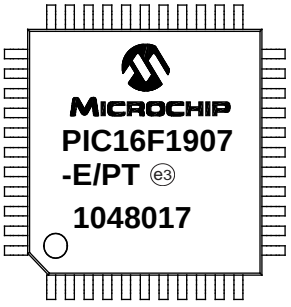
Example



44-Lead TQFP (10x10x1 mm)



Example

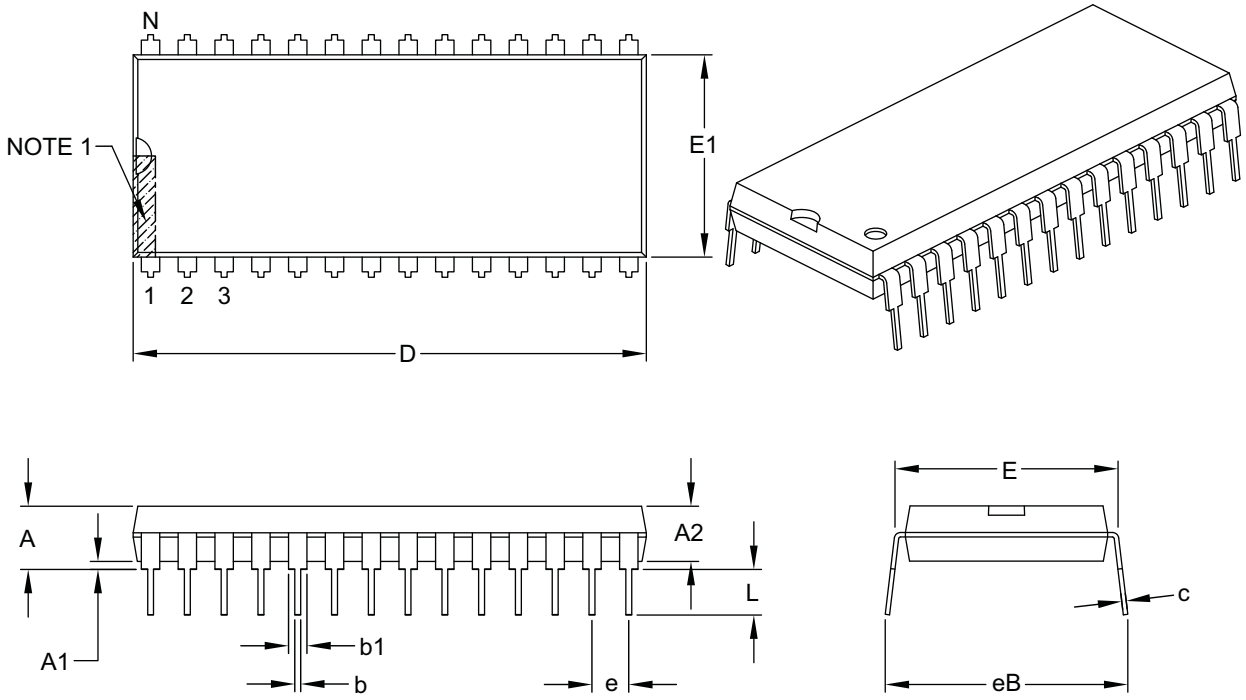


25.2 Package Details

The following sections give the technical details of the packages.

28-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.380	–	1.565
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.022
Overall Row Spacing §	eB	–	–	.700

Notes:

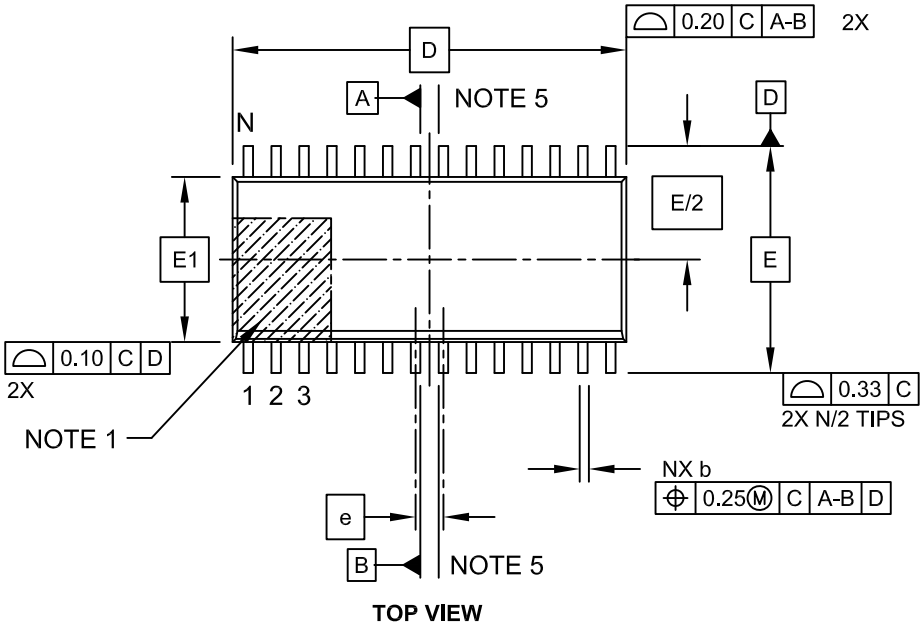
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

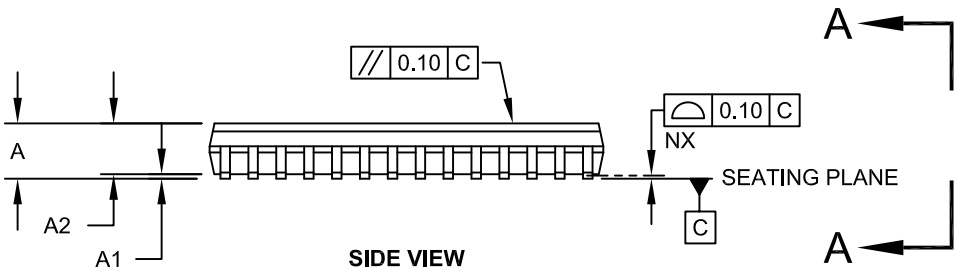
Microchip Technology Drawing C04-079B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

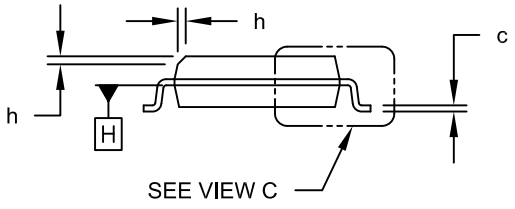
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

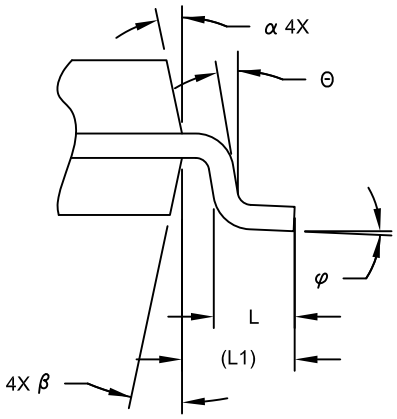


VIEW A-A

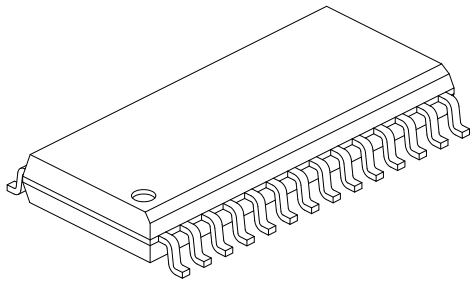
Microchip Technology Drawing C04-052C Sheet 1 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

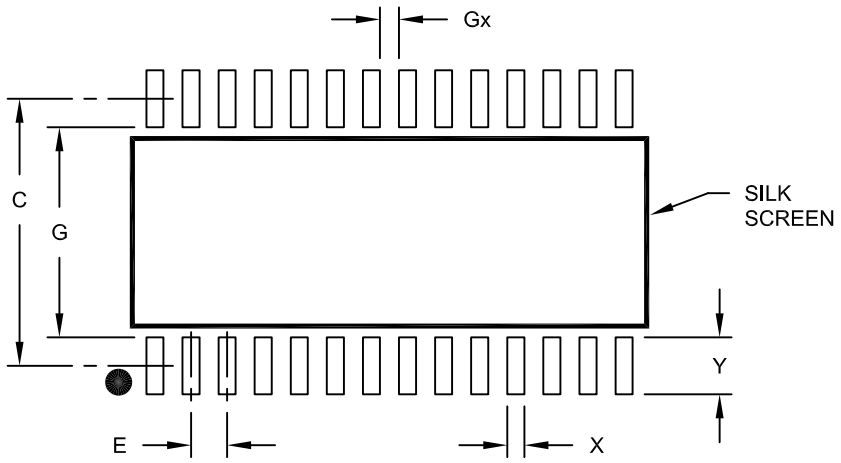
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

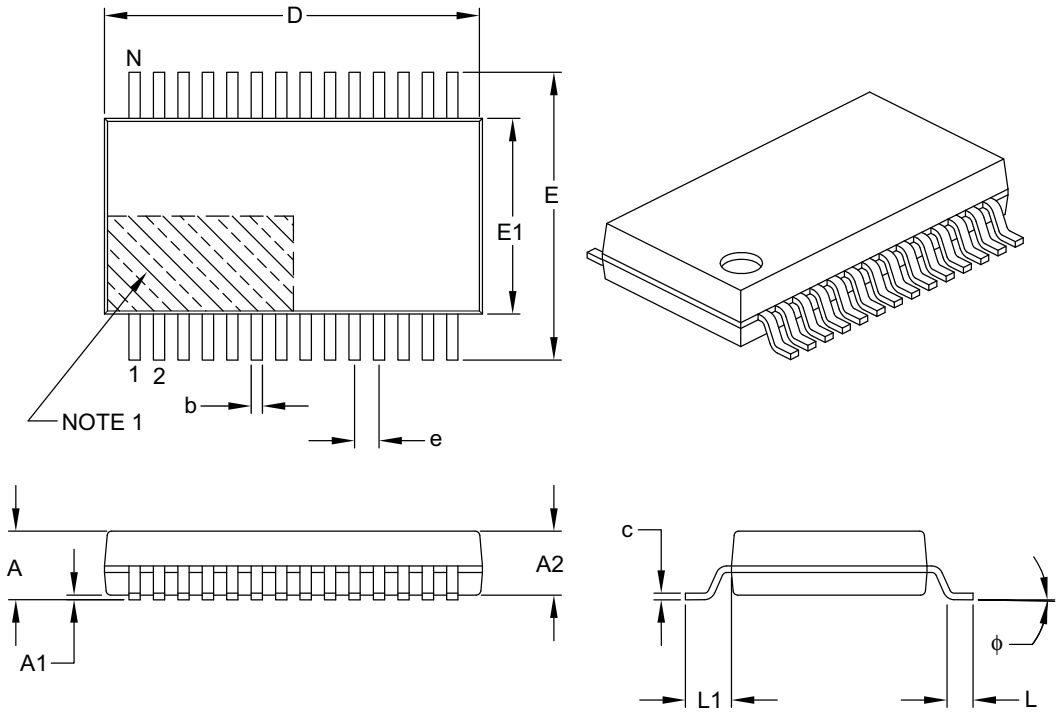
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

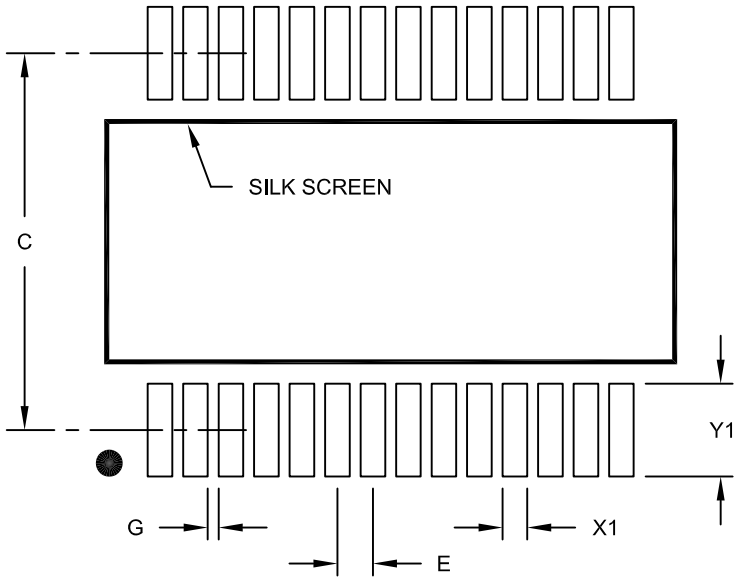
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

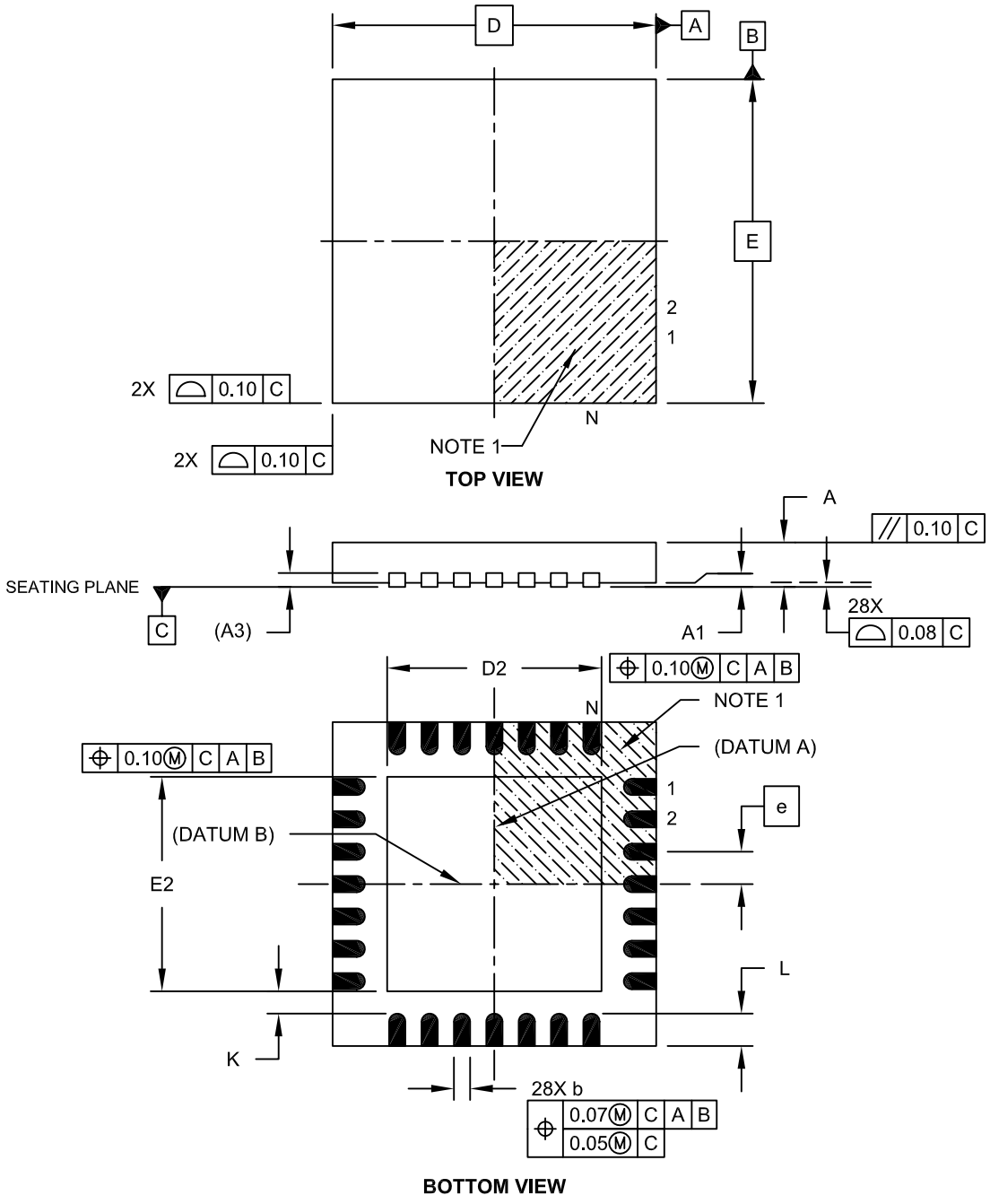
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

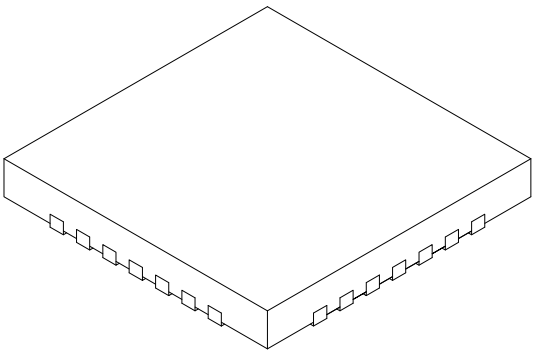
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-152A Sheet 1 of 2

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.55	2.65	2.75
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.55	2.65	2.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

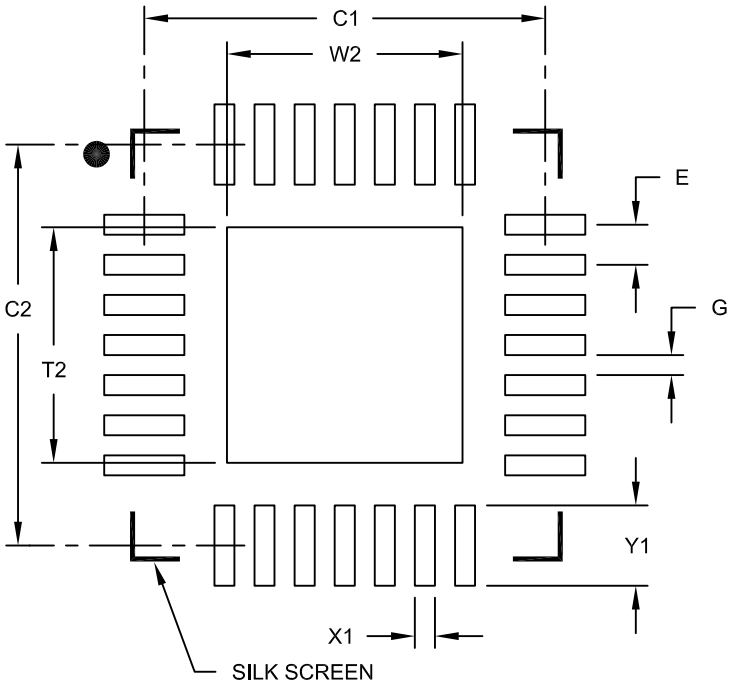
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-152A Sheet 2 of 2

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 4x4 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			2.35
Optional Center Pad Length	T2			2.35
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

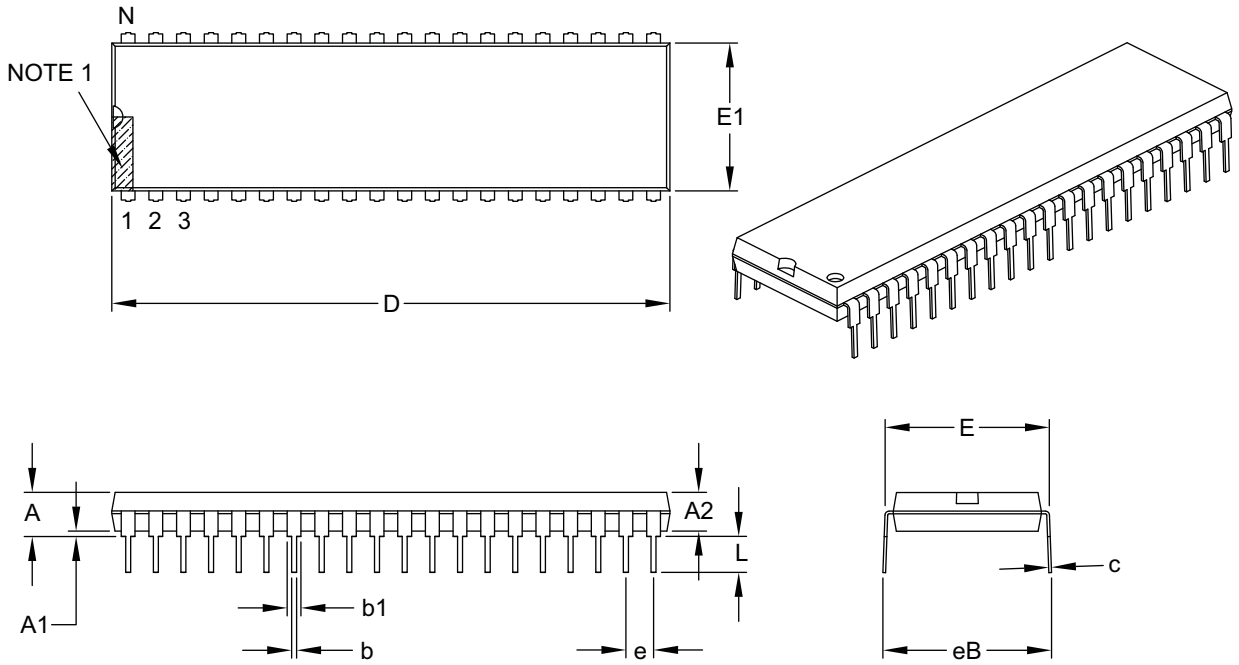
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2152A

40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

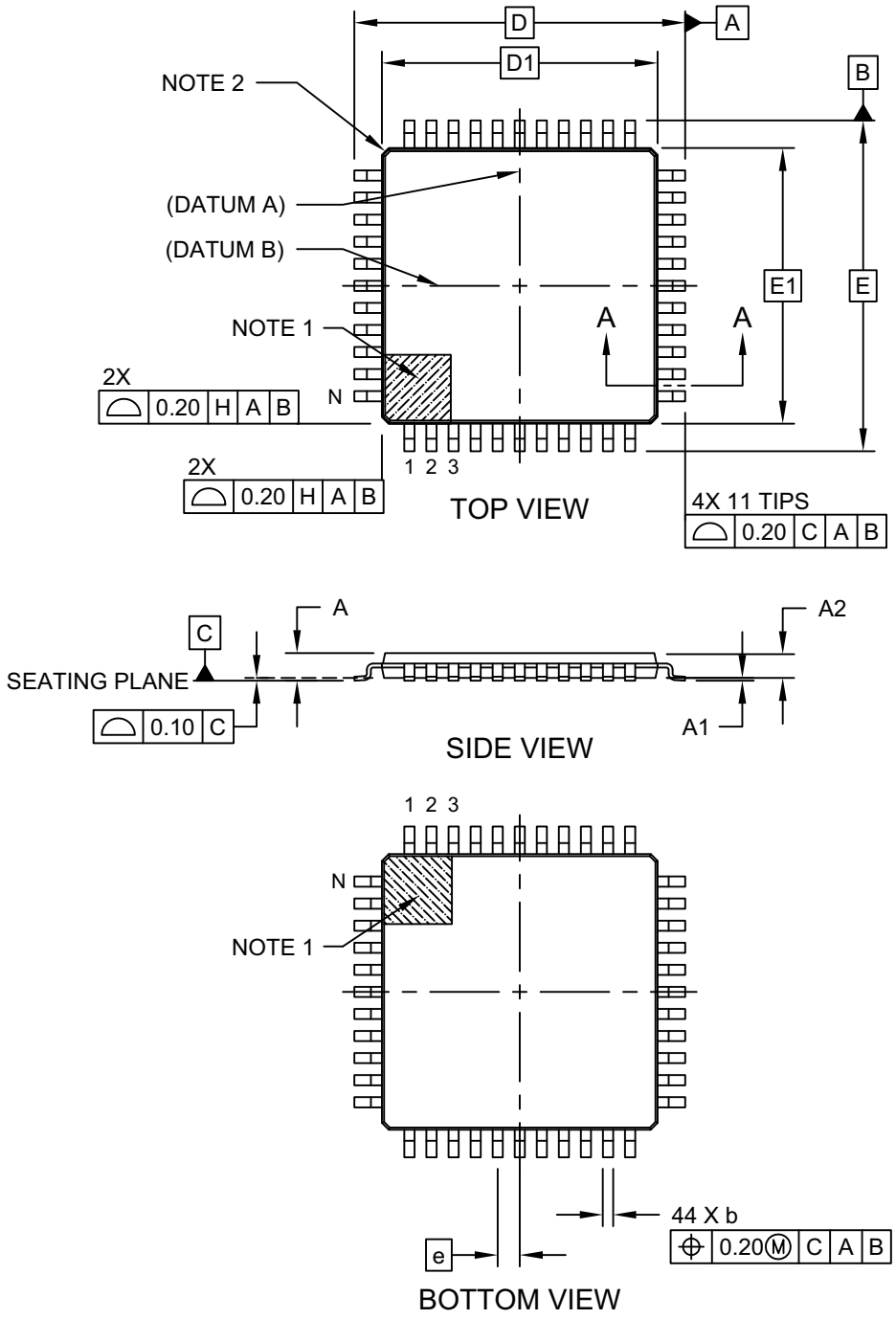
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B

44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

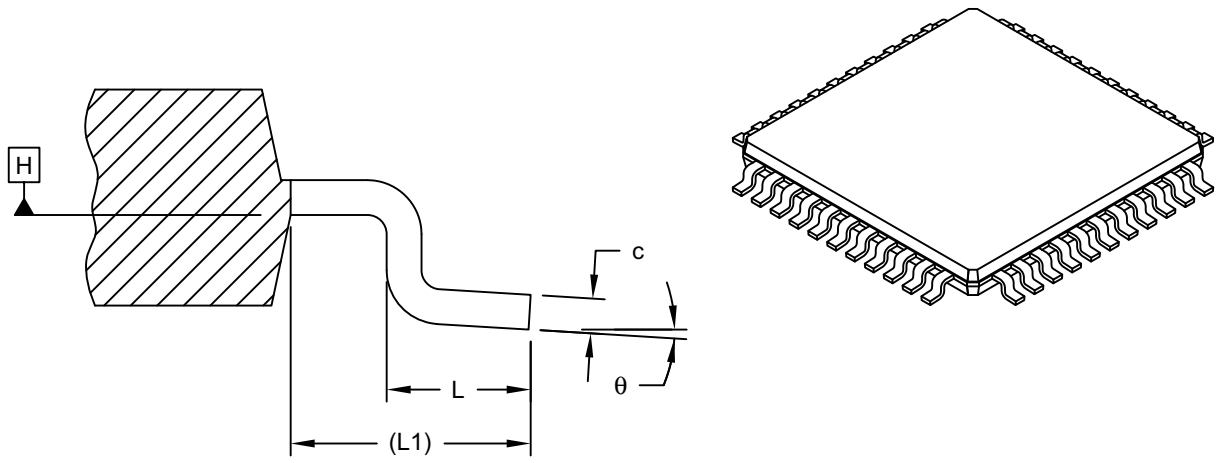
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-076C Sheet 1 of 2

44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Width	E		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Width	b	0.30	0.37	0.45
Lead Thickness	c	0.09	-	0.20
Lead Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	θ	0°	3.5°	7°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Exact shape of each corner is optional.
3. Dimensioning and tolerancing per ASME Y14.5M

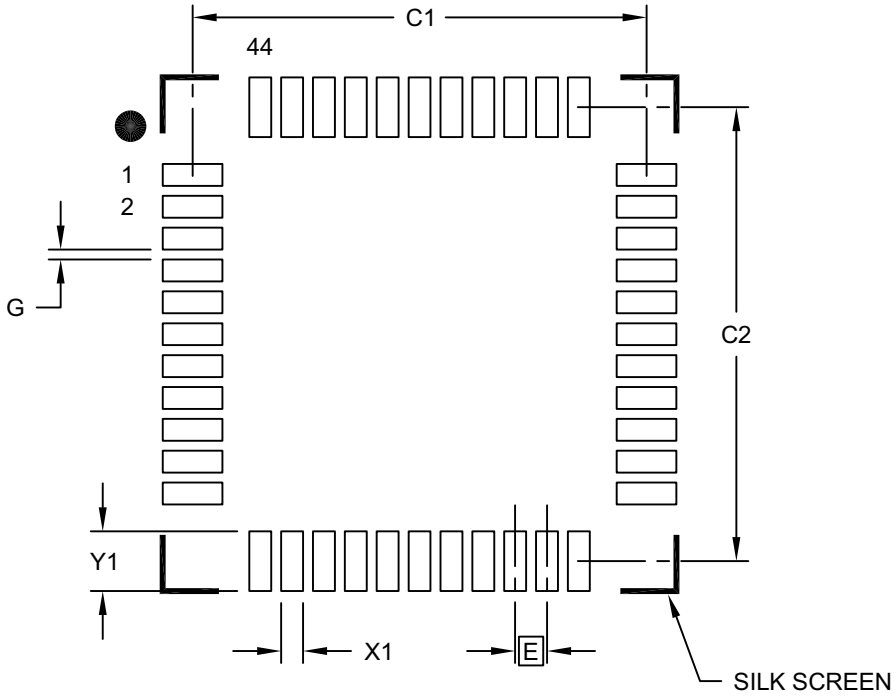
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076C Sheet 2 of 2

44-Lead Plastic Thin Quad Flatpack (PT) - 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

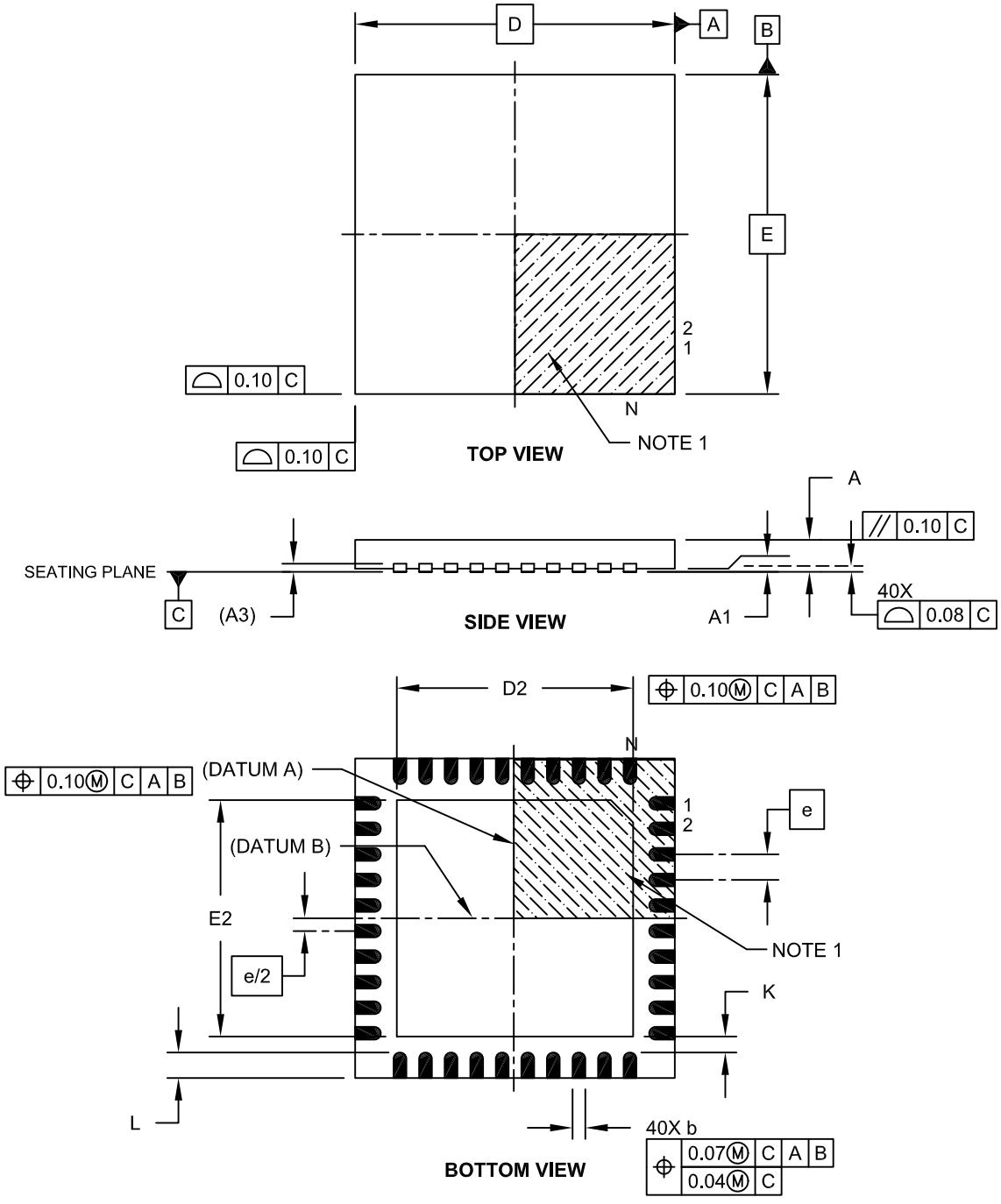
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

40-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) – 5x5x0.5 mm Body [UQFN]

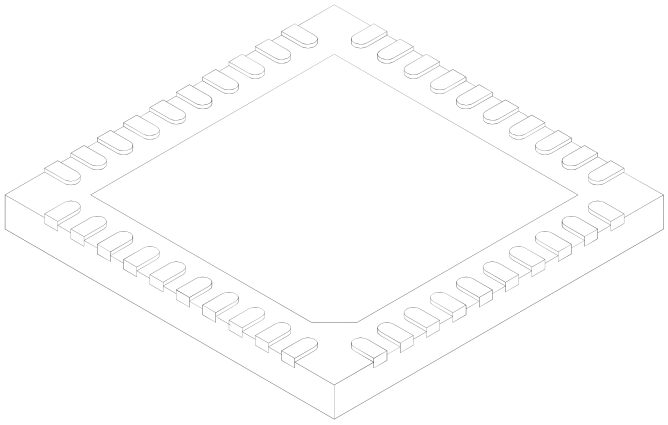
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-156A Sheet 1 of 2

40-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) – 5x5x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.70	3.80
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.70	3.80
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

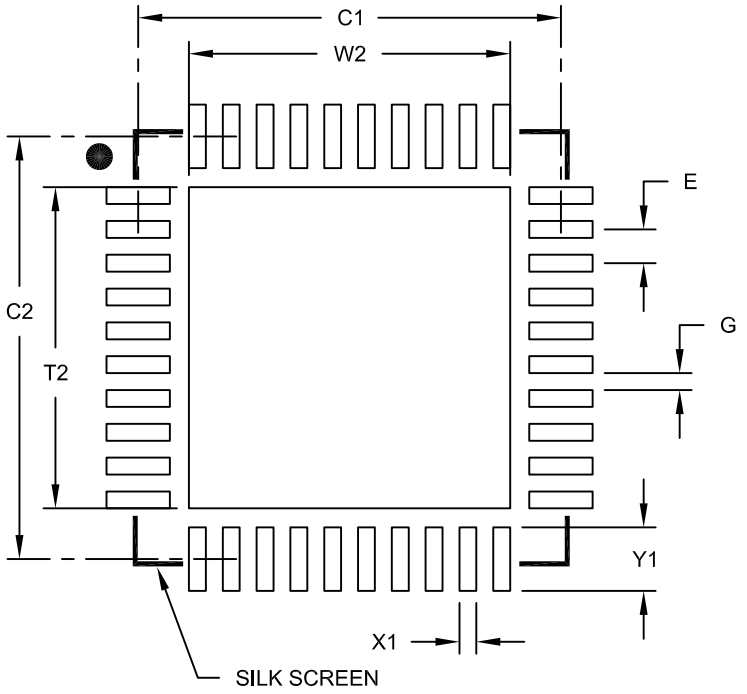
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-156A Sheet 2 of 2

40-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) - 5x5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			3.80
Optional Center Pad Length	T2			3.80
Contact Pad Spacing	C1		5.00	
Contact Pad Spacing	C2		5.00	
Contact Pad Width (X40)	X1			0.20
Contact Pad Length (X40)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2156B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (03/2011)

Original release.

Revision B (08/2014)

Added Tables 9-3 and 9-4.

Updated PIC16LF190X Family Types Table.

Updated Equation 15-1; Example 3-2; Figures 1 through 5, 6-4, 15-1, 15-4, 19-7 22-2, 22-8; Registers 4-1, 4-2, 11-17, 15-1; Sections 4.1, 6.2.2.2, 10.0, 13.0, 15.1.3, 18.1.1.2, 18.1.1.3, 18.1.1.7, 18.1.2.9, 18.1.2.10, 18.2, 18.4.1.2, 19.1, 19.4.5, 22.0, 22.1, 22.5, 22.6, 22.7, 22-8, 22-10; Tables 1, 3-1, 3-3, 3-5, 5-1, 9-2, 10-3, 10-4, 17-2, 19-1, 22-2, 22-3, 22-4, 22-5, 22-6, 22-7, 22-8, 22-12.

Updated Package Marking Information.

Removed Section 18.1.2.3: Receive Data Polarity and Section 18.4.1.4: Data Polarity.

Data sheet went from Preliminary to Final data sheet.

Revision C (01/2016)

Added ‘Memory’ section and updated the ‘PIC16LF190X Family Types’ table; Other minor corrections.

Revision D (05/2016)

Minor changes to Figure 22-2, Table 22-8, and Table 22-10, in Electrical Specifications chapter; Updated Packaging: 28L SOIC, 44L TQFP, 28L UQFN, 40L UQFN. Removed Table 19-7, LCD Worksheet.

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PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16LF1904, PIC16LF1906, PIC16LF1907	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:	MV P PT SO SS	= UQFN (4x4x0.5) = PDIP = TQFP (44-pin) = SOIC = SSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16LF1904T - I/MV 301
Tape and Reel,
Industrial temperature,
UQFN package,
QTP pattern #301

b) PIC16LF1906 - I/P
Industrial temperature
PDIP package

c) PIC16LF1906 - E/SS
Extended temperature,
SSOP package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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